HP ScanJet Pro N4000 snw1 Sheetfeed Scanner

Get fast, two-sided scans in a single pass—recommended for 4000 pages per day.

Fast, affordable, and designed to handle everything from simple color jobs to complex workflows. Quickly and reliably digitize larger projects with scan speeds up to 40 ppm/80 ipm and a 50-page ADF.¹ Recommended for 4,000 pages per day.











Fast scanning. Superb results. Every page.

- Produce scans at up to 40 ppm/80 ipm¹ with two-sided scanning that captures both sides at once.
- Wi-Fi Direct enables scanning from a wireless mobile device without requiring a connection to a network or the internet.
- Capture every page easily—even stacks of mixed media—with HP $\mathsf{EveryPage}$ and an ultrasonic sensor.^3
- Rely on this scanner time after time—recommended for 4000 pages per day.

Optimize workflows with one-touch scanning

- Streamline routine work with one-touch scanning—create one-button, custom settings for recurring scan jobs.
- Scan images directly into applications with included and full-featured TWAIN and ISIS[®].
 Easily transfer scans into editable text, searchable PDF files, and more file types, using
- built-in OCR.Quickly share or archive scans directly to popular cloud destinations with HP Scan software.

Capture business documents like a pro

- Tackle tasks quickly and easily with the simple 2.8" color touchscreen
 - Define scan profiles for common document types, and scan to multiple destinations with HP Scan software.
- Capture and organize documents, business cards, and other file types with feature-rich software.
- Produce clear, legible scans—up to 1,200-dpi resolution.





Technical specifications

Scan	
Color scanning	Yes
Scan speed ³	ADF: Up to 40 ppm / 80 ipm
Scan type / Technology ³	Sheetfed / CMOS CIS (Contact Image Sensor)
Scan resolution	Hardware: 600 × 600 dpi; Optical: Up to 600 dpi
Scan file format	For text & images: PDF, PDF/A, Encrypted PDF, JPEG, PNG, BMP, TIFF, Word, Excel, PowerPoint Text (.txt), Rich Text (.rtf) and Searchable PDF
Scan input modes	7.1 cm (2.8 inch) Color touch screen on front-panel for HP scan in Win OS, HP Easy Scan/ICA in Mac OS and third parties applications via TWAIN, ISIS and WIA
Scan Size	ADF: 8.5 x 122 in Maximum; 2 x 2 in Minimum
Scanner advanced features	Auto exposure, Auto threshold, Auto detect color, Background smooth/removal, Auto detect size, Straighten content, Enhance content, Multi-streaming, Auto feed, Multi-feed detection sensor, Advanced multi-feed detection, Auto orient, Multi-color dropout, Edge erase, Delete blank page, Barcode, Zonal Dorpes, Hole fill, IPDF permissions, Document separation (Blank page, Barcode, Zonal Darcode, Zonal OCR)
Duplex ADF scanning	Yes
ADF capacity	Standard, 50 sheets
Multi feed detection	Yes
Light source (scanning)	LED
Output resolution dpi settings	75; 150; 200; 240; 300; 400; 500; 600; 1200 ppi
Twain version	Windows: 32-bit and 64-bit TWAIN version 2.1; Mac: n/a
Bit depth / Grayscale levels	24-bit (external), 48-bit (internal)/256
Digital sending standard features	Scan to PC, Scan to USB Drive, Scan to Email, Scan to Network Folder, Scan to SharePoint, Scan to Shortcut, Scan to Cloud
Connectivity	
Standard connectivity	Ethernet 10/100 Base-T, USB 3.0, WiFi 802.11 b/g/n, WiFi Direct
Wireless capability	Yes, WiFi 802.11 b/g/n, WiFi Direct
Memory	Standard:512 MB
Processor speed	ARM-1176 666 MHz /
Duty cycle (daily)	Recommended daily duty cycle: 4000 pages

Media types supported	Cut Sheet Paper, Printed Paper (Laser and ink), Pre-Punched Paper, Bank Checks, Business Cards, Freight Bills, Cardonless forms, Plastic Carrier sheets for easily damaged documents, Previously stapled media with staple removed, Plastic cards (up to 1.24mm)
What's in the box	6FW08A Power cord; Power Adapter; USB Cable; Scanner Engine; Flyers; Install Guide
Product dimensions	W x d x h: 11.8 × 6.8 × 6.1 in; Maximum: 11.8 × 16.2 × 12.2 in
Product weight	6.2 lb
Warranty features	One-year bench limited warranty whole unit replacement, phone and Web support included. Warranty may vary by country as required by law. Go to hp.com/support to learn about HP world-class service and support options in your region.
Energy star certified	Yes
Energy efficiency compliance	CECP; ENERGY STAR [®] 3.0 certified; EPEAT [®] Silver
Control panel	Control panel with a total of four buttons on the right side of the resistive touch panel (sleep/power, home, back, help buttons).
Display description	Resistive, RGB color and 2.8 "touch panel with a resolution of 140 dpi (240 \times 320 dots).
Software included	Windows: HP WIA scan driver, HP TWAIN scan driver (32-bit and 64-bit), HP Scan, HP Scanner Tools Utility, I.R.I.S Readiris Pro, I.R.I.S Cardiris, OpenText ISIS
Compatible operating system	s Microsoft® Windows® (10, 8.1, 7, XP: 32-bit and 64-bit, 2008 R2, 2012 R2, 2016, 2019); MacOS (Catalina 10.15, Mojave 10.14, High Sirrar 10.13); Linux (Ubuntu, Fedora, Debian, RHEL, Linux Mint, Open Suse, Manjaro); Cirix ready
Minimum system requirements	PC: macOS Catalina 10.15,macOS Mojave 10.14, macOS High Sierra 10.13, Microsoft® Windows® 10, 8, 1, 7, XP: 32-bit and 64-bit, 2008 R2, 2012 R2, 2016, 2019, 2 GB available hard disk space, CD-ROM/DVD drive or Internet connection, USB port, Microsoft® Internet Explorer; Mac macOS Catalina 10.15,macOS Mojave 10.14, macOS High Sierra 10.13; 1 GB HD; Internet required; USB
Power ¹	Power supply type: External power adapter; Power requirements: Input Voltage range: 90 - 264 VAC, Rated Frequency: 50 - 60HZ, Worldwide use; Power consumption: 5.9 Watts (ready), 24 Watts (scanning), 1.8 Watts (sleep), 0.1 Watts (auto-off), 0.1 Watts (off)
Acoustics	Acoustic power emissions: 59 (dB), 5.9 (B)
Operating environment	Operating temperature range: 10 to 35°C; Recommended operating temperature: 17.5 to 25°C; Storage temperature range: -40 to 60°C; Non-operating humidity range: ; Operating humidity range: 15 to 80% RH; Recommended humidity operating range: 30% to 70% relative humidity (RH)
Accessories	C9943B HP ADF Cleaning Cloth Package; 70H79A HP Scanlet 2000s2/3000s4/4000snw1 Roller Replacement Kit; 8PA50A HP Scanlet 2000s2/3000s4/4000snw1 Sheet Kit; L2756A HP Scanlet 5000 s4/7000 s3 Roller Replacement Kit
HP Service and Support options	UD3E1E - HP 3 year Standard Exchange Scan Let Pro N4000 Service; UD3E2E - HP 3 year Next Business Day Exchange Scan Let Pro N4000 Service; UD3E3E - HP 3 year Next Business Day Onsite Exchange Scan Let Pro N4000 Service; UD3E4E - HP 3 year Next Business Scan Let Pro N4000 Service; UD3E5PE - HP 1 year Post Warranty Next Business Day Exchange Scan Let Pro N4000 Service; UD3E5PE - HP 1 year Post Warranty Next Business Day Exchange Scan Let Pro N4000 Service; UD3E5PE - HP 1 year Post Warranty Next Business Day Charle Exchange Scan Let Pro N4000 Service; UD3E7PE - HP 1 year Post Warranty Next Business Day Onsite Exchange Scan Let Pro N4000 Service; UD3E7PE - HP 1 year Post Warranty Next Business Day Onsite Scan Let Pro N4000 Service; UD3E7PE - HP 1 year Post Warranty Next Business Day Onsite Printer Pro N4000 Service; UD3E7PE - HP 1 year Post Warranty Next Business Day Onsite Scan Let Pro N4000 Service; UD3E7PE - HP 1 year Post Warranty Next Business Day Onsite Printer Pro N4000 Service; UD3E7PE - HP 1 year Post Warranty Next Business Day Onsite Printer Pro N4000 Service; UD3E7PE - HP 1 year Post Warranty Next Business Day Onsite

Learn more at hp.com

¹ Power requirements are based on the country/region where the printer is sold. Do not convert operating voltages. This will damage the printer and void the product warranty. Power consumption values typicallty based on measurement of 115V device. ² EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. ³ Sheet feed speeds: (All resolutions up to and including 300 ppi). Simplex 40 A-4 pages per minute. Duplex 80 A-4 images per minute



HP ScanJet Pro N4600 fnw1



(20G07A)

Network connected, high-speed flatbed Scanner with HP EveryPage technology.

Boost productivity for professional scanning tasks with the fast, reliable, network connected HP ScanJet Pro, designed forscanning up to 6,000 pages daily. Automate workflows with shortcuts and fast, two-sided scanning from the auto document feeder.





Work-team Productivity.

- Scan up to 80 images (40 pages) per minute¹ with a 100-page, two-sided, single-pass auto document feeder.
- Optimize document workflows. Scan directly to e-mail, network folders, or a PC via Ethernet or WiFi connection.
- Don't wait for warm-up—Instant-on Technology lets you begin scanning quickly.²
- Place the scanner where the work happens. With a compact design that fits on the desktop.

Easy to use.

- Scan a variety of documents including books, magazines, and ID cards from the ADF or the Legal-size flatbed.
- Connect and scan directly to a storage device using the host USB plug.
- Simplify work processes with pre-configured workflows, and powerful editing tools from HP Scan Pro software.
- Scan directly to document applications using HP's full-featured WIA, ISIS and TWAIN support.

Workteam Reliability.

- Capture every page easily, HP EveryPage technology uses ultrasonic sensing to separate pages in the ADF.
- Designed for the productive workteam with high daily volumes of scanning up to 6,000 pages daily.
- Rely on automated scanning from the 100-page automatic document feeder with single-pass two-sided scanning.
- Get sharp, true-to-life scans of documents, graphics, and photos with up to 1200 dpi resolution.

Strong Security.

- Secure with genuine HP boot code signature validation that prevents booting if the code has been altered.
- Worry-free updates, validate and ensure any firmware updates are codesigned, Only authentic HP code is loaded.

Footnotes

¹ Scan speeds measured at 300 dpi (black and white, grayscale, and color). Actual processing speeds may vary depending on scan resolution, network conditions, computer performance, and application software.

² Compared with products that use traditional fusing and cold cathode fluorescent lamp (CCFL) copying.

³ Wireless performance is dependent on physical environment and distance from access point, and may be limited during active VPN connections.

Accessories and services

Maintenance Kit	4T8E5A HP ScanJet A Separation Unit (100,000 pages)
	618J9A HP ScanJet B Roller Unit (100,000 pages)
Service and Support	U35KDE HP 3 year Next Business Day Advanced Exchange Service for ScanJet Pro N4600 U34X1PE HP 1 year Post Warranty Next Business Day Advanced Exchange Service for ScanJet Pro N4600 U34X2PE HP 1 year Post Warranty Onsite Exchange Service for ScanJet Pro N4600

Technical specifications

Control panel	2.8-in (7.11-cm) Touchscreen, Buttons (Power, Back, Home, Help)
Scanner specifications	Scanner type ADF; CIS scanning technology; Flatbed; Scan technology: ADF; Flatbed; Contact Image Sensor (CIS); Scan input modes: Scan front-panel function : Scan to Computer, Scan to E-mail, Scan Network Folder, Scan to Share Folder, Scan to USB Drive and Everyday Scan. HP Scan in Win OS, HP Easy Scan/ICA in Mac OS and THIRD parties applications via TWAIN.; Twain version: Version 2.4; Colou scanning. Yes; Output resolution dpi settings: 75, 150; 200; 240; 300; 400; 500; 1200 ppi; Image scaling or enlargement range: Will not perform any arbitrary scaling
Scan Size	ADF: 216 x 5362 mm Maximum; 89 x 148 mm Minimum; Flatbed: 216 x 356 mm
Scan speed ²	Up to 40 ppm/80 ipm (b&w, gray and color, 300 dpi)
Scan resolution	Optical Up to 600 dpi (color and mono, ADF); Up to 1200 dpi (color and mono, flatbed); Hardware: Up to 600 x 600 dpi (color and mono, ADF); Up to 1200 x 1200 dpi (color and mono, flatbed)
Scan file format	For text and image pages : PDF, JPEG, PNG, BMP, TIF, Text(TXT), Rich Text(RTF), SEARCHABLE PDF, PDF/A, Word(DOC), Word(DOCX), Excel(XLS), Excel(XLSX), CSV
Scanner advanced features	One pass duplex scanning: Multi-feed detection sensor; Configurable Scan shortcuts with HP Scan (included): OCR; Auto exposure: Auto threshold; Auto detect colour; Background smooth/removal; Au detect size; Straighten content; Enhance content; Auto orient; Multicolour dropout; Edge erase; Blank Page politons: Delete Blank Page, Blank Page Detection Sensitivity, Zonal Blank Detect; Merge pages; Document separation options: Zonal Text Separation, Blanck Dege Separation [Front/Back/Both/Any side selection]. Add Page Separation Farce Separation, Blank Page Separation [Front/Back/Both/Any side selection]. Add Page Separation Farce Separation, Blank Page Separation [Front/Back/Both/Any side selection]. Add Page Separation Farce Separation, Blank Page Separation [Front/Back/Both/Any side selection]. Add Page Separation, Buto Feed; Show Viewer After Scan and Post Scan Operations are: Mark the image for Deletion, Rotate option, Move Lef/Right, Create/Delete New Selection, Add Page Separation Sistent, Remove Makes, Multi-Streaming; Single zone Selection for Zonal OCR, Barcode and QR Code; PDF options: PDF Security Settings (Applicable for PDF and Searchable PDF). Password Security & Document Permission Settings, PDF – iHQC compression, File Size/Quality Silder; TIFF Compression Options: Tor Gray or Color: Uncompressed/LZW/Jpeg-Tiff, for BW: Uncompressed/LZW/Tiff G3/Tiff G4; File Name Options: Base Name, Date, Time, Document Counter, Barcode Value, Zonal Text, File name sequence Settings, If File name already exists Actions - Overwrite/Append Date Time Stamp/Pormpt for File Name, Intelligent File Naming; Destinations options: Dens and Evance, SharePoint, SharePoint365, Google Drive, Dropbox, One Drive for Business and more Fanale Book Scan (Flatbed); Vertical Streak Removal/Detection; Multi Document Scanning; Enable Desktop Icons creation for Scan Profiles/Shortcuts; Shortcut Management: Create new Scan Shortcut, Delete Bhortcut, Berawer Shortcut, Delete Shortcut, Shortcut, Shortcut, Shortcut, Shortcut, Shortcut, Short
Grayscale levels/Bit depth	256/24-bit (external), 48-bit (internal)
Duty cycle	Recommended daily duty cycle: 6000 pages
Auto document feeder capacity	Standard, 100 sheets (80 g/m ²)
Connectivity	Standard Ethernet 10/100/1000 Base-T, USB 3.0, WiFi 802.11 b/g/n, WiFi Direct;
Memory	Standard 512 MB
Media handling	
Media types	Paper (banner, inkjet, photo, plain), envelopes, labels, cards (greeting, index)
Media size (ADF)	Letter; Legal; Executive; A4; A5; A6; B5; B5 (JIS)
Media weight (ADF)	45 to 120 g/m ²
Compatible operating systems	Windows 11; Windows 10; Windows 8; Windows 8.1; Windows 7; Windows Server; macOS 10.14 Mojave; macOS 10.15 Catalina; macOS 11 Big Sur; macOS 12 Monterey; Linux
Minimum system requirements	PC: Microsoft® Windows® (11, 10, 8.1, 7 : 32-bit and 64-bit, 2008 R2, 2012 R2, 2016, 2019); 2 GB available hard disk space, Internet connection, Microsoft® Internet Explorer or any browser
Software included	HP Scan Software, HP Scanner Device Driver, HP WIA scan driver, HP TWAIN scan driver, HP Scanner Tools Utility, ISIS driver
Print Server Specifications	·
Security management	Power button to on/off
Dimensions and weight	
Product dimensions (W x D x H)	Minimum: 536.5 x 325.4 x 133.3 mm; Maximum: 536.5 x 442.6 x 387.42 mm
Package dimensions (W x D x H)	645 x 245 x 499 mm
Product weight	6.1 kg
Package weight	7.8 kg
Operating environment	Temperature: 17.5 to 25°C Humidity: 30 to 70% RH
Storage	Temperature: -40 to 60°C
Power	Requirements: Input Voltage: 100 to 240 VAC; Consumption: 17.4 watts (Active-Scanning), 7.5 watts (Ready), 1.9 watts (Sleep), 0.06 watts (Auto-Off), 0.06 watts (Manual-Off); ENERGY STAR: Yes
Certifications	IEC62368-1:2018, IEC 60950-1:2005 +A1 and all applicable amendments; CSA/UL 60950-1, 2nd edition (2007); EN 60950-1:2006 +A11 +A1 +A12+A2; EAC safety; Canada CUL CoC; China CCC; European Union CE; Kenya PVOC; Kuwait TER; Nigeria SON; Saudi Arabia SASO; South Africa NRCS; Taiwan BSM; Ukraine safety approval Electromagnetic compatibility . Class B Emissions; CISPR 32:201 (International); European Union EMC Directive 2004/108/EC, EN 55032:2015 (CE mark); China GB9254-2008 (CCC); Taiwan CNS13438:2006 (BSMI); USA CFR47 Part 15, Subpart B (FCC); ICES-003:2021 (Issue 7 (Canada); Australia C-tick (includes New Zealand); KN 22 and Korea KCC; EAC EMC Certificate; Ukraine EMC approval; EN 61000-3-2:2014 (harmonics); EN 61000-3-3:2013 (ficker); Immunity 505035:2017 (ECP; SEPA; IT ECO Declaration; EPEAT® Silver registered
What's in the box	20G07A HP ScanJet Pro N4600 fnw1 Scanner; Install guide; Supporting flyers; Cushions; USB cable; Power adapter; Power cords
Warranty	One-year limited hardware warranty, phone and Web support included. Warranty may vary by country as required by law. Go to http://www.hp.com/support to learn about HP world-class service and

Technical specifications disclaimers

¹ EPEAT® Silver registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. ² Scan speeds of up to 40 ppm measured at 300 dpi (color) from automatic document feeder when scanning to digital file. Actual speeds may vary depending on scan resolution, network conditions, computer performance and application software.



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Overview

HP EliteBook 650 15.6 inch G9 Notebook PC



- 1. Internal Microphones (2)
- 2. Webcam LED (Optional)
- 3. Camera Shutter (Only available with webcam)
- 4. HD TNR and IR Camera (Optional)
- 5. IR Camera LED (Optional)
- 1. RJ-45 port icon may vary.

Left

- 6. Clickpad
- 7. Smartcard Reader (Optional)
- 8. SuperSpeed USB Type-A 5Gbps signaling rate port (USB 3.2 Gen 1)
- 9. Ethernet Port (RJ-45)¹
- 10. Nano Security Lock Slot (Lock sold separately)

Overview



Right

9.

- 1. Power Button Key
- 2. Power Connector
- Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling 8. rate (USB Power Delivery, DisplayPort[™] 1.4)¹
- SuperSpeed USB Type-A 5Gbps signaling rate port (Powered port) (USB 3.2 Gen 1)
- 5. SuperSpeed USB Type-A 5Gbps signaling rate port (USB 3.2 Gen 1)
- 1. SuperSpeed USB 20Gbps is not available with Thunderbolt $^{\rm TM}$ 4

- 6. HDMI 2.0b Port (Cable not included)
- 7. Audio Combo Jack
 - External SIM Card Slot (Optional)
 - Touch Fingerprint Sensor (Select Models)

Overview

AT A GLANCE

- Preinstalled with Windows 11 versions or FreeDOS
- Choice of 12th generation Intel[®] Core[™] i7, i5 and i3 processors
- NVIDIA® GeForce® MX570 discrete graphics with 2 GB GDDR6 video memory
- NVIDIA® GeForce® MX570A discrete graphics with 2 GB GDDR6 video memory
- Fast and upgradeable dual channel DDR4 SODIMM memory up to 64 GB
- Choice of 39.6 cm (15.6") diagonal HD, Ultra Wide Viewing Angle FHD, Touch or Non-Touch screen option
- Features redesigned quiet and responsive HP Keyboard with the HP Programmable key and backlit options
- Choice of solid state drives up to 1 TB
- Multi-layered security with HP SureStart Gen7¹, HP Privacy Camera, HP Sure View Gen4², HP Wolf Security (Includes HP Sure Sense³ and HP Sure Click⁴), HP Secure Erase⁵, HP Client Security Manager Gen7 (Includes Sure Run Gen5⁶, Sure Recover Gen5⁷), Touch Fingerprint reader⁸, and Tamper Lock⁹
- Supports wireless options for connectivity on the go including gigabit-speed Wi-Fi® 6e and CAT9 4G/LTE WWAN
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles¹⁰
- Designed to support HP docking options
- Passed MIL-STD 810H tests¹¹
- Battery Life up to 13 hours with the optional 51.3Whr battery
- Optimize your video calls with an HD camera and Temporal Noise Reduction that adjusts to the lighting in your environment.
- Audio G2G

1. HP Sure Start Gen7 is available on select HP PCs.

2. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

3. HP Sure Sense is available on select HP PCs and is not available with Windows11Home.

4. HP Sure Click requires Windows 11. See https://bit.ly/2PrLT6A_SureClick for complete details.

5. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® OptaneTM.

6. HP Sure Run Gen4 is available on select Windows based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors.

7. HP Sure Recover Gen5 is available on select HP PCs and requires Windows 10 and higher and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.

8. Sold separately or as an optional feature

9. HP Tamper Lock must be enabled by the customer or your administrator.

10. HP notebooks up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a

minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

11. MIL STD 810H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Technical Specifications

PRODUCT NAME

HP EliteBook 650 15.6"? G9 Notebook PC

OPERATING SYSTEM

Preinstalled

Windows 11 Pro¹

Windows 11 Pro Education¹ Windows 11 Home - HP recommends Windows 11 Pro for Business¹ Windows 11 Home Single Language - HP recommends Windows 11 Pro for Business¹ Windows 11 Pro (Windows 11 Enterprise available with a Volume Licensing Agreement)¹ Windows 10 Pro (available through downgrade rights from Windows 11 Pro)^{1,2} FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

Processor	Cores	Number of	Number of	Threads	L3	Max T Frequ			ise Jency	Intel SIPP/ vPro®	Intel vPro®
3,4,5,6,7	cores	P-cores	E-cores	Cache	Cache	P- cores	E- cores	P- cores	E- cores	Enterprise	Essentials
Intel® Core TM i7- 1270P	12	4	8	16	18MB	4.8 GHz	3.5 GHz	2.2 GHz	1.6 GHz	Х	
Intel® Core TM i5- 1250P	12	4	8	16	12MB	4.4 GHz	3.3 GHz	1.7 GHz	1.2 GHz	X	
Intel® Core™ i7- 1265U	10	2	8	12	12MB	4.8 GHz	3.6 GHz	1.8 GHz	1.3 GHz	X	
Intel® Core™ i7- 1255U	10	2	8	12	12MB	4.7 GHz	3.5 GHz	1.7 GHz	1.2 GHz		x
Intel® Core™ i5- 1245U	10	2	8	12	12MB	4.4 GHz	3.3 GHz	1.2 GHz	1.2 GHz	X	
Intel® Core™ i5- 1235U	10	2	8	12	12MB	4.4 GHz	3.3 GHz	1.3 GHz	0.9 GHz		x
Intel® Core™ i3- 1215U	6	2	4	8	10MB	4.4 GHz	3.3 GHz	1.2 GHz	0.9 GHz		

PROCESSORS

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

Technical Specifications

5. Intel[®] Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

6.In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

7. Intel vPro[®] requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro[®] Essentials and Enterprise vary. See http://intel.com/vpro

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel[®] Iris[®] Xe Graphics (Core i5 and Core i7) ⁸ Intel[®] UHD Graphics (Core i3)

Discrete

NVIDIA GeForce ®MX570 Controller NVIDIA GeForce ®MX570A Controller

Supports

Support HD decode, DX12, HDMI 2.1b 9

8. Intel[®] Iris[®] Xe Graphics capabilities require system to be configured with Intel[®] CoreTM i5 or i7 processors and dual channel memory. Intel[®] Iris[®] Xe Graphics with Intel[®] CoreTM i5 or 7 processors and single channel memory will only function as UHD graphics 9. HD content required to view HD images.

DISPLAY

Non-Touch

39.6 cm (15.6") diagonal FHD (1920x1080) UWVA eDP, anti-glare, LED, low power, narrow bezel bent, 400 nits, 100% for HD + IR camera for WWAN ^{9,11}

39.6 cm (15.6") diagonal FHD (1920x1080) UWVA eDP, anti-glare, WLED, low power, narrow bezel bent, 400 nits, 100% for HD camera ^{9,11}

39.6 cm (15.6") diagonal FHD (1920x1080) UWVA eDP, anti-glare, LED, narrow bezel bent, 250 nits, 45% for HD + IR camera for WWAN ^{9,11}

39.6 cm (15.6") diagonal FHD (1920x1080) UWVA eDP, anti-glare, LED, narrow bezel bent, 250 nits, 45% for HD + IR camera ^{9,11}

39.6 cm (15.6") diagonal FHD (1920x1080) UWVA eDP, anti-glare, WLED, narrow bezel bent, 250 nits, 45% for HD camera for WWAN ^{9,11}

39.6 cm (15.6") diagonal FHD (1920x1080) UWVA eDP, anti-glare, WLED, narrow bezel bent, 250 nits, 45% for HD camera ^{9,11} 39.6 cm (15.6") diagonal FHD (1920x1080) UWVA eDP 1.2 w/o PSR, anti-glare, WLED, narrow bezel bent, 250 nits, 45% ^{9,11} 39.6 cm (15.6") diagonal HD (1920x1080) SVA, eDP 1.2 w/o PSR, anti-glare, WLED, narrow bezel bent, 250 nits, 45% ^{9,11} 39.6 cm (15.6") diagonal HD (1920x1080) SVA, eDP, anti-glare, WLED, narrow bezel bent, 250 nits, 45% for HD camera ^{9,11}

Touch

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare narrow bezel bent touch-on-panel screen, 250 nits, 45% NTSC for HD + IR camera and WWAN (1920 x 1080) ^{9,10,11,12}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare narrow bezel bent touch-on-panel screen, 250 nits, 45% NTSC for HD camera (1920 x 1080) ^{9,10,11,12}

Technical Specifications

Display Size 15.6" diagonal 39.6 cm (15.6") diagonal

9. HD content required to view HD images.
10. Sold separately or as an optional feature.
11. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
12. Actual brightness will be lower with touchscreen.

Docking (Sold Separately)

Docking station model #1HP USB-C Dock G5Docking station model #2HP USB-C/A Universal Dock G2Docking station model #3HP Thunderbolt Dock G2For additional aftermarket options and docking specs please see page 41.

STORAGE AND DRIVES

Primary M.2 Storage

1 TB PCIe[®] Gen4x4 NVMeTM M.2 TLC Solid State Drive ¹³ 512 GB PCIe[®] Gen4x4 NVMeTM M.2 TLC Self Encrypted OPAL2 Solid State Drive ¹³ 512 GB PCIe[®] Gen4x4 NVMeTM M.2 TLC Solid State Drive ¹³ 512 GB PCIe[®] NVMeTM M.2 SSD ¹³ 256 GB PCIe[®] Gen4x4 NVMeTM M.2 TLC Self Encrypted OPAL2 Solid State Drive ¹³ 256 GB PCIe[®] Gen4x4 NVMeTM M.2 TLC single-sided Solid State Drive ¹³ 256 GB PCIe[®] NVMeTM M.2 SSD ¹³

Secondary M.2 Storage (Optional)

128 GB PCIe[®] NVMeTM M.2 Value Solid State Drive ^{13,14} 256 GB PCIe[®] NVMeTM M.2 Value Solid State Drive ^{13,14}

13. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software

14. Second storage is only available with non-WWAN base Unit AND Primary M.2 storage

MEMORY

Technical Specifications

Maximum Memory 64 GB DDR4-3200 SDRAM ¹⁵

Memory

64 GB DDR4-3200 SDRAM (2x32GB) ¹⁵ 32 GB DDR4-3200 SDRAM (2x16GB) ¹⁵ 32 GB DDR4-3200 SDRAM (2x16GB) ¹⁵ 16 GB DDR4-3200 SDRAM (1x32GB) ¹⁵ 16 GB DDR4-3200 SDRAM (1x16GB) ¹⁵ 8 GB DDR4-3200 SDRAM (1x8GB) ¹⁵

Memory Slots

2 SODIMM Both slots are customer accessible / upgradeable DDR4 PC4 SODIMMS (Alder Lake runs at 3200) Supports Dual Channel Memory

15. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel® AX211 Wi-Fi 6E and Bluetooth® 5.2 M.2 2230 160MHz CNVi World-Wide WLAN ¹⁶ Intel® AX211 Wi-Fi 6E and Bluetooth® 5.2 M.2 2230 vPro 160MHz CNVi World-Wide WLAN ¹⁶

WWAN

Intel[®] XMMTM 7560 R+ LTE-Advanced Pro ¹⁷

NFC

NXP NPC300 Near Field Communication Module (NFC Mirage WNC XRAV-1)

Miracast

Native Miracast Support

Ethernet

Intel[®] I219-LM 1 Gigabit Network Connection LOM (vPro) ¹⁸ Intel[®] I219v 1 Gigabit Network Connection LOM (non-vPro) ¹⁸

Wake on WLAN

Support on S3 AC mode only

16. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.
 17. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

18. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Technical Specifications

AUDIO/MULTIMEDIA

Audio

2 Integrated stereo speakers Integrated microphone (Dual Array)

Speaker Power

2W/4ohm Per speaker

Camera

720p HD camera with Temporal Noise Reduction ⁹ 720p HD camera+IR Camera with Temporal Noise Reduction ^{9,10}

9. HD content required to view HD images. 10. Sold separately or as an optional feature.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with numeric keypad and optional backlit function ¹⁹

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

- F1 Display Switching
- F2 Blank
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Blank or Backlit Toggle
- F10 Insert
- F11 Wireless
- F12 Programmable key

Hidden Function Keys

Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock

19. Backlit keyboard is an optional feature.

SOFTWARE AND SECURITY

Preinstalled Software Software HP Quick Touch HP Quick Drop ²⁰ myHP HP Smart Support ²¹

Technical Specifications

HP Connection Optimizer HP Power Manager HP Hotkey Support HP Support Assistant ²² HP Notifications HP Privacy Settings Buy Microsoft Office (Sold separately)

Manageability Features

HP Manageability Integration Kit Gen4 (download)²³ HP Driver Packs (download) HP Client Catalog (download) HP Client Management Script Library (download) HP Image Assistant (download)

NOTE: To enhance brightness, level go to the Intel[®] Graphics Command Center app, click on System and turn off the Display Power Savings function.

Security Management

HP Wolf Security for Business²⁴ includes: HP Sure Click ²⁵ HP Sure Sense ²⁶ HP Sure Run Gen5 ²⁷ HP Sure Recover Gen5 ²⁸ HP Sure Start Gen7 ²⁹ HP Tamper Lock HP Sure Admin ³⁰ HP Client Security Manager Gen7 ³¹ TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

BIOS

HP BIOSphere Gen6 ³² HP Secure Erase ³³ Absolute Persistence Module ³⁴ HP DriveLock & Automatic DriveLock BIOS Update via Network HP Wake on WLAN HP Fingerprint Sensor ³⁵ Secured-Core PC Enable ³⁶

Security

TPM Model: Infineon SLB9672VU2.0 Version: 15.21 Revision: TPM 2.0 FIPS 140-2 Compliant: Yes

Smartcard Reader

Model number: Alcor AU9560 FIPS 201 Compliant: Yes

IPv6 Support

Yes

FirstNet Certified No

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?: Yes

Technical Specifications

UEFI version: 2.7 Class: 3

20. HP Quick Drop requires Internet access and Windows 10 or higher PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP OuickDrop app. 21. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support. 22. HP Support Assistant requires Windows and Internet Access. 23. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement. 24. HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features and OS requirement. 25. HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details. 26. HP Sure Sense is available on select HP PCs with Windows 10 Pro, Windows 10 Enterprise, Windows 11 Pro, or Windows 11 Enterprise OS 27. HP Sure Run Gen5 is available on select HP PCs and requires Windows 10 and higher. 28. HP Sure Recover Gen5 is available on select HP PCs and requires Windows 10 and higher and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module. 29. HP Sure Start Gen7 is available on select HP PCs and requires Windows 10 and higher. 30. HP Sure Admin requires Windows 10 or higher. HP BIOS. HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store. 31. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs. 32. HP BIOSphere Gen6 features may vary depending on the platform and configuration. 33. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] OptaneTM. 34. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full

activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/.

35. Fingerprint Reader is an optional feature that must be configured at purchase.

36. Requires an Intel[®] vPro[®], AMD RyzenTM Pro processor or Qualcomm[®] processor with SD850 or higher and requires 8 GB or more system memory. Secured-core PC is enabled from the factory.

POWER

Technical Specifications

Power Supply

HP Smart 65 W External AC power adapter ³⁷ HP Smart 65 W EM External AC power adapter ³⁷ HP Smart 65 W USB Type-CTM adapter ³⁷ HP Smart 45 W External AC power adapter ³⁷ HP Smart 45 W USB Type-CTM adapter ³⁷

Battery

HP Long Life 3-cell, 42.75 Wh Polymer ^{38,39} HP Long Life 3-cell, 51.3 Wh Polymer ^{38,39} Compliant with UL 1642 Standard

Power Cord

3-wire plug - 1m ³⁷ 2-wire plug - 1m ³⁷

Battery life

Up to 13 hours with 51whr battery (HP Long Life 3-Cell, 51 Whr Polymer, UMA graphic, Intel U15, 200 nits display, 2*4G memory, 25 GB SSD)⁴⁰

Up to 12 hours and 15 minutes with 51 whr battery (HP Long Life 3-Cell, 51 Whr Polymer, UMA graphic, Intel P28, 200 nits display, 2*4G memory, 256 GB SSD)⁴⁰

Up to 11 hours with 42whr battery (HP Long Life 3-Cell, 42 Whr Polymer, UMA graphic, Intel U15, 200 nits display, 2*4G memory, 25 GB SSD)⁴⁰

Battery Weight

HP Long Life 3-cell - 42.72 Wh Polymer .40 lb 181.83 g

HP Long Life 3-cell - 51.3 Wh Polymer .45 lb

203.56 g

37. Availability may vary by country.

38. Battery is internal and not replaceable by customer. Serviceable by warranty.

39. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors. 40. Windows 10 MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONs

Product Weight Starting at 3.83 lb ⁴¹ Starting at 1.74 kg ⁴¹

Product Dimensions (W x D x H)

14.15 x 9.20 x 0.78 in 35.94 x 23.39 x 1.99 cm

41. Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

Technical Specifications

- 1 ThunderboltTM 4 with USB4TM Type-C[®] 40 Gbps signaling rate (USB Power Delivery, DisplayPortTM 2.1b)⁴²
- 3 SuperSpeed USB Type-A 5Gbps signaling rate Port includes 1 Powered port (USB 3.2 Gen 1)
- 1 AC power
- 1 HDMI 2.0b 43
- 1 Headphone/microphone combo jack
- 1 Nano SIM slot for WWAN (optional)
- 1 RJ-45 44

Expansion Slots

Smart Card Reader (optional)

- 42. SuperSpeed USB 20Gbps is not available with Thunderbolt[™] 4
- 43. HDMI cable sold separately.

44. RJ-45 port icon may vary.

SERVICE AND SUPPORT

HP Services offers 1-year or 3-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.145

45. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit

http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated t Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such right are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance: Energy Efficiency Compliance: Environmental Specifications: Environmental Specifications: ENERGY STAR[®] certified EPEAT[®] registered⁴⁶ Low halogen⁴⁷ TCO 9.0 Certification

46. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.
47. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

SYSTEM UNIT

Technical Specifications

Stand Alana Bawar Baguiraments (AC Bawar)	
Stand-Alone Power Requirements (AC Power)	101/
Nominal Operating Voltage	
Average Operating Power	U15 UMA 3.72W/U15 DSC 4.56W/U28 3.80W
Integrated graphics	Yes
Discrete Graphics	Yes, GN20-S5
Max Operating Power	Discrete < 65W
_ .	UMA U15 < 45W, UMA U28 < 65W
Temperature	
Operating	32° to 95° F (0° to 35° C)
	(No sustained direct exposure to sunlight)
	(System performance may be reduced above 32°C (89.6°F))
Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	
Operating	10% to 90% (non-condensing)
Non-operating	5% to 95%
	(38.7° C (101.6° F) maximum wet bulb tempera-ture; non-condensing)
Shock	
Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine
Random Vibration	
Operating	1.043 grams
Non-operating	3.5 grams
Altitude (unpressurized)	-
Operating	10,000 ft (3,048 m)
Non-operating	40,000 ft (12,192 m)
Planned Industry Standard Certifications	
Regulatory Model Number	HSN-Q33C-5
UL	Yes
CSA	Yes
FCC Compliance	Yes
ENERGY STAR [®]	Yes ⁴⁸
EPEAT [®]	EPEAT [®] Gold in the United States ⁴⁹
ICES	Yes
Australia /	Yes
NZ A-Tick Compliance	Yes
CCC	Yes
Japan VCCI Compliance	Yes
KC	Yes
BSMI	Yes
CE Marking Compliance	Yes
BNCI or BELUS	Yes
CIT	Yes
	fes
EAC	Yes
Saudi Arabian Compliance (ICCP)	Yes
SABS	Yes
UKRSERTCOMPUTER	
	Yes

48. Configurations of the HP EliteBook 650 G9 that are ENERGY STAR[®] qualified are identified as HP EliteBook 650 G9 ENERGY STAR on HP websites and on http://www.energystar.gov.

49. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by hp's component manufacturers; actual performance may vary either higher or lower.

1. Actual brightness will be lower with touchscreen or HP Sure View.

(1920 x 1080) Anti-Giare WLED Active Area 344.160 x 193.590 mm (typ. UWV A 45percent cg 250nits eDP Neight 380 g (max) 1.2 w/o PSR bent Touch on Panel Diagonal Size 15.6 inch NWBZ Diagonal Size 15.6 inch Diagonal Size 3.2 mm / 5.2 mm (5.2 mm (FCB) (max) Interface eDP 1.2 Surface Treatment Anti-Giare On-cell Touch Enabled Yes1 Contrast Ratio 600:1 (typ.) Refresh Rate 60 Hz Brightness 250 nits1 Pixel Resolution - Format 1920 x 1080 (FHD) Backlight LED Viewing Angle UWVA 85/85/85/85 Low Blue Light No Power Consumption (W, EBL@ 2.54 (Max) / 3.12 (Max) 15.6 inch FHD (1920 x 1080) Active Area 344.160 x 193.590 mm (typ. Antti-Giare WLED UWVA 8K6B Outline Dimensions (W x H) 349.460 x 204.790 mm (max) 14.+PSR2 bent LP NWBZ Active Area 344.160 x 193.590 mm (typ.) Refresh Rate 60 Hz Surface Treatment Thickness 2.6 mm / 4.6 mm (PCB) (max) 100percent cg 400nits eDP </th <th>Technical Specifications</th> <th></th> <th></th>	Technical Specifications				
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Brightness250 nits1Pixel Resolution - Format1920 x 1080 (FHD)BacklightLEDPixel ResolutionRGB StripeColor Gamut CoverageNTSC 45%Color Depth6 bitsViewing AngleUWVA 85/85/85/85Low Blue LightNoPower Consumption (W, EBL@2.54 (Max) / 3.12 (Max)15.6 inch FHD (1920 x 1080)Outline Dimensions (W x H)349.460 x 204.790 mm (maxAnti-Glare WLED UWVA sRGBActive Area344.160 x 193.590 mm (typ.100percent cg 400nits eDPWeight325 g (max)1.4+PSR2 bent LP NWBZDutline Dimensions (W x H)349.460 x 204.790 mm (maxInterfaceeDP 1.4Surface TreatmentAnti-GlareTouch EnabledNoContrast Ratio1200:1 (typ.)Refresh Rate60 HzBrightness400 nitsPixel Resolution - Format1920 x 1080 (FHD)BacklightLEDPixel Resolution - Format1920 x 1080 (FHD)BacklightLEDPixel Resolution - Format1920 x 1080 (FHD)BacklightLEDPixel ResolutionRGB StripeColor Gamut CoveragesRGB 100% (NTSC 72%)Color Depth8 bitsViewing AngleUWVA 85/85/85/85Low Blue LightNoPower Consumption (W, EBL@1.13(Max)/1.37(Max)		Contrast Ratio	600:1 (typ.)		
Pixel Resolution - Format 1920 x 1080 (FHD) Backlight LED Pixel Resolution RGB Stripe Color Gamut Coverage NTSC 45% Color Depth 6 bits Viewing Angle UWVA 85/85/85/85 Low Blue Light No Power Consumption (W, EBL@ 2.54 (Max) / 3.12 (Max) 15.6 inch FHD (1920 x 1080) Outline Dimensions (W x H) 349.460 x 204.790 mm (max Anti-Glare WLED UWVA sRGB Active Area 344.160 x 193.590 mm (typ. 100percent cg 400nits eDP Weight 325 g (max) 10agonal Size 15.6 inch Thickness 2.6mm / 4.6mm (PCB) (max) Interface eDP 1.4 Surface Treatment Anti-Glare Touch Enabled No Contrast Ratio 1200:1 (typ.) Refresh Rate 60 Hz Brightness 400 nits Pixel Resolution - Format 1920 x 1080 (FHD) Backlight LED Pixel Resolution - Format 1920 x 1080 (FHD) Backlight LED Pixel Resolution RGB Stripe Color Gamut Coverage		Refresh Rate	60 Hz		
BacklightLEDPixel ResolutionRGB StripeColor Gamut CoverageNTSC 45%Color Depth6 bitsViewing AngleUWVA 85/85/85/85Low Blue LightNoPower Consumption (W, EBL@)2.54 (Max) / 3.12 (Max)150nits max/ 200nits max)349.460 x 204.790 mm (maxAnti-Glare WLED UWVA sRGBActive Area1.4+PSR2 bent LP NWBZOutline Dimensions (W x H)349.460 x 204.790 mm (typ.)Diagonal Size15.6 inchThickness2.6mm / 4.6mm (PCB) (max)InterfaceeDP 1.4Surface TreatmentAnti-GlareTouch EnabledNoContrast Ratio1200:1 (typ.)Refresh Rate60 HzBrightness400 nitsPixel Resolution - Format1920 x 1080 (FHD)BacklightLEDPixel Resolution - Format1920 x 1080 (NTSC 72%)Color Gamut CoveragesRGB 100% (NTSC 72%)Color Depth8 bitsViewing AngleUWVA 85/85/85/85Low Blue LightNoPower Consumption (W, EBL@1.13(Max)/1.37(Max)		Brightness	250 nits ¹		
Pixel ResolutionRGB StripeColor Gamut CoverageNTSC 45%Color Depth6 bitsViewing AngleUWVA 85/85/85/85Low Blue LightNoPower Consumption (W, EBL@ 150nits max/ 200nits max)2.54 (Max) / 3.12 (Max)15.6 inch FHD (1920 x 1080)Outline Dimensions (W x H)349.460 x 204.790 mm (maxAnti-Glare WLED UWVA sRGB 100percent cg 400nits eDPActive Area344.160 x 193.590 mm (typ.100percent cg 400nits eDPWeight325 g (max)1.4+PSR2 bent LP NWBZDiagonal Size15.6 inchThickness2.6mm / 4.6mm (PCB) (max)InterfaceeDP 1.4Surface Treatment Touch EnabledAnti-GlareTouch EnabledNoContrast Ratio1200:1 (typ.)Refresh Rate60 HzBrightness400 nitsPixel Resolution - Format1920 x 1080 (FHD)BacklightLEDPixel Resolution - Format1920 x 1080 (FHD)BacklightLEDViewing AngleUWVA 85/85/85/85Low Blue LightNoPower Consumption (W, EBL@1.13(Max)/1.37(Max)		Pixel Resolution - Format	1920 x 1080 (FHD)		
Color Gamut Coverage NTSC 45% Color Depth 6 bits Viewing Angle UWVA 85/85/85/85 Low Blue Light No Power Consumption (W, EBL@ 2.54 (Max) / 3.12 (Max) 150nits max/ 200nits max) 15.6 inch FHD (1920 x 1080) Anti-Glare WLED UWVA 8RGB 100percent cg 400nits eDP 1.4+PSR2 bent LP NWBZ Diagonal Size 15.6 inch Thickness 2.6mm / 4.6mm (PCB) (max) Interface eDP 1.4 Surface Treatment Anti-Glare Touch Enabled No Contrast Ratio 1200:1 (typ.) Refresh Rate 60 Hz Brightness 400 nits Pixel Resolution - Format 1920 x 1080 (FHD) Backlight LED Pixel Resolution - Format 1920 x 1080 (FHD) Backlight LED Pixel Resolution RGB Stripe Color Gamut Coverage SRGB 100% (NTSC 72%) Color Depth 8 bits Viewing Angle UWVA 85/85/85/855 Low Blue Light No Power Consumption (W, EBL@ 1.13(Max)/1.37(Max)		Backlight	LED		
Color Depth 6 bits Viewing Angle UWVA 85/85/85/85 Low Blue Light No Power Consumption (W, EBL@ 2.54 (Max) / 3.12 (Max) 150nits max/ 200nits max) 15.6 inch FHD (1920 x 1080) Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP 1.4+PSR2 bent LP NWBZ Uiagonal Size 15.6 inch Thickness 2.6mm / 4.6mm (PCB) (max) Interface eDP 1.4 Surface Treatment Anti-Glare Touch Enabled No Contrast Ratio 1200:1 (typ.) Refresh Rate 60 Hz Brightness 400 nits Pixel Resolution - Format 1920 x 1080 (FHD) Backlight LED Pixel Resolution RGB Stripe Color Gamut Coverage sRGB 100% (NTSC 72%) Color Depth 8 bits Viewing Angle UWVA 85/85/85/85 Low Blue Light No Power Consumption (W, EBL@ 1.13(Max)/1.37(Max)		Pixel Resolution	RGB Stripe		
Viewing Angle Low Blue LightUWVA 85/85/855 No15.6 inch FHD (1920 x 1080) Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP 1.4+PSR2 bent LP NWBZOutline Dimensions (W x H) Active Area349.460 x 204.790 mm (max A4tive Area1.4+PSR2 bent LP NWBZOutline Dimensions (W x H) Weight325 g (max) 15.6 inch1.4+PSR2 bent LP NWBZDiagonal Size15.6 inch Thickness1.4+PSR2 bent LP NWBZDiagonal Size15.6 inch Thickness1.6Diagonal Size15.6 inch Thickness1.6Diagonal Size2.6mm / 4.6mm (PCB) (max)1.14+PSR2 bent LP NWBZDiagonal Size2.6mm / 4.6mm (PCB)1.15Diagonal Size1200:1 (typ.)1.16Diagonal Size1200:1 (typ.)1.17Dia		Color Gamut Coverage	NTSC 45%		
Low Blue Light No Power Consumption (W, EBL@ 2.54 (Max) / 3.12 (Max) 150nits max/ 200nits max) 15.6 inch FHD (1920 x 1080) Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP 1.4+P5R2 bent LP NWBZ Uagonal Size 15.6 inch Thickness 2.6mm / 4.6mm (PCB) (max) Interface eDP 1.4 Surface Treatment Anti-Glare Touch Enabled No Contrast Ratio 1200:1 (typ.) Refresh Rate 60 Hz Brightness 400 nits Pixel Resolution - Format 1920 x 1080 (FHD) Backlight LED Pixel Resolution - Format 1920 x 1080 (FHD) Backlight LED Pixel Resolution RGB Stripe Color Gamut Coverage SRGB 100% (NTSC 72%) Color Depth 8 bits Viewing Angle UWVA 85/85/855/855 Low Blue Light No Power Consumption (W, EBL@ 1.13(Max)/1.37(Max)		Color Depth	6 bits		
Power Consumption (W, EBL@ 150nits max/ 200nits max)2.54 (Max) / 3.12 (Max)15.6 inch FHD (1920 x 1080) Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP 1.4+PSR2 bent LP NWBZOutline Dimensions (W x H) Active Area349.460 x 204.790 mm (max 344.160 x 193.590 mm (typ.) 325 g (max)1.4+PSR2 bent LP NWBZWeight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Brightness325 g (max) 1.400 mits1.4Surface Treatment Touch Enabled Diagonal SizeAnti-Glare 1200:1 (typ.) Refresh Rate Brightness60 Hz BrightnessPixel Resolution - Format Backlight Diago nut Coverage Color Gamut Coverage920 x 1080 (FHD) B bitsBacklight Viewing Angle UWVA 85/85/85/85 Low Blue LightNoNo Power Consumption (W, EBL@1.13(Max)/1.37(Max)		Viewing Angle	UWVA 85/85/85		
150nits max/ 200nits max) 15.6 inch FHD (1920 x 1080) Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP 1.4+PSR2 bent LP NWBZ Diagonal Size 15.6 inch Thickness 2.6 mm / 4.6mm (PCB) (max) Interface eDP 1.4 Surface Treatment Anti-Glare Touch Enabled No Contrast Ratio 1200:1 (typ.) Refresh Rate 60 Hz Brightness 400 nits Pixel Resolution - Format 1920 x 1080 (FHD) Backlight LED Pixel Resolution RGB Stripe Color Gamut Coverage sRGB 100% (NTSC 72%) Color Depth 8 bits Viewing Angle UWVA 85/85/85/85 Low Blue Light No Power Consumption (W, EBL@ 1.13(Max)/1.37(Max)		Low Blue Light	No		
15.6 inch FHD (1920 x 1080) Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP 1.4+PSR2 bent LP NWBZOutline Dimensions (W x H)349.460 x 204.790 mm (max 325 g (max)Ueight325 g (max)Diagonal Size15.6 inchThickness2.6mm / 4.6mm (PCB) (max)InterfaceeDP 1.4Surface TreatmentAnti-GlareTouch EnabledNoContrast Ratio1200:1 (typ.)Refresh Rate60 HzBrightness400 nitsPixel Resolution - Format1920 x 1080 (FHD)BacklightLEDPixel ResolutionRGB StripeColor Gamut CoveragesRGB 100% (NTSC 72%)Color Depth8 bitsViewing AngleUWVA 85/85/85Low Blue LightNoPower Consumption (W, EBL@1.13(Max)/1.37(Max)		• • • •	2.54 (Max) / 3.12 (Max)		
Power Consumption (W, EBL@ 1.13(Max)/1.37(Max)	Anti-Glare WLED UWVA sRGB 100percent cg 400nits eDP	Active Area Weight Diagonal Size Thickness Interface Surface Treatment Touch Enabled Contrast Ratio Refresh Rate Brightness Pixel Resolution - Format Backlight Pixel Resolution Color Gamut Coverage Color Depth	344.160 x 193.590 mm (typ.) 325 g (max) 15.6 inch 2.6mm / 4.6mm (PCB) (max) eDP 1.4 Anti-Glare No 1200:1 (typ.) 60 Hz 400 nits 1920 x 1080 (FHD) LED RGB Stripe sRGB 100% (NTSC 72%) 8 bits		
Power Consumption (W, EBL@ 1.13(Max)/1.37(Max)		• •			
150nits max/ 200nits max)		Power Consumption (W, EBL@			

Technical Specifications				
15.6 inch FHD (1920 x 1080)	Outline Dimensions (W x H)	350.960 x 205.540mm (max)		
Anti-Glare WLED UWVA 45percent	Active Area	344.160 x 193.590 mm (typ.) 370 g (max) 15.6 inch		
cg 250nits eDP 1.2 w/o PSR bent	Weight			
NWBZ	Diagonal Size			
	Thickness	3.0 mm/ 5.0 mm (w/PCB) (max)		
	Interface	eDP 1.2 (2 lane)		
	Surface Treatment	Anti-Glare		
	Touch Enabled	Νο		
	Contrast Ratio	600:1 (typ.)		
	Refresh Rate	60 Hz		
	Brightness	250 nits		
	Pixel Resolution - Format	1920 x 1080 (FHD)		
	Backlight	LED		
	Pixel Resolution	RGB Stripe		
	Color Gamut Coverage	NTSC 45%		
	Color Depth	6 bits (Hi FRC supportive w/ condition to enable)		
	Viewing Angle	UWVA 85/85/85/85		
	Low Blue Light	No		
	Power Consumption (W, EBL@	2.62 (Max) / 3.27 (Max)		
	150nits max/ 200nits max)			
15.6-in HD (1366 x 768)	Outline Dimensions (W x H)	350.960 x 205.540 mm (max)		
Anti-Glare WLED SVA 45percent cg 250nits eDP 1.2 w/o PSR NWBZ	Active Area	344.230 x 193.540 mm (typ.)		
bent	Weight Bis source Circo	370 g (max)		
	Diagonal Size	15.6 inch		
	Thickness	3.2 mm / 5.0 mm (w/PCB) (max)		
	Interface	eDP 1.2 (1 lane)		
	Surface Treatment	Anti-Glare		
	Touch Enabled	No		
	Contrast Ratio	300:1 (typ.)		
	Refresh Rate	60 Hz		
	Brightness	250 nits		
	Pixel Resolution - Format	1366 x 768 (HD)		
	Backlight	LED		
	Pixel Resolution	RGB Stripe NTSC 45%		
	Color Gamut Coverage			
	Color Depth	6 bits SVA 45/45/15/35		
	Viewing Angle			
	Low Blue Light			
	Power Consumption (W, EBL@	2.49 (Max) / 2.78 (Max)		
	150nits max/ 200nits max)			

STORAGE AND DRIVES

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software

Technical Specifications				
SSD 128GB 2230 PCIe NVMe Value	Form Factor	M.2 2230		
	Capacity	128GB		
	NAND Type	Value		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.01 lb (5 g)		
	Interface	PCIe NVMe Gen3		
	Maximum Sequential Read	Up to 2100 MB/s		
	Maximum Sequential Write	Up to 1200 MB/s		
	Logical Blocks	250,069,680		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	Pyrite; TRIM; L1.2		
SSD 256GB 2230 PCIe NVMe Value	Form Factor	M.2 2230		
	Capacity	256 GB		
	NAND Type	Value		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen3		
	Maximum Sequential Read	up to 2500 MB/s		
	Maximum Sequential Write	up to 1300 MB/s		
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	Pyrite; TRIM; L1.2		
SSD 256GB 2280 PCIe NVMe Value	Form Factor	M.2 2280		
	Capacity	256GB		
	NAND Type	Value		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen3		
	Maximum Sequential Read	Up to 2900 MB/s		
	Maximum Sequential Write	Up to 1400 MB/s		
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security; TRIM; L1.2		

Technical Specifications				
SSD 256GB 2280 PCIe-4x4 NVMe	Form Factor	M.2 2280		
Three Layer Cell	Capacity	256 GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4		
	Maximum Sequential Read Maximum Sequential Write Logical Blocks	Up to 6,400 MB/s Up to 2,700 MB/s 500,118,192		
	Operating Temperature Features	32° to 158°F (0° to 70°C) [ambient temp] Pyrite 2.0; TRIM; L1.2		
256GB PCIe-4x4 2280 NVME Self	Form Factor	M.2 2280		
Encrypted OPAL2 Three Layer Cell	Capacity	256GB		
Solid State Drive	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4		
	Maximum Sequential Read	6400		
	Maximum Sequential Write	2700		
	Logical Blocks Operating Temperature	500,118,192 32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2		
SSD 512GB 2280 PCIe NVMe Value	Form Factor	M.2 2280		
	Capacity	512GB		
	NAND Type	Value		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen3		
	Maximum Sequential Read	Up to 3500 MB/s		
	Maximum Sequential Write	up to 3000 MB/s		
	Logical Blocks	1,000,215,216		
	Operating Temperature Features	32° to 158°F (0° to 70°C) [ambient temp] TRIM; L1.2		

Technical Specifications				
SSD 512GB 2280 PCIe-4x4 NVMe	Form Factor	M.2 2280		
Three Layer Cell	Capacity	512GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4		
	Maximum Sequential Read	Up to 6,600 MB/s		
	Maximum Sequential Write	Up to 5,100 MB/s		
	Logical Blocks	1,000,215,216		
	Operating Temperature Features	32° to 158°F (0° to 70°C) [ambient temp] Pyrite 2.0; TRIM; L1.2		
	reatures	Fyitte 2.0, TRIM, LT.2		
512GB PCIe-4x4 2280 NVME Self	Form Factor	M.2 2280		
Encrypted OPAL2 Three Layer Cell	Capacity	512GB		
Solid State Drive	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4		
	Maximum Sequential Read	Up to 6,600 MB/s		
	Maximum Sequential Write	Up to 5,100 MB/s		
	Logical Blocks	1,000,215,216		
	Operating Temperature Features	32° to 158°F (0° to 70°C) [ambient temp] ATA Security (Option); TCG Opal 2.0; TRIM; L1.2		
SSD 1TB 2280 PCIe-4x4 NVMe Three Layer Cell	Form Factor	M.2 2280		
	Capacity	1TB TLC		
	NAND Type	0.09 in (2.3 mm)		
	Height Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4		
	Maximum Sequential Read	Up to 7,100 MB/s		
	Maximum Sequential Write	Up to 5,200 MB/s		
	Logical Blocks	2,000,409,264		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	Pyrite 2.0; TRIM; L1.2		

NETWORKING/COMMUNICATIONS

Intel® AX211 Wi-Fi 6E + Bluetooth® 5.2 M.2 160MHz CNVi WW WLAN vPro ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i

Technical Specifications

	IEEE 802.11k IEEE 802.11r IEEE 802.11v	
Interoperability	Wi-Fi certified	
Frequency Band	 802.11b/g/n/ax 2.402 - 2.482 GHz 802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz 5.955 - 6.415 GHz 6.435 - 6.515 GHz 6.535 - 6.875 GHz 6.895 - 7.115 GHz 	
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : 1733Mbps 802.11ax : max 2.4Gbps 	
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM	
Security ³	IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ²	802.11b : +17dBm minimum 802.11g : +16dBm minimum 802.11a : +17dBm minimum 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz) : +13dBm minimum 802.11n HT20(5GHz) : +14dBm minimum 802.11n HT40(5GHz) : +13dBm minimum 802.11ac VHT80(5GHz) : +10dBm minimum 802.11ax HE40(2.4GHz) : +10dBm minimum 802.11ax HE40(2.4GHz) : +10dBm minimum 802.11ax HE80(5GHz) : +10dBm minimum	
Power Consumption	Transmit mode2.0 W Receive mode1.6 W Idle mode (PSP)180 mW(WLAN Associated) Idle mode50 mW(WLAN unassociated) Connected Standby 10mW Radio disabled8 mW	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity ⁴	802.11b, 1Mbps : -93.5dBm maximum	

Technical Specifications

	802.11a/g, 6Mbp 802.11a/g, 54Mb 802.11n, MCS07 802.11n, MCS15 802.11ac, MCS0(802.11ac, MCS9(802.11ac, MCS9(802.11ax, MCS11 802.11ax, MCS11	s : -84dBm maximum os : -86dBm maximum ops : -72dBm maximum : -67dBm maximum : -64dBm maximum VHT80) : -84dBm maximum VHT80) : -59dBm maximum VHT160) : -59dBm maximum I (HE40): -57dBm maximum I (HE80): -54dBm maximum I (HE160): -53.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2	MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g 2. Type 1216: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber - Radio OFF LED OFF - Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1/5.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.

1.Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Technical Specification	ons	
Intel® AX211 Wi-Fi 6E + Bluetooth® 5.2 M.2 160MHz CNVi WW WLAN non-vPro ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11r IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	 802.11b/g/n/ax 2.402 - 2.482 GHz 802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz 5.955 - 6.415 GHz 6.435 - 6.515 GHz 6.535 - 6.875 GHz 6.895 - 7.115 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : 1733Mbps 802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ³	IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	802.11b : +17dBm minimum 802.11g : +16dBm minimum 802.11a : +17dBm minimum 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz) : +13dBm minimum 802.11n HT20(5GHz) : +14dBm minimum 802.11n HT40(5GHz) : +10dBm minimum 802.11ac VHT80(5GHz) : +10dBm minimum 802.11ax HE40(2.4GHz) : +12dBm minimum 802.11ax HE40(5GHz) : +10dBm minimum 802.11ax HE40(5GHz) : +10dBm minimum

Technical Specifications

HP Integrated Module

	-		
	Power Consumption		W 80 mW(WLAN Associated) (WLAN unassociated) by 10mW
	Power Management		ess compliant power management t power saving mode
	Receiver Sensitivity ⁴	802.11b, 11Mbps 802.11a/g, 6Mbp 802.11a/g, 54Mb 802.11n, MCS07 802.11n, MCS15 802.11ac, MCS0(V 802.11ac, MCS9(V 802.11ac, MCS9(V 802.11ax, MCS11 802.11ax, MCS11	-93.5dBm maximum : -84dBm maximum s: -86dBm maximum ps: -72dBm maximum -67dBm maximum -64dBm maximum /HT80) : -84dBm maximum /HT80) : -59dBm maximum /HT160) : -58.5dBm maximum (HE40): -57dBm maximum (HE80): -54dBm maximum (HE160): -53.5dBm maximum
	Antenna type	enclosure Two embedded d	ntenna with spatial diversity, mounted in the display ual band 2.4/5 GHz antennas are provided to the card to MO communications and Bluetooth communications
	Form Factor	PCI-Express M.2 N	1iniCard
	Dimensions		x 22.0 x 30.0 mm 7 x 12.0 x 16.0 mm
	Weight	1. Type 2230: 2.8 2. Type 1216: 1.3	-
	Operating Voltage	3.3v +/- 9%	
	Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)
	Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
	Altitude	Operating	0 to 10,000 ft (3,048 m)
		Non-operating	0 to 50,000 ft (15,240 m)
	LED Activity	LED Amber - Radi LED Off - Radio O	•
e with	Bluetooth 4.0/4.1/4.2/5.0/	5.1/5.2 Wireless T	echnology
	Bluetooth Specification	4.0/4.1/4.2/5.0/5	.1/5.2 Compliant
	Frequency Band	2402 to 2480 MH	Z
	Number of Available Channels	Legacy: 0~79 (1 N BLE: 0~39 (2 MHz	
	Data Rates and Throughput	BLE: 1 Mbps data	ata rate; throughput up to 2.17 Mbps rate; throughput up to 0.2 Mbps your Connection Oriented links up to 2.64 kbps, upice

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

maximum transmit power of + 9.5 dBm for BR and EDR.

The Bluetooth component shall operate as a Class II Bluetooth device with a

Transmit Power

1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. Wi-Fi 6E is

Technical Specifications

designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® XMM [™] 7560 R+ LTE- Advanced Pro ¹	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band
		19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700
		(Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66), 600 (band 71).
		TDD LTE: 2100 (Band 34), 2600 (Band 38), 1900 (Band 39),
		2400 (Band 40), 2500 (Band 41), 3500 (Band 42), 3700 (Band
		43), 3700 (band 48), 5200 (Band 46 RX only) MHz;
		HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),
		850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW
		throughput up to 978Mbps; UL-CAT.13 40MHz throughput up
		to 150Mbps
		WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone GPS/Beidou/Glonass, A-GPS (MS-A, MS-B)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou
	 .	1561.098 MHz
	Maximum data rates	LTE: 978 Mbps (Download), 150 Mbps (Upload)
		DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload)
		HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm in all band except B41
		LTE B41 HPUE = 26dBm
	Mauliuuu aanaa aanaa tian	HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average)
	Form Factor	HSPA+: 1,100 mA (peak); 800 mA (average) M.2, 3042-S3 Key B
	Weight	· · ·
	Dimensions	6 g 42 x 30 x 2.3 mm
		42 X JU X 2.3 IIIIII
	(Length x Width x Thickness)	Constant.
	eSIM	Support

1. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications		
NXP NPC300 Near Field Communication Module	Dimensions (L x W x H) Chipset System interface NFC RF standards	Module 17 mm by 10 mm by 2.0 mm NPC300 I2C ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator
	NFC Forum Support Reader (PCD-VCD) Mode(1)	ECMA-320 NFCIP-2 Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2 ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa
	Card Emulation (PICC-VICC) Mode(1)	Jewel and Topaz cards ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa
	Frequency	13.56 MHz
	NFC Modes Supported	Reader/Writer, Peer-to-Peer
	Raw RF Data Rates	106, 212, 424, 848 kbps
	Operating temperature	0°C to 70°C
	Storage temperature	-20°C to 125°C
	Humidity	10-90% operating
	numurty	5-95% non-operating
	Supply Operating voltage	2.97 to 5.5 Volts
	I/O Voltage	1.8V or 3.3V
Power Consumption	1/0 voltage	1.0 0 0.5 0
(Booster enable, VBAT= 3.3V, V		
(DOOSTEP enable, VDAT = 3.3V, V	-	Device Consumption Turical
	Mode	Power Consumption, Typical
	Polling	7.3 mA
	Detected Test Tag Type 1	32.9 mA
	Detected Test Tag Type 2	70.7 mA
	Detected Test Tag Type 3	79.2 mA
	Detected Test Tag Type 4	64.9 mA
	Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.

Technical Specifications		
Intel® I219-LM 1 Gigabit Network	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses
Connection LOM (vPro)		13-14)
		100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3
		clauses 21-30)
		1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
		Auto-Negotiation (Automatic Speed Selection)
		Full Duplex Operation at all Speeds, Half Duplex operation at
		10 and 100 Mbit/s
	Power Management	ACPI compliant - multiple power modes
		Situation-sensitive features reduce power consumption
		Advanced link down power saving for reducing link down power
	Performance Features	consumption TCP/IP/UDP Checksum Offload (configurable)
	Per formance reatures	Protocol Offload (ARP & NS)
		Large send offload and Giant send offload
		Receiving Side Scaling(Hash Mode Only)
		Jumbo Frame 9K
	Manageability	Wake-on-LAN from modern standby or sleep state (Magic
		Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off
		(Magic Packet only) PXE 2.1 Remote Boot
		Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet
		MIB (802.3x, clause 30))
		Comprehensive diagnostic and configuration software suite
		Virtual Cable Doctor for Ethernet cable status
	Interface	PCI (Intel proprietary) + SMBus
	NIC Device Driver Name	Intel(R) Ethernet Connection (13) I219-LM
Intel® I219v 1 Gigabit Network	Ethernet Features	1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3
Connection LOM (non-vPro)		clauses 13-14)
		2.100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3
		clauses 21-30)
		3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 ab; IEEE 802.3 ab; IEEE 802.3 ab; IEEE 802.3 ab;
		4. Auto-Negotiation (Automatic Speed Selection)
		Full Duplex Operation at all Speeds, Half Duplex operation at
		10, 100 & 1000 Mbit/s
	Power Management	ACPI compliant - multiple power modes
		Situation-sensitive features reduce power consumption
		Advanced link down power saving for reducing link down power consumption
	Performance Features	TCP/IP/UDP Checksum Offload (configurable)
		Protocol Offload (ARP & NS)
		Large send offload and Giant send offload
		Receiving Side Scaling(Hash Mode only)
	A	Jumbo Frame 9K
	Manageability	Wake-on-LAN from modern standby or sleep state (Magic
		Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)
		PXE 2.1 Remote Boot
		Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet
		MIB (802.3x, clause 30))
		Comprehensive diagnostic and configuration software suite
	Interface	Virtual Cable Doctor for Ethernet cable status
	Interface NIC Device Driver Name	PCI(Intel proprietary) + SMBus Intel(R) Ethernet Connection I219-V
	MIC DEVICE DI IVEI MAIILE	ווונכוות) בנוופווופג נטווופגנוטוו וב וש-ע

Technical Specifications

POWER

AC Adapter 45 Watt nPFC Standard USB type C Straight 1.8m	Dimensions Weight Input	94.0 mm x 40.0 mm x 26.5 mm 192.5g +/-10% 100~240 VAC
	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%
	Input frequency range	47 to 63 Hz
	Input AC current	Max. 1.4 A at 90 Vac
	Output	
	Output power	5V/15W 9V/27W 12V/36W 15V/45W
	DC output	5V/9V/12V/15V
	Hold-up time	5ms at 115 Vac input
	Output current limit	<5.0A
	Connector	USB Type-C
	Environmental Design	
	Operating temperature	32° to 95° F (0° to 35° C)
	Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
	EMI and Safety Certifications	Eg. *CE Mark - full compliance with LVD and EMC directives *Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. *MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 45 Watt		
Smart nPFC Standard		
Barrel 4.5mm Right		
Angle 1.8m		

Dimensions
Weight
Input
Input Efficiency
Input frequency range
Input AC current
Output
Output power
DC output
Hold-up time
Output current limit
Connector
Environmental Design
Operating temperature
Non-operating (storage)
temperature
Altitude

95 x 45 x 26.5 mm unit: 200g +/- 10g 100~240 VAC 87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63 Hz Max. 1.4 A at 90 Vac 45W 19.5V 5ms at 115 Vac input <8.0A 4.5mm Barrel Type 32° to 95° F (0° to 35° C) -4° to 185° F (-20° to 85° C)

0 to 16,400 ft (0 to 5000m)

echnical Specificatio	ns	
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1 SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.
AC Adapter 65 Watt	Dimensions	90.0 x 51 x 28.5mm
nPFC Standard USB type	Weight	unit: 250g +/- 10g
C Straight 1.8m	Input	100~240 VAC
	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 88% 15V: 88% 20V: 89%
	Input frequency range	47 ~ 63Hz
	Input AC current	1.6 A at 90 VAC and maximum load
	Output	
	Output power DC output	5V/15W 9V/27W 12V/60W 15V/60W 20V/65W 5V/9V/12V/15V/20V
	Hold-up time	5ms at 115 Vac input
	Output current limit	<8.0A
	Connector	USB Type-C
	Environmental Design Operating temperature Non-operating (storage) temperature	32° to 95° F (0° to 35° C) -4° to 185° F (-20° to 85° C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC
		Class B, CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.

Technical Specifications

	D ¹	102 55 20.00
AC Adapter 65 Watt	Dimensions	102 x 55 x 30mm
Smart nPFC EM Barrel	Weight	unit: 250g +/- 10g
4.5mm New EM	Input	100~240 VAC
	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
	Input frequency range	47 ~ 63 Hz
	Input AC current	Max. 1.7 A at 90 Vac
	Output	
	Output power	65W
	DC output	19.5V
	Hold-up time	5ms at 115 Vac input
	Output current limit	<11.0A
	Connector	4.5mm Barrel Type
	Environmental Design	
	Operating temperature	32°F to 95°F (0°to 35°C)
	Non-operating (storage)	-4ºF to 185ºF (-20ºto 85ºC)
	temperature	
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
	EMI and Safety Certifications	Eg:
		*CE Mark - full compliance with LVD and EMC directives
		* Worldwide safety standards - IEC60950-1 and/or IEC62368-1,
		EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1 , Class1, SELV;
		Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC
		Class B, CISPR32 Class B, CCC, NOM-001 NYCE.
		* MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt
Smart nPFC Standard
Barrel 4.5mm Right
Angle 1.8m

Dimensions	90 x 51 x 28.5mm
Weight	230g +/-10%
Input	100~240 VAC
Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
Input frequency range	47 ~ 63 Hz
Input AC current	Max. 1.7 A at 90 Vac
Output	
Output power	65W
DC output	19.5V
Hold-up time	5 ms at 115 Vac input
Output current limit	<11.0A
Connector	4.5mm Barrel Type
Environmental Design	
Operating temperature	32°F to 95°F (0°to 35°C)
Non-operating (storage)	-4°F to 185°F (-20°to 85°C)
temperature	
Altitude	0 to 16,400 ft (0 to 5000m)
Humidity	20% to 95%
Storage Humidity	10% to 95%
EMI and Safety Certifications	Eg:
	*CE Mark - full compliance with LVD and EMC directives
	* Worldwide safety standards - IEC60950-1 and/or IEC62368-1,
	EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1,
	SELV;
	Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC

Technical Specifications

Class B, CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.

RH 42Whr ¹ Long Life	Dimensions (H x W x L)	6.2 x 76.25 x 249.50 mm (0.244 x 3.002 x 9.823 inch)
Polymer Fast Charge ² 3	Weight	0.18 kg (0.397 lb)
cell Battery	Cells/Type	3cell Lithium-Ion Polymer cell / 545974
	Energy	
	Voltage	11.4V
	Amp-hour capacity	3.752Ah
	Watt-hour capacity	42.75Wh
	Temperature	
	Operating (Charging)	32? to 113? F (0? to 45? C)
	Operating (Discharging)	14? to 122? F (-10? to 60? C)
	Fuel Gauge LED	NA
	Warranty	Follow Product Spec.
	Optional Travel Battery	No
	Available	
1 Actual battory Matt by	ours (Mb) will yory from docigr	conscitu. Pottoru conscitu will noturally docroaco with chalf lif

Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.
 Recharges your battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

RH 51Whr ¹ Long Life Polymer Fast Charge ² 3 cell Battery	Dimensions (H x W x L) Weight Cells/Type	6.50 x 67.80 x 254.00 mm (0.256 x 2.669 x 10 inch) 0.2025 kg (0.446 lb) 3cell Lithium-Ion Polymer cell / 566075
	Energy	
	Voltage	11.58V
	Amp-hour capacity	4.431Ah
	Watt-hour capacity	51.3Wh
	Temperature	
	Operating (Charging)	32? to 113? F (0? to 45? C)
	Operating (Discharging)	14? to 122? F (-10? to 60? C)
	Fuel Gauge LED	NA
	Warranty	Follow Product Spec.
	Optional Travel Battery Available	No

1. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors. 2. Recharges your battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance

Audio

Technical Specifications

HD Stereo Codec Audio I/O Ports	ALC3247-CG Headset: CTIA only and Headphone-out
Internal Speaker Amplifier	ALC 3247 has Embedded Class-D 2W Stereo Amplifier
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio.
Sampling	Following MSFT Behavior DAC:44.1k/48kHz ADC:48kHz
Wavetable Syntheses	NA
Analog Audio	Support 3.5mm Headset: CTIA only and Headphone-out
# of Channels on Line-Out	NA
Internal Speaker	Yes

Fingerprint reader Sensor vendor Sensor type DPI resolution Scan area False Rejection Rate False Acceptance Rate Mobile Voltage Operation Operating Temperature Current Consumption Image Low Latency Wait For Finger Capture Rate ESD Resistance	Elan efsa80ST Capacitive 508 dpi 80*80 pixels <3% 1/100K 2.7V to 3.6V -4 - 175°F (-20° ~ +80°C) 50mA peak 900uA 30 frame/sec +15KV
Detection Matrix	80*80 pixels/ 508 dpi / 4*4mm sensor area

ENVRIONMENTAL DATA

This product has received or is in the process of being certified to the following approvals and may
be labeled with one or more of these marks:
IT ECO declaration
US ENERGY STAR®
 US Federal Energy Management Program (FEMP)
• EPEAT? Gold registered in the United States. See http://www.epeat.net for registration status
in your country.
TCO Certified
 China Energy Conservation Program (CECP)
China State Environmental Protection Administration (SEPA)
Taiwan Green Mark
Korea Eco-label
Japan PC Green label*
Ocean-bound plastic in Speaker
 10% post-consumer recycled plastic
Low halogen
 Outside Box and corrugated cushions are 100% sustainably sourced and
recyclable
 Molded Paper Pulp Cushion inside box is 100% sustainably sourced and
recyclable
Bulk packaging available

Technical Specifications

System Configuration	The configuration used for the Energy Consumption and Decla Notebook model is based on a "Typically Configured Notebook				
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 5	iOHz	100VAC, 50Hz	
Normal Operation (Sort					
dle)	4.28 W	4.36 W	<u> </u>	4.37 W	
Normal Operation (Long	1.75.14	1 77 1	,		
dle) Sleep	1.25 W 1.25 W	<u>1.37 V</u> 1.37 V		<u> </u>	
Off	0.3 W	0.35 V	1	0.31 W	
	Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.				
Heat Dissipation*	115VAC, 60Hz	230VAC, 5	۰. ۱۳۰۰	100VAC, 50Hz	
Normal Operation (Short	113VAC, 00H2	230VAC, 3		100VAC, 50H2	
idle)	14.6 BTU/hr	14.9 BTU	/hr	14.9 BTU/hr	
Normal Operation (Long	11.0 510/11	11.5 510	/	11.5 510/11	
dle)	4.3 BTU/hr	4.7 BTU	/hr	4.3 BTU/hr	
Sleep	4.3 BTU/hr	4.7 BTU		4.3 BTU/hr	
Off	1 BTU/hr	1.2 BTU	/hr	1.1 BTU/hr	
Declared Noise Emissions	attained for one hour. Sound Power			Sound Pressure	
(in accordance with ISO 7779 and ISO 9296)	(L _{WAd} , bels)		(L _{pAm} , decibels)		
Typically Configured - Idle	2.6		13.7		
Fixed Disk - Random writes	2.8		21.2		
Optical Drive - Sequential	3.8		32.6		
reads Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the				
Additional Information	end of production.	pliance with the		nd or for up to "5"? years after the f Hazardous Substances (RoHS)	
 This HP product is designed to comply with the Waste Electrical and Elect Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of Califor Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per Is and ISO1043. This product is 93.3% recycle-able when properly disposed of at end of life. 			tion 65 (State of California; Safe PEAT) standard at the Gold level, roduct are marked per ISO11469		

Technical Specifications

Packaging Materials	External:	PAPER/Corrugated	295 g	
		PAPER/Molded Pulp	192 g	
	Internal:	PLASTIC/Polyethylene low density - LDPE	10 g	
RoHS Compliance	 The plastic packaging material contains at least 0.0% recycled content. The corrugated paper packaging materials contains at least 60.6% recycled content. HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances-including PVC, BFRs, and certain phthalates-in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS 			
Material Usage	 requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see Error! Hyperlink reference not valid. HP RoHS position statement. This product does not contain any of the following substances in excess of regulatory limits (reference) 			
	the HP General S http://www.hp.co Asbestos Certain Az Certain Bru Cadmium Chlorinate Bis(2-Ethy Benzyl but Dibutyl ph Diisobutyl Formaldef Halogenat Lead carbo Lead and I Mercuric O Nickel - fir or carried Ozone Dep Polybromi Polybromi Polybromi Polybromi Polychlori Polychlori Polyvinyl O voluntarily Radioactiv	specification for the Environment at com/hpinfo/globalcitizenship/environment/supply co Colorants ominated Flame Retardants - may not be used as fla ed Hydrocarbons d Paraffins /lhexyl) phthalate (DEHP) tyl phthalate (BBP) thalate (DBP) phthalate (DBP) phthalate (DIBP) hyde ced Diphenyl Methanes onates and sulfates Lead compounds Dxide Batteries hishes must not be used on the external surface des by the user. Deleting Substances inated Biphenyls (PBBs) inated Biphenyl Ethers (PBBEs) inated Biphenyl (PCB) nated Terphenyls (PCT) Chloride (PVC) - except for wires and cables, and cer y removed from most applications. // Substances in (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBT)	chain/gen_specifications.html): ame retardants in plastics signed to be frequently handled rtain retail packaging has been	
Packaging Usage	Eliminate materials.Eliminate	e guidelines to decrease the environmental impa the use of heavy metals such as lead, chromium, m the use of ozone-depleting substances (ODS) in pac ckaging materials for ease of disassembly.	nercury and cadmium in packagi	

Technical Specification	S
	 Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment:
	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and
footnotes	 <u>http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</u> Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
	 External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced
	 certified and recycled fibers. Fiber cushions made from 100% recycled wood fiber and organic materials.

COUNTRY OF ORIGIN

China

Options and Accessories (sold separately and availability may vary by country)

(incl.the notebo Max.resolutions Dock Connector Technical limita Docking station Total number of	supported displays ok display) s supported s tions model #2	HP USB-C Dock G5 3 Dual 5K@ 30Hz + 1 4K UHD (multi-function mode) 5120x2880 1xHDMI, 2xDP Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode. Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in Multi-function mode The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port. HP USB-C/A Universal Dock G2
(incl.the notebo Max.resolutions Dock Connector Technical limita Docking station Total number of	ok display) s supported 's tions model #2	Dual 5K@ 30Hz + 1 4K UHD (multi-function mode) 5120x2880 1xHDMI, 2xDP Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode. Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in Multi-function mode The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Max.resolutions Dock Connector Technical limitar Docking station Total number of	s supported 's tions model #2	1xHDMI, 2xDP Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode. Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in Multi-function mode The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Technical limita Docking station Total number of	tions model #2	Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode. Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in Multi-function mode The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Docking station Total number of	model #2	Resolution mode. Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in Multi-function mode The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Total number of		Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in Multi-function mode The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Total number of		plus one 4K UHD@ 30 Hz on HDMI in Multi-function mode The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Total number of		The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Total number of		mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Total number of		
Total number of		HDUSE C/Allpinereal Dack C2
	ovelazih hetroaanuz ⁷	HP USD-C/A UNIVERSAL DUCK GZ
(incl.the notebo		3
Max.resolutions		Triple 4K UHD@ 60Hz 3840x2160
Dock Connector		1xHDMI, 2xDP
Technical limita	-	The best resolution for dual or triple displays is 4K UHD@ 60Hz.
		For use with the USB-A adapter that comes in the box the maximum
		number of displays supported is (2) 4k x 60 Hz on the Type-A Gen 1
		connection from the host
Docking station		HP Thunderbolt Dock G2
	supported displays	4
(incl.the notebo Max.resolutions		Dual 4K @30Hz or dual 4K UHD @ 60Hz is supported
riax.i cjuaciui.	Supporteu	Dual 8K@ 60Hz for TB hosts or USB-C hosts DP 1.4 with DSC in high res
		mode
Dock Connector		2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode
Technical limita	tions	Thunderbolt Hosts:
		Maximum of (4) displays with maximum resolution of 5K@ 30Hz running Thunderbolt host.
		Maximum resolution possible is dual 8K displays @ 60Hz running
		Thunderbolt host or running a non-Thunderbolt host in high resolution
		mode @30Hz
		Non-Thunderbolt hosts:
		The highest resolution for dual displays running a non-Thunderbolt host in multi-function mode is
		(1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port
		Non-Thunderbolt hosts support (3) displays with a maximum
		resolution of (2) 5K single cable + (1) 4K UHD @ 60 Hz in high
		resolution mode. In multi-function mode the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz + (1) 4K UHD @ 30Hz.

Category	Description	Part Number
Audio/Video	HP Wired USB-A Stereo Headset	428K6AA
	HP Wired 3.5mm Stereo Headset	428K7AA
Cases	HP Business Slim 17.3 Top Load	2UW02AA
	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Executive 17.3 Backpack	6KD05AA

Options and Accessories (sold separately and availability may vary by country)

Options and Acc	essories (solu separately and availability may vary by country)	
	HP Executive 17.3 Top Load	6KD08AA
	HP Executive Leather 15.6 Top Load	6KD09AA
	HP Prelude G2 15.6 Backpack	1E7D6AA
	HP Prelude G2 15.6 Top Load	1E7D7AA
	HP Prelude Pro Recycled 15.6 Backpack	1X644AA
	HP Prelude Pro Recycled 15.6 Top Load	1X645AA
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA
	HP Renew Business 17.3 Laptop Bag	3E2U6AA
	HP Renew Business 15.6 Laptop Bag	3E5F8AA
Docking	HP Thunderbolt 120W G2 Dock	2UK37AA
	HP Thunderbolt 120W G2 Dock w/Audio	3YE87AA
	HP Thunderbolt 120W G4 Dock	4J0A2AA
	HP Thunderbolt 230W G2 Dock w/Combo Cable	3TR87AA
	HP Thunderbolt 280W G4 Dock w/Combo Cable	4JOG4AA
	HP USB-C/A 120W G2 Universal Dock	5TW13AA
	HP USB-C 120W G5 Dock	26D32AA
Hub	HP USB-C Mini Dock	1PM64AA
1140	HP Universal USB-C Multiport Hub	50H55AA
	HP USB-C Travel Dock G2	7PJ38AA
	HP USB-C to USB-A Hub	Z6A00AA
		5543044
Adapter	HP HDMI to DVI Adapter	F5A28AA
	HP HDMI to VGA Adapter	H4F02AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to HDMI 2.0 Adapter	N7P47AA
	HP USB-C to USB 3.0 Adapter	1WC36AA
	HP USB-C to VGA Adapter	N9K76AA
Keyboard/Combo	HP 975 USB+BT Dual-Mode Wireless Keyboard	3Z726AA
	HP 455 Programmable Wireless Keyboard	4R177AA
	HP 125 WD USB Keyboard	266C9AA
	HP 320K WD USB Keyboard	9SR37AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 235 Wireless Mouse and Keyboard Combo	1Y4D0AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
Mouse	HP USB Premium Wireless Mouse	1JR31AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
	HP 125 USB-A Wired Mouse	265A9AA
	HP 128 USB Laser Wired Mouse	265D9AA
	HP 320M USB-A Wired Mouse	9VA80AA
	HP Creator USB-A+Bluetooth 935 Wireless Mouse Black	1DOK8AA
	HP USB-A+Bluetooth Multi-Device 635 Wireless Mouse Black	1DOK2AA
	HP USB-A+Bluetooth Travel Bluetooth Mouse	6SP30AA
Power	HP 65W USB-C Auto Chevy AC Power Adapter	5TQ76AA

Options and Accessories (sold separately and availability may vary by country)

Summary of Changes

Date of change:	Version History:	Updated	Description of change:
April 11, 2022	V1 to V2	Added	Environmental Data and Reference for USB ports
May 13, 2022	V2 to V3	Updated	Battery life
June 6, 2022	V3 to V4	Added	RJ-45 disclaimer in overview and ports section; Manageability disclaimer
June 22, 2022	V4 to V5	Updated	Discrete in Graphics section
July 20, 2022	V5 to V6	Added	Input value in Power section

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Overview

HP Elite x360 1040 14 inch G9 2-in-1 Notebook PC



- 1. Internal Microphones (2)
- 2. Ambient Light Sensor (Optional)
- 3. Webcam
- 4. Camera Shutter
- 5 IR Camera (Optional)
- 6. IR Camera LEDs (Optional)
- 7. Glass Clickpad
- 1. SuperSpeed USB 20Gbps is not available with Thunderbolt $^{\mathsf{TM}}$ 4.

Left

- 8. Smartcard Reader (Optional)
- 9. LED Indicator
- **10.** Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)¹
- **11.** ThunderboltTM 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPortTM 1.4)¹
- 12. SuperSpeed USB Type-A 5Gbps signaling rate (USB 3.2 Gen 1)
- 13. HDMI 2.0b Port (Cable not included)

Overview



Right

- 1. Power Button Key
- 2. Audio Combo Jack
- SuperSpeed USB Type-A 5Gbps signaling rate (Charging) 6. (USB 3.2 Gen 1)
- 4. Nano Security Lock Slot (Lock sold separately)
- 5. SIM Card Slot (Optional)
 - . Touch Fingerprint Sensor (Select models)

Overview

At a Glance

- Preinstalled with Windows 11 versions or FreeDOS
- A new x360 ultraslim design with precision-crafted magnesium chassis for a premium look and feel
- 12th Generation Intel[®] Core[™] i5, i7 U series, up to ten-core
- New 16:10 ratio screen reduces the need to scroll by showing more vertical content than 16:9
- New 5MP camera with HP Auto Frame allows you around a little without losing viewers' attention during video calls
- New DDR5 memory (up to 16GB) and PCI Gen4 SSDs provide fast access to your work.
- Choice of displays:

35.6 cm (14"?) diagonal BV WUXGA (1920x1200) LED-backlit, 250 nits, 45% NTSC, touchscreen

35.6 cm (14"?) diagonal AG WUXGA (1920x1200) LED-backlit, 400 nits, 100% sRGB, touchscreen with HP Eye Ease

35.6 cm (14"?) diagonal BV WUXGA (1920x1200) LED-backlit, 400 nits, 100% sRGB, touchscreen with HP Eye Ease

35.6 cm (14"?) diagonal AG WUXGA (1920x1200) LED-backlit, 1000 nits, 100% sRGB, HP Sure View Reflect, touchscreen with HP Eye Ease

35.6 cm (14") diagonal BV WUXGA (1920x1200) LED-backlit, 1000 nits, 100% sRGB, HP Sure View Reflect, touchscreen with HP Eye Ease

- An optional HP Rechargeable Active Pen 3 with Magnetic Attach and 4096 Levels of pressure
- Choose from 38Wh or 51Wh battery options
- HP Wolf Security for Business creates a hardware-enforced, always-on, resilient defense.
- Larger Clickpad surface for easier, more intuitive input
- Connectivity with optional Intel[®] 5000 5G/WWAN available world-wide, and Thunderbolt[™] Docking (Dock sold separately)
- Undergoes MIL-STD 810H tests
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles
- Designed to support all HP docking options including the HP Universal Dock G5

NOTE: See important legal disclosures for all listed specs in their respective features sections.

PRODUCT NAME

HP Elite x360 1040 14 inch G9 2-in-1 Notebook PC

OPERATING SYSTEMS

Preinstalled

Windows 11 Pro¹ Windows 11 Pro Education¹ Windows 11 Home - HP recommends Windows 11 Pro for business¹ Windows 11 Home Single Language - HP recommends Windows 11 Pro for business¹ Windows 11 Pro (Windows 11 Enterprise available with a Volume Licensing Agreement)¹ Windows 10 Pro (available through downgrade rights from Windows 11 Pro)^{1,2} FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

Processor	Cores	Number of	Number of	Threads	L3 Cache		ſurbo uency	Ba Frequ	se uency	Intel SIPP/vPro®
3,4,5,6,7	CUIES	P-cores	E-cores	i ili caus	LS Cacile	P-	E-	P-	E-	Enterprise
						cores	cores	cores	cores	
Intel [®] Core™	10	2	8	12	12MB	4.8	3.6	1.8	1.3	X
i7-1265U						GHz	GHz	GHz	GHz	
Intel [®] Core™	10	2	8	12	12MB	4.7	3.5	1.7	1.2	
i7-1255U						GHz	GHz	GHz	GHz	
Intel [®] Core [™]	10	2	8	12	12MB	4.4	3.3	1.2	1.2	Х
i5-1245U						GHz	GHz	GHz	GHz	
Intel [®] Core [™]	10	2	8	12	12MB	4.4	3.3	1.3	0.9	
i5-1235U						GHz	GHz	GHz	GHz	

PROCESSORS

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
 5. Intel[®] Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on product configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

7. Intel vPro[®] requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LA and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro[®] Essentials and Enterprise vary. See http://intel.com/vpro

Technical Specifications

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel[®] Iris[®] X? Graphics ⁸

Supports

Support HD decode, DX12, HDMI 2.0b, HDCP 2.3 ⁹

8. Intel[®] Iris[®] X? Graphics capabilities require system to be configured with Intel[®] CoreTM i5 or i7 processors and dual channel memory. Intel[®] Iris[®] X? Graphics with Intel[®] CoreTM i5 or 7 processors and single channel memory will only function as UHD graphics 9. HDMI cable sold separately

DISPLAY

Touch

35.56 cm (14") diagonal WUXGA Bent touch screen, BrightView UWVA, eDP, 250 nits, 45% NTSC, time of flight sensor, with 5MP+IR camera (1920 x 1200) ^{10,11,13}

35.56 cm (14") diagonal WUXGA Bent touch screen, BrightView UWVA, eDP, 250 nits, 45% NTSC, time of flight sensor, with 5MP+IR camera for WWAN (1920 x 1200) ^{10,11,13}

35.56 cm (14") diagonal WUXGA Bent touch screen, Low Blue Light, anti-glare UWVA eDP1.4+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR Camera (1920 x 1200) with HP Eye Ease ^{10,11,13} 35.56 cm (14") diagonal WUXGA Bent touch screen, Low Blue Light, anti-glare UWVA eDP1.4+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR Camera for WWAN (1920 x 1200) with HP Eye Ease ^{10,11,13}

35.56 cm (14") diagonal WUXGA Bent touch screen, Low Blue Light, BrightView UWVA eDP1.4+PSR, 400 nits, 100% sRGB, Low Power Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR Camera (1920 x 1200) with HP Eye Ease ^{10,11,13} 35.56 cm (14") diagonal WUXGA Bent touch screen, Low Blue Light, BrightView UWVA eDP1.4+PSR, 400 nits, 100% sRGB, Low Power Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR Camera for WWAN (1920 x 1200) with HP Eye Ease ^{10,11,13}

35.56 cm (14") diagonal WUXGA Bent touch screen, Low Blue Light, anti-glare UWVA eDP1.3+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR camera (1920 x 1200) with HP Eye Ease ^{10,11,12,13}

35.56 cm (14") diagonal WUXGA Bent touch screen, Low Blue Light, anti-glare UWVA eDP1.3+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR camera for WWAN (1920 x 1200) with HP Eye Ease ^{10,11,12,13}

35.56 cm (14") diagonal WUXGA Bent touch screen, Low Blue Light, BrightView UWVA eDP1.3+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR camera (1920 x 1200) with HP Eye Ease ^{10,11,12,13}

35.56 cm (14") diagonal WUXGA Bent touch screen, Low Blue Light, BrightView UWVA eDP1.3+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR camera for WWAN (1920 x 1200) with HP Eye Ease ^{10,11,12,13}

DisplayPort[™] 1.2

HDMI 2.0 Support resolution up to 4K @60 Hz⁸ **Displays support** Supports dual display through the dock

Display Size (diagonal) 14" 35.56 cm (14")

Technical Specifications

- 9. HDMI cable sold separately
- 10. HD content required to view HD images.
- 11. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

12. HP Sure View Reflect integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

13. Actual brightness will be lower with touchscreen or HP Sure View.

DOCKING (Sold Separately)

Docking station model #1 Docking station model #2 Docking station model #3 HP Thunderbolt Dock G2 HP USB-C Dock G5 HP USB-C/A Universal Dock G2

For additional aftermarket options and docking specs please see page 40.

STORAGE AND DRIVES

Primary M.2 Storage

2 TB PCIe[®] Gen4x4 NVMeTM M.2 SSD TLC ¹⁴ 1 TB PCIe[®] Gen4x4 NVMeTM M.2 SSD TLC ¹⁴ 512 GB PCIe[®] Gen4x4 NVMeTM M.2 SSD TLC ¹⁴ 512 GB PCIe[®] Gen4x4 NVMeTM SED TLC OPAL2 ¹⁴ 512 GB PCIe[®] NVMeTM Value M.2 SSD ¹⁴ 256 GB PCIe[®] Gen4x4 NVMeTM M.2 SSD TLC ¹⁴ 256 GB PCIe[®] Gen4x4 NVMeTM SED TLC OPAL2 ¹⁴ 256 GB PCIe[®] NVMeTM Value M.2 SSD ¹⁴

14. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software.

MEMORY

Maximum Memory 16 GB DDR5-4800¹⁵

Memory 16 GB DDR5-4800 ¹⁵ 8 GB DDR5-4800 ¹⁵

Memory Slots

Memory soldered down DDR5 SODIMMS, system runs at 4800 Supports Dual Channel Memory

15. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel® AX211 Wi-Fi6E +BT5.2 M.2 160MHz CNVi World-Wide WLAN vPro ^{16,17,18} Intel® AX211 Wi-Fi6E +BT5.2 M.2 160MHz CNVi World-Wide WLAN non-vPro ^{16,18} WWAN

Intel® 5000 5G Solution WWAN ^{19,20} Intel® XMM 7560 R+ LTE-Advanced Pro WWAN (Cat 16) ¹⁹

NFC

Near Field Communications Controller ²¹ HP Module with NXP NFC Controller NPC300 I2C NCI

Miracast

Native Miracast Support ²²

16. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

17. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. 18. For full Intel® vProTM functionality, Windows, a vPro supported processor, vPro enabled chipset, vPro enabled WLAN card and discrete TPM 2.0 are required. See https://www.intel.com/content/www/us/en/architecture-and-technology/vpro/vpro-platform-general.html

19. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

20. Intel 5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported. 21. Sold separately or as an optional feature.

22. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

AUDIO/MULTIMEDIA

Technical Specifications

Audio

Audio by Bang & Olufsen 2 Integrated stereo speakers Discrete Amplifiers Integrated dual array microphone

Speaker Power

2W/4ohm Per speaker

Camera

5 MP camera ²¹ 5 MP+IR camera ²¹

Sensors

ALS (ambient light sensor) Magnetometer Hall Sensor Gyro Accelerometer HP Tamper Lock ²³

21. Sold separately or as an optional feature.23. HP Tamper Lock must be enabled by the customer or your administrator.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant, Backlit keyboard and DuraKeys

Pointing Device

Clickpad with multi-touch gesture support, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

ESC: system information F1 - Display Switching F2 - Blank or Privacy F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Blank or Backlit Toggle F10 - Insert F11 - Airplane Mode F12 - HP Command Center home end Power Button (with LED) Delete

Technical Specifications

Hidden Function Keys

Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock

SOFTWARE AND SECURITY

Software

HP Quick Touch HP Quick Drop ²⁴ HP Easy Clean ²⁵ HP PC Hardware Diagnostics Windows myHP HP Smart Support ²⁶ HP Connection Optimizer HP Hotkey Support HP Support Assistant ²⁷ HP Notifications HP Privacy Settings HP Power Manager Buy Microsoft Office (Sold separately)

Manageability Features

HP Image Assistant Gen5 (download) HP Manageability Integration Kit (download) ²⁸ HP Client Management Script Library (download) HP Driver Packs (download) HP Cloud Recovery ²⁹ HP Client Catalog (download)

Security Management

HP Wolf Security of Business ³⁰ includes:

HP Sure Click ³¹ HP Sure Sense ³² HP Sure Run Gen5 ³³ HP Sure Recover Gen5 ³⁴ HP Sure Start Gen7 ³⁵ HP Tamper Lock HP Sure Admin ³⁶ HP Client Security Manager Gen7 ³⁷

BIOS

HP BIOSphere Gen6 ³⁸ HP Secure Erase ³⁹ Absolute Persistence Module ⁴⁰ HP DriveLock & Automatic DriveLock BIOS Update via Network HP Wake on WLAN HP Fingerprint Sensor ⁴¹ Secured-Core PC Enable ⁴² TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

Security TPM

Model: Infineon SLB9672VU2.0 Version: 15.21 Revision: TPM 2.0 FIPS 140-2 Compliant: Yes

Smartcard Reader Model number: Alcor AU9560 FIPS 201 Compliant: Yes

IPv6 Support Yes

FirstNet Certified

Yes

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?: Yes

UEFI version: 2.7 Class: Class 3

24. HP Quick Drop requires Internet access and Windows 10 or higher PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.

25. HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.

26. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.

27. HP Support Assistance requires Windows and Internet Access.

28. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html. 29. HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.

30. HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite. RPOS and Workstation products. See product details for included security features and OS requirement.

31. HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.lv/2PrLT6A SureClick for complete details. 32. HP Sure Sense is available on select HP PCs with Windows 10 Pro. Windows 10 Enterprise. Windows 11 Pro. or Windows 11 Enterprise OS.

33. HP Sure Run Gen5 is available on select HP PCs and requires Windows 10 and higher.

34. HP Sure Recover Gen5 with Embedded Reimaging is an optional feature which requires Windows 10 and higher must be configured at purchase. You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.

35. HP Sure Start Gen7 is available on select HP PCs and requires Windows 10 and higher.

36. HP Sure Admin requires Windows 10 or higher, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

37. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.

38. HP BIOSphere Gen6 features may vary depending on the platform and configuration.

39. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® OptaneTM.

40. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/.

41. HP Fingerprint sensor is an optional feature that must be configured at purchase. 42. Secured-Core PC Enable requires an Intel® vPro®, AMD RyzenTM Pro processor or Qualcomm® processor with SD850 or higher

and requires 8 GB or more system memory. Secured-core PC is enabled from the factory.

POWER

Technical Specifications

Power Supply

HP Smart 65 W USB Type-C adapter ⁴³ HP Smart 65 W Slim USB Type-C adapter ⁴³ HP Smart 45 W USB Type-C adapter ⁴³

Battery

HP Long Life 3-cell, 38 Wh Polymer ^{44,45} HP Long Life 3-cell, 51 Wh Polymer ^{44,45} Compliant with UL 1642 Standard

Power Cord

3-wire plug - 1m 2-wire plug - 1m

Battery Life

Up to 13 hours 45 minutes (51 Whr battery) ⁴⁶ Up to 10 hours (38 Whr battery) ⁴⁶

43 Availability may vary by country.

44. Battery is internal and not replaceable by customer. Serviceable by warranty.

45. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors. 46. MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight- 38 Wh ⁴⁷ Starting at 2.98 lb Starting at 1.35 kg

Product Dimensions (W x D x H) 12.42 x 8.89 x 0.75 in 31.56 x 22.565 x 1.92 cm

47. Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

2 ThunderboltTM 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPortTM 1.4) ⁴⁸

2 Super Speed USB Type-A 5Gbps signaling rate (1 charging) (USB 3.2 Gen 1)

1 HDMI 2.0 ⁹

- 1 Headphone/microphone combo jack
- 1 Nano Security Lock Slot (Lock sold separately)
- 1 Smartcard reader (Optional)
- 1 nano SIM card slot

9. HDMI cable sold separately
48. SuperSpeed USB 20Gbps is not available with ThunderboltTM 4.

SERVICE AND SUPPORT

1-year warranty and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.⁴⁹

49. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated t Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such right are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Type-C Adapter
Nominal Operating Voltage	AC 20V
Average Operating Power	
Integrated graphics	Yes
Discrete Graphics	N/A
Max Operating Power	UMA<65W
Temperature	
Operating	32° to 95° F (0° to 35° C)
Non-operating	41° to 95° F (5° to 35° C) (writing optical)
Relative Humidity	
Operating	10% to 90%, non-condensing
Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	
Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine
Random Vibration	
Operating	0.75 grams
Non-operating	1.50 grams
Altitude (unpressurized)	
Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard	
Certifications	
Regulatory Model Number	HSN-145C
UL	Yes
CSA	Yes
FCC Compliance	Yes
ENERGY STAR [®]	Certified ⁵⁰
EPEAT [®]	EPEAT [®] Gold in the United States ⁵¹
ICES	Yes
Australia /	Yes
NZ A-Tick Compliance	Yes
CCC	Yes
Japan VCCI Compliance	Yes

Technical Specifications

кс	Yes
BSMI	Yes
CE Marking Compliance	Yes
BNCI or BELUS	Yes
СІТ	Yes
GOST	Yes
Saudi Arabian Compliance (ICCP)	Yes
SABS	Yes

50. Configurations of the HP Elite x360 1040 14 inch G9 2-in-1 Notebook PC that are ENERGY STAR® qualified are identified as HP Elite x360 1040 14 inch G9 2-in-1 Notebook PC ENERGY STAR on HP websites and on http://www.energystar.gov. 51. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.energystar.gov.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

1. Actual brightness will be lower with touchscreen or HP Sure View.

14.0 in WUXGA
(1920 x 1200) Anti-Glare
UWVA LED NTSC NB2X 250
eDP 1.2 w/o PSR 45 bent LCD
Panel

Outline Dimensions (W x H x D)	307.590 x 199.550 (max)
Active Area	301.590 X 188.500 (typ)
Weight	300 (max)
Diagonal Size	14
Thickness	3.0 / 5.0 (max)
Interface	eDP 1.2
Surface Treatment	Anti-Glare
Touch Enabled	Yes ¹
Contrast Ratio	1000:1(typ)
Refresh Rate	60 Hz
Brightness	250 nits ¹
Pixel Resolution - Format	1920 x 1200 (WUXGA)
Backlight	WLED
P.P.I.	162
Pixel Resolution - configuration	RGB
Color Gamut Coverage	NTSC 45%
Color Depth	8 bits
Viewing Angle	UWVA 89/89/89/89
Low Blue Light	No
Power Consumption (W, EBL@ 150nits max/ 200nits max)	2.20 (max) / 2.70 (max)

Technical Specifications

14.0 in WUXGA (1920 x 1200) Anti-Glare UWVA WLED+LBL sRGB NB2X 400 eDP 1.4+PSR2 Low- Power 100 bent LCD Panel	Outline Dimensions (W x H x D)Active AreaWeightDiagonal SizeThicknessInterfaceSurface TreatmentTouch EnabledContrast RatioRefresh RateBrightnessPixel Resolution - FormatBacklightP.P.I.Pixel Resolution - configurationColor Gamut CoverageColor Depth	307.590 x 199.550 (max) 301.590 X 188.500 (typ) 210 (max) 14 2.0 / 3.8 (max) eDP 1.4 Anti-Glare Yes ¹ 1000:1(typ) 60 Hz 400 nits ¹ 1920 x 1200 (WUXGA) WLED 162 RGB 5RGB 100% 8 bits
	Color Gamut Coverage	sRGB 100%

14.0 in WUXGA (1920 x 1200) Anti-Glare UWVA WLED+LBL sRGB NB2Y 1000 eDP 1.3+PSR 100 PrivacyG4 Plus bent LCD Panel

Outline Dimensions (W x H x D)	307.600 x 199.550 (typ)
Active Area	301.680 x 188.500 (typ)
Weight	238 (max)
Diagonal Size	14
Thickness	2.2 / 3.9 (max)
Interface	eDP 1.3
Surface Treatment	Anti-Glare
Touch Enabled	Yes ¹
Contrast Ratio	1500:1(typ)
Refresh Rate	60 Hz
Brightness	1000 nits ¹
Pixel Resolution - Format	1920 x 1200 (WUXGA)
Backlight	WLED
P.P.I	162
Pixel Resolution - configuration	RGB
Color Garmut Coverage	sRGB 100%
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85
Low Blue Light	Yes
Power Consumption (W, EBL@ 150nits max/ 200nits max)	N/A

Technical Specifications

STORAGE AND DRIVES

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software.

SSD 256GB 2280 PCIe-4x4	Form Factor	M.2 2280
NVMe Three Layer Cell	Capacity	256GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen4X4
	Maximum Sequential Read	4000 MB/s ±20%
	Maximum Sequential Write	2000 MB/s ±20%
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite 2.0; TRIM; L1.2
SSD 512GB 2280 PCIe-4x4	Form Factor	M.2 2280
NVMe Three Layer Cell	Capacity	512GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen4X4
	Maximum Sequential Read	6400 MB/s ±20%
	Maximum Sequential Write	3500 MB/s ±20%
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite 2.0; TRIM; L1.2
SSD 1TB 2280 PCIe-4x4 NVMe	Form Factor	M.2 2280
Three Layer Cell	Capacity	1TB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen4X4
	Maximum Sequential Read	6400 MB/s ±20%
	Maximum Sequential Write	5000 MB/s ±20%
	Logical Blocks	2,000,409,264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite 2.0; TRIM; L1.2

Technical Specifications

SSD 2TB 2280 PCIe-4x4 NVMe	Form Factor	M.2 2280
Three Layer Cell	Capacity	2TB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen4X4
	Maximum Sequential Read	6400 MB/s ±20%
	Maximum Sequential Write	5000 MB/s ±20%
	Logical Blocks	4,000,797,360
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite 2.0; TRIM; L1.2

256GB PCIe-4x4 2280 NVME	Form Factor	M.2 2280
Self Encrypted OPAL2 Three	Capacity	256GB
Layer Cell Solid State Drive	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen4X4
	Maximum Sequential Read	4000 MB/s ±20%
	Maximum Sequential Write	2000 MB/s ±20%
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TCG Opal 2.0; TRIM; L1.2

512GB PCIe-4x4 2280 NVME	Form Factor	M.2 2280
Self Encrypted OPAL2 Three	Capacity	512GB
Layer Cell Solid State Drive	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen4X4
	Maximum Sequential Read	6400 MB/s ±20%
	Maximum Sequential Write	3500 MB/s ±20%
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TCG Opal 2.0; TRIM; L1.2

Technical Specifications

5SD 256GB 2280 PCIe NVMe	Form Factor	M.2 2280
/alue	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	1500 MB/s ±20%
	Maximum Sequential Write	750 MB/s ±20%
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite 2.0; TRIM; L1.2

SSD 512GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	1500 MB/s ±20%
	Maximum Sequential Write	750 MB/s ±20%
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite 2.0; TRIM; L1.2

NETWORKING/COMMUNICATIONS

Intel® AX211 Wi-Fi 6E + Bluetooth® 5.2 M.2 160MHz CNVi_World-Wide	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g
WLAN vPro ^{1,5}		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	 802.11b/g/n/ax 2.402 - 2.482 GHz 802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz

Technical Specifications	
	5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz 5.955 - 6.415 GHz 6.435 - 6.515 GHz 6.535 - 6.875 GHz 6.895 - 7.115 GHz
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : 1733Mbps 802.11ax : max 2.4Gbps
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security ²	IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification IEEE 802.11i WAPI
Network Architecture Models	Ad-hoc (Peer to Peer)
Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points
Output Power ³	802.11b : +17dBm minimum 802.11g : +16dBm minimum 802.11a : +17dBm minimum 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz) : +13dBm minimum 802.11n HT20(5GHz) : +13dBm minimum 802.11n HT40(5GHz) : +13dBm minimum 802.11ac VHT80(5GHz) : +10dBm minimum 802.11ax HE40(2.4GHz) : +10dBm minimum 802.11ax HE40(2.4GHz) : +10dBm minimum 802.11ax HE40(5GHz) : +10dBm minimum 802.11ax HE40(5GHz) : +10dBm minimum 802.11ax HE80(5GHz) : +10dBm minimum
Power Consumption	Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0(VHT80) : -84dBm maximum 802.11ac, MCS9(VHT80) : -59dBm maximum 802.11ac, MCS9(VHT60) : -59dBm maximum 802.11ax, MCS11(HE40): -57dBm maximum 802.11ax, MCS11(HE40): -54dBm maximum 802.11ax, MCS11(HE60): -53.5dBm maximum

Technical Specifications

reclinical specification.	3		
	Antenna type	enclosure Two embedded du	tenna with spatial diversity, mounted in the display ual band 2.4/5 GHz antennas are provided to the card to
		support WLAN MIMO communications and Bluetooth communications	
	Form Factor	PCI-Express M.2 MiniCard	
	Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm	
	Weight	1. Type 2230 : 2.8g	
	Operating Voltage	3.3v +/- 9%	
	Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)
	Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
	Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
	LED Activity	LED Amber - Radi	o OFF; LED OFF - Radio ON
HP Integrated Module with I	Bluetooth 4.0/4.1/4.2/5.0/5.	1/5.2 Wireless Tecl	hnology
	Bluetooth Specification	4.0/4.1/4.2/5.0/5.	.1/5.2 Compliant
	Frequency Band	2402 to 2480 MHz	2
	Number of Available Channels	Legacy : 0~79 (1 M BLE : 0~39 (2 MHz	
	Data Rates and Throughput	BLE : 1 Mbps data Legacy : Synchron channels Legacy : Asynchro	ata rate; throughput up to 2.17 Mbps rate; throughput up to 0.2 Mbps nous Connection Oriented links up to 3, 64 kbps, voice nous Connection Less links 2178.1 kbps/177.1 kbps 15) or 864 kbps symmetric (3-EV5)
	Transmit Power		nponent shall operate as a Class II Bluetooth device with a it power of + 9.5 dBm for BR and EDR.
	Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend	V
	Bluetooth Software Supported Link Topology	Microsoft Window	rs Bluetooth Software
	Power Management	Microsoft Window	s ACPI, and USB Bus Support
	Certifications		15C, Section 15.247 & 15.249
	Power Management Certifications	ETS 300 328, ETS Low Voltage Direc UL, CSA, and CE Ma	tive IEC950
	Bluetooth Profiles Supported	LE L2CAP Connect Train Nudging & Ir BT4.2 ESR08 Com LE Secure Connect LE Privacy 1.2 -Lir	e Directed Advertising tion Oriented Channels nterlaced Scan pliance tion- Basic/Full nk Layer Privacy tended Scanner Filter Policies ngth Extension file (BIP)2

Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions **Channel Selection Algo** Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range

1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

5. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Intel® AX211 Wi-Fi 6E +	Wireless LAN Standards	IEEE 802.11a
Bluetooth [®] 5.2 M.2		IEEE 802.11b
160MHz CNVi World-Wide		IEEE 802.11g
WLAN non-vPro ^{®1,5}		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	• 802.11b/g/n/ax
		2.402 - 2.482 GHz
		• 802.11a/n/ac/ax
		4.9 - 4.95 GHz (Japan)
		5.15 - 5.25 GHz
		5.25 - 5.35 GHz
		5.47 - 5.725 GHz
		5.825 - 5.850 GHz
		5.955 - 6.415 GHz
		6.435 - 6.515 GHz
		6.535 - 6.875 GHz
		6.895 - 7.115 GHz
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	Data kates	 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• • • • • • •
		• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11n: max 300Mbps
		• 802.11ac : 1733Mbps
		• 802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum
	_	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ²	IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware

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	802.1x authentic WPA, WPA2: 802 WPA2 certificatic WPA3 certificatic IEEE 802.11i WAPI	2.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
Network Architecture Models	Ad-hoc (Peer to F Infrastructure (A	Peer) ccess Point Required)	
Roaming	IEEE 802.11 com	pliant roaming between access points	
Output Power ³	802.11b : +17dBm minimum 802.11g : +16dBm minimum 802.11a : +17dBm minimum 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz) : +13dBm minimum 802.11n HT20(5GHz) : +14dBm minimum 802.11n HT40(5GHz) : +13dBm minimum 802.11ac VHT80(5GHz) : +10dBm minimum 802.11ax HE40(2.4GHz) : +10dBm minimum 802.11ax HE40(5GHz) : +10dBm minimum 802.11ax HE80(5GHz) : +10dBm minimum 802.11ax HE80(5GHz) : +10dBm minimum		
Power Consumption	Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW		
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode		
Receiver Sensitivity ⁴	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0(VHT80) : -84dBm maximum 802.11ac, MCS9(VHT80) : -59dBm maximum 802.11ac, MCS9(VHT160) : -59dBm maximum 802.11ax, MCS11(HE40): -57dBm maximum 802.11ax, MCS11(HE40): -54dBm maximum 802.11ax, MCS11(HE80): -54dBm maximum		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8g 2. Type 1216: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating Non-operating	Operating 0 to 10,000 ft (3,048 m)	

Technical Specifications

recinical Specifications		
L	ED Activity	LED Amber - Radio OFF; LED OFF - Radio ON
HP Integrated Module with Blu	uetooth 4.0/4.1/4.2/5.0/5.	1/5.2 Wireless Technology
B	luetooth Specification	4.0/4.1/4.2/5.0/5.1/5.2 Compliant
Fi	requency Band	2402 to 2480 MHz
	umber of Available hannels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Si	ignaling Data Rate	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Т	ransmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
P	ower Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
	luetooth Software upported Link Topology	Microsoft Windows Bluetooth Software
P	ower Management	Microsoft Windows ACPI, and USB Bus Support
Ca	ertifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
	ower Management ertifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
	luetooth Software upported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range

1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. 2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

5. Wi-Fi 6E is designed to support algabit data rate when transferring files between two devices connected to the same router. Requires

a wireless router, sold separately, that supports 80MHz and higher channels.

Intel(R) 5G Solution	Technology/Operating bands	WCDMA/HSPA+ operating bands:
5000 ¹		Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
		Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
		Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL)
		Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
		Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
		LTE FDD/TDD operating bands:
		Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
		Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
		Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)
		Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL)
		Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
		Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
		Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL)
		Band 12: 055 to 710 Mil2 (01), 725 to 740 Mil2 (01) Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL)
		Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL)
		Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL)
		Band 17: 704 (07 10 Mil2 (02), 754 (07 40 Mil2 (02)) Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL)
		Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL)
		Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL)
		Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL)
		Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL)
		Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)
		Band 29: 717 to 728 MHz (DL)
		Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL)
		Band 32: 1452 to 1496 MHz (DL)
		Band 34: 2010 to 2025 MHz (UL/DL)
		Band 38: 2570 to 2620 MHz (UL/DL)
		Band 39: 1880 to 1920 MHz (UL/DL)
		Band 40: 2300 to 2400 MHz (UL/DL)
		Band 41: 2496 to 2690 MHz (UL/DL)
		Band 42: 3400 to 3600 MHZ (UL/DL)
		Band 43: 3400 to 3800 MHZ (UL/DL)
		Band 46: 5150 to 5925 MHZ (DL)
		Band 48: 3550 to 3700 MHZ (UL/DL)
		Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL)
		Band 71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)
		5GNR Sub 6GHZ
		n1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
		n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
		n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)
		n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
		n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
		n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL)
		n25: 1850 to 1915 MHz (UL), 191 to 821 MHz (DL)
		n28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)
		n38: 2570 to 2620 MHz (UL/DL)
		n40: 2300 to 2400 MHz (UL/DL)
		n41: 2496 to 2690 MHz (UL/DL)
		n48: 3550 to 3700 MHZ (UL/DL)
		n66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL)
		n71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)
		n77: 3300 to 4200 MHz (UL/DL)
		n79: 3300 to 3200 MHz (UL/DL)

n78: 3300 to 3800 MHz (UL/DL)

Wireless protocol standards	n79: 4400 to 5000 MHz (UL/DL) 5GNR Air Interface 3GPP Rel15 5G NR sub-6 LTE Rel14 20 layers and 2 Gbps downlink (DL) throughput - 4 ? 4 MIMO across 5x CA 200 Mbps/uplink (UL) throughput - 40 MHz ULCA and 256 QAM WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
GPS	Standalone, A-GPS (MS-A, MS-B)
GPS bands	GPS: L1 (1575.42MHz)
	GLONASS: L1 (1602MHz)
	BeidouB1(1561.098MHz)
	Galileo E1 (1575.42)
	QZSS(1575.42 MHz)
Maximum data rates	SA 5G/NR sub-6 Peak: DL4.67Gbps/ UL 1.25Gbps
	5G NSA sub 6G : DL: 3.8 Gbps/UL 700Mbps
	LTE: ue-CategoryDL 19, (DL : 1.6 Gbps)
	ue-CategoryUL 13 , (UL: 150Mbps) DC-HSPA+: 42 Mbps (Download), 11.5 Mbps (Upload)
Maximum output power	LTE: 23 dBm in all band except B41
Haxinani output power	LTE B41 HPUE = 26dBm
	NR: 23 dBm in all band except n41, n77, n78 and n79
	LTE n41, n77, n78 and n79 HPUE = 26dBm
	HSPA+: 23.5 dBm
Maximum power consumption	5G Sub 6 : 2500 mA
	LTE: 1,300 mA (peak); 1100 mA (average)
	HSPA+: 1,100 mA (peak); 800 mA (average)
Form Factor	М.2, 3042-S3 Кеу В
Weight	8 g
Dimensions	52 mm ? 30 mm ? 2.6 mm
(Length x Width x Thickness)	

1. Intel 5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported.

recinical Specificatio	JII5	
Intel® XMM [™] 7560 R+ LTE-Advanced Pro ¹	Technology/Operating bands	 FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66), 600 (band 71). TDD LTE: 2100 (Band 34), 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41), 3500 (Band 42), 3700 (Band 43), 3700 (band 48), 5200 (Band 46 RX only) MHz; HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW throughput up to 978Mbps; UL-CAT.13 40MHz throughput up to 150Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone GPS/Beidou/Glonass, A-GPS (MS-A, MS-B)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
	Maximum data rates	LTE: 978 Mbps (Download), 150 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm in all band except B41 LTE B41 HPUE = 26dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	6 g
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm
	eSIM	Support

Technical Specifications

1. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications

Dimensions (L x W x H) Near Field Module 25 mm by 10 mm by 2.0 mm Communications Chipset NPC100 **Controller** (optional) System interface 12C **NFC RF standards** ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2 **NFC Forum Support** Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2 Reader (PCD-VCD) ISO/IEC 14443 A Mode (1) ISO/IEC 14443 B ISO/IEC 15693 **MIFARE 1K MIFARE 4K MIFARE DESFire** FeliCa Jewel and Topaz cards **Card Emulation (PICC-**ISO/IEC 14443 A VICC) Mode (1) ISO/IEC 14443 B and B' MIFARE FeliCa Frequency 13.56 MHz **NFC Modes Supported** Reader/Writer, Peer-to-Peer **Raw RF Data Rates** 106, 212, 424, 848 kbps **Operating temperature** 0°C to 70°C Storage temperature -20°C to 125°C Humidity 10-90% operating 5-95% non-operating Supply Operating voltage 4.35 to 5.25 Volts I/O Voltage 1.8V or 3.3V **Power Consumption** (Booster enable, VBAT= 3.3V, VCC_BOOST = 5V) Mode Power Consumption, Typical Polling 7.3 mA Detected Test Tag Type 1 Total 283.8 mA Net Module 236.8 mA Detected Test Tag Type 2 Total 288.8 mA Net Module 241.8 mA Detected Test Tag Type 3 Total 287.7 mA Net Module 240.7 mA Detected Test Tag Type 4 Total 282.3 mA Net Module 235.3 mA Antenna Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.

POWER

1. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors

Technical Specification	S				
AC Adapter 45 Watt nPFC Dimensions (H x W x D)		94.0mm x 40.0mm x 26.5mm			
Standard USB type C	Weight	192.5g +/-10%			
Straight 1.8m	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%		
		Input frequency range	47 ~ 63Hz		
		Input AC current	Max. 1.4 A at 90 Vac		
	Output	Output power	5V/15W 9V/27W 12V/36W 15V/45W		
		DC output	5V/9V/12V/15V		
		Hold-up time	5ms at 115 Vac input		
		Output current limit	<5.0A		
	Connector	C6			
	Environmental Design	Operating temperature	32°Fto 95°F (0° to 35°C)		
		Non-operating (storage) temperature	-4ºF to 185ºF (-20º to 85ºC)		
		Altitude	0 to 16,400 ft (0 to 5000m)		
		Humidity	20% to 95%		
		Storage Humidity	10% to 95%		
	EMI and Safety Certifications	 s Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class E CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. 			
AC Adapter 65 Watt nPFC Slim USB type C Straight	Dimensions (H x W x D)	88 x 53.5 x 21mm			
1.8m	Weight	unit: 220g +/- 10g			
	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A		
		Input frequency range	47 ~ 63 Hz		
		Input AC current	1.6 A at 90 VAC and maximum load		
	Output	Output power	65W		
		DC output	5V/9V/12V/15V/20V		
		Hold-up time	5ms at 115 Vac input		
		Output current limit	<8.0A		
	Connector	C6			
	Environmental Design	Operating temperature	32°Fto 95°F (0° to 35°C)		

Technical Specification	S		
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	Eg: *CE Mark - full compliance * Worldwide safety standa and/or EN62368-1, UL609 Agency approvals - C-UL-U CISPR32 Class B, CCC, NOM	e with LVD and EMC directives ards - IEC60950-1 and/or IEC62368-1, EN60950-1 950-1 and/or UL62368-1 , Class1, SELV; JS, NORDICS, DENAN, EN55032 Class B, FCC Class B,
AC Adapter 65 Watt nPFC	Dimensions (H x W x D)	90.0mm x 51.0mm x 28.5r	mm
Standard USB type C	Weight	250g +/-10%	
Straight 1.8m	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V : 81.5% 9V : 86.7% 12V : 88% 15V : 88% 20V : 89%
		Input frequency range	47 ~ 63Hz
		Input AC current	Max. 1.6 A at 90 Vac
	Output	Output power	5V/15W 9V/27W 12V/60W 15V/60W 20V/65W
		DC output	5V/9V/12V/15V/20V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
	Connector	C6	
	Environmental Design	Operating temperature	32°Fto 95°F (0° to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	*CE Mark - full compliance * Worldwide safety standa and/or EN62368-1, UL609 Agency approvals - C-UL-U CISPR32 Class B, CCC, NOM	e with LVD and EMC directives ards - IEC60950-1 and/or IEC62368-1, EN60950-1 150-1 and/or UL62368-1 , Class1, SELV; JS, NORDICS, DENAN, EN55032 Class B, FCC Class B, I-001 NYCE. urs at 25°C ambient condition.

Technical Specificatio	ns				
HP 3-cell Long Life Li-Ion	Dimensions (H x W x D)	251.8 x 66.1 x 6.82mm (9.91 x 2.6 x 0.27 inch)			
(38Wh) ¹	Weight	0.184kg +/- 10g(0.406lb) 3cell Lithium-Ion Polymer cell / 564975			
	Cells/Type				
	Energy	Voltage	11.58V		
		Amp-hour capacity	3.283Ah		
		Watt-hour capacity ¹	38Wh		
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)		
		Operating (Discharging)	14° to 140° F (-10° to 60° C)		
		Fuel Gauge LED	NA		
		Warranty	Follow product spec		
		Optional Travel Battery Available	No		
HP 3-cell Long Life Li-Ion (51 Wh) ¹	Dimensions (H x W x D)	251.8 x 70.3 x 6.82mm (9.			
	Weight	0.229kg +/- 10g (0.505 lb)			
	Cells/Type	3cell Lithium-Ion Polymer	cell / 566075		
	_				
	Energy	Voltage	11.58V		
	Energy	Amp-hour capacity	4.431Ah		
		Amp-hour capacity Watt-hour capacity ¹	4.431Ah 51.3Wh		
	Energy Temperature	Amp-hour capacity Watt-hour capacity ¹ Operating (Charging)	4.431Ah 51.3Wh 32° to 113° F (0° to 45° C)		
		Amp-hour capacity Watt-hour capacity ¹ Operating (Charging) Operating (Discharging)	4.431Ah 51.3Wh 32° to 113° F (0° to 45° C) 14° to 140° F (-10° to 60° C)		
		Amp-hour capacity Watt-hour capacity ¹ Operating (Charging) Operating (Discharging) Fuel Gauge LED	4.431Ah 51.3Wh 32° to 113° F (0° to 45° C) 14° to 140° F (-10° to 60° C) NA		
		Amp-hour capacity Watt-hour capacity ¹ Operating (Charging) Operating (Discharging)	4.431Ah 51.3Wh 32° to 113° F (0° to 45° C) 14° to 140° F (-10° to 60° C)		

AUDIO

HD Stereo Codec Audio I/O Ports	Realtek ALC3315 Headset: CTIA only and Headphone-out
Internal Speaker Amplifier	Cirrus Logic High-Efficiency Boosted Class D Amplifier
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio. Following MSFT Behaviour
Sampling	DAC: 44.1k/48kHz ADC: 48kHz
Wavetable Syntheses	
Analog Audio	Support 3.5mm Headset: CTIA only and Headphone-out
# of Channels on Line-Out	
Internal Speaker	Yes

FINGERPRINT READER

Technical Specifications

Sensor vendor	Synaptics FS7604
Sensor type	Capacitive
DPI resolution	363DPI
Scan area	7.4x6mm sensor area
False Rejection Rate	<1%
False Acceptance Rate	1:50K FAR
Mobile Voltage Operation	3.0V to 3.6V
Operating Temperature	0~60°C
Current Consumption Image	100mA Max
Low Latency Wait For Finger	260 uA
Capture Rate	<30msec per image
ESD Resistance	IEC 61000-4-2 4B (+/-15KV)
Detection Matrix	363 dpi / 7.4x6mm sensor area

ENVIRONMENTAL DATA

Eco-Label Certifications &	This product has receive	d or is in the process of be	ing certified to the following approvals and may be			
declarations	labeled with one or more		5 511 5			
	IT ECO declaration					
	 US ENERGY S 	TAR®				
		Management Program (FE				
	 EPEAT[?] Gold registered in the United States. See http://www.epeat.net for registration 					
	in your country.					
	 TCO Certified 					
		servation Program (CECP)				
		onmental Protection Admi	nistration (SEPA)			
	Taiwan Green Marl	<				
	Korea Eco-label	14				
Custoinable Imaget	Japan PC Green lab					
Sustainable Impact	Ocean-bound p					
Specifications		umer recycled plastic				
	Low halogen					
		id corrugated cushions	s are 100% sustainably sourced and			
	recyclable					
		Pulp Cushion inside bo	ox is 100% sustainably sourced and			
	recyclable					
	 Bulk packaging 					
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook"?.					
Energy Consumption						
(in accordance with US						
ENERGY STAR® test						
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz			
Normal Operation (Sort						
idle)	4.83 W	5.13 W	4.97 W			
Normal Operation (Long		4.0.11				
idle)	1.11 W	<u>1.2 W</u>	1.33 W			
Sleep	1.11 W	1.2 W	1.33 W			
Off	0.43 W	0.47 W	0.43 W			
	Nata					
	Note:	todic for an ENEDCY CTA	D® compliant product if offered within the model			
		Energy efficiency data listed is for an ENERGY STAR [®] compliant product if offered within the model family. HP computers marked with the ENERGY STAR [®] Logo are compliant with the applicable U.S.				
			TAR® specifications for computers. If a model			
		A A A A A A A A A A A A A A A A A A A	TAN Specifications for computers, if a model			

Technica

echnical Specifications						
	for a typically		ng a hard disk d		energy efficiency data listed is ncy power supply, and a	
Heat Dissipation*	115VAC,	60Hz 230V	/AC, 50Hz		100VAC, 50Hz	
Normal Operation (Short idle)	16.5 BTL	16.5 BTU/hr 17.5 B			17 BTU/hr	
Normal Operation (Long idle)	3.8 BTU	/hr 4.1	BTU/hr		4.5 BTU/hr	
Sleep	3.8 BTU	/hr 4.1	BTU/hr		4.5 BTU/hr	
Off	1.5 BTU	/hr 1.6	6 BTU/hr		1.5 BTU/hr	
Declared Noise Emissions (in accordance with	attained for one hour. Sound Power (L _{WAd} , bels)				Pressure decibels)	
ISO 7779 and ISO 9296)				44.0		
Typically Configured - Idle		2.6		14.3		
Fixed Disk - Random writes Optical Drive - Sequential	3.2			27.0 32.0		
reads	-					
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.					
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product is 93.4% recycle-able when properly disposed of at end of life. 					
Packaging Materials	External:	PAPER/Corrugated			269 g	

Packaging Materials	External:	PAPER/Corrugated	269 g	
		PAPER/Paper	3 g	
		PAPER/Molded Pulp	108 g	
	Internal:	PLASTIC/Polyethylene low density - LDPE	13 g	
	The plastic packaging material contains at least 0.0% recycled content.			
	The corrug	ated paper packaging materials contains at least 59.1	% recycled content.	
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.			
	We believe the RoHS directive and similar laws play an important role in promoting industry- wide elimination of substances of concern. We have supported the inclusion of additional substances-including PVC, BFRs, and certain phthalates-in future RoHS legislation that pertains to electrical and electronics products.			
	We met our voluntary objective to achieve worldwide compliance with the new EU RoHS			

Technical Specifications

	requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.
	To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at
	http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/
	gen_specifications.html):
	Asbestos
	Certain Azo Colorants Certain Description Determinante in plantice
	 Certain Brominated Flame Retardants - may not be used as flame retardants in plastics Cadmium
	Chlorinated Hydrocarbons
	Chlorinated Paraffins
	Bis(2-Ethylhexyl) phthalate (DEHP)
	Benzyl butyl phthalate (BBP)
	Dibutyl phthalate (DBP)
	Diisobutyl phthalate (DIBP)
	Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	Lead and Lead compounds Marcuric Oxide Patteries
	 Mercuric Oxide Batteries Nickel - finishes must not be used on the external surface designed to be frequently handled or
	carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	 Polybrominated Biphenyl Oxides (PBBOs)
	 Polychlorinated Biphenyl (PCB)
	 Polychlorinated Terphenyls (PCT)
	Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	 Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	 Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
	 Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	 Design packaging materials for ease of disassembly.
	• Maximize the use of post-consumer recycled content materials in packaging materials.
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	 Reduce size and weight of packages to improve transportation fuel efficiency.
	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Technical Specifications

HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment:
	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.htm
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and
• • •	http://www.hp.com/hpinfo/qlobalcitizenship/environment/pdf/cert.pdf
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1- 2018 standard.
	 External power supplies, WWAN modules, power cords, cables and peripherals excluded.
	 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
	• Fiber cushions made from 100% recycled wood fiber and organic materials.

COUNTRY OF ORIGIN

China

Options and Accessories (Sold separately and availability may vary by country)

DOCKING (Sold Separately)

Docking station model #1	HP Thunderbolt Dock G2
Total number of supported displays (incl.the notebook display)	4
Max.resolutions supported	Dual 4K @30Hz or dual 4K UHD @ 60Hz is supported Single 8K@ 30Hz (multiple tiles) for Thunderbolt hosts Non-TBT hosts DP 1.4 in high res mode (1) 8K video single cable@30Hz [10]
Dock Connectors	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode
Technical limitations	 Thunderbolt Hosts: Maximum of (4) displays with maximum resolution of 5K@ 30Hz running Thunderbolt host. Max resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a non-Thunderbolt host in High Resolution mode @30Hz Non-Thunderbolt hosts: The highest resolution for dual displays running a non-Thunderbolt host in multi-function mode is (1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port Non-Thunderbolt hosts support (3) displays with a max resolution of: (2) 5K single cable + (1) 4K UHD @ 60 Hz in high resolution mode. In multi-function mode the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz + (1) 4K UHD @ 30Hz.
Docking station model #2	HP USB-C Dock G5
Total number of supported displays (incl.the notebook display) Max.resolutions supported	3
Dock Connectors	Dual 5K@ 30Hz + (1) 4K UHD (multi-function mode) [10] 1xHDMI, 2xDP
Technical limitations	Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode. Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in multi-function mode The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Docking station model #3	HP USB-C/A Universal Dock G2
Total number of supported displays (incl.the notebook display) Max.resolutions supported	3 Triple 4K UHD@ 60Hz [10]
Dock Connectors	1xHDMI, 2xDP
Technical limitations	The best resolution for dual or triple displays is 4K UHD@ 60Hz. For use with the USB-A adapter that comes in the box the maximum number of displays supported is (2) 4k x 60 Hz on the Type-A Gen 1 connection from the host

Туре	Description	Part Number
Audio/Video	HP Wired USB-A Stereo Headset	428K6AA
	HP Wired 3.5mm Stereo Headset	428K7AA
Cases	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Executive Slim 14.1 Top Load	6KD04AA
	HP Prelude G2 15.6 Backpack	1E7D6AA
	HP Prelude G2 15.6 Top Load	1E7D7AA
	HP Prelude Pro Recycled 15.6 Backpack	1X644AA
	HP Prelude Pro Recycled 15.6 Top Load	1X645AA

Options and Accessories (Sold separately and availability may vary by country)

	HP Renew 14 Laptop Sleeve	2E6U9AA,2E6V0AA
	HP Renew Business 14.1 Laptop Bag	ЗЕ5Г9АА
	HP Renew Business 14.1 Laptop Sleeve	3E2U7AA
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA
	HP Renew Business 17.3 Laptop Bag	3E2U6AA
	HP Renew Business 15.6 Laptop Bag	3E5F8AA
Docking	HP Thunderbolt 120W G2 Dock	2UK37AA
	HP Thunderbolt 120W G2 Dock w/Audio	3YE87AA
	HP Thunderbolt 230W G2 Dock w/Combo Cable	3TR87AA
	HP USB-C 120W G5 Dock	5TW10AA
	HP USB-C/A 120W G2 Universal Dock	5TW13AA
Digital Pen	HP Active RECHBL G3 Moonracer 2.0 Pen	6SG43AA
Hub	HP USB-C Mini Dock	1PM64AA
	HP Universal USB-C Multiport Hub	50H55AA
	HP USB-C Travel Dock G2	7PJ38AA
	HP USB-C to USB-A Hub	Z6A00AA
Adapter	HP HDMI to DVI Adapter	F5A28AA
	HP HDMI to VGA Adapter	H4F02AA
	HP USB to Gigabit RJ45 Adapter	N7P47AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to VGA Adapter	N9K76AA
	HP USB-C to RJ45 Adapter G2	4Z527AA
	HP USB 3.0 to Gigabit RJ45 Adapter G2	4Z7Z7AA
Keyboard/Combo	HP 975 USB+BT Dual-Mode Wireless Keyboard	3Z726AA
	HP 455 Programmable Wireless Keyboard	4R177AA
	HP 125 WD USB Keyboard	266C9AA
	HP 320K WD USB Keyboard	9SR37AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 225 Wired Mouse and Keyboard Combo HP 235 Wireless Mouse and Keyboard Combo	286J4AA 1Y4D0AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
Mouse	HP USB Premium Wireless Mouse	1JR31AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
	HP 125 USB-A Wired Mouse	265A9AA
	HP 128 USB Laser Wired Mouse	265D9AA
	HP 320M USB-A Wired Mouse	9VA80AA

Options and Accessories (Sold separately and availability may vary by country)

	HP Creator USB-A+Bluetooth 935 Wireless Mouse Black	1D0K8AA
	HP USB-A+Bluetooth Multi-Device 635 Wireless Mouse Black	1D0K2AA
	HP USB-A+Bluetooth Travel Bluetooth Mouse	6SP30AA
Power	HP 65W USB-C Auto Chevy AC Power Adapter	5TQ76AA
	HP 45W USB-C G2 Zeus AC Power Adapter	1HE07AA
	HP 45W USB-C LC Dali AC Power Adapter	1MZ01AA
	HP 65W USB-C Hades AC Power Adapter	1HE08AA
	HP 65W USB-C LC AC Power Adapter	1P3K6AA
	HP 65W USB-C Travel Slim Kermit AC Power Adapter	3PN48AA
Commoditu	HP USB DVD-Writer EXT ODD	F2B56AA
Commodity		FZDOOAA
	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Master Keyed Cable Lock	1AJ40AA
	HP SureKey Standard/Nano/Wedge Cable Lock	6UW42AA

Change Log

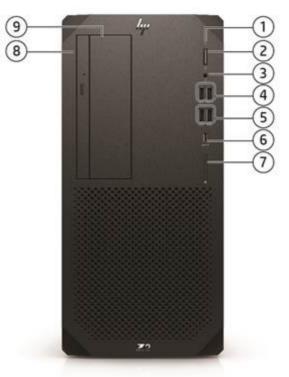
Date of change:	Version History:		Description of change:
September 7, 2022	V1 to V2	Removed	Tile App
-	V2 to V3		

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Overview

HP Z2 G9 Tower Workstation Desktop PC

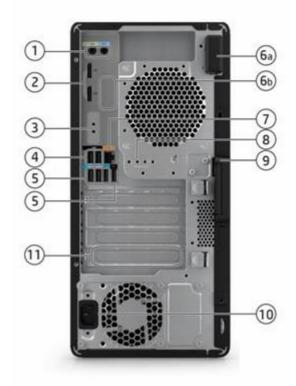


front

- 1. HDD Activity LED
- 2. Power button
- 3. Universal audio jack (with CTIA & OMTP headset support)
- (2) Type-A SuperSpeed USB 10Gbps signaling rate port (1 charge port 9. supports up to 5V/2.1A)
- 5. (2) Type-A SuperSpeed USB 10Gbps signaling rate port

- 6. (1) Type-C[®] SuperSpeed USB 20Gbps signaling rate port (optional, charge supports up to 5V/3A)
- 7. SD card reader 4.0 (optional)
- 8. Slim ODD bay
 - . External 5.25" bay

Overview



rear

- 1. (1) Audio Line-in jack (1) Audio Line-out jack
- 2. (2) DisplayPort 1.4
- 3. Flex I/O module: choose one from the following: 7. RJ-45 (1) DisplayPort 1.4, (1) HDMI 2.0b, (1) VGA, (1) Dual Type-A 8. SuperSpeed USB 5Gbps signaling rate port, (1) Type-C® SuperSpeed USB 10Gbps signaling rate port (Power Delivery 15W, Alt Mode DisplayPort), (1) 2nd 1 GbE LAN, (1) Thunderbolt 3₁₀. Power connector with Type-C[®] SuperSpeed/ USB4 40Gbps signaling rate* (cabled to PCIe AIC) (1) 1Gbps Fiber LC NIC
- 4. (2) Hi-Speed USB 480Mbps signaling rate port
- 5. (2) Type-A SuperSpeed USB 10Gbps signaling rate port (1) Type A SuperSpeed USB 5Gbps signaling rate port (1) Hi-Speed USB 480Mbps signaling rate port

*Maximum speed requires DisplayPortTM and PCIe aggregation. **Thunderbolt only support on PCI-E slot4.

Note: Onboard Display support DP1.4/HBR2. Flex I/O module Display support DP1.4/HBR3. Resolution all support up to 5120x3200 24bpp @60Hz.

Form Factor	Tower
Operating Systems	 Preinstalled: Windows 11 Pro - HP recommends Windows 11 Pro² Windows 11 Home - HP recommends Windows 11 Pro² Windows 10 Pro (available through downgrade rights from Windows 11 Pro) ^{1,2,3} Linux[®]-ready⁵

Ubuntu 20.04 LTS⁴

- WLAN Antenna (optional) 6.
- Internal а.
- b. External
- 2nd serial port (optional)

9. Hood lock (optional)

Overview

Web-supported only:

• Windows 10 Enterprise 64² Supported Version:

- HP tested Windows 10, versions 20H2, 21H1 and 21H2 on this platform. For testing information on newer versions of Windows 10, please see: https://support.hp.com/document/c05195282.
- Red Hat® Enterprise Linux® Workstation 8⁶
- SUSE Linux® Enterprise Desktop 15⁶
- Ubuntu 20.04, 22.04 LTS⁵

¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

⁵A certified preloaded version of Ubuntu[®] 20.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for upgrades.

⁶For detailed Linux[®] OS/hardware support information, see:

http://www.hp.com/support/linux_hardware_matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel[®] and AMD[®] 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

Processors

Overview

Name	Cores	Clock Speed (GHz)	Threads	Cache (MB)	Memory Speed (MT/s) ⁵	Hyper- Threading	Integrated Graphics	Intel® Turbo Boost Technology ³	Featuring Intel® vPro® Technology ⁴	16GB Intel® Optane TM memory ²	TDP (W)
Intel [®] Core TM i9- 12900K Processor	16	3.2	24	30	4800	Y	Intel® UHD Graphics 770	5.2	Y	N	125
Intel® Core [™] i9- 12900 Processor	16	2.1	24	30	4800	Y	Intel® UHD Graphics 770	5.1	Y	N	65
Intel® Core TM i7- 12700K Processor	12	3.6	20	25	4800	Y	Intel® UHD Graphics 770	5.0	Y	N	125
Intel® Core TM i7- 12700 Processor	12	2.1	20	25	4800	Y	Intel® UHD Graphics 770	4.9	Y	N	65
Intel® Core TM i5- 12600K Processor	10	3.7	16	20	4800	Y	Intel® UHD Graphics 770	4.9	Y	N	125
Intel® Core TM i5- 12600 processor	6	3.3	12	18	4800	Y	Intel® UHD Graphics 770	4.8	Y	N	65
Intel® Core™ i5- 12500 processor	6	3.0	12	18	4800	Y	Intel® UHD Graphics 770	4.6	Y	N	65
Intel® Core TM i5- 12400 processor	6	2.5	12	18	4800	Y	Intel® UHD Graphics 730	4.4	N/A	N	65
Intel® Core [™] i3- 12300 processor	4	3.5	8	12	4800	Y	Intel® UHD Graphics 730	4.4	N/A	N	60
Intel® Core™ i3- 12100 processor	4	3.3	8	12	4800	Y	Intel® UHD Graphics 730	4.3	N/A	N	60

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Intel[®] OptaneTM memory system acceleration does not replace or increase the DRAM in your system.

³ Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

⁴ Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro

⁵ Memory will run at 4400 speed (MT/s) if there is one DIMM per channel. 2 DIMMS per channel will run 4800 speed (MT/s)

Note: ECC memory is supported on the following: Intel® CoreTM i9-12900K, Intel® CoreTM i9-12900, Intel® CoreTM i7-12700K, Intel® CoreTM i7-12700, Intel® CoreTM i5-12600K, Intel® CoreTM i5-12700, Intel® CoreTM i5-12600K, Intel® CoreTM i5-12700, Intel® CoreTM i5-12700K, Intel® CoreTM i5-12700, Intel® CoreTM i5-12600K, Intel® CoreTM i5-12700, Intel® CoreTM i5-12700K, Intel® CoreTM i5-12700, Intel

Black
No
Slot 1:
PCIe Gen5 x16
Slot 2:
PCIe Gen3 x1 - with x4 Connector
Slot 3:
PCIe Gen3 x4 - with x16 Connector

Overview

	Slot 4: PCIe Gen3 x4
Expansion Bays (see	(2) Internal 3.5" bays
storage section for more	
details)	(1) Internal 2.5" bay (for SSD only) (1) Dedicated 9.5mm slim optical disk drive bay
Front I/O	2 Type-A SuperSpeed USB 10Gbps signaling rate port (1 charge port supports up to 5V/2.1A), 2 Type-A SuperSpeed USB 10Gbps signaling rate port, 1 Type-C SuperSpeed® USB 20Gbps signaling rate port (charge supports up to 5V/3A, optional), 1 SD card reader (optional), 1 universal audio jack
Internal I/O [5]	 (1) Hi-Speed USB 480Mbps signaling rate header for SD card reader (1) serial port available with header (1) serial and PS/2 available with header
Rear I/O	2 DisplayPort 1.4 [3], 1 Audio Line out, 1 Audio Line in, 1 RJ-45, 3 Hi-Speed USB 480Mbps signaling rate port, 2 Type-A SuperSpeed USB 10Gbps signaling rate port, 1 Type-A SuperSpeed USB 5Gbps signaling rate port, 1 serial (optional), 1 Flex I/O port (VGA, HDMI 2.0b, DisplayPort 1.4, Type-C [®] SuperSpeed USB 10Gbps signaling rate port (Power Delivery 15W, Alt Mode Display Port), Dual Tye-A SuperSpeed USB 5Gbps signaling rate port, 2nd 1GbE LAN, 1 Thunderbolt 3 with SuperSpeed/USB4 Type-C [®] 40Gbps signaling rate (cabled to PCIe AIC), 1 1Gbps Fiber LC NIC
Optional I/O	Flex IO* - choose one of the following options: 1 DisplayPort TM 1.4, 1 HDMI 2.0b, 1 VGA,1 2nd 1GbE LAN, 1 1Gbps Fiber LC NIC, 1 Dual SuperSpeed USB Type-A 5Gbps signaling rate,1 SuperSpeed USB Type-C [®] 10Gbps signaling rate (15W USB Power Delivery, Alt Mode DisplayPort TM) 1 Thunderbolt TM 3 with SuperSpeed USB4 Type-C [®] 40Gbps signaling rate (cabled to PCIe [®] AIC); Front - 1 SuperSpeed USB Type-C [®] ? 20Gbps signalin charging), 1 SD card reader; Rear -1 serial; Front - choose one of the following options: 1 SuperSpeed USB Type 20Gbps signaling rate (1 charging), 1 SD 4.0 card reader
	*Flex IO port and one PCIe slot will be occupied when Thunderbolt is installed. Thunderbolt will be available in Q2, 2022 (1 st refresh).
Interfaces Supported	SD card reader (optional)
On-board RAID Support	SATA and NVME RAID 0 Striped Array SATA RAID and NVME RAID 1 Mirror Array
Chassis Dimensions (H x W x D)	H: 14" [356mm] W: 6.7" [169mm] D: 15.2" [385mm]
Packaged Dimensions	H: 20.39" (518mm) W: 11.61" (295mm) D: 19.29" (490mm)
Rack Dimensions	40
Weight	Exact weights depend upon configuration (System weight only). Starting at 6.2kg (13.7lbs.)
Temperature	Operating: 5° to 35° C (40° to 95° F) Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation Non-operating: -40° to 60° C (-40° to 140° F) Maximum rate of change: 10°C/hr
Humidity	Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb
Maximum Altitude (non-	Operating (with Rotational Hard Drives): 3,048 m (10,000 feet)
pressurized) ⁶	Operating (with only Solid-State Drives): 5,000 m (16,404 feet) Non-operating: 12,192 m (40,000 feet)
	Mon-operating: 12,192 m (40,000 reet) Maximum operating temperature is reduced as altitude increases. See Temperature for details.
Power Supply	700W wide-ranging, active Power Factor Correction, 92% Efficiency. 500W wide-ranging, active Power Factor Correction, 90% Efficiency. 450W wide-ranging, active Power Factor Correction, 90% Efficiency. 350W wide-ranging, active Power Factor Correction, 92% Efficiency.
	NOTE: The Power Supply Efficiency Report for the 700W 92% Efficiency, 500W 90% Efficiency, 450W 90% Efficiency and 350W 92% Efficiency Power Supply may be found at the following links:

Overview

	700W PSU: https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2
	500W PSU: https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2
	450W PSU: https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2
	350W PSU: https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2
Backup Devices	For a complete listing of compatible DAT tape drives, LTO tape drives and RDX Removable Disk Backup System offerings, please visit http://www.hp.com/go/connect
Chipset	Intel® W680 chipset
Memory	4 DIMM slots, supporting up to 128GB ECC/non-ECC, DDR5 4800 MT/s speed depending on the system configuration

Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	12th Generation Intel [®] Core TM Processors*				
	Intel [®] Core TM i9-12900K Processor	Y	Ν		
	Intel [®] Core TM i9-12900 Processor	Y	Ν		
	Intel [®] Core TM i7-12700K Processor	Y	Ν		
	Intel [®] Core TM i7-12700 Processor	Y	Ν		
	Intel [®] Core TM i5-12600K Processor	Y	Ν		
	Intel [®] Core [™] i5-12600 processor	Y	Ν		
	Intel [®] Core [™] i5-12500 processor	Y	Ν		
	Intel [®] Core [™] i5-12400 processor	Y	Ν		1
	Intel [®] Core [™] i3-12300 processor	Y	Ν		1
	Intel [®] Core TM i3-12100 processor	Y	Ν		1

Note: ECC memory is supported on the following: Intel[®] CoreTM i9-12900K, Intel[®] CoreTM i9-12900, Intel[®] CoreTM i7-12700K, Intel[®] CoreTM i7-12700, Intel[®] CoreTM i5-12600K, Intel[®] CoreTM i5-12600 and Intel[®] CoreTM i5-12500 processors

NOTE 1: These processors support only non-ECC memory **NOTE 2:** No iGfx. A discrete graphics card must be purchased at the same time.

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
	500GB SATA 7200 rpm 6Gb/s 3.5" HDD	Y	Y	LQ036AA
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD	Y	Y	LQ037AA
	2TB SATA 7200 rpm 6Gb/s 3.5" HDD	Y	Y	QB576AA
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	WOR10AA
	2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	2Z274AA
	4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	K4T76AA
	8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	2Z273AA
	12TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	5S461AA
	500GB SATA 7.2K SED HDD	Y	Y	D8N29AA

NOTE: For internal bay install, HDD option kits require separate purchase of 6Z9U6AA HP Z2 Tower HDD Cable Kit. For external bay install, HDD options kits require separate purchase of 6Z9U6AA HP Z2 Tower HDD Cable Kit & NQ099AA HP Optical Bay HDD Mounting Bracket.

Supported Components

PCIe Solid State Drives				
	HP ZTurbo 512GB PCIe-Gen 4x4 TLC Z2 SSDKit	Y	Y	201G0AA/AT
	HP ZTurbo 512GB PCIe-Gen 4x4 SED Z2 SSDKit	Y	Y	201F9AA
	HP ZTurbo 1TB PCIe-Gen 4x4 TLC Z2 SSDKit	Y	Y	201F5AA/AT
	HP ZTurbo 2TB PCIe-Gen 4x4 TLC Z2 SSDKit	Y	Y	201F8AA
	Z Turbo 1TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD	Y	Y	223A3AA/AT
	Z Turbo 2TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD	Y	Y	223A4AA/AT
	256GB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Y	Y	4M9Z1AA
	512GB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Y	Y	4M9Z2AA
	1TB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Y	Y	4M9Z3AA
	Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 Z2 Kit SSD	Y	Y	5S492AA
	Z Turbo 2TB PCIe-4x4 TLC SSD Module	Y	Y	38T75AA
	Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Y	Y	38T76AA
	Z Turbo 1TB PCIe-4x4 TLC SSD Module	Y	Y	38T77AA
	Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Y	Y	38T79AA
	Z Turbo 512GB PCIe-4x4 TLC SSD Module	Y	Y	38T80AA
	Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Y	Y	38T81AA
	Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD Module	Y	Y	5S496AA
	Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Y	Y	5S497AA
	Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z2 Kit SSD	Y	Y	5S498AA
	NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. 36GB of system disk (for Windows) is reserved for system recovery			acity is less. Up to

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
Graphics Cable Adapters	HP DisplayPort To HDMI True 4k Adapter	Y	Y	2JA63AA	
	HP Single miniDP-to-DP Adapter Cable	Y	Y	2MY05AA	
	HP DisplayPort To DVI-D Adapter	Y	Y	FH973AA	
	HP DisplayPort To DVI Adapter (Bulk 90)	Y	Y	FH973A6	
	HP DisplayPort To VGA Adapter	Y	Y	AS615AA/AT	
	HP DisplayPort to VGA Adapter Bulk Qty.90)	Y	Y	AS615A6	
	HP DisplayPort To VGA Adapter	Y	Y	F7W97AA	
	HP USB-C to DisplayPort Adapter	Y	Y	4SH08AA	
	HP USB-C to HDMI Adapter	Y	Y	4SH07AA	
	HP USB-C to VGA Adapter	Y	Y	4SH06AA	
Entry 3D	NVIDIA [®] T400 2 GB Graphics ^{1,2}	Y	Y	340K8AA	2
	NVIDIA [®] T400 4 GB Graphics ²	Y	Y	5Z7E0AA/AT	2
	NVIDIA [®] T600 4 GB Graphics ^{1,2}	Y	Y	340K9AA	2
	AMD Radeon RX 6400 4 GB DH DP+HDMI Graphics	Y	Y	6Q3U4AA/AT	1
Mid-range 3D	NVIDIA [®] T1000 4 GB Graphics ²	Y	Y		2
	NVIDIA [®] T1000 8 GB Graphics ²	Y	Y	5Z7D8AA/AT	2
	NVIDIA Long-Life T1000E 8 GB 4mDP Graphics	Y	Y	6V9V4AA/AT	2
	NVIDIA RTX TM A2000 12GB Graphics* ²	Y	Y	5Z7D9AA/AT	2
	NVIDIA Long-Life RTX A2000E 12 GB 4mDP Graphics	Y	Y	6V9V5AA/AT	2

Supported Components

	AMD Radeon [™] Pro W6600 Graphics (8GB GDDR6 dedicated) *	Y	Y	340K5AA	1		
High-End 3D	AMD Radeon [™] Pro W6800 Graphics (32 GB GDDR6 dedicated) *	Y	Y	340K7AA	1		
	NVIDIA [®] RTX TM A5000 24 GB Graphics*	Y	Y	20X23AA/AT	1		
	Note 1: May go End of Life in late 2022. Note 2: When dual graphics is supported (expected May 2022), the 450W and 500W base units will require the AMO HP Z2 TWR Dual Front Fan Kit part number 4N007AA. * Requires 700W chassis.						

** Requires at least 500W chassis.

Memory

	Factory		Option Kit Part	Support
	Configured	Option Kit	Number	Notes
HP 8GB (1x8GB) DDR5-4800 nECC UDIMM	Y	Y	4M9X9AA	
HP 16GB (1x16GB) DDR5-4800 nECC UDIMM	Y	Y	4M9Y0AA	
HP 16GB (1x16GB) DDR5-4800 ECC UDIMM	Y	Y	4M9Y1AA	1
HP 32GB (1x32GB) DDR5-4800 nECC UDIMM	Y	Y	4M9Y2AA	
HP 32GB (1x32GB) DDR5-4800 ECC UDIMM	Y	Y	4M9Y3AA	1

NOTE 1: ECC memory is supported on the following: Intel[®] CoreTM i9-12900K, Intel[®] CoreTM i9-12900, Intel[®] CoreTM i7-12700K, Intel[®] CoreTM i5-12600K, Intel[®] CoreTM i5-12600 and Intel[®] CoreTM i5-12500 processors

NOTE 2: Two channels of DDR5 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.

NOTE 3: Though the memory modules can run up to 4800MHz, the current platform will support maximum memory speed of 4400MHz.

Module Configuration	Description of configuration	Max Memory Speed (Actual Memory speed is dependent on CPU)
Single DIMM per channel	Configurations that contain only one or two DIMM modules with DIMMs only in the black slots	4400MHz
Two single ranked DIMMs in a channel	Configurations with 3 or 4 single ranked DIMMs (8GB and 16GB) installed in a system	4000MHz
Two dual ranked DIMMs in a channel	Configurations with 3 or 4 dual ranked DIMMs (32GB) installed in a system	3600MHz

Note: When more than one memory slot is populated, symmetric configurations are required for 2 DIMMs per channel. Mix of different part numbers or mix of single and dual ranks within a channel is not allowed.

Supported Components

Optical and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number
	HP DX175 Removable HDD Frame/Carrier	Y	Y	1ZX71AA
	HP DX175 Removable HDD Spare Carrier	Y	Y	1ZX72AA
	HP Z2 TWR SuperMulti DVD-Writer 9.5mm Slim ODD	Y	Y	4L5K0AA
	HP Z2 TWR DVD-ROM 9.5mm Slim ODD	Y	Y	4L5K1AA
	HP CRU QX328 5.25 in Front Removable Frame/Carrier	Y	Y	4N011AA
	HP CRU Secure High Performance Storage Module with 2TB M.2 SSD	Y	Y	56Q87AA
	HP CRU Secure High Performance Storage Module with 1TB M.2 SSD	Y	Y	56Q88AA
	HP CRU Secure High Performance Storage Module with 512GB M.2 SSD	Y	Y	56Q89AA
	HP CRU SHIPS M.2 Spare Carrier	Y	Y	633X9AA

NOTE: With Blu-Ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not quaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this Desktop PC.

NOTE: Duplication of copyrighted material is strictly prohibited. Actual speeds may vary. Double Layer media compatibility will widely vary with some home DVD players and DVD-ROM drives. Note that DVD-RAM cannot read or write to 2.6GB Single Sided/5.2 Double Sided-Version 1.0 Media.

NOTE: 4N011AA HP CRU QX328 5.25in Front Removeable Frame/Carrier requires a separate purchase of HP CRU SHIPS Storage Module(s).

NOTE: HP CRU SHIPS Storage Module Kit contains CRU SHIPS Storage Module and M.2 SSD for install into a factory configured or after market option front removeable storage carrier (HP CRU QX328 Frame/Carrier). NOTE: HP CRU QX328 Frame/Carrier requires separate purchase of HP CRU Secure High Performance Storage (SHIPS) Module(s).

NOTE: HP CRU Secure High Performance Storage (SHIPS) Module Kit contains CRU SHIPS Module and M.2 SSD for install into a factory configured or after market option front removeable storage carrier (HP CRU QX328 Frame/Carrier).

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number
	Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro® with Intel® AMT 16.0)	Y	Ν	
	HP 1GbE LAN Flex Port 2020	Y	Y	141J6AA/AT
	HP Flex 1GbE Fiber LC Single Port	Y	Y	20J15AA
	NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC ¹	Y	Y	436M8AA
	Intel Ethernet I350-T4 4-Port 1Gb NIC*	Ν	Y	W8X25AA
	Intel X550 10GBASE-T Dual Port NIC	Y	Y	1QL46AA
	Intel Ethernet Network Adapter I225-T1	Y	Y	406L9AA
	Intel Wi-Fi 6E AX211 BT 5.2 M.2 non-vPro ^{1,**}	Y	Ν	
	Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Y	Y	6E3Y9AA/AT
	 *Intel I350-T4 4-port GbE NIC is an After Market Option only. ¹ Intel AX211 with Internal antenna support WIFI 6/WIFI 6E **Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function access points limited. Wi-Fi 6E is backwards compatible with prio Wi-Fi 6E is supported. NOTE: The integrated network connection is required to support NOTE: If AMT is provisioned, then network teaming with the integrated NOTE: "Gigabit" Ethernet indicates compliance with IEEE standard 	or 802.11 specs Intel® vPro® Te grated LAN por	s. And availat echnology. t is not possi	ble in countries wher

Supported Components

connote actual operating speed of 1 Gb/sec. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

HP USB 320K KeyboardYY9SR37AAHP 320M Wired MouseYY9VA80AAHP Wired Desktop 320MK Mouse and KeyboardNY9SR36AAHP 125 Wired KeyboardYY266C9AAHP 975 USB+BT Dual Mode WirelessNY3Z726AA	Input Devices		Factory Configured	Option Kit	Option Kit Part Number
HP Wired Desktop 320MK Mouse and KeyboardNY9SR36AAHP 125 Wired KeyboardYY266C9AA		HP USB 320K Keyboard	Y	Y	9SR37AA
HP 125 Wired KeyboardYY266C9AA		HP 320M Wired Mouse	Y	Y	9VA80AA
		HP Wired Desktop 320MK Mouse and Keyboard	Ν	Y	9SR36AA
HP 975 USB+BT Dual Mode Wireless N Y 3Z726AA		HP 125 Wired Keyboard	Y	Y	266C9AA
		HP 975 USB+BT Dual Mode Wireless	Ν	Y	3Z726AA
HP 655 Wireless USB BLK KBD/MSE Kit N Y N/A		HP 655 Wireless USB BLK KBD/MSE Kit	Ν	Y	N/A
HP 125 Wired Mouse Y Y 265A9AA		HP 125 Wired Mouse	Y	Y	265A9AA
HP 128 Laser Wired Mouse Y Y 265D9AA		HP 128 Laser Wired Mouse	Y	Y	265D9AA
HP 935 Creator Wireless Mouse N Y 1DOK8AA		HP 935 Creator Wireless Mouse	Ν	Y	1D0K8AA
HP 455 Programmable Wireless Keyboard Y Y 4R177AA		HP 455 Programmable Wireless Keyboard	Y	Y	4R177AA
HP 455 Programmable Wireless Keyboard (Bulk Qty.12) Y Y 4R177A6		HP 455 Programmable Wireless Keyboard (Bulk Qty.12)	Y	Y	4R177A6
HP 655 Wireless Keyboard and Mouse Combo Y Y 4R009AA		HP 655 Wireless Keyboard and Mouse Combo	Y	Y	4R009AA
HP 655 Wireless Keyboard and Mouse Combo (Blk Qty.10) Y Y 4R009A6		HP 655 Wireless Keyboard and Mouse Combo (Blk Qty.10)	Y	Y	4R009A6
HyperX Cloud MIX Wireless GAM HEADSET N Y 4P5K9AA		HyperX Cloud MIX Wireless GAM HEADSET	Ν	Y	4P5K9AA
HyperX Cloud Core BLK GAM HEADSET N Y 4P4F2AA		HyperX Cloud Core BLK GAM HEADSET	Ν	Y	4P4F2AA
HyperX Cloud Flight - Wireless Gaming Headset (Black-Red) (HX- N Y 4P5L4AA HSCF-BK/AM)			Ν	Y	4P5L4AA
HyperX Cloud Stinger Core GAM HEADSET PC N Y 4P4F4AA		HyperX Cloud Stinger Core GAM HEADSET PC	Ν	Y	4P4F4AA
HyperX SoloCast - USB Microphone (Black) (HMIS1X-XX-BK/G) N Y 4P5P8AA		HyperX SoloCast - USB Microphone (Black) (HMIS1X-XX-BK/G)	Ν	Y	4P5P8AA
Note: Keyboard and Mouse are optional or add on features.		Note: Keyboard and Mouse are optional or add on features.			

Flex Module (Rear IO)		Factory Configured	Option Kit	Option Kit Part Number
	HP 1GbE LAN Flex Port 2020	Y	Y	141J6AA/AT
	HP DP Flex Port 2020	Y	Y	141J7AA/AT
	HP Dual USB-A 3.2 Gen1 Flex Port 2020	Y	Y	141J8AA/AT
	HP HDMI Flex Port	Y	Y	69D47AA/AT
	HP USB-C 3.2 Gen2 Alt Flex Port 2020	Y	Y	141K6AA/AT
	HP VGA Flex Port 2020	Y	Y	141K7AA/AT
	HP Flex 1GbE Fiber LC Single Port	Y	Y	20J15AA

Supported Components

Other Hardware		Factory Configured	Option Kit	Option Kit Part Number
	HP Single TBT3 wType C and USB4 PCIe x4 Card	Y	Ν	N/A
	HP Z2 Internal Serial Port and PS/2 Port	Y	Y	141K9AA/AT
	HP Z2 Power Cord Kit	Y	Y	1N1D5AA
	HP Z2 2nd serial port adapter	Y	Y	141K8AA/AT
	HP Z2 Tower Dust Filter	Y	Y	141L2AA/AT
	HP Z2 Tower Dust Filter and bezel	Y	Y	141L3AA/AT
	HP PCIe x1 Parallel Port Card	Y	Y	N1M40AA
	HP Z2 G9 Single Type-C SuperSpeed USB 20Gbps Front Port	Y	Y	4M9X8AA/AT
	HP Z2 TWR Dual Front Fan Kit	Y	Y	4N007AA
	HP Optical Bay HDD Mounting Bracket	Y	Y	NQ099AA
	HP Z2 Tower HDD Cable Kit	Ν	Y	6Z9U6AA
	¹ Available in Q3, 2021			

Racking and Physical Security		Factory Configure d	Option Kit	Option Kit Part Number
	HP Z2 Mini and Z2/Z4/Z6 TWR Depth Adjustable Fixed Rail Rack Kit	Y	Y	2A8Y5AA
	HP Keyed Cable Lock	Y	Y	T1A62AA
	HP Master Keyed Cable Lock 10mm	Y	Y	T1A63AA
	HP Business PC Security Lock V3 Kit	Y	Y	3XJ17AA

Software		Factory Configured	Option Kit	Support Notes
	HP Performance Advisor	Y	Ν	1
	HP PC Hardware Diagnostics UEFI (Windows OS only)	Y	Ν	2
	HP PC Hardware Diagnostics Windows		Ν	3
	HP Wolf Security	Y	Ν	
	HP Notifications	Y	Ν	
	HP Desktop Support Utility	Y	Ν	
	HP Documentation	Y	Ν	
	HP Image Assistant	Ν	Ν	
	HP Support Assistant	Ν	Ν	
	HP Quick Drop	Y	Ν	
	myHP	Y	Ν	
	HP Easy Clean	Y	Ν	
	HP Smart Health	Y	Ν	7
	Kingsoft WPS Office	Y	Ν	4
	My Office	Y	Ν	5
	Adobe Substance 3D Collection Plan	Ν	Y	6
	WSL2/Ubuntu Data Science Stack	Y	Ν	7
	Notes:			

1. Supports, and preinstalled with Windows 10 only. Also available as a free download from http://www.hp.com/go/performanceadvisor

2. Windows OS only

Supported Components

- 3. Not available in Russia
- 4. Only available in China
- 5. Only available in Russia
- 6. Not available in China
- 7. Optional Software

Operating Systems Windows 11 Pro - HP recommends Windows 11 Pro²

Windows 11 Home - HP recommends Windows 11 Pro² Windows 10 Pro (available through downgrade rights from Windows 11 Pro) ^{1,2,3} Linux®-ready⁵ Ubuntu 20.04 LTS⁴

¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

⁵For detailed Linux[®] OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel[®] and AMD[®] 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

Supported Components

HP BIOS

Additional HP BIOS Features:

- Power-On password Helps prevent an unauthorized user from powering on the system.
- Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
- S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:

-Power to expansion connectors / slots

-Most Wake events other than power buttons and WOL(Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled) -USB charging ports

HP Sure Start Gen7 Start

- BIOS Integrity checking Sure Start protection ensures that only trusted BIOS code is executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown and while the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability. Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.
- Audit enabled System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating
 Note: HP Sure Start Gen7 is available on HP Workstation products equipped with Intel[®] 12th generation processors.

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Support Assistant ¹⁴ HP Image Assistant HP Desktop Support Utility HP Documentation HP Notifications HP PC Hardware Diagnostics UEFI HP PC Hardware Diagnostics Windows HP Performance Advisor¹ myHP HP QuickDrop¹⁹ HP Easy Clean²⁰ HP Smart Health²¹ WSL/Ubuntu Data Science Stack HP Privacy Settings Touchpoint Customizer for Commercial

Manageability Features

HP Driver Packs² HP UWP Pack

Supported Components

HP System Software Manager (SSM) HP Manageability Integration Kit Gen4³ HP Smart Support⁵ HP Client Catalog (download) HP Image Assistant (download) HP Cloud Recovery HP Client Management Script Library (download) HP BIOSphere Gen6 ¹³

Client Security Software

HP Client Security Suite Gen7⁴ including: (including Credential Manager, HP Password Manager⁶, HP Spare Key) HP Power On Authentication Microsoft Defender⁷

Security Management

HP Secure Erase ¹⁶ HP Wolf Pro Security Edition (optional) ¹⁸ HP Wolf Security for Business²² Includes: HP Sure Click¹¹ HP Sure Sense¹² HP Sure Run Gen5⁹ HP Sure Recover Gen4 ¹⁰ HP Sure Start Gen7⁸ HP Tamper Lock HP Sure Admin ¹⁷ HP Client Security Manager Gen 7⁴

¹ HP Performance Advisor Software - HP Performance Advisor is ready to help you get the most out of your HP Workstation from dat one-and every day after. Learn more or download at: http://hp.com/PerformanceAdvisor

² HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

³ HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html

⁴ HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.

⁵ HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.

⁶ HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.

⁷ Microsoft Defender Opt in and internet connection required for updates.

⁸ HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.

⁹ HP Sure Run Gen5 is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors

¹⁰ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module

¹¹ HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details. ¹² HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google ChromeTM, and ChromiumTM. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

¹³ HP BIOSphere Gen6 features may vary depending on the platform and configurations.

¹⁴ HP Support Assistant requires Windows and Internet access.

¹⁶ Secure Erase - For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] Optane.

¹⁷ HP Sure Admin requires Windows 11, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

¹⁸ HP Wolf Pro Security Edition is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-

Supported Components

year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"?). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.

¹⁹ HP Quick Drop requires Internet access and Windows 10 or higher PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.

²⁰ HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.

²¹ HP Smart Health automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.

²² HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features

System Technical Specifications

System Board

System Duaru				
System Board Form Factor	Customized PCB 36.0	056 x 25.130 mm (14	.197 x 9.894 inch)	
Processor Socket	Single LGA-1700			
CPU Bus Speed	DMI Gen4			
Chipset	Intel [®] PCH W680			
Super I/O Controller	Nuvoton SIO21			
Memory Expansion Slots	4 DDR5 memory slot	ts		
Memory Type Supported	DDR5, UDIMM (Unbut	ffered), ECC& non-EC	C	
Memory Modes	Non-Interleaved for	single channel. Interl	eaved when both channels	are populated.
Memory Speed Supported	3600MT/s to 4400M	T/s DDR5, dependent	on memory configuration	1
	¹ Though the memory maximum memory s) to 4800MHz, the current	platform will only be able to support the
	The system speed wi Module Configuration Single DIMM per channel	Description of config	ontain only one or two DIMM	Max Memory Speed (Actual Memory speed is dependent on CPU) 4400MHz
	Two single ranked DIMMs in a channel		or 4 single ranked DIMMs	4000MHz
	Two dual ranked DIMMs in a channel		or 4 dual ranked DIMMs	3600MHz
Memory Protection	ECC available on data	a		
Maximum Memory	128GB			
Memory Configuration (Supported)	8GB, 16GB and 32GB memory DIMMs cann			s are supported. ECC and non-ECC
PCI Express Connectors	 PCI Express Gen3 PCI Express Gen3 PCI Express Gen3 PCI Express Gen3 M.2 2280 Storage M.2 2280 Storage M.2 2280 Storage M.2 2230 WLAN (INCRE) NOTE: The PCIe Gen5 	slot x4 mechanical/ > slot x16 mechanical/ slot x4 mechanical/ e (PCIe Gen4 x4) e (PCIe Gen4 x4) e (PCIe Gen4 x4) PCIe Gen3 x1+ Intel C	ed and passed PCI-SIG elect	l length, open-ended) ull length)
	-	upport any PCIe Gen5	cards in the market.	
Supported Interfaces	SATA		Integrated (4) Serial ATA RAID 0 and 1 supported. Windows only.	interfaces (6Gb/s SATA). Factory integrated RAID for Microsoft
	Integrated Graphics		12100) processors); Intel processors); Based on Unified Memory system memory is reserv display. Support for Microsoft Dir on Intel® UHD Graphics 73 Based on Unified Memory	(on Core i5-12400/i3-12300/i3- (© UHD Graphics 770 (on Core i5/i7/i9) y Architecture (UMA) - a region of yed and dedicated to the graphics ectX 12, OpenGL 4.6 and OpenCL 3.0 30/770; y Architecture (UMA) - a region of yed and dedicated to the graphics

System Technical Specifications

display.

		2 DP 1.4 graphics ports integrated in motherboard; Supports up to three simultaneous displays across DisplayPort*/HDMI*/DVI outputs. Max. resolution supported on onboard DP 1.4/HBR2 ports: 4096x2304 @ 60Hz, 24bpp Max. resolution supported on FlexIO DP 1.4/HBR3 port: 5120x3200 @60Hz, 24bpp
	Network Controller	Integrated Ethernet PHY Connection I219LM. Management capabilities: WOL, PXE 2.1 and AMT 16
	Serial	1 internal header (requires optional Serial Port and PS/2 Combo Kit with PCIe bracket)
	2nd Serial	1 internal header(requires optional Serial Port Adapter Kit)
USB Connector(s)	Front	2 Type-A SuperSpeed USB 10Gbps signaling rate port (charge supports up to 5V/2.1A); 2 Type-A SuperSpeed USB 10Gbps signaling rate port; 1 Type- C® SuperSpeed USB 20Gbps signaling rate port (optional, charge supports up to 5V/3A)
	Rear	3 High-speed USB 480Mbps signaling rate port; 1 Type-A SuperSpeed USB 5Gbps signaling rate port; 2 Type-A SuperSpeed USB 10Gbps signaling rate port; Flex I/O option: 1 SuperSpeed USB Type-C® 10Gbps signaling rate (Power Delivery 15W, Alt Mode DisplayPort); 1 Dual SuperSpeed USB Type-A 5Gbps signaling rate
	Internal	1 High-speed USB 480Mbps signaling rate header for SD Card Reader
HD Integrated Audio	Realtek ALC3252	
Flash ROM	Yes	
CPU Fan Header	Yes	
Memory Fan Header	None	
Chassis Fan Header	1 Rear System Chassis Fan Header, 1 Grap	ohic chassis Fan Header.
Front PCI Fan Header	None	
Front Control Panel/Speaker Header	Yes	
CMOS Battery Holder -		
Lithium	Yes	
Integrated Trusted Platform Module	Integrated TPM 2.0 (Infineon SLB9672) Convertible to FIPS 140-2 Certified mode	through firmware v15.21
Power Supply Headers	Yes	
Power Switch, Power LED & Hard Drive LED Header	Yes	
Clear Password Jumper	None	
Keyboard/Mouse	USB or PS/2 (option)	
Power Supply	700W EPA92, 500W EPA90, 450W EPA90	and 350W EPA92
¹ Maximum memory capaciti		

32-bit Windows Operating Systems support up to 4 GB.

²M.2 storage supports compatible devices up to 80mm

System Technical Specifications

System Configurations					
Example Configuration #1	Processor Info	Core i5-12500,6C 3.0G 65W			
	Memory Info	2 x 8G DDR5 4800 UDIMM NECC			
	Graphics Info	NVIDIA T400 4GB			
	Disks/Optical/Floppy	512GB SSD Z Turbo			
	PSU	350W			
	Other	NA			

Energy Consumption		115 VAC		230 VAC		100 VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	17.866		17.912		17.804	
	Windows short Idle (S0)	18.926		19.024		18.883	
	Windows Busy Typ (SO)	160.167		155.973		161.10	
	Windows Busy Max (SO)	192.	557	187.	067	193.	063
	Sleep (S3)	1.367	1.259	1.401	1.367	1.259	1.401
	Off (S5)	0.555	0.552	0.561	0.555	0.552	0.561
	Zero Power Mode (EuP)	0.171		0.173		0.168	

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (SO)	60.9	959	61.116		60.747	
	Windows short Idle (SO)	64.576		64.91		64.429	
	Windows Busy Typ (SO)	546.489		532.181		549.707	
	Windows Busy Max (SO)	657.	003	638.271		658.	732
	Sleep (S3)	4.664	4.296	4.78	4.664	4.296	4.78
	Off (S5)	1.894	1.883	1.914	1.894	1.883	1.914
	Zero Power Mode (EuP)	0.5	83	0.59		0.573	

Example Configuration #2	Processor Info	Core i7-12700,12C 2.1G 65W
	Memory Info	2 x 16G DDR5 4800 UDIMM NECC
	Graphics Info	NVIDIA T1000 8GB
	Disks/Optical/Floppy	512GB SSD Z Turbo
	PSU	450W
	Other	NA

Energy Consumption		115 VAC		230 VAC		100 VAC	
(Watts)		LAN	LAN	LAN	LAN	LAN	LAN
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled
	Windows long Idle (S0)	20.	169	20.	335	20.087	
	Windows short Idle (S0)	21.222		21.547		21.195	
	Windows Busy Typ (SO)	119.48		117.953		120.406	
	Windows Busy Max (SO)	157	157.13 155.03		5.03	157.833	
	Sleep (S3)	1.575	1.461	1.582	1.575	1.461	1.582
	Off (S5)	0.944	0.941	0.952	0.944	0.941	0.952
	Zero Power Mode (EuP)	0.204		0.207		0.202	

System Technical Specifications

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN	LAN	LAN	LAN	LAN	LAN
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled
	Windows Idle (SO)	68.	817	69.	383	68.537	
	Windows short Idle (S0) 72.409 73.5		73.518		72.317		
	Windows Busy Typ (SO)	407	.666	402.457		410.824	
	Windows Busy Max (SO)	536	.128	528.962		538.527	
	Sleep (S3)	5.374	4.985	5.398	5.374	4.985	5.398
	Off (S5)	3.221	3.211	3.248	3.221	3.211	3.248
	Zero Power Mode (EuP)	0.696		0.706		0.689	

Example Configuration #3	Processor Info	Core i9-12900,16C 2.4G 65W						
	Memory Info	2 x 16G DDR	5 4800 UDIN	IM ECC				
	Graphics Info	NVIDIA RTX	A2000					
	Disks/Optical/Floppy	512GB SSD Z Turbo						
	PSU	450W						
	Other	NA						
Energy Consumption		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows long Idle (S0)	22.555		23.324		22.484		
	Windows short Idle (S0)	23.4	414	24.656		23.397		
	Windows Busy Typ (SO)	159.	.883	156.	853	161.463		
	Windows Busy Max (SO)	189	.99	185.89		190.127		
	Sleep (S3)	1.585	1.492	1.694	1.585	1.492	1.694	
	Off (S5)	0.952	0.95	1.083	0.952	0.95	1.083	
	Zero Power Mode (EuP)	0.	21	0.2	17	0.1	98	

Heat Dissipation		115	115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (SO) 76.958		79.581		76.715			
	Windows short Idle (SO)	s Busy Typ (SO) 545.522		84.126		79.831		
	Windows Busy Typ (SO)			535.184		550.913		
	Windows Busy Max (SO)			634.257		648.712		
	Sleep (S3)	5.408	5.091	5.78	5.408	5.091	5.78	
	Off (S5)	3.248	3.241	3.695	3.248	3.241	3.695	
	Zero Power Mode (EuP) 0.717		0.3	74	0.6	76		

Example Configuration #4	Processor Info	Core i7-12700K,12C 3.6G 125W
	Memory Info	4 x 16G DDR5 4800 UDIMM NECC
	Graphics Info	NVIDIA RTX A4000
	Disks/Optical/Floppy	1T SSD Z Turbo
	PSU	700W
	Other	NA

System Technical Specifications

Energy Consumption		115 VAC		230 VAC		100 VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	22.	551	22.	964	22.	486
	Windows short Idle (S0)	23.	911	24.168 267.963		23.749	
	Windows Busy Typ (SO)	272	2.74			274.65	
	Windows Busy Max (SO)	322	322.833 316.		16.03 323.367		.367
	Sleep (S3)	1.994	1.892	1.997	1.994	1.892	1.997
	Off (S5)	0.653	0.641	0.666	0.653	0.641	0.666
	Zero Power Mode (EuP)	0.215		0.217		0.212	

Heat Dissipation		115 VAC		230 VAC		100 VAC		
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (SO)	76.	944	78.353		76.722		
	Windows short Idle (SO)	81.	584	82.461		81.032		
	Windows Busy Typ (SO)	930	.589	914.291		937.106		
	Windows Busy Max (SO)	1101	1101.507		1078.294		1103.327	
	Sleep (S3)	6.804	6.456	6.814	6.804	6.456	6.814	
	Off (S5)	2.228	2.187	2.272	2.228	2.187	2.272	
	Zero Power Mode (EuP) 0.734		0.74		0.723			

Example Configuration #5	Processor Info	Core i9-12900K,16C 3.2G 125W
	Memory Info	4 x 32G DDR5 4800 UDIMM ECC
	Graphics Info	NVIDIA RTX A5000
	Disks/Optical/Floppy	1T SSD Z Turbo
	PSU	700W
	Other	NA

Energy Consumption		115 VAC 230 VAC		100 VAC			
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	24.038		24.681		23.994	
	Windows short Idle (S0)	25.	764	25.958		25.621	
	Windows Busy Typ (SO)	465	65.05 459.71		9.71	468.377	
	Windows Busy Max (SO)	467.623		438.733		474.68	
	Sleep (S3)	2.261	2.148	2.273	2.261	2.148	2.273
	Off (S5)	0.772	0.659	0.777	0.772	0.659	0.777
	Zero Power Mode (EuP)	le (EuP) 0.318		0.319		0.315	

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (SO)	82.	018	84.212		81.	868
	Windows short Idle (SO)	87.	907	88.569		87.419	
	Windows Busy Typ (SO)	158	6.75	1568.531		1598.101	
	Windows Busy Max (SO)	1595.531		1496.958		1619.608	
	Sleep (S3)	7.715	7.329	7.755	7.715	7.329	7.755
	Off (S5)	2.634	2.249	2.651	2.634	2.249	2.651
	Zero Power Mode (EuP) 1.085		1.088		1.075		

NOTE: The Power Supply Efficiency report may be found at the following links:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

System Technical Specifications

Operating Voltage Range	90-269 VAC
Rated Voltage Range	100-240 VAC
Rated Line Frequency	50-60 Hz
Operating Line Frequency Range	47-63 Hz
Rated Input Current	8.2A @ 100-240V
Heat Dissipation	Typical: 1598.101 btu/hr (402.984 kcal/hr) Maximum: 1619.608 btu/hr (408.407 kcal/hr)
ENERGY STAR [®] certified (Config Dependent)	Yes
CECP Compliant @ 220V	Yes
FEMP Standby Power Compliant	Yes, with Wake-on-LAN disabled: <1W in S4/S5 - Power Off
Built-in Self Test (BIST) LED	Yes
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)	Yes
Hood Lock Header	Yes
ErP Lot 6- Tier 1 Compliance @ 230V (<1W in S5 - Power Off)	Yes
ErP Lot 6- Tier 2 Compliance @ 230V (<0.5W in S5 - Power Off)	Yes

Declared Noise Emissions (Entry-level, Mid-level, and High-end configurations; tested on floor)				
System Configuration (Entry level)	Processor Info	Intel® CPU Core i5-12400 6C LGA 2.50G 18 MB 65W (Intel - Alder Lake-S)		
	Memory Info	32GB 4800 SK hynix memory		
	Graphics Info	Intel® UHD		
	Disks/Optical	1*2TB Samsung M.2 SSD		
	Power Supply	Chicony 700W EPA92		

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.36	14.9
	Hard drive Operating (Drive Random Seek)	3.78	20.3
	Hard drive Operating (Active mode)	3.45	17.7

System Configuration (Mid-level)	Processor Info	Intel® CPU Core i9-12900 16C LGA 2.40G 30 MB 65W ECC (Intel - Alder Lake-S)
	Memory Info	4* 32GB 4800 SK hynix memory
	Graphics Info	NVIDIA® RTX A5000
	Disks/Optical	3*2TB Samsung M.2 SSD; 2*WD 2TB 7200RPM SATA HDD
	Power Supply	Chicony 700W EPA92

System Technical Specifications

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.59	18.5
	Hard drive Operating (Drive Random Seek)	3.82	20.1
	Hard drive Operating (Active mode)	3.97	23.6

System Configuration (High-end)	Processor Info	Intel® Core i9-12900K 16C 3.20G LGA 30 MB 125W ECC (Intel - Alder Lake-S)
	Memory Info	4* 32GB 4800 SK hynix memory
	Graphics Info	NVIDIA® RTX A5000
	Disks/Optical	3*2TB Samsung M.2 SSD; 2*WD 2TB 7200RPM SATA HDD
	Power Supply	Chicony 700W EPA92

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
l l	dle	3.58	18.2
	Hard drive Operating (Drive Random Seek)	3.78	20
	Hard drive Operating (Active mode)	4.05	20.9

Environmental Requirements	Temperature	Operating: 5° to 35° C (40° to 95° F) Non-operating: -40° to 60° C (-40° to 140° F) Maximum rate of change: 10°C/hr
	Humidity	Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb
	Maximum Altitude	Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet) Non-operating: 12,192 m (40,000 feet) Maximum operating temperature is reduced as altitude increases. See Cooling for details.
	Dynamic	Shock Operating: ?-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ?-sine: 160 cm/s, 2-3ms (~105g) square: 422 cm/s, 20g
		Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g?/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g?/Hz
	Cooling	Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation, up to 3048 m (10,000 feet)
	NOTE:	System enduring or operating beyond the environmental requirement range is not recommended and may compromise system reliability permanently.

System Technical Specifications

Physical Security and Serviceability

Assas Danal	
Access Panel	Tool-less Includes support information
Optical Drive	Tool-less, except for Screw-In carrier
Hard Drives	Tool-less, except for 2.5" bay
Expansion Cards	Tool-less
Processor Socket	Tool-less, except for the processor heatsink
Blue User Touch Points	Yes, on tool-less internal chassis mechanisms
Color-coordinated Cables and Connectors	Yes
Memory	Tool-less
System Board	Screw-In
Padlock Support	Yes (optional): Locks side cover and secures chassis from theft 0.22-in diameter padlock loop at rear of system
Cable Lock Support	Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3 mm x 7 mm slot at rear of system
Universal Chassis Clamp Lock Support	Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows multiple units to be chained together when used with optional cable Threaded feature at rear of system
Solenoid Lock and Hood Sensor	Yes (optional) The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through software and a password. You can also lock and unlock the chassis remotely over the network. The Sensor Kit detects when the access panel has been removed.
Rear Port Control Cover	Νο
CPUs and Heatsinks	A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be removed. CPU removal is tool-less
Internal Speaker	Yes
Power Supply Fans	70mm x 70mm x 25mm 4-wire PWM (non-serviceable)
Access Panel Key Lock	No
Integrated Chassis Handles	Rear Recessed Handle
Power Supply	Requires T15 Torx or flat blade screwdriver
PCI Card Retention	Yes, rear (all), middle (optional), front (full-length cards with extender)

Service, Support, and Warranty

On-site Warranty and Service¹: Three-years, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - 5pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise class HDDs.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at:

http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

System Technical Specifications

BIOS

BIOS 64-bit Services	BIOS supports 64-bit Operating systems only.
PCI 3.0 Support	Full BIOS support for PCI Express through industry standard interfaces.
ATAPI	ATAPI Removable Media Device BIOS Specification Version 1.0.
BBS	BIOS Boot Specification v1.01.(Not support)
WMI Support	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.
BIOS Boot Spec 1.01+	Provides more control over how and from what devices the workstation will boot.(Not Support)
BIOS Power On	Users can define a specific date and time for the system to power on.
ROM Based Computer Setup Utility (F10)	Review and customize system configuration settings controlled by the BIOS.
System/Emergency ROM	Recovers system BIOS in corrupted Flash ROM.
Flash Recovery with Video	
Replicated Setup	Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).
SMBIOS	System Management BIOS 3.4, for system management information.
Boot Control	Disables the ability to boot from removable media on supported devices.
Memory Change Alert	Alerts management console if memory is removed or changed.
Thermal Alert	Monitors the temperature state within the chassis. Three modes:
	 NORMAL - normal temperature ranges. ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown. SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs.
Remote ROM Flash	Provides secure, fail-safe ROM image management from a central network console.
ACPI (Advanced	Allows the system to enter and resume from low power modes (sleep states).
Configuration and Power Management Interface)	Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system. Supports ACPI 6.0 for full compatibility with 64-bit operating systems.
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.
Remote Wakeup/Remote Shutdown	System administrators can power on, restart, and power off a client computer from a remote location.
Instantly Available PC (Suspend to RAM - ACPI sleep state S3)	Allows for very low power consumption with quick resume time.
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW applications can use and report this information.
System board revision level	Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.

System Technical Specifications

-	
Auto Setup when new hardware installed	System automatically detects addition of new hardware.
Keyboard-less Operation	The system can be booted without a keyboard.
Localized ROM Setup	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings.
Asset Tag	The user or MIS to set a unique tag string in non-volatile memory.
Per-slot Control	Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually.
Adaptive Cooling	Control parameters are set according to detected hardware configuration for optimal acoustics.
Pre-boot Diagnostics	(Pre-video) critical errors are reported via beeps and blinks on the power LED.
UEFI Specification	
Revision	2.7
ACPI	Advanced Configuration and Power Management Interface, Version 6.0
ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
CD Boot	"El Torito" Bootable CD-ROM Format Specification Version 1.0
EDD	Enhanced Disk Drive Specification Version 1.1
	BIOS Enhanced Disk Drive Specification Version 3.0(Not support)
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0
PCI	PCI Local Bus Specification, Revision 2.3
	PCI Power Management Specification, Revision 1.1
	PCI Firmware Specification, Revision 3.0, Draft .7
PCI Express	PCI Express Base Specification, Revision 2.0 PCI Express Base Specification, Revision 3.0
	PCI Express Base Specification, Revision 4.0
	PCI Express Base Specification, Revision 5.0 Ready
PMM	POST Memory Manager Specification, Version 1.01
SATA	Serial ATA Specification, Revision 1.0a
	Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5
	Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0
SPD	JEDEC JESD300-5
ТРМ	Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9670).
	Common Criteria EAL4+ certified. FIPS 140-2 Certification
	TCG TPM Certified products list:
	http://www.trustedcomputinggroup.org/certification/tpm-certified-products/
UHCI	Universal Host Controller Interface Design Guide, Revision 1.1
USB	Universal Serial Bus Revision 1.1 Specification
	Universal Serial Bus Revision 2.0 Specification
	Universal Serial Bus Revision 3.1 Specification
	Universal Serial Bus Revision 3.2 Specification
SMBIOS	System Management BIOS Reference Specification, Version 3.4
	External BIOS simulator found at: http://csrsml.itcs.hp.com/
	External bios simulator round at. http://csrsmit.cs.np.com/

Social and Environmental Responsibility

Eco-Label CertificationsThis product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT? Gold registered in the United States. See http://www.epeat.net for registration status in your country.

Upgrading

System Technical Specifications

 China State Environmenta Taiwan Green Mark Korea Eco-label Japan PC Green label* Ocean-bound plastic ir 50% post-consumer re Low halogen Outside Box and corrure recyclable Molded Paper Pulp Curecyclable Bulk packaging available 	l Protection Administration (SE n System FAN, CPU FAN a ecycled plastic Igated cushions are 100% Ishion inside box is 100% s	and Speaker sustainably sourced and sustainably sourced and
115445 504-	220146 504-	1001/06 501-
		100VAC, 50Hz
34.16 W	34.01 W	34.39 W
j 32.77 W	32.74 W	33.15 W
2.57 W	2.54 W	2.57 W
0.67 W	0.68 W	0.67 W
family . HP computers marked wi Environmental Protection Agency family does not offer ENERGY ST	ith the ENERGY STAR® Logo are y (EPA) ENERGY STAR® specifica AR® compliant configurations, t	compliant with the applicable U.S. itions for computers. If a model hen energy efficiency data listed
	 China Energy Conservation China State Environmenta Taiwan Green Mark Korea Eco-label Japan PC Green label* Ocean-bound plastic ir 50% post-consumer re Low halogen Outside Box and corrure recyclable Molded Paper Pulp Curecyclable Bulk packaging availab The configuration used for the Err Notebook model is based on a "Type" 115VAC, 60Hz 34.16 W 32.77 W 2.57 W 0.67 W Note: Energy efficiency data listed is for family . HP computers marked wite Environmental Protection Agency 	 China Energy Conservation Program (CECP) China State Environmental Protection Administration (SE Taiwan Green Mark Korea Eco-label Japan PC Green label* Ocean-bound plastic in System FAN, CPU FAN at 50% post-consumer recycled plastic Low halogen Outside Box and corrugated cushions are 100% recyclable Molded Paper Pulp Cushion inside box is 100% strecyclable Bulk packaging available The configuration used for the Energy Consumption and Declare Notebook model is based on a "Typically Configured Notebook"? 115VAC, 60Hz 230VAC, 50Hz 34.16 W 32.77 W 2.57 W 2.57 W 2.57 W 2.57 W 2.54 W 0.67 W 0.68 W

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	116.8 BTU/hr	116.3 BTU/hr	117.6 BTU/hr
Normal Operation (Longidle)	g 112.1 BTU/hr	112 BTU/hr	113.4 BTU/hr
Sleep	8.8 BTU/hr	8.7 BTU/hr	8.8 BTU/hr
Off	2.3 BTU/hr	2.3 BTU/hr	2.3 BTU/hr
	*NOTE: Heat dissipation is calcula attained for one hour.	ated based on the measured watt	s, assuming the service level is
Declared Noise			

Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured - Idle	3.36	14.9
Fixed Disk - Random writes	3.78	20.3
Optical Drive - Sequential reads	5.00	33.4
Longevity and	This product can be upgraded, possibly extendin	g its useful life by several years. U

d This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

System Technical Specifications

	Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.		
Batteries	This battery in this product complies with EU Directive 2006/66/EC		
	Battery size: CR2032 (coir	n cell)	
	Battery type: Lithium Meta	I	
	The battery in this product	does not contain:	
Additional Information	 directive - 2011/65/E This HP product is des (WEEE) Directive - 200 This product is in com Drinking Water and To This product is in com www.epeat.net Plastics parts weighin ISO1043. 	an 10ppm by weight ppm by weight pliance with the Restrictions of Haz C. signed to comply with the Waste Ele	ectrical and Electronic Equipment 55 (State of California; Safe standard at the Gold level, see at are marked per ISO11469 and
Packaging Materials	External:	PAPER/Corrugated	1214 g
	Internal:	PAPER/Molded Pulp PLASTIC/Polyethylene low density - LDPE	890 g 40 g
	The plastic packaging mater	ial contains at least 0.0% recycled c	ontent.
		ging materials contains at least 62.	-
RoHS Compliance	extend the restrictions in the (RoHS) Directive to our pro-	materials regulations. We were a be European Union (EU) Restriction oducts worldwide through the HP (islation in Europe, as well as Chin	on of Hazardous Substances GSE. HP has contributed to the
	industry-wide elimination o additional substances-inclu	tive and similar laws play an impo f substances of concern. We have uding PVC, BFRs, and certain phtl electrical and electronics products	e supported the inclusion of halates-in future RoHS
	requirements for virtually a	ctive to achieve worldwide complia Il relevant products by July 2013, a ent to include further restricted sul	and we will continue to extend
	To obtain a copy of the HF <mark>statement</mark> .	RoHS Compliance Statement, se	ee HP RoHS position
Material Usage	to the HP General Specificat http://www.hp.com/hpinfo/ gen_specifications.html): Asbestos Certain Azo Colorants	globalcitizenship/environment/sup	plychain/

System Technical Specifications

- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
 - Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:		
	 Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. 		
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.		
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.		
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment:		
	Global Citizenship Report		

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

System Technical Specifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

footnotes

- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.

Technical Specifications - Processors

Name	Cores	Clock Speed (GHz)	Threads	Cache (MB)	Memory Speed (MT/s)	Hyper- Threading	Integrated Graphics	Intel® Turbo Boost Technology ³	Featuring Intel® vPro® Technology ⁴	16GB Intel® Optane TM memory ²	TDP (W)
Intel® Core™ i9- 12900K Processor	16	3.2	24	30	4800	Y	Intel® UHD Graphics 770	5.2	Y	N	125
Intel® Core™ i9- 12900 Processor	16	2.1	24	30	4800	Y	Intel® UHD Graphics 770	5.1	Y	N	65
Intel® Core™ i7- 12700K Processor	12	3.6	20	25	4800	Y	Intel® UHD Graphics 770	5.0	Y	N	125
Intel® Core™ i7- 12700 Processor	12	2.1	20	25	4800	Y	Intel® UHD Graphics 770	4.9	Y	N	65
Intel® Core™ i5- 12600K Processor	10	3.7	16	20	4800	Y	Intel® UHD Graphics 770	4.9	Y	N	125
Intel® Core™ i5- 12600 processor	6	3.3	12	18	4800	Y	Intel® UHD Graphics 770	4.8	Y	N	65
Intel® Core™ i5- 12500 processor	6	3.0	12	18	4800	Y	Intel® UHD Graphics 770	4.6	Y	N	65
Intel® Core™ i5- 12400 processor	6	2.5	12	18	4800	Y	Intel® UHD Graphics 730	4.4	N/A	N	65
Intel® Core™ i3- 12300 processor	4	3.5	8	12	4800	Y	Intel® UHD Graphics 730	4.4	N/A	N	60
Intel® Core™ i3- 12100 processor	4	3.3	8	12	4800	Y	Intel® UHD Graphics 730	4.3	N/A	N	60

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Intel[®] OptaneTM memory system acceleration does not replace or increase the DRAM in your system.

³ Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

⁴ Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro

Note: ECC memory is supported on the following: Intel® CoreTM i9-12900K, Intel® CoreTM i9-12900, Intel® CoreTM i7-12700K, Intel® CoreTM i7-12700K, Intel® CoreTM i7-12700K, Intel® CoreTM i7-12700, Intel® CoreTM i5-12600K, Intel® CoreTM i5-12600 and Intel® CoreTM i5-12500 processors

	00GB SATA 7200 rpm Gb/s 3.5" HDD	Capacity Protocol Form Factor Controller Height Width Interface Synchronous Transfer Rate (Maximum) Buffer Seek Time (typical read includes controller	32MB	3.5 in; 8.9 cm 4 in; 10.17 cm , NCQ enabled
Workstations 60	Gb/s 3.5" HDD	Form Factor Controller Height Width Interface Synchronous Transfer Rate (Maximum) Buffer Seek Time (typical read	3.5" AHCI 1 in; 2.54 cm Media Diameter Physical Size Serial ATA (6.0Gb/s). Up to 600MB/s * 32MB	4 in; 10.17 cm
		Controller Height Width Interface Synchronous Transfer Rate (Maximum) Buffer Seek Time (typical read	AHCI 1 in; 2.54 cm Media Diameter Physical Size Serial ATA (6.0Gb/s). Up to 600MB/s * 32MB	4 in; 10.17 cm
		Height Width Interface Synchronous Transfer Rate (Maximum) Buffer Seek Time (typical read	1 in; 2.54 cm Media Diameter Physical Size Serial ATA (6.0Gb/s) Up to 600MB/s * 32MB	4 in; 10.17 cm
		Width Interface Synchronous Transfer Rate (Maximum) Buffer Seek Time (typical read	Media Diameter Physical Size Serial ATA (6.0Gb/s) Up to 600MB/s * 32MB	4 in; 10.17 cm
		Interface Synchronous Transfer Rate (Maximum) Buffer Seek Time (typical read	Physical Size Serial ATA (6.0Gb/s) Up to 600MB/s * 32MB	4 in; 10.17 cm
		Synchronous Transfer Rate (Maximum) Buffer Seek Time (typical read	Serial ATA (6.0Gb/s) Up to 600MB/s * 32MB	
		Synchronous Transfer Rate (Maximum) Buffer Seek Time (typical read	Up to 600MB/s * 32MB	, NCQ enabled
		Rate (Maximum) Buffer Seek Time (typical read	32MB	
		Seek Time (typical read		
			ls, Single Track	
		includes controller		2 ms *
		overhead, including	Average	11 ms *
		settling)	Full Stroke	21 ms *
		Rotational Speed	7,200 rpm	
		Logical Blocks	976,773,168	
		Operating Temperatu	re 41° to 131° F (5° to 5	55° C)
11	1TB SATA 7200 rpm	Capacity	1TB	
1T	1TB SATA 7200 mm	Canacity	1TB	
			SATA	
		Form Factor	3.5"	
		Controller	AHCI	
	I	Height	1 in; 2.54 cm	
		Width	Media Diameter	3.5 in; 8.9 cm
			Physical Size	4 in; 10.17 cm
	I	Interface	Serial ATA (6.0Gb/s), N	CQ enabled
		Synchronous Transfer Rate (Maximum)	Up to 600 MB/s *	
		Buffer	64MB	
		Seek Time (typical reads,	Single Track	2 ms *
		ncludes controller	Average	11 ms *
		overhead, including settling)	Full Stroke	21 ms *
		Rotational Speed	7,200 rpm	
		Logical Blocks	1,953,525,168	
		Operating Temperature	41° to 131° F (5° to 55°	° C)
NO.		ary. billion bytes. TB = 1 trillion byte served for system recovery sof		ty is less. Up to 36GB of

2TB SATA 7200 rpm	Capacity	2TB		
6Gb/s 3.5" HDD	Protocol	SATA		
	Form Factor	3.5"		
	Controller	AHCI		
	Annualized Failure Rate			
	(based on Rated POH)	<0.62%		
	Height	1 in; 2.54 cm		
	Width	Media Diameter	3.5 in; 8.9 cm	
		Physical Size	4 in; 10.17 cm	
	Interface	Serial ATA (6.0 Gb/s), N	CQ Enabled	
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s *		
	Buffer	64MB		
	Seek Time (typical reads	s, Single Track	2.0 ms *	
	includes controller overhead, including	Average	11 ms *	
	settling)	Full Stroke	21 ms *	
	Rotational Speed	7,200 rpm		
	Logical Blocks	3,907,029,168		
	Operating Temperature 41° to 131° F (5° to 55° C)			

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB SATA 7200 rpm	Capacity	1TB	
6Gb/s 3.5" HDD	Height	1 in; 2.54 cm	
(Enterprise Class)	Protocol	SATA	
	Form Factor	3.5"	
	Controller	AHCI	
	Reliability	2.0M hours	
	Rated Power On Hours	8760/yr	
	Annualized Failure Rate		
	(based on Rated POH)	<0.62%	
	Width	Media Diameter	3.5 in; 8.9 cm
		Physical Size	4 in; 10.17 cm
	Interface Serial ATA (6.0 Gb/s), NCQ Enabled		Q Enabled
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s *	
	Buffer	128MB	
	Seek Time (typical reads	, Single Track	0.32ms*
	includes controller overhead, including	Average	7.45ms*
	settling)	Full Stroke	14.2ms*
	Rotational Speed	7,200 rpm	
	Operating Temperature	e41° to 140° F (5° to 60°	C)
	Performance	Sequential Read	up to 226MB/s*
		Sequential Write	up to 226MB/s*
	Enterprise Class Features	High Reliability	

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2TB SATA 7200 rpm 6Gb/s	Capacity	2TB	
3.5" HDD (Enterprise	Protocol	SATA	
Class)	Form Factor	3.5"	
	Controller	AHCI	
	Reliability (MTBF)	2.0M hours	
	Rated Power On Hours	8760/yr	
	Annualized Failure Rate (based on Rated POH)	<0.62%	
	Rated for 24/7/365 Operation		
	Physical Size (Height)	1 in; 2.54 cm	
	Physical Size (Width)	4 in; 10.17 cm	
	Media Diameter	3.5 in; 8.9 cm	
	Interface	Serial ATA (6Gb/s), NCQ	enabled
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
	Buffer	128MB	
	Seek Time (typical reads	, Single Track	0.7ms*
	includes controller	Average	8.5ms*
	overhead, including settling)	Full Stroke	15.7ms*
	Rotational Speed	7,200 rpm	
	Operating Temperature	9 41° to 131° F (5° to 55° (<u>-</u>)
	Performance	Sequential Read	up to 226MB/s*
		Sequential Write	up to 226MB/s*
	Enternrise Class Features	High Reliability	

Enterprise Class Features High Reliability

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

4TB SATA 7200 rpm	Capacity	4TB
6Gb/s 3.5" HDD	Protocol	SATA
(Enterprise Class)	Form Factor	3.5"
	Controller	AHCI
	Reliability	2.0M hours
	Rated Power On Hours	8760/yr
	Annualized Failure Rate (based on Rated POH)	<0.62%
	Rated for 24/7/365 Operation	
	Physical Size (Height)	1 in; 2.54 cm
	Physical Size (Width)	4 in; 10.17 cm
	Media Diameter	3.5 in; 8.9 cm
	Physical Size	4 in; 10.17 cm
	Interface	Serial ATA (6Gb/s), NCQ enabled
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s*
	Buffer	256MB

Seek Time (typical reads	5, Single Track	0.7ms*
includes controller overhead, including	Average	8.5ms*
settling)	Full Stroke	15.7ms*
Rotational Speed	7,200 rpm	
Operating Temperature	e 41° to 131° F (5° to 55°	C)
Performance	Sequential Read	up to 226MB/s*
	Sequential Write	up to 226MB/s*
Enterprise Class Features	High Reliability	

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

8TB SATA 7200 rpm 6Gb/s	Capacity	8TB	
3.5" HDD (Enterprise Class)	Protocol	SATA	
	Form Factor	3.5"	
	Controller	AHCI	
	Reliability	2.0M hours	
	Width	Media Diameter	3.5 in; 8.9 cm
		Physical Size	4 in; 10.17 cm
	Interface	Serial ATA (6.0Gb/s), NCQ enabled	
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s [1]	
	Buffer	256MB	
	Seek Time (typical reads, includes controller	, Single Track	0.7ms*
		Average	8.5ms*
	overhead, including settling)	Full Stroke	15.7ms*
	Rotational Speed	7,200 rpm	
	Operating Temperature	e 41° to 140° F (5° to 60° C	.)
	Performance	Sequential Read	up to 226MB/s ¹
		Sequential Write	up to 226MB/s ¹
	Enterprise Class Features	High Reliability	

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Technical Specifications - Hard Drives

500GB SATA 7.2K SED 2.5"	Capacity	500GB	
HDD	Protocol	SATA	
	Form Factor	2.5"	
	Height	0.275 in; 0.7 cm	
	Width	Media Diameter	2.5 in; 6.36 cm
		Physical Size	2.75 in; 6.99 cm
	Interface	Serial ATA (6.0Gb/s), NCC	enabled
	Synchronous Transfer Rate (Maximum)	e Up to 600MB/s*	
	Buffer	64MB	
	Seek Time (typical reads, includes controller overhead, including	Single Track	1ms*
		Average	4.2ms*
	settling)	Full Stroke	25ms (Typical)*
	Rotational Speed	7,200 rpm	
	Operating Temperature	32° to 131° F (0° to 60° C)
	Self-Encrypting Drive Support	Yes	
*Actual porformanco mayu	u aru		

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 512GB TLC PCIe SSD (Z2G9)	Capacity	512GB		
	Protocol	PCIe		
	Form Factor	M.2 in native Slot on mo	otherboard	
	Controller	NVMe		
	NAND Type	3D TLC		
	Endurance	150TBW (TB Written)		
	Reliability (MTBF)	1.5M hours		
	Interface	PCI Express 4.0 x4 electrical		
	Operating Temperature	32° to 178° F (0° to 81° C)		
	Performance	Sequential Read	6400MB/s*	
		Sequential Write	3400MB/s*	
		Random Read	600K IOPS*	
		Random Write	600K IOPS*	

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Technical Specifications - Hard Drives

HP Z Turbo Drv PCIE-4X4	Capacity	1TB	
1TB TLC PCIe SSD (Z2G9)	Protocol	PCle	
	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	300TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 electrical	
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6500MB/s*
		Sequential Write	5000MB/s*
		Random Read	800K IOPS*
		Random Write	800K IOPS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4	Capacity	2TB	
2TB TLC PCIe SSD (Z2G9)	Protocol	PCIe	
	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	600TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6500MB/s*
		Sequential Write	5000MB/s*
		Random Read	800K IOPS*
		Random Write	800K IOPS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Technical Specifications - Hard Drives

HP Z Turbo Drv PCIE-4X4 4TB	Capacity	4TB	
	Protocol	PCIe	
TLC PCIe SSD	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	1200TBW (TB Written)	
	Reliability (MTBF)	1.5M Hours	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6500MB/s*
		Sequential Write	5000MB/s*
		Random Read	700K IOPS*
		Random Write	700K I0PS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE Gen4x4 4TB	Capacity	4TB	
	Protocol	PCIe	
TLC PCIe SED OPAL2	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	1200TBW (TB Written)	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6500MB/s*
		Sequential Write	5000MB/s*
		Random Read	700K I0PS*
		Random Write	700K I0PS*
	Self-Encrypting Drive Support	OPAL2	

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Technical Specifications - Hard Drives

HP Z Turbo Drv 512GB TLC PCIe SED OPAL2 (Z2G9)	Capacity	512GB	
	Protocol	PCIe	
	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	150TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6400MB/s*
		Sequential Write	3400MB/s*
		Random Read	600K IOPS*
		Random Write	600K IOPS*
	Self-Encrypting Drive Support	OPAL2	

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 1TB TLC PCIe SED	Capacity	1TB	
	Protocol	PCIe	
OPAL2 (Z2G9)	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	300TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6500MB/s*
		Sequential Write	5000MB/s*
		Random Read	800K IOPS*
		Random Write	800K IOPS*
	Self-Encrypting Drive Support	OPAL2	

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Technical Specifications - Hard Drives

HP Z Turbo Drv 2TB TLC PCIe SED	Capacity	2TB	
	Protocol	PCIe	
OPAL2 (Z2G9)	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	600TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6500MB/s*
		Sequential Write	5000MB/s*
		Random Read	800K IOPS*
		Random Write	800K IOPS*
	Self-Encrypting Drive Support	OPAL2	

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

256GB 2280 PCIe-4x4 Value M.2 SSD	Capacity	256GB	
	Protocol	PCIe	
	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	200TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3100MB/s*
		Sequential Write	1400MB/s*
		Random Read	200K IOPS*
		Random Write	400K I0PS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Technical Specifications - Hard Drives

512GB 2280 PCIe-4x4	Capacity	512GB	
Value M.2 SSD	Protocol	PCIe	
	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	300TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3400MB/s*
		Sequential Write	2500MB/s*
		Random Read	380K IOPS*
		Random Write	430K IOPS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB 2280 PCIe-4x4 Value M.2 SSD	Capacity	1TB	
	Protocol	PCIe	
	Form Factor	M.2 in native Slot on m	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	400TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3400MB/s*
		Sequential Write	2500MB/s*
		Random Read	500K IOPS*
		Random Write	440K IOPS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Technical Specifications - Graphics

AMD Radeon TM Pro	Form Factor	Single slot, full-height, 9.5" length
W6600 8GB Graphics	Graphics Controller	Navi23 architecture Power: 122 Watts
		Cooling Solution: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x8
	Memory	8GB GDDR6 Memory Memory Bandwidth: 224 GB/s Memory Interface: 128 bit
	Connectors	4x DisplayPort TM 1.4 with DSC - HDR Ready - Supports Multi-Stream Transport (MST)
	Max simultaneous displays	@ 60Hz with HDR Enabled 4x @ 3840x2160px (4K) 4x @ 5120x2880px (5K) 1x @ 7680x4320px (8K)
	Shading Architecture	DirectX 12 Shader Model 6.5
	Supported Graphics APIs	DirectX®12 Ultimate OpenGL® 4.6 OpenCL TM 2.1 Vulkan TM 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site:
		http://welcome.hp.com/country/us/en/support.html
AMD Radeon TM Pro W6800 32GB Graphics	Form Factor	Double slot, full-height, 10.5"? length
	Graphics Controller	Navi21 architecture Power: 261 Watts Cooling Solution: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x16
	Memory	8GB GDDR6 Memory Memory Bandwidth: 512 GB/s Memory Interface: 256 bit
	Connectors	6x Mini-DisplayPort TM 1.4 with DSC - HDR Ready - Supports Multi-Stream Transport (MST)
	Max simultaneous displays	@ 60Hz with HDR Enabled 6x @ 3840x2160px (4K) 6x @ 5120x2880px (5K) 2x @ 7680x4320px (8K)
	Shading Architecture	DirectX 12 Shader Model 6.5
	Supported Graphics APIs	DirectX®12 Ultimate OpenGL® 4.6 OpenCL TM 2.1 Vulkan TM 1.2

Vulkan[™] 1.2

Technical Specifications - Graphics

NVIDIA® T400 2GB	Form Factor	Single Slot, Low Profile (2.7"? H x 6.1"? L)
Graphics*	Graphics Controller	Turing architecture Max Power: 30 Watts Cooling Solution: Active fan heatsink
	Bus Type	PCI Express 3.0 x16
	Memory	2GB GDDR6 Memory Memory Bandwidth: 80 GB/s Memory Interface: 64 bit
	Connectors	3x mDP (Mini DisplayPort TM) 1.4 Connectors
	Max simultaneous displays	- 3x 3840 x 2160 @ 120Hz - 3x 5120 x 2880 @ 60Hz - supports Multi-Stream Transport (MST)
	Shading Architecture	DirectX 12 Shader Model 5.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

*May go End of Life in late 2022

NVIDIA® T400 4GB	Form Factor	Single Slot, Low Profile (2.7"? H x 6.1"? L)
Graphics	Graphics Controller	Turing architecture Max Power: 30 Watts Cooling Solution: Active fan heatsink
	Bus Type	PCI Express 3.0 x16
	Memory	4GB GDDR6 Memory Memory Bandwidth: 80 GB/s Memory Interface: 64 bit
	Connectors	3x mDP (Mini DisplayPort TM) 1.4 Connectors
	Max simultaneous	
	displays	- 3x 3840 x 2160 @ 120Hz - 3x 5120 x 2880 @ 60Hz - supports Multi-Stream Transport (MST)
	Shading Architecture	DirectX 12 Shader Model 5.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics	Windows 10 64-bit Windows 11 64-bit
	Drivers	Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

Technical Specifications - Graphics

NVIDIA® T600 4GB	Form Factor	Single Slot, Low Profile (2.7"? H x 6.1"? L)
Graphics*	Graphics Controller	Turing architecture Max Power: 40 Watts Cooling Solution: Active fan heatsink
	Bus Type	PCI Express 3.0 x16
	Memory	4GB GDDR6 Memory Memory Bandwidth: 160 GB/s Memory Interface: 128 bit
	Connectors	4x mDP (Mini DisplayPort™) 1.4 Connectors
	Max simultaneous displays	- 4x 3840 x 2160 @ 120Hz - 4x 5120 x 2880 @ 60Hz - 2x 7680 x 4320 @ 60Hz - supports Multi-Stream Transport (MST)
	Shading Architecture	DirectX 12 Shader Model 5.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

*May go End of Life in late 2022

NVIDIA® T1000 4GB Graphics	Form Factor	Single Slot, Low Profile (2.7"? H x 6.1" ? L)
	Graphics Controller	Turing architecture Max Power: 50 Watts Cooling Solution: Active fan heatsink
	Bus Type	PCI Express 3.0 x16
	Memory	4GB GDDR6 Memory Memory Bandwidth: 160 GB/s Memory Interface: 128 bit
	Connectors	4x mDP (Mini DisplayPort TM) 1.4 Connectors
	Max simultaneous displays	- 4x 3840 x 2160 @ 120Hz - 4x 5120 x 2880 @ 60Hz - 2x 7680 x 4320 @ 60Hz - supports Multi-Stream Transport (MST)
	Shading Architecture	DirectX 12 Shader Model 5.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit

Technical Specifications - Graphics

Linux[®] 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

NVIDIA® T1000 8GB Graphics	Form Factor	Single Slot, Low Profile (2.7"? H x 6.1" ? L)
	Graphics Controller	Turing architecture Max Power: 50 Watts Cooling Solution: Active fan heatsink
	Bus Type	PCI Express 3.0 x16
	Memory	8GB GDDR6 Memory Memory Bandwidth: 160 GB/s Memory Interface: 128 bit
	Connectors	4x mDP (Mini DisplayPort™) 1.4 Connectors
	Max simultaneous displays	- 4x 3840 x 2160 @ 120Hz - 4x 5120 x 2880 @ 60Hz - 2x 7680 x 4320 @ 60Hz - supports Multi-Stream Transport (MST)
	Shading Architecture	DirectX 12 Shader Model 5.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® RTX TM A2000	Form Factor	Low-Profile Double Slot (2.7"? H x 6.1"

NVIDIA® RTX TM A2000 12GB Graphics	Form Factor	Low-Profile Double Slot (2.7"? H x 6.1" ? L)
	Graphics Controller	Ampere architecture Power: 70 Watts Cooling: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x16
	Memory	12GB GDDR6 memory Memory Bandwidth: 288 GB/s Memory Interface: 192 bit Support Error-correcting code (ECC)
	Connectors	4x mDP (Mini DisplayPort™) 1.4 Connectors
	Max simultaneous displays	4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz
	Shading Architecture	Shader Model 6.5

Technical Specifications - Graphics

Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
	HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX [™] A4000	Form Factor	Full Height Single Slot (9.5"? Length)
16GB Graphics	Graphics Controller	Ampere architecture Power: 140 Watts Cooling: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x16
	Memory	16GB GDDR6 memory Memory Bandwidth: 448 GB/s Memory Interface: 256 bit Support Error-correcting code (ECC)
	Connectors	4x DP 1.4 Connectors
	Max simultaneous displays	4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz, 2x 7680 x 4320 @ 60 Hz
	Shading Architecture	Shader Model 6.5
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
_		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

Technical Specifications - Graphics

NVIDIA® RTX TM A4500 20GB Graphics	Form Factor	Full Height Double Slot (10.5"? Length)
	Graphics Controller	Ampere architecture Power: 200 Watts Cooling: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x16
	Memory	20GB GDDR6 memory Memory Bandwidth: 640 GB/s Memory Interface: 320 bit Support Error-correcting code (ECC)
	Connectors	4x DP 1.4 Connectors
	Max simultaneous displays	4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz, 2x 7680 x 4320 @ 60 Hz
	Shading Architecture	Shader Model 6.5
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ A5000 24GB Graphics	Form Factor	Full Height Double Slot (10.5"? Length)
	Graphics Controller	Ampere architecture Power: 230 Watts Cooling: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x16
	Memory	24GB GDDR6 memory Memory Bandwidth: 768 GB/s Memory Interface: 384 bit Support Error-correcting code (ECC)
	Connectors	4x DP 1.4 Connectors
	Max simultaneous displays	4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz, 2x 7680 x 4320 @ 60 Hz
	Shading Architecture	Shader Model 6.5
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site:

Technical Specifications - Graphics

http://welcome.hp.com/country/us/en/support.html

AMD Radeon TM RX 6700 XT	Form Factor	Dual slot, Full Length (254mm L x 38mm W x 108.65mm H)
	Graphics Controller	AMD Radeon TM RX 6700 XT Graphics GPU: 2560 Navi2 Stream Processors Memory: 12GB GDDR6 Power: 230 Watts, Standard graphics 8pin + 6pin auxiliary power Cooling: Active, Dual Axial fan
	Bus Type	PCI Express 4.0 x16
	Connectors	3DP 1.4 + HDMI 2.1 Outputs
	Maximum Resolution	DisplayPort [™] 1.4 with DSC: - up to 4x 5210 x 3200 x 24 bpp @ 60Hz, uncompressed - up to 7680 x 4320, compressed Display Outputs 3 DP + 1 HMDI
	Shading Architecture	Microsoft DirectX 12 Shader Model 6.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Feature Level 12_1 Vulkan 1.1 OpenCL 2.2
Available G	Available Graphics Drivers	Windows 11 Linux® 64-bit (selected distributions) Typically, latest drivers will be available from amd.com
	not have formal profession development, real-time en Consumer graphic cards ar	or Consumer graphics card, and not a Professional graphics card. As such, it does al application validation, but is intended per AMD to function properly for game gine, and many prosumer application workloads. Customers using Prosumer or e likely to experience higher acoustics in comparison with Professional graphic observed with non-professional graphics is expected, as HP Workstations' l in this area.

Technical Specifications - Optical and Removable Storage

HP 9.5mm Slim DVD	Description	9.5mm height, tray-load		
Writer	Mounting Orientation	Either horizontal or vertica	1	
	Interface Type	SATA/ATAPI	ι ι	
	Dimensions (WxHxD)	128 x 9.5 x 127mm		
	Supported Media Types	DVD+R DVD+R DL DVD-R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW		
	Disc Capacity	DVD-ROM	8.5 GB DL or 4.7 GB standard	
	Access Times	Full Stroke DVD	< 200 ms (seek)	
		Full Stroke CD	< 200 ms (seek)	
	Maximum Data Transfer Rates	CD ROM Read	CD-ROM, CD-R Up to 24X CD-RW Up to 24X	
		DVD ROM Read	DVD+RW Up to 8X DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD-ROM DL Up to 8X DVD-R Up to 8X	
	Power	Source	SATA DC power receptacle	
		DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p	
		DC Current	5 VDC -< 800 mA typical, <1600 mA maximum	
	Operating Environmental	Temperature	41° to 122° F (5° to 50° C)	
	(all conditions non-	Relative Humidity	10% to 80%	
	condensing)	Maximum Wet Bulb Temperature	84° F (29° C)	
	Operating Systems Supported	Windows 11, Windows 10, Windows 7 Professional 64-bit, Windows Vista Business 64*, Windows 2000. Linux®.		
	Kit Contents	HP SATA DVD Writer drive, installation guide.		
	Approvals	USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport Specification Rev. 1.0, Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE, BSMI, C-Tick, VCCI, MIC, cUL, TUVT		
	NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.			

Technical Specifications - Optical and Removable Storage

HP 9.5mm Slim DVD-ROM Drive	Description Mounting Orientation Interface Type Dimensions (WxHxD) Disc Capacity	9.5mm height, tray-load Either horizontal or vertical SATA / ATAPI 128 x 9.5 x 127mm DVD-ROM	l Single layer: Up to 4.7 GB Double layer: Up to 8.5 GB
	Access Times	DVD-ROM Single Layer	< 110 ms (typical)
		CD-ROM Mode 1	< 110 ms (typical)
		Full Stroke DVD	< 230 ms (typical)
		Full Stroke CD	< 220 ms (typical)
	Power	Source	SATA DC power receptacle
		DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p
		DC Current	5 VDC - <800mA typical, < 1600 mA maximum
(all condi	Operating Environmental	Temperature	41° to 122° F (5° to 50° C)
	(all conditions non-	Relative Humidity	10% to 80%
	condensing)	Maximum Wet Bulb Temperature	84° F (29° C)
	Operating Systems Supported	Windows 11, Windows 10, V	Windows 7 Professional 64-bit,
		Windows Vista Business 64 Linux®.	*, Windows 2000.
	Kit Contents	9.5mm Slim DVD-ROM Drive	e, slim SATA data/power cable, installation guide
,	Approvals	Specification Rev. 1.0,	ith USB Mass Storage Class Bulk only Transport I/O Connectivity Design Guide V. 1.3, FCC, CE, , TUVT
	commercially available DV storage of your original material	/D movies or other copyright aterial and other lawful uses er, double-layer discs burned	AM (DVD Writer). Does not permit copying of protected materials. Intended for creation and . Double Layer discs can store more data than with this drive may not be compatible with many

Technical Specifications - Networking and Communications

	_		
Integrated Intel® I219LM	Connector	RJ-45	
PCIe GbE Controller (Intel®	Cabling	Twisted pair up to 100m	
vPro [®] with Intel [®] AMT 16.0 ¹)	Controller	Intel® I219LM GbE platform LAN connect networking controller	
10.0 /	Memory	3 KB Tx and 3KB Rx FIFO packet buffer memory	
	Data Rates Supported	10/100/1000 Mbps	
	Compliance	802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u, 802.3z	
	Bus Architecture	PCI Express and SMBus	
	Data Transfer Mode	PCIe-based interface for active state operation (S0 state) and SMBus for host and management traffic (Sx low power state)	
	Power Requirement	Requires 3.3V (integrated regulators for core Vdc)	
	Boot ROM Support	Yes	
	Network Transfer Mode	Full-duplex; Half-duplex	
	Network Transfer Rate	10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps	
	Management Capabilities	vPro®, WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, ACPI, Advanced cable diagnostic, loopback modes, AMT 16.0 support, Circuit Breaker, VLAN, Multicast Listener Discovery (MLD)	
	network hardware and soft based VPN, when connectin dependent upon hardware,	nd a system with a corporate network connection, an Intel® AMT enabled chipset, and d software. For notebooks, Intel AMT may be unavailable or limited over a host OS- necting wirelessly, on battery power, sleeping, hibernating, or powered off. Results ware, setup, and configuration. For more information, visit: n/content/www/us/en/architecture-and-technology/intel-active-management-	

HP 1-Port 1GbE Flex IO NIC	Connector	RJ-45
	Cabling	1GbE over Category 5e (or better) up to 100m
	Controller	Realtek RTL8153
	Data Rates Supported	10/100/1000 Mbps
	Compliance	802.3 (LAN) 802.3u (100BASE-TX) 802.3ab (1000BASE-T) 802.3x (Ethernet Flow Control) 802.1Q (Virtual LAN) 802.3az (Energy Efficient Ethernet)
	Bus Architecture	USB
	Power Requirement	Requires 3.3V (integrated regulators for core Vdc)
	Boot ROM Support	Yes
	Network Transfer Mode	Full-duplex; Half-duplex
	Network Transfer Rate	10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps
	Operating Temperature	32° to 131° F (0° to 55° C)
	Dimensions (HxW)	1.5 in x 1.5 in. x 0.75 in (3.81 cm x 3.81 cm x 1.9 cm)

Technical Specifications - Networking and Communications

	Operating System Driver Support	Windows 11 64-bit Windows 10 64-bit Linux®				
Intel® X550-T2 2-Port	Connector	Dual-port RJ-45				
10GbE NIC	Cabling	10GbE: Cat6a (or better) up to 100m 5GbE and below: Cat5e (or better) up to 100m				
	Controller	Intel [®] Ethernet Controller X550				
	Network Transfer Rates Supported	10GbE, 5GbE, 2.5GbE, 1GbE, 100MbE				
	Data Path Width	PCIe Gen3x4				
	Power Requirement	11.2W (typical) 13.0 (Maximum)				
	Operating Temperature	32° to 131° F (0° to 55° C)				
	Dimensions (H×W)	5.1 x 2.7 in (without brackets)				
	Operating System Driver Support	Windows 11 64-Bit Windows 10 64-bit Linux®				
	Kit Contents	 Intel® X550-T2 2-Port 10GbE NIC with standard height bracket attached Low-profile bracket Product Literature 				
Intel® 1350-T4 4-Port 1GbE	Connector	4 RJ-45				
NIC	Cabling	Cat5e (or better) up to 100m				
	Controller	Intel® Ethernet I350 Controller				
	Network Transfer Rates Supported	1GbE, 100MbE, 10MbE				
	Data Path Width	PCIe Gen2.1x4				
	Power Requirement	5W (typical)				
	Operating Temperature	32° to 131° F (0° to 55° C)				
	Dimensions (HxW)	2.75 x 5.5 inches (without brackets)				
	Operating System Driver Support	Windows 11 Windows 10 Linux®				
	Kit Contents	 Intel® I350-T4 4-Port 1GbE NIC with standard height bracket attached Low-profile bracket Product Literature 				

Technical Specifications - Networking and Communications

	j							
HP Flex 1GbE Fiber LC	Connector	Fiber						
Single Port	Cabling	1GbE over Category OM1 (or better) up to 100m						
	Controller	Microchip LAN7801						
	Data Rates Supported	100/1000 Mbps IEEE 802.1p priority encoding/tagging (QoS, CoS) IEEE 802.1q VLAN tagging IEEE 802.3x flow control USB Requires 3.3V (integrated regulators for core Vdc) Yes						
	Compliance							
	Bus Architecture							
	Power Requirement							
	Boot ROM Support							
	Network Transfer Mode	Full-duplex; Half-duplex						
	Network Transfer Rate	100BASE-X (half-duplex) 100 Mbps 1000BASE-X (half-duplex) 1000 Mbps 1000BASE-X (full-duplex) 2000 Mbps						
	Operating Temperature	32° to 158° F (0°C to 70°C)						
	calvin	1.5 in x 1.7 in. x 0.75 in (3.84 cm x 4.3 cm x 1.9 cm)						
	Operating System Driver Support	Windows 11 64-Bit Windows 10 64-bit Linux®						
Intel® I225-T1 1-Port	Connector	RJ-45						
2.5GbE NIC	Cabling	Cat5e (or better) up to 85m						
	Controller	Intel® Ethernet 1225 Controller						
	Network Transfer Rates Supported	2.5GbE, 1GbE, 100MbE, 10MbE						
	Data Path Width	PCIe Gen3.1x1						
	Power Requirement	1.9W (typical)						
	Operating Temperature	32° to 158° F (0°C to 70°C)						
	Dimensions (HxW)	2.7 in x 2.57 in. (68.7mm x 65.3mm)						
	Operating System Driver	Windows 11 64-Bit Windows 10 64-bit Linux®						
	Kit Contents	 Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracket attached 						

Low-profile bracketProduct Literature

Technical Specifications - Networking and Communications

•	5						
Intel® Wi-Fi 6E* AX211 802.11ax, BT 5.2, M.2 With Internal Antenna	WLAN Standards	802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support - Wi-Fi 6E					
	Antenna	2x2 Dual-Band (internal)					
	Bluetooth Standards	5.2					
	Operating Temperature	32° to 176° F (0° to 80° C)					
	Interface	M.2 CNVio2					
	Dimensions	M.2 2230					
	Kit Contents	Not Available					
	NOTE: The AX211 with inte	ernal antenna only support WIFI 6					
	*Wi-Fi 6E requires a Wi-Fi	6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in					
Intel® Wi-Fi 6E* AX211 802.11ax, BT 5.2, M.2 With External Antenna	WLAN Standards	802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support - Wi-Fi 6E					
	Antenna	2x2 Dual-Band (External)					
	Bluetooth Standards	5.2					
	Operating Temperature	32° to 176° F (0° to 80° C)					
	Interface	M.2 CNVio2					
	Dimensions	M.2 2230					
	Kit Contents	ANTENNA, External, Dipole, WLAN, WIFI 6E					
	*Wi-Fi 6E requires a Wi-Fi	ernal antenna support WIFI 6E 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in					

Summary of Changes

Date of change:	Version History:		Description of change:
March 8, 2022	From v1 to v2	Changed	Format
March 16, 2022	From v2 to v3	Changed	Social and Environmental Responsibility section
May 6, 2022	From v3 to v4	Changed	Processors, Graphics, Networking and Communications sections
June 1, 2022	From v4 to v5	Changed	Operating Systems and SATA Hard Drives sections
June 15, 2022	From v5 to v6	Changed	Networking and Communications section
July 1, 2022	From v6 to v7	Changed	Graphics section
July 8, 2022	From v7 to v8	Changed	System Board section
August 1, 2022	From v8 to v9	Changed	SATA Hard Drives, Other Hardware sections
August 4, 2022	From v9 to v10	Changed	Format
September 1, 2022	From v10 to v11	Changed	Storage / Hard Drives, Graphics, Optical and Removable Storage
			Networking and Communications sections

title

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Overview

Important Note: Features and Supported Configurations will differ between the Z4 G4 Workstations with Intel® Xeon®W Processors and the Z4 G4 Workstation with Intel® CoreTM X Processors. Where different - features are shown side by side. Supported configurations are indicated by the CPU Support references.

HP Z4 G4 Workstation



Front view

1. Front I/O module options

- Premium (optional): power button, 2 USB 3.1 G1 Type-A, 2 USB 3.1 G2 Type-CTM, Headset audio, SD Card Reader (optional) (Left-most Type-A port has charging capability)
- Standard (shown here): power button, 4 USB 3.1 G1 Type-A (left-most Type-A port has charging capability), Headset audio, SD Card Reader (optional)
- 2. Front handle
- 3. 2 x 5.25"? external drive bays

Overview





Internal view

4.

5.

6.

7.

8.

PSU:

x4, 1 PCIe G3 x8

1 PCIe G3 x4 M.2 for SSDs

Adapters

Intel[®] CoreTM X-series Processors

Core i9-X configs/Core i7 9800X: 2 PCIe G3 x16, 2 PCIe G3

Other Core i7-X configs: 1 PCIe G3 x16, 1 PCIe G3 x16 (x8 electrical), 2 PCIe G3 x4, 1 PCIe G3 x8 (mechanical only)

1000W 90% efficient with up to 4 graphics power

8 DIMM slots: DDR4-2666 Non-ECC Unbuffered RAM

Intel[®] Core TM i7-X-series processors

Intel[®] Core [™] i9-X Series processors Intel[®] Core [™] i9 Extreme Edition processor

Intel[®] Xeon® W Processors

- 4. Intel[®] Xeon[®] Processors: W-2100 family
- 5. 2 PCIe G3 x16, 2 PCIe G3 x4, 1 PCIe G3 x8
- 6. 2 PCIe G3 x4 M.2 for SSDs
- 7. 8 DIMM slots; DDR4-2666 ECC Registered RAM
- 8. PSU options:
 - 465W 90% efficient with 0 graphics power adapters
 - 750W 90% efficient with 2 graphics power adapters
 - 1000W 90% efficient with up to 4 graphics power
 Adapters

Adaj

9.	2 x 5.25"? external drive bays
10.	2 x 2.5"?/3.5"? internal drive bays
11.	Front card guide and fan (select configurations)
12.	6 x 6Gb/s SATA ports

Overview

		Rear view
	Intel [®] Xeon® W Processors	Intel [®] Core [™] X-series Processors
13.		Rear power button
14.		Rear handle
15.		Padlock loop
16.		Kensington lock slot
17.	Rear I/O (top to bottom):	17. Rear I/O (top to bottom):
-	Audio in/out,	- Audio in/out,
-	Keyboard/Mouse PS/2	- Keyboard/Mouse PS/2
-	USB: 6 USB 3.1 G1 Type-A	USB: 5 USB 3.1 G1 Type-A
-	2x 1GbE ports	- 1x 1GbE port
18.		Side panel barrel keylock (optional)

Supported Components

HP Z4 G4 Workstation

Overview

Form Factor Operating Systems

Minitower

Intel® Xeon® W Processors

- Preinstalled:
 - Windows 11 Pro for Workstations**
 - Windows 10 Pro for Workstations*,**
 - Ubuntu 20.04 LTS
 - HP Linux-ready (minimal OS ready for customer OS installation)
 - Red Hat[®] Enterprise Linux[®] Desktop Workstation (Paper license with 1-year support; no preinstalled OS)

Tested and Documented:

- Red Hat[®] Enterprise Linux[®] Workstation 6, 7, 8
- SUSE Linux[®] Enterprise Desktop 12, 15
- Ubuntu 16.04, 18.04, 20.04 LTS

Notes: For detailed Linux[®] OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

Intel[®] CoreTM X-series Processors Preinstalled:

- Windows 11 Pro**
- Windows 10 Pro*,**
- HP Linux-ready (minimal OS ready for customer OS installation)
- Red Hat[®] Enterprise Linux[®] Desktop Workstation (Paper license with 1-year support; no preinstalled OS)

Tested and Documented:

- Red Hat[®] Enterprise Linux[®] Workstation 6, 7, 8
- SUSE Linux[®] Enterprise Desktop 12, 15
- Ubuntu 16.04, 18.04, 20.04 LTS

* Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

**Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

*Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for updates.

Note: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel[®] and AMD 7th Generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com

Available Processors

Supported Components

Name	Cores	Clock Speed (GHz)	Cache (MB)	-	ECC memory support	Max memory support	Hyper- Threadin g	Featuring Intel® vPro™ Technolog y	Intel® Turbo Boost Technology 2.0 (GHz) ¹	Intel® Turbo Boost Max Technology 3.0 (GHz) ²	TDP (W)
	··			In	itel® Xeo	n® W Pro	cessors				
Intel® Xeon® W-2295 processor	18	3.0	24.75	2933	YES	512GB	YES	YES	3.8, 4.6	4.8	168
Intel® Xeon® W-2275 processor	14	3.3	19.25	2933	YES	512GB	YES	YES	4.1, 4.6	4.8	165
Intel® Xeon® W-2265 processor	12	3.5	19.25	2933	YES	512GB	YES	YES	4.3, 4.6	4.8	165
Intel® Xeon® W-2255 processor	10	3.7	19.25	2933	YES	512GB	YES	YES	4.3, 4.5	4.7	165
Intel® Xeon® W-2245 processor	8	3.9	16.5	2933	YES	512GB	YES	YES	4.5, 4.5	4.7	155
Intel® Xeon® W-2235 processor	6	3.8	8.25	2933	YES	512GB	YES	YES	4.3, 4.6	N/A	130
Intel® Xeon® W-2225 processor	4	4.1	8.25	2933	YES	512GB	YES	YES	4.5, 4.6	N/A	105
Intel® Xeon® W-2223 processor	4	3.6	8.25	2666	YES	512GB	YES	YES	3.7, 3.9	N/A	120
				Intel®	© Core™	X-Series I	Processor	5			
Intel® Core [™] i9- 10980XE Extreme Edition processor	18	3.0	24.75	2933	NO	256GB	YES	NO	3.8, 4.6	4.8	165
Intel® Core [™] i9- 10940X X-series processor	14	3.3	19.25	2933	NO	256GB	YES	NO	4.1, 4.6	4.8	165
Intel® Core [™] i9- 10920X X-series processor	12	3.5	19.25	2933	NO	256GB	YES	NO	4.3, 4.6	4.8	165
Intel® Core™ i9- 10900X X-series processor	10	3.7	19.25	2933	NO	256GB	YES	NO	4.3, 4.5	4.7	165
	maxim For Int frequer ² Intel T increas Turbo	um turb el® Core ncy. Furbo Bo sed perfe Boost M	o freque e TM pro post Ma prmanc lax Tec	ency, du ocessors ax Techn re on tho hnology	al core n , the spe ology 3.0 se cores 3.0 frequ) identifies by taking uency is th	turbo frequ s shown in s the best p advantage ne clock fre	this column this column performing c e of power a equency of t	refer to dual ore(s) on a pr nd thermal he	t the following core maximur rocessor and p adroom. Intel	m turbo provides ®

Available ProcessorsDisclaimersMulticore is designed to improve performance of certain software products. Not all customers or
software applications will necessarily benefit from use of this technology. Performance and clock
frequency will vary depending on application workload and your hardware and software configurations.
Intel's numbering, branding and/or naming is not a measurement of higher performance.ColorBlackConvertibilityNoExpansion Slots (see
system board section for
Slot 0: Mechanical-only, for use with devices that require only rear bulkhead mounting

Supported Compone	nts					
more details)	Slot 1: PCI Express Gen3 x16 (from CPU)					
	Slot 2: PCI Express Gen3 x4 (from PCH) with open-	ended connector*				
	Slot 3:	Slot 3:				
	PCI Express Gen3 x16 (from CPU)	Core i9-X and Core i7-9800X configs: PCI Express Gen3 x16 (from CPU)				
		Other Core i7-X configs: PCI Express Gen3 x16(mechanical) x8(electrical) (from CPU)				
	Slot 4: PCI Express Gen3 x4 (from PCH) with open-	ended connector*				
	Slot 5:	Slot 5:				
	PCI Express Gen3 x8 (from CPU) with open-ended connector*	 Core i9-X and Core i7-9800X configs: PCI Express Gen3 x8 (from CPU) with open-ended connector* 				
		 Other Core i7-X configs: PCI Express Gen3 x8 (mechanical-only, no data) with open-ended connector* 				
	M.2 Slot 1: M.2 PCIe Gen 3 x4 (from CPU) up to 80	-				
	M.2 Slot 2: M.2 PCIe Gen 3 x4 (from CPU) up to 80mm storage	M.2 Slot 2:				
	devices	ישי איט צווע אוגב נטווופננטר/גוטג available				
	* Open-ended connector allows a greater bandwid lower bandwidth connector/slot.	dth (e.g. x16) card to be installed physically into a				
Expansion Bays (see storage section for more details)	 2 internal 3.5"? bays (with acoustic dampening dr available. 2 external 5.25" bays 3rd and 4th 3.5" HDD each occupy one external of the structure of	rnal bay				
Front I/O	 Base: Power button with power/fault Type A (1 charging, provides 1.5A at 	LED, 1 Headset audio port, 4 USB 3.1 G1				
	 Premium (optional): Power button wi 	th power/fault LED, Drive activity LED, 1 /pe-A (1 charging, provides 1.5A at 5V), 2				
Internal I/O	1 USB 3.1 G1 single-port header, 1 USB 2.0 single-	port header and 1 USB 2.0 dual-port header				
Rear I/O	Intel® Xeon® W Processor Family 6x USB 3.1 G1 Type-A* 2x 1GbE LAN ports (1x supporting Intel AMT)	Intel® Core TM X- Series Processor Family 5x USB 3.1 G1 Type-A 1x 1GbE LAN ports				
	Audio: 1 Line out, 1 Line in (Line in can be retasked port, 1 Rear power button Optional: 1 serial port (cable up to rear bulkhead),	d as microphone), 1 PS/2 mouse port, 1 PS/2 keyboard 2 Thunderbolt 3**				
	*All rear I/O motherboard USB-A ports are 0.9A at **HP's add-in Thunderbolt card provides two USB					
Interfaces Supported	SD card reader (optional) 6-channel SATA interface (6 @ 6.0 Gb/s) 6 channels are eSATA configurable for use with e Thunderbolt 3 (optional) USB 2.0, USB 3.1 G1 (aka USB 3.0), USB 3.1 G2 (opt	SATA CTO/AMO Kit (No hot plug / hot swap supported) ional)				
On-board RAID Support	SATA RAID 0 Striped Array Configuration SATA RAID 1 Mirrored Array Configuration SATA RAID 5 Striped/Parity Configuration SATA RAID 10 Striped/Mirrored Configuration					

Supported Components

Chassis Dimensions (H x W x D)	H: 15.2" (3 W: 6.65" (1 D: 17.5" (4	169mm)					
Packaged Dimensions	H: 22.5" (5 W: 12.4" (3 D: 22.2" (5	314mm)					
Palletization Profile		6 units x 3 layers = 18 units per pallet 1200x1000x1836mm (pallet included)					
Rack Dimensions	4U						
Weight	Minimum: Standard: Maximum:	ghts depend upon configuration (System weight only). 10.2 kg (22.4 lbs.) 11.3 kg (24.9 lbs.) 17.3 kg (38.2 lbs.)					
Temperature	Operating Above 152 every 305 Maximum	ating: -40° to 60° C (-40° to 140° F) : 5° to 35° C (40° to 95° F) 24 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for m (1,000 feet) increase in elevation rate of change: 10 °C/hr sustained sunlight					
Humidity		: 10% to 85% relative humidity, non-condensing, 35° C maximum wet bulb ating: 10% to 90% relative humidity, non-condensing, 35° C maximum wet bulb					
Maximum Altitude (non- pressurized)	Operating Non-opera	(with Rotational Hard Drives): 3,048 m (10,000 feet) (with only Solid-State Drives): 5,000 m (16,404 feet) ating: 12,192 m (40,000 feet) operating temperature is reduced as altitude increases. See Temperature for details.					
Power Supply	Processoi Support	r					
	xw	ENTRY 465 watts wide-ranging, active Power Factor Correction, 90% Efficient, with no 6-pin graphics power cables. The Z4 G4 465W power supply efficiency report can be found at this link: https://plugloadsolutions.com/psu_reports/HP%20INC_DPS-465AB- 3%20A_465W_ECOS%204939_Report.pdf MD_RANGE 750 watts wide-ranging, active Power Factor Correction, 90% Efficient, with 2x 6-pin graphics power cables. The Z4 G4 750W power supply efficiency report can be found at this link: https://plugloadsolutions.com/psu_reports/HP%20INC_DPS-750AB- 36%20A_750W_ECOS%204938_Report.pdf					
	XW, CX (i9)	1000 watts wide-ranging, active Power Factor Correction, 90% Efficient. Includes 4x 6+2-pin graphics power cables: also includes a Front Fan and Card Guide kit to enable support for dual high end graphics solutions.					
	CX (i7)	1000 watts wide-ranging, active Power Factor Correction, 90% Efficient. Includes 2x 6+2-pin graphics power cables.					
		The Z4 G4 1000W power supply efficiency report can be found at this link: https://plugloadsolutions.com/psu_reports/HP_D15- 1K0P1A_1000W_ECOS%204838_Report.pdf NOTE: 1000 W internal power supply, up to 90% efficiency, active PFC available the first half of 2018 NOTE: All power cords supplied by HP for Desktop Workstations are between 1.83m and					
		2.5m (dependent on country localization and platform).					

Supported Components

Workstation ISV Certifications See the latest list of certifications at http://www8.hp.com/us/en/campaigns/workstations/industries-and-partners.html

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® W-Series CPU				
	Intel® Xeon® W-2295 3.0 2933 18C CPU	Y	Ν		
	Intel® Xeon® W-2275 3.3 2933 14C CPU	Y	Ν		
	Intel® Xeon® W-2265 3.5 2933 12C CPU	Y	Ν		
	Intel® Xeon® W-2255 3.7 2933 10C CPU	Y	Ν		
	Intel® Xeon® W-2245 3.9 2933 8C CPU	Y	Ν		
	Intel® Xeon® W-2235 3.8 2933 6C CPU	Y	Ν		
	Intel® Xeon® W-2225 4.1 2933 4C CPU	Y	Ν		
	Intel® Xeon® W-2223 3.6 2933 4C CPU	Y	Ν		
	Intel® Xeon® W-2145 3.7 2666 8C CPU	Y	Ν		
	Intel® Xeon® W-2133 3.6 2666 6C CPU	Y	Ν		
	Intel® Core [™] X-Series CPU				
	Intel® Core [™] i9-10980XE 3.0 2933 18C CPU	Y	Ν		
	Intel® Core [™] i9-10940X 3.3 2933 14C CPU	Y	Ν		
	Intel® Core [™] i9-10920X 3.5 293312C CPU	Y	Ν		
	Intel® Core [™] i9-10900X 3.7 2933 10C CPU	Y	Ν		
	Intel® Core TM i7-9800X 3.8 2666 8C CPU	Y	Ν		

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Monitors /				Option Kit	
Displays		Processor Supports	Factory Configured Option Kit	Part Number	Support Notes
	HP Z Display Z22n G2	XW, CX	Y	1JS05AA	
	HP Z Display Z23n G2	XW, CX	Y	1JS06AA	
	HP Z Display Z24i G2	XW, CX	Y	1JS08AA	
	HP Z Display Z24n G2	XW, CX	Y	1JS09AA	
	HP Z Display Z24nf G2	XW, CX	Y	1JS07AA	
	HP Z Display Z27n G2	XW, CX	Y	1JS10AA	
	HP Z Display Z27s (4K display)	XW, CX	Y	J3G07AA	
	Supported by all operating systems an Screen size measured diagonally	vailable from HP			

Storage / Hard Drives*

Option

SAS Hard Drives

	SAS Hard Drives for HP Workstations	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	
	HP 300GB 15k SAS SFF	XW	Y	Y	L5B74AA		
NOTE: Only available on Xeon W configs SAS controller add-in card required							

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity may be less. Up to 32GB (for Windows 10) is reserved for system recovery software.

SATA Hard Drives

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
SATA (Serial ATA) Hard Drives for HP Workstations					
500GB SATA 7200RPM 6Gb/s 3.5"? HDD	XW, CX	Y	Y	LQ036AA	
500GB SATA 7200RPM 6Gb/s OPAL2 SFF 3.5"? HDD	XW, CX	Y	Y	D8N29AA	
1TB SATA 7200RPM 3.5"? HDD	XW, CX	Y	Y	LQ037AA	
1TB SATA 7200RPM Ent 3.5"? HDD	XW, CX	Y	Y	WOR10AA	
2TB SATA 7200RPM 3.5"? CMR HDD	XW, CX	Y	Y	QB576AA	
2TB SATA 7200RPM 3.5"? SMR HDD	XW, CX	Y	Y	8VE04AA/AT	
2TB 7200RPM SATA 3.5in Enterprise		Y	Y	2Z274AA	
4TB SATA 7200RPM Ent 3.5"? HDD	XW, CX	Y	Y	K4T76AA	
6TB SATA 7200RPM Ent 3.3"? HDD	XW, CX	Y	Y	3DH90AA	
8TB 7200RPM SATA 3.5in Enterprise		Y	Y	2Z273AA	
NOTE: Up to (4) 3.5-inch 7200 rpm SATA drives	: 32 TB max t	otal (4x 8TB)			

SATA Solid State Drives

	••••••						
	Processor Supports	Factory Configured	Option Kit	Kit Part Number	Support Notes		
HP Solid State Drives (SSDs) for Workstations							
HP 256GB SATA SSD	XW, CX	Y	Y	A3D26AA/AT			
HP 512GB SATA SSD	XW, CX	Y	Y	D8F30AA			
HP 1TB SATA SSD	XW, CX	Y	Y	F3C96AA/AT			
HP 2TB SATA SSD	XW, CX	Y	Y	Y6P08AA/AT			
HP 256GB SATA SED OPAL2 SSD	XW, CX	Y	Y	G7U67AA			
HP 512GB SATA SED OPAL2 SSD	XW, CX	Y	Y	N8T26AA			
HP 240GB SATA Enterprise SSD	XW, CX	Y	Y	T3U07AA			
HP 480GB SATA Enterprise SSD	XW, CX	Y	Y	T3U08AA			
HP 960GB 2.5in Enterprise SATA-3 SSD		Y	Y	1W6P8AA			
1920GB 2.5in Enterprise SATA-3 SSD		Y	Y	1W6P9AA			

PCIe Solid State					Option	
Drives		Processor	Factory	Option	Kit Part	Support
		Supports	Configured	Kit	Number	Notes
	PCIe SSDs for HP Workstations					

Supported Components

-					
HP Z Turbo Drive 256GB MLC Z4/Z6 G4 SSD Kit	XW, CX	Ν	Ν	EOL	
HP Z Turbo Drive 512GB MLC Z4/Z6 G4 SSD Kit	XW, CX	Ν	Ν	EOL	
HP Z Turbo Drive 1TB MLC Z4/Z6 G4 SSD Kit	XW, CX	Ν	Ν	EOL	
HP Z Turbo Drive 256GB TLC Z4/Z6 G4 SSD Kit	XW, CX	Y	Y	1PD59AA/AT	
HP Z Turbo Drive 512GB TLC Z4/Z6 G4 SSD Kit	XW, CX	Y	Y	1PD60AA	
HP Z Turbo Drive 1TB TLC Z4/Z6 G4 SSD Kit	XW, CX	Y	Y	1PD61AA	
HP Z Turbo Drive 2TB TLC Z4/Z6 G4 SSD Kit	XW, CX	Y	Y	ЗКРЗ9АА	
HP Z Turbo Drive 256GB Z4/Z6 G4 SED Kit	XW, CX	Y	Y	4YZ41AA	
HP Z Turbo Drive 512GB Z4/Z6 G4 SED Kit	XW, CX	Y	Y	4YZ44AA/AT	
HP Z Turbo Drive 1TB SED TLC Z4/Z6 G4 SSD Kit	XW, CX	Y	Y	6YT76AA	
HP Z Turbo Drive 1TB SED TLC Z4/Z6 G4 SSD Module	XW, CX	Y	Y	6YT79AA	2
HP Z Turbo 2TB SED OPAL2 TLC M.2 Z4/Z6 SSD	XW, CX	Y	Y	2Y7W6AA	
HP 256GB M.2 2280 PCIe NVMe TLC SSD Z2/Z4/Z6 Kit	XW, CX	Y	Y	8PE68AA	
HP 512GB M.2 2280 PCIe NVMe TLC SSD Z2/Z4/Z6 Kit	XW, CX	Y	Y	8PE69AA	
HP 1TB M.2 2280 PCIe NVMe TLC SSD Z2/Z4/Z6 Kit	XW, CX	Y	Y	8PE70AA	
HP 256GB M.2 2280 PCIe NVMe TLC SSD Module	XW, CX	Ν	Y	8PE62AA	2
HP 512GB M.2 2280 PCIe NVMe TLC SSD Module	XW, CX	Ν	Y	8PE63AA	2
HP 1TB M.2 2280 PCIe NVMe TLC SSD Module	XW, CX	Ν	Y	8PE64AA	2
HP 2TB PCIe NVME TLC M.2 Z4/6 G4 SSD	XW, CX	Y	Y	35F74AA	
HP Z Turbo Drive Quad Pro					
HP Z Turbo Drive Quad Pro 2x256GB TLC PCIe® SSD	XW, CX (i9)	Y	Y	4YZ38AA	1,3
HP Z Turbo Drive Quad Pro 2x512GB TLC PCIe® SSD	XW, CX (i9)	Y	Y	4YZ39AA/AT	1,3
HP Z Turbo Drive Quad Pro 2x1TB TLC PCIe [®] SSD	XW, CX (i9)	Y	Y	4YZ40AA	1,3
HP Z Turbo Drive Quad Pro 2x2TB PCIe® SSD	XW, CX (i9	Y	Y	3KP42AA	
HP Z Turbo Drive Quad Pro 256GB TLC SSD module	XW, CX (i9)	Ν	Y	4YZ35AA	1, 2, 3
HP Z Turbo Drive Quad Pro 512GB TLC SSD module	XW, CX (i9)	Ν	Y	4YZ36AA/AT	1, 2, 3
HP Z Turbo Drive Quad Pro 1TB TLC SSD module	XW, CX (i9)	Ν	Y	4YZ37AA	1, 2, 3
HP Z Turbo Drive Quad Pro 2TB TLC SSD module	XW, CX (i9	Ν	Y	3KP43AA	2
HP Z Turbo Drive Dual Pro					
HP Z Turbo Drive Dual Pro 256GB TLC SSD		Y	Y	4YF60AA	
HP Z Turbo Drive Dual Pro 512GB TLC SSD		Y	Y	4YF61AA	
HP Z Turbo Drive Dual Pro 1TB TLC SSD		Y	Y	4YF62AA	
HP Z Turbo Drive Dual Pro 2TB TLC SSD		Y	Y	4YF63AA	
HP 256GB M.2 2280 PCIe NVMe TLC SSD Dual Pro Kit	XW, CX	Y	Y	8PE74AA	
HP 512GB M.2 2280 PCIe NVMe TLC SSD Dual Pro Kit	XW, CX	Y	Y	8PE75AA	
HP 1TB M.2 2280 PCIe NVMe TLC SSD Dual Pro Kit	XW, CX	Y	Y	8PE76AA	
Intel® 905p Series SSD (Opatane SSD)					
Intel [®] Optane SSD 905p 280GB AiC**		Y	Y	2SC47AA	
Intel® Optane SSD 905p 480GB AiC**		Y	Y	2SC48AA	
Intel® Optane SSD 905P 380GB M.2 PCIe Dual		Y	Y	6LA63AA	1
Intel® Optane SSD 905P 2x380GB M.2 PCIe Quad		Y	Y	6LA65AA	1
Intel® Optane SSD 905P 380GB M.2 SSD Module		Y	Y	6LA66AA	2, 3

Note 1: All HP Z Turbo Drive Quad Pro modules require the Z4 G4 Fan & Front Card Kit, available as CTO (1MY89AV) and AMO (1XM33AA)

Note 2: M.2 SSD module only, designed to be installed into the Z Turbo Drive Quad Pro or Dual Pro carrier **Note 3:** Z Turbo Drive Quad Pro is not supported on Core i7-X configurations ** PCIe card installed in standard PCIe x4 slot

Supported Components

	ntel® Virtual RAID on CPU (Intel VROC) for NVMe	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	
Ir	ntel® VROC NVMe SSD Standard Controller Module		Ν	Y	3FJ80AA	1,3	
Ir	ntel® VROC NVMe SSD Premium Controller Module		Ν	Y	3FJ81AA	2,3	

NOTE 1: Enables RAID 0, 1 & 10 **NOTE 2:** Enables RAID 0, 1 & 10 plus RAID 5 with write hole closure options. **NOTE 3:** Xeon processor required

Hard Drive Controllers		Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SAS Controller					
	MicroSemi SmartHBA2100-4i4e SAS Controller	XW	Y	Y	1FV90AA	
	NOTE: Only available on Xeon W configurations					

Graphics

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	Supported # of cards
Graphics Cable Adapters		-				
HP DisplayPort to HDMI Adapter	XW, CX	Y	Y	K2K92AA		
HP DisplayPort to Dual Link DVI Adapter	XW, CX	Y	Y	NR078AA		
HP DisplayPort to DVI-D Adapter	XW, CX	Y	Y	FH973AA		
HP DisplayPort to DVI-D Adapter (2-pack)	XW, CX	Y	Ν			
HP DisplayPort to DVI-D Adapter (4-pack)	XW, CX	Y	Ν			
HP DisplayPort to DVI-D Adapter (6-pack)	XW, CX	Y	Ν			
HP miniDP-to-DP Adapter	XW, CX	Y	Y	2MY05AA		
HP miniDP-to-DP Adapter (2-pack)	XW, CX	Y	Ν			
HP miniDP-to-DP Adapter (4-pack)	XW, CX	Y	Ν			
HP miniDP-to-DP Adapter (8-pack)	XW, CX	Y	Ν			
Graphics Card Connectors						
NVIDIA [®] SLI 2-slot Graphics Connector	XW, CX	Y	Y	2YY84AA		
Quadro [®] RTX NVLink 2-slot Bridge (RTX 5000)	XW, CX	Ν	Y	6FY12AA		
Quadro® RTX NVLink High-Bandwidth 2-slot Bridge (RTX 6000 & 8000)	^e XW, CX	Ν	Y	6FY11AA		
NVIDIA NVLink 2-Slot Bridge (RTX A6000, RTX A5000)		Ν	Y	340L2AA		2
Entry 3D						
NVIDIA [®] Quadro [®] P620 2GB Graphics	XW, CX	Y	Y	3ME25AA	4	2
NVIDIA [®] T400 2GB Graphics	XW, CX	Y	Y	340K8AA	4	2
NVIDIA [®] T400 4GB Graphics	XW, CX	Y	Y	5Z7E0AA/AT	4	2
NVIDIA [®] T600 4GB Graphics	XW, CX	Y	Y	340K9AA	4	2
Mid-range 3D						
NVIDIA [®] T1000 8GB Graphics	XW, CX	Y	Y	5Z7D8AA	3,4	2
NVIDIA [®] T1000 4GB Graphics	XW, CX	Y	Y	20X22AA	3,4	2
NVIDIA [®] Quadro [®] P1000 4GB Graphics	XW, CX	Y	Y	1ME01AA	3,4	2

Supported Components

NVIDIA [®] RTX A2000 6GB Graphics	XW, CX	Y	Y	340L0AA	3,4	2
NVIDIA [®] RTX A2000 12GB Graphics	XW, CX	Y	Y	5Z7D9AA	3,4	2
AMD Radeon TM Pro WX 3100 4GB Graphics	XW, CX	Y	Y	2TF08AA	3,4	2
AMD Radeon TM Pro WX 3200 4GB Graphics	XW, CX	Y	Y	6YT68AA	3,4	2
AMD Radeon [™] Pro WX 4100 4GB Graphics	XW, CX	Ν	Y	ZOB15AA	3,4	2
AMD Radeon TM Pro W6600 8GB Graphics	XW, CX	Y	Y	340K5AA	1,2	2
AMD Radeon TM RX 6700 XT 12GB Graphics	XW, CX	Y	Ν		2	
High-End 3D						
NVIDIA [®] Quadro [®] P4000 8GB Graphics	XW, CX	Y	Y	1ME40AA	1, 2, 5	2
NVIDIA [®] Quadro [®] RTX 4000 8GB Graphics	XW, CX	Y	Y	5JV89AA	1, 2	2
NVIDIA [®] RTX A4000 16GB 4DP Graphics	XW, CX	Y	Y	20X24AA/AT	1, 2	2
NVIDIA [®] RTX A4500 20GB Graphics	XW, CX	Y	Y	5S458AA/AT	1, 2, 5	2
AMD Radeon TM Pro W5500 8GB Graphics	XW, CX	Y	Y	9GC16AA	1, 2	2
AMD Radeon TM Pro W5700 8GB Graphics	XW, CX	Y	Y	9GC15AA/AT	1, 2, 5	2
AMD Radeon TM Pro W6800 32GB Graphics	XW, CX	Y	Y	340K7AA	1, 2, 5	2
AMD Radeon TM Pro WX 7100 8GB Graphics	XW, CX	Y	Y	ZOB14AA	1, 2	2
Ultra High-End 3D						
NVIDIA [®] Quadro [®] GP100 16GB Graphics	XW, CX	Ν		1ZE81AA	1, 2, 5	2
NVIDIA [®] Quadro [®] GV100 32GB Graphics	XW, CX	Y		3ME26AA	1, 2, 5	2
NVIDIA [®] Quadro [®] P5000 16GB Graphics	XW, CX	Y	Y	ZOB13AA	1, 2, 5	2
NVIDIA [®] Quadro [®] P6000 24GB Graphics	XW, CX	Y	Y	ZOB12AA	1, 2, 5	2
NVIDIA [®] Quadro [®] RTX 5000 16GB Graphics	XW, CX	Y	Y	5JH81AA	1, 2	2
NVIDIA [®] Quadro [®] RTX 6000 24GB Graphics	XW, CX	Y	Y	5JH80AA	1, 2	2
NVIDIA [®] Quadro [®] RTX 8000 48 GB Graphics	XW, CX	Y	Y	6NB51AA	1, 2	2
NVIDIA [®] RTX A5000 24 GB Graphics	XW, CX	Y	Y	20X23AA	1,2, 5	2
NVIDIA [®] RTX A6000 48GB Graphics	XW, CW	Y	Y	2S6U3AA	1,2, 5	2
AMD Radeon TM Pro WX 9100 16GB Graphics	XW, CX	Y		2TF01AA	1, 2	1
NVIDIA® Quadro® Sync II	XW, CX	Ν	Y	1WT20AA		

NOTE 1: Single graphics configuration requires the HP Z4 G4 Fan and Front Card Guide Kit, which is available both CTO (1MY89AV) and AMO (1XM33AA).

NOTE 2: Single graphics configuration requires the 750W chassis or 1000W chassis.

NOTE 3: Dual graphics configuration requires the HP Z4 G4 Fan and Front Card Guide Kit, which is available both CTO (1MY89AV) and AMO (1XM33AA).

NOTE 4: Dual graphics configuration requires the 750W chassis or 1000W chassis.

NOTE 5: Dual graphics configuration requires the 1000W chassis.

Supported Components

Memory	SL Processor	CL Processor	Processor Supports	Factory Configur ed	Option Kit	Option Kit Part Number	Suppo rt Notes
HP 8GB (1x8GB) DDR4-2666 ECC Reg RAM	Y	Ν	XW	Y	Y	1XD84AA/AT	1
16GB (1x16GB) DDR4-2666 ECC Reg RAM	Y	Ν	XW	Y	Y	1XD85AA/AT	1
32GB (1x32GB) DDR4-2666 ECC Reg RAM	Y	Ν	XW	Y	Y	1XD86AA/AT	1,2
HP 8GB (1x8GB) DDR4- 2933 ECC Reg RAM	Y	Y	XW	Y	Y	5YZ56AA /AT	1,3
16GB (1x16GB) DDR4- 2933 ECC Reg RAM	Ν	Y	XW	Y	Y	5YZ54AA/AT	1,3
32GB (1x32GB) DDR4- 2933 ECC Reg RAM	Ν	Y	XW	Y	Y	5YZ55AA / AT	1,2,3
64GB (1x64GB) DDR4- 2933 ECC Reg RAM	Ν	Y	XW	Y	Y	5YZ57AA / AT	1,3,4
HP 8GB (1x8GB) DDR4-2933 nECC RAM	Y	Y	СХ	Y	Y	7ZZ64AA /AT	1,3,5
HP 16GB (1x16GB) DDR4-2933 nECC RAM	Ν	Y	СХ	Y	Y	7ZZ65AA / AT	1,3,5
HP 32GB (1x32GB) DDR4-2933 nECC RAM	Ν	Y	СХ	Y	Y	7ZZ66AA/AT	1,3,4

SL Processor: Are processors formerly known as as Intel[®] Skylake that are sold under the model name Intel[®] Xeon[®] W-2100 Family or Intel[®] CoreTM i7X, CoreTM i9-7900X/XE, and CoreTM i9-9000X/XE family

CL Processor: Are processors formerly known as Cascade Lake that are in model name Intel[®] Xeon[®] W-2200 family or Intel[®] CoreTM i9-10900X/XE family

NOTES

1: ONLY DDR4 DIMMs are supported.

2: Memory configurations using Xeon Skylake (W-21xx) processors and 32GB Registered DIMMs require the HP Z4 Memory Cooling Solution, which is available both CTO (1MY90AV) and AMO (8TC68AA). Memory configurations using Xeon Cascade Lake and 32GB Registered DIMMs do not require the Memory Cooling Solution.

3: Intel[®] Core[™] i9-10900X/XE and Intel[®] Xeon[®] W-2200 family processors only support 2933 speed memory. **4:**

- 32GB nECC Memory is only available with Intel® CoreTM i9-10900X/XE family processors.
- 64GB Registered Memory is only available with Intel® Xeon® W-2200 family processors.

5: Discontinued Core i7X, Core i9-7900X/XE, and Core i9-9000X/XE family processors are only compatible with Memory Option Kit 7ZZ64AA/AT 8GB (1x8GB) DDR4 2933 NECC UDIMM Memory

Option Kit 7ZZ65AA/AT 16GB (1x16GB) DDR4 2933 NECC UDIMM Memory has transitioned to newer 16Gbit DRAM and is incompatible with these discontinued Core X processors.

NOTE: Factory-configured CTO (xxxxxAV) and aftermarket AMO (xxxxxAA, xxxxAT) HP memory part numbers designated as "2666"? may ship with "2933" or "3200" speed memory components. Similarly, HP Memory part numbers designated as "2933 may ship with "3200" speed memory. This does not affect HP part number availability, nor does it affect system performance or operation. All hardware configurations currently supporting HP memory part numbers designated as "2633 have been fully qualified to work with fast speed memory and are fully supported by HP under standard support terms.

Supported Components

Factory Configured System Memory Solutions	Available with Intel Xeon Processor & Registered Memory	Available with Intel Core X Processor & nECC Memory
8GB (1x8GB) DDR4	Yes	Yes
16GB (1x16GB) DDR4	Yes	Yes
16GB (2x8GB) DDR4	Yes	Yes
24GB (3x8GB) DDR4	Yes	Yes
32GB (2x16GB) DDR4	Yes	Yes
32GB (4x8GB) DDR4	Yes	Yes
64GB (2x32GB) DDR4	Yes	Yes (Note 1)
64GB (4x16GB) DDR4	Yes	Yes
64GB (8x8GB) DDR4	Yes	Yes
128GB (2x64GB) DDR4	Yes (Note 2)	No
128GB (4x32GB) DDR4	Yes	Yes (Note 1)
128GB (8x16GB) DDR4	Yes	Yes
192GB (6x32GB) DDR4	Yes	Yes (Note 1)
256GB (4x64GB) DDR4	Yes (Note 2)	No
256GB (8x32GB) DDR4	Yes	Yes (Note 1)
384GB (6x64GB) DDR4	Yes (Note 2)	No
512GB (8x64GB) DDR4	Yes (Note 2)	No

NOTE 1: 32GB nECC Memory Configurations are only available with Intel[®] CoreTM i9-10900X/XE family processors. **NOTE 2:** 64GB Registered Memory Configurations are only available with Intel[®] Xeon[®] W-2200 family processors.

Multimedia and Audio Devices

				Option Kit	
	Processor Supports	Factory Configured	Option Kit	Part Number	Support Notes
Integrated Realtek HD ALC221 Audio	XW, CX	Y	Ν		

Optical and Removable Storage

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP SlimTray Optical Drives					
HP 9.5mm Slim Blu Ray Disc Writer	XW, CX	Y	Y	K3R65AA	1
HP 9.5mm Slim DVD ROM	XW, CX	Y	Y	K3R63AA	1
HP 9.5mm Slim DVD Writer*	XW, CX	Y	Y	K3R64AA	1
HP HH DVD Writer (16x RW DVD-R)	XW, CX	Y	Y	4AR67AA	
HP SD Card Reader					
HP SD 4 Card Reader	XW, CX	Y	Y	2VK54AA	
NVMe Frame/Carrier					
HP QX310 Removable NVMe Frame/Carrier w/PCIe card	XW, CX	Y	Ν		
HP QX310 Removable Carrier only	XW, CX	Ν	Y	8GQ91AA/AT	2

NOTE 1: Installing an optical drive into Z4 G4 requires a 5.25"? external bay adapter (Option Kit Part number NQ099A).

NOTE 2: Only approved HP Z Turbo storage devices are supported.

*Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Networking and Communications

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Intel® i350-T2 PCIe Dual Port Gigabit NIC	XW, CX	Y	Y	V4A91AA	
Intel® i350-T4 PCIe 4-Port Gigabit NIC	XW, CX	Ν	Y	W8X25AA	
Intel® Ethernet I210-T1 PCIe x1 Gb NIC	XW, CX	Y	Y	E0X95AA	
Aquantia [®] AQN-108 Single-Port 5GbE NIC	XW, CX	Ν	Y	1PM63AA	
Intel [®] X550-T2 10GbE Dual Port NIC	XW, CX	Y	Y	1QL46AA	
Intel [®] X710-DA2 10GbE SFP+ Dual Port NIC	XW, CX	Y	Y	1QL47AA	1
HP 10GbE SFP+ SR Transceiver	XW, CX	Y	Y	C3N53AA	
Intel 8265 802.11 a/b/g/n/ac + BT PCIe WLAN	XW, CX	Ν	Y	1QL48AA	
Intel® Wi-Fi 6 AX200 & BT PCIe	XW, CX	Ν	Y	7CE01AA	
Intel AX210 Wi-Fi 6e non-vPro +Bluetooth 5.2 External Antenna WLAN	XW, CX	Ν	Y	340L7AA	
Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC		Y	Y	6E3Y9AA/AT	
Allied Telesis AT-2914SX/LC-901 1GB LC Fibe Note 1: Windows 7 is NOT supported	r NIC	Y	Y	1C7Q2AA	

Racking and Physical Security

Supported Components

				Option Kit	
	Processor Supports	Factory Configured	Option Kit	Part Number	Support Notes
HP Z4/Z6 Side Panel Barrel Keylock	XW, CX	Y	Ν		
HP Solenoid Lock / Hood Sensor	XW, CX	Y	Ν		
HP Z4/Z6 G4 Depth Adjustable Fixed Rail Rack	Kit XW, CX	Ν	Y	2HW42AA	
HP Z2 Mini/Z2 TWR/Z4/Z6 Depth Adj Rail Rak K	Kit		Y	2A8Y5AA	
HP Keyed Cable Lock 10mm	XW, CX	Ν	Y	T1A62AA	
HP Master Keyed Cable Lock 10mm	XW, CX	Ν	Y	T1A63AA	

Input Devices

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Wireless Business Slim Keyboard and Mouse	XW, CX	Y	Y	N3R88AA	
Business Slim PS/2 Wired Keyboard	XW, CX	Y	Y	N3R86AA	
USB Business Slim Wired Keyboard	XW, CX	Y	Y	N3R87AA	
USB Premium Wired Keyboard	XW, CX	Y	Y	Z9N40AA/AT	
USB Wired SmartCard CCID Keyboard	XW, CX	Y	Y	E6D77AA	
HP Optical USB Mouse	XW, CX	Y	Y	QY777AA/AT	
HP PS/2 Mouse	XW, CX	Y	Y	QY775AA/AT	
HP USB Hardened Mouse	XW, CX	Y	Y	P1N77AA/AT	
HP Creator 935 Black Wireless Mouse	XW, CX	Ν	Y	1DOK8AA	
HP Wired 320M Mouse	XW, CX	Y	Y	9VA80AA	

Other Hardware

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP ENERGY STAR [®] Certified Configuration	XW, CX	Y			
HP Z Premium Front I/O 2xUSB-A 2xUSB-C	XW, CX	Y	Y	1XM32AA	
HP Thunderbolt 3 PCIe 2 Port I/O Card	XW, CX	Y	Y	3UU05AA	
HP Z4 G4 Memory Cooling Solution	XW, CX	Y	Y	8TC68AA	Note 1
HP Z4 G4 Fan and Front Card Guide Kit	XW, CX	Y	Y	1XM33AA	Note 2
HP Internal USB Port Kit	XW, CX	Ν	Y	EM165AA	Note 3
HP eSATA 2 port PCIe Bulkhead Kit	XW, CX	Y	Y	GM110AA	
HP Serial Port Adapter	XW, CX	Y	Y	PA716A	
HP Workstation Mouse Pad	XW, CX	Y			

Note 1: The HP Z4 G4 Memory Cooling Solution is available to add to any configuration for improved system cooling, but is required for memory configurations using Xeon Processors and 32GB Registered DIMMs.

Note 2: Fan and Front Card Guide required with the following components:

- Specific graphics configurations (see Graphics section above)

- Any HP Z Turbo Quad Pro configuration

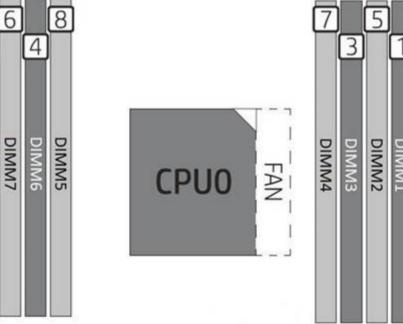
Note 3: The HP Internal USB Port kit has a single USB 2.0 type A connector.

Supported Components

Application Software		Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Juitware	Sobey Video Editing SW	XW, CX	Y	Ν		China only
	ZCentral Remote Boost	XW, CX	Ν	Ν		
	Data Science Stack	XW, CX	Y	Ν		1, 2
	WSL2/Ubuntu Data Science Stack	XW, CX	Y	Ν		1,3
	*Not all Application Software for Z Note 1: Only available with NVIDIA 7th generation processors. Note 2: Only available with Ubuntu Note 3: Only available with Window	graphics card 20.04 LTS pr	ds selections. reinstall.	Available o	on products equippe	

Operating Systems		Processor Supports	Support Notes
JYSLEIIIS	Windows 11 Pro for Workstations	XW	Note 1,5,6
	Windows 11 Pro	СХ	Note 5,6
	Windows 10 Pro for Workstations	XW	Note 1,4,5,6
	Windows 10 Pro	СХ	Note 4,5,6
	Ubuntu 20.04 LTS	XW	Note 2
	HP Linux [®] Ready	XW, CX	Note 2
	Red Hat® Enterprise Linux® (RHEL) Workstation - Paper License (1yr)	XW, CX	Note 2,3
	NOTE 1: Only applicable to Xeon W configurations.		
	NOTE 2: For detailed Linux [®] OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix		
	 NOTE 3: This second OS must be ordered with the HP Linux[®] Installer I NOTE 4: Device comes with Windows 10 and a free Windows 11 upgrade Windows 11. Upgrade timing may vary by device. Features and app are Certain features require specific hardware (see Windows 11 Specificate NOTE 5: Not all features are available in all editions or versions of Windows functionality. Windows is automatically updated and enable Microsoft account required. ISP fees may apply and additional required updates. See http://www.windows.com. NOTE 6: Available with Windows Subsystem for Linux[®] (WSL 2). 	de or may be vailability may ions). dows. System BIOS update t oled. High spec	preloaded with vary by region. s may require to take full advantage ed internet and

System Board System Board Form Factor Processor Socket	Main Syste 27.7 x 28 10.9 x 11. Single LGA	3.0 cm 0 inches
Chipset	Intel [®] Xeon [®] W Processor Family	Intel [®] Core TM X-series Processors
Cilipset	Intel [®] C422 Chipset	
Super 1/0 Controller	Nuvoton NPCD31	Intel [®] X299 chipset
Super I/O Controller		
Memory Expansion Slots	8 DDR4 mei	-
Memory Type Supported	DDR4, RDIMM (Registered), ECC	DDR4, UDIMM, non-ECC
Memory Modes	Channel Int	
Memory Speed	2933MT/s, 2666MT/s, 24	00MT/s, and 2133MT/s
Supported		
Memory Protection	ECC available on data, parity on address and command	N/A
Maximum Memory	Supports up to 512GB	Supports up to 256GB
Memory Configuration	Only Registered DIMMs are supported.	Only non-ECC unbuffered DIMMs are supported
(Supported)		
Memory Load Order		
	6 8	7 5



Note on Maximum Memory DIMM8

Maximum memory capacities assume 64-bit operating systems such as Windows 10 Pro.

For systems installed with Microsoft Windows 7 (Ultimate, Enterprise or Pro), the maximum accessible system memory is 192GB

PCI Express Connectors

Intel® Xeon® W Processor Family

Intel[®] CoreTM X-series Processors

Slot 1 (top): PCI Express Gen3 x16 supplied by CPU.

Slot 2 (PCH): PCI Express Gen3 x4 supplied by PCH with open-ended connector. **

System Technical Sp	ecifications	
	Slot 3:	Slot 3:
	PCI Express Gen3 x16 supplied by CPU	Core i9-X and Core i7-9800X configs: PCI Express Gen3 x16 supplied by CPU
		Core i7-X configs: PCI Express Gen3 x16 (mechanical)/ x8 (electrical)supplied by CPU
	Slot 4 (PCH): PCI Express Gen3 x4 sup	plied by PCH with open-ended connector**
	Slot 5:	Slot 5:
	PCI Express Gen3 x8 supplied by CPU with open-end	
	connector**	 Core i9-X and Core i7-9800X configs: PCI Express Gen3 x8 supplied by CPU with open-ended connector**
		 Other Core i7-X configs: PCI Express Gen3 x8 (mechanical-only, no data) with open-ended connector**
	NOTE: Slots 1 through 5 support fu	ll-height, full-length cards (with extender)
	•	ss Gen3 x4 supplied by CPU
		2260-D5-M, 2280-D5-M, 22110-D5-M
	M.2 Slot 2:	M.2 Slot 2:
	PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, H4.2, sizes 2260-D5-M, 2280-D5-M, 22110-D5-M	No 2nd M.2 connector/slot available
		idth (e.g. x16) card to be installed physically into a lower a connector/slot.
Supported Drive Interfaces		
SATA		oorts RAID 0,1, 5, and 10 A RAID is Microsoft Windows only
Serial Attached SCSI	Intel [®] Xeon [®] W Processor Family	Intel [®] Core TM X-series Processors
Jenat Actachea Jesi	Requires Optional PCIe card	not supported
Factory Configured RAID		
	 RAID 1 mirrored array 	
	 RAID 10 striped and mirrored array 	
	· · · ·	Use SW RAID functionality provided in the Red Hat [®] stem instead.
Integrated Graphics	١	lo
Network Controller	Intel® Xeon® W Processor Family	Intel [®] Core TM X-series Processors
	Intel [®] I219-LM PCIe GbE LAN	Intel [®] I219-V PCIe GbE LAN
	Intel® I210-AT PCIe GbE LAN Supports the following management functionalities Intel AMT11.1x, TXT, DASH 1.1, WOL, VLAN, Teaming and PXE 2.1	
External SATA (eSATA)	Supported on all SATA ports config	urable with optional eSATA* cable kit ot supported with eSATA
IDE connector	١	lo
Floppy connector	١	lo
Serial	1 intern	al header
2nd Serial Parallel		lo lo
	ľ	

System Technical Specifi	cations				
AUX IN (audio)			No		
IEEE 1394 Connector(s)					
Front			None		
Rear			None		
Internal			None		
USB Connector(s)					
Front	Front US	5B depends on v	which FIO module	is selected:	
	- S	tandard: 4 USB	3.1 G1 Type A (1 o	charging)	
	- Premium: 2 l	ISB 3.1 G2 Type	° (™. 2 USB 3.1 G	1 Type A (1 charging)	
			,200000		
Rear	Intel® Xeon® W Processor	Family	Intel®	[®] Core TM X-series Proc	essors
	6 USB 3.1 G1 Type	-		5 USB 3.1 G1 Type-A	
Internal			single-port heade	ir	
			ngle-port header dual-port header		
UD Integrated Audia	Realtek ALC221				
HD Integrated Audio Flash ROM	Yes				
CPU Fan Header	Yes				
Rear Chassis Fan Header	Yes				
Front PCI Fan Header	Yes				
Front Control Panel/Speaker Header	Yes				
CMOS Battery Holder - Lithium	Yes				
Integrated Trusted Platform	Trusted Platform Module (TP	M) 2.0 (Infineon	SLB 9670)		
Module	Common Criteria EAL4+ Cert				
	Convertible to FIPS 140-2 Centre TPM Cortified products list	rtified mode thr	rough firmware v	7.85	
	TPM Certified products list: https://trustedcomputinggro	oup.org/membe	ership/certificatio	n/tpm-certified-produ	ucts/
Power Supply Headers	Yes				
Power Switch, Power LED &	Yes				
Hard Drive LED Header					
Clear Password Jumper	Yes				
Serial Port	1 internal header				
Parallel Port Keyboard/Mouse	No USB or PS/2				
Reyboal u/Mouse	030017372				
Hood Lock Header	Yes				
Hood Sensor Header	Yes				
Memory Fan	1 Memory Fan Header				
AUX IN (audio) Beween Guerra In	No				
Power Supply	750W 90% Efficient,	Custom PSI I	46	5W 90% Efficient, C	ustom PSU
Power Supply			40		100011100
	(Wide-Ranging, A	,		(Wide-Ranging, Act	,
Operating Voltage Range	90-269 V		400	90-269 VAC	
Rated Voltage Range Rated Line Frequency	100-240 VAC 50-60 Hz	118 VAC 400 Hz		-240 VAC 0-60 Hz	118 VAC 400 Hz
Nateu Line Frequency	JU-00 HZ	400 HZ	50		400 172

up to 2000V)

System Technical Specifications **Operating Line Frequency** 47-66 Hz 47-66 Hz 393-407 Hz 393-407 Hz Range 100-240V @ 10A 118V @ 10A 100-240V @ 6A 118V @ 6A **Rated Input Current** Heat Dissipation Typical = 1850 btu/hr Typical = 1147 btu/hr (Configuration and software Max = 3084 btu/hrMax = 1912 btu/hr dependent) **Power Supply Fan** 80x25 mm variable speed 80x25 mm variable speed **ENERGY STAR® Certified** Yes Yes (Configuration dependent) 90% Efficient 90% Efficient The Z4 G4 750W power supply efficiency report The Z4 G4 465W power supply efficiency report **80 PLUS® Compliant** can be found at this link: can be found at this link: https://plugloadsolutions.com/psu reports/ https://plugloadsolutions.com/psu reports/ HP%20INC DPS-750AB-HP%20INC DPS-465AB-36%20A 750W ECOS%204938 Report.pdf 3%20A 465W ECOS%204939 Report.pdf 1000W 90% Efficient, Custom PSU **Power Supply** (Wide-Ranging, Active PFC) 90-269 VAC **Operating Voltage Range** 100-127 VAC **Rated Voltage Range** 118 VAC 200-240 VAC **Rated Line Frequency** 50-60 Hz 400 Hz **Operating Line Frequency** 47-66 Hz 393-407 Hz Range 12A @100-127 VAC 12A @ 118VAC **Rated Input Current** 6.3A @ 200-240 VAC **Heat Dissipation** Typical = 2467 btu/hr (Configuration and software Max = 4112 btu/hr dependent) **Power Supply Fan** 80x25 mm variable speed **ENERGY STAR® Certified** Yes (Configuration dependent) 90% Efficient The Z4 G4 1000W power supply efficiency report can be found at this link: 80 PLUS® Compliant https://plugloadsolutions.com/psu reports/HP D15-1K0P1A 1000W ECOS%204838 Report.pdf **FEMP Standby Power** Compliant @115V Yes Yes <1W in S5 - Power Off) EuP Compliant @ 230V Yes Yes (<0.5 W in S5 - Power Off) **CECP Compliant @ 220V** Yes; Configuration dependent (<4W in S3 - Suspend to Yes; Configuration dependent RAM) **Power Consumption in** sleep mode (as defined by ENERGY TBD TBD STAR®) - Suspend to RAM (S3) (Instantly Available PC) **Built-in Self Test LED** Yes Yes Surge Tolerant Full **Ranging Power Supply** Yes Yes (withstands power surges

System Technical Specifications

NOTE: 1000 W internal power supply, up to 90% efficiency, active PFC available the first half of 2018

System Configuration

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Example Z4 G4	Processor	1x Intel Xeor	W-2102 4C 2	.9GHz				
Workstation	Memory	1x 8GB DDR	x 8GB DDR4-2666 (Registered DIMM)					
Configuration #1	Graphics	1x NVIDIA Q	x NVIDIA Quadro P400					
ENERGY STAR®	Disks / Optical	1x 500GB S	ATA 7200 ; 1x	Slim DVD-R	OM SATA			
Certified	Power Supply	465W 90% c	custom PSU					
	Other	N/A						
		115	VAC	230	VAC	100	VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
Energy	Windows Idle (SO)	42	.323	41.3	338	42.	585	
Consumption	Windows Busy Typ(SO)	Т	BD	TE	3D	ТІ	3D	
	Windows Busy Max (S0)	90	.231	92.3	323	90.786		
	Sleep (S3)	3.449	3.440	3.566	3.558	3.530	3.410	
	Off (S5)	1.041	1.014	1.242	1.231	1.310	1.180	
	Zero Power Mode (ErP)	0.	187	0.43		0.174		
		115	VAC	230	VAC	100	VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
Heat Dissipation	Windows Idle (S0)	144	4.406	141	.045	145	.301	
(Btu/hr)	Windows Busy Typ(S0)	Т	BD	TE	3D	TE	3D	
	Windows Busy Max (S0)	30	7.868	315	.006	309.761		
	Sleep (S3)	11.767	11.737	12.167	12.140	12.044	11.634	
	Off (S5)	3.551	3.459	4.237	4.200	4.469	4.026	
	Zero Power Mode (ErP)	0.	638	1.4	167	0.5	594	

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Processor	1x Intel Xeor	W-2123 4C 3	.6GHz					
Memory	2x 8GB DDR	4-2666 (Regist	tered DIMM)					
Graphics	1x NVIDIA Q	1x NVIDIA QuadroP1000						
Disks / Optical	1x 500GB S	ATA 7200 ; 1x	Slim DVD-R	OM SATA				
Power Supply	750W 90% o	ustom PSU						
Other	N/A							
	115 VAC 230 VAC 100 VAC							
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
Windows Idle (S0)	39.947		39.569		40.956			
Windows Busy Typ(S0)	Т	BD	TE	3D	TBD			
Windows Busy Max (S0)	14	9.543	150	.789	147.845			
Sleep (S3)	3.615	3.566	3.801	3.798	3.634	3.621		
Off (S5)	1.079	1.016	1.440	1.238	1.320	1.170		
Zero Power Mode (ErP)	0.204 0.430 0.191							
	115	VAC	230	VAC	100	VAC		
	Graphics Disks / Optical Power Supply Other Windows Idle (S0) Windows Busy Typ(S0) Windows Busy Max (S0) Sleep (S3) Off (S5) Zero Power Mode	Memory2x 8GB DDRGraphics1x NVIDIA QDisks / Optical1x 500GB S/Power Supply750W 90% cOtherN/A115LAN EnabledWindows Idle (S0)39Windows BusyTTyp(S0)149Sleep (S3)3.615Off (S5)1.079Zero Power Mode0.(ErP)0.	Memory $2x 8GB DDR4-2666 (RegistGraphics1x NVIDIA QuadroP1000Disks / Optical1x 500GB SATA 7200 ; 1xPower Supply750W 90% custom PSUOtherN/A115 VACLAN EnabledLAN DisabledWindows Idle (S0)39.947Windows BusyTBDTyp(S0)149.543Sleep (S3)3.6153.566Off (S5)1.0791.016Zero Power Mode0.204$	Memory 2x 8GB DDR4-2666 (Registered DIMM) Graphics 1x NVIDIA QuadroP1000 Disks / Optical 1x 500GB SATA 7200 : 1x Slim DVD-R0 Power Supply 750W 90% custom PSU Other N/A 115 VAC 230 LAN Enabled LAN Disabled Windows Idle (S0) 39.947 Windows Busy TBD Typ(S0) TBD Windows Busy Max 149.543 (S0) 3.615 Sleep (S3) 3.615 Off (S5) 1.079 0.204 0.2	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c c c c c c c c c c c c c $		

System Technical Specifications

		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
Heat Dissipation	Windows Idle (S0)	130	6.299	135	.009	139	.741
(Btu/hr)	Windows Busy Typ(S0)	Т	BD	TE	3D	TE	3D
	Windows Busy Max (S0)	51(510.241		514.492		.447
	Sleep (S3)	12.338	12.167	12.969	12.959	12.399	12.355
	Off (S5)	3.681	3.466	4.913	4.224	4.504	3.992
	Zero Power Mode (ErP)	0.	696	1.4	167	0.6	651

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Example Z4 G4 Workstation	Processor	1	W-2133 6C 3				
Configuration #3	Memory	1	4-2666 (Regis	tered DIMM)			
Configuration #3	Graphics	1x NVIDIA Q					
	Disks/Optical	2x 1TB SAT	A7200 ; 1x Slir	n SuperMulti	DVDRW SA	ТА	
	Power Supply	750W 90% o	custom PSU				
	Other	N/A					
Energy		115	VAC	230	VAC	100	VAC
Consumption		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
(Watts)	Windows Idle (S0)	48	.759	46.	321	46.	578
	Windows Busy Typ(S0)	TBD		199	9.56	206	.055
	Windows Busy Max (S0)	209.60		208.66		198.82	
	Sleep (S3)	4.360	4.351	4.538	4.508	4.299	4.277
	Off (S5)	1.039	1.017	1.42	1.219	1.015	0.997
	Zero Power Mode (ErP)	0.	203	0.3	399	0.191	
		1					
			VAC	1	VAC	î	VAC
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
	Windows Idle (S0)	1	6.366		.047		.924
(Btu/hr)	Windows Busy Typ(S0)	Т	BD	TBD		TBD	
	Windows Busy Max (S0)	71	5.155	711	.947	678.373	
	Sleep (S3)	14.876	14.845	15.483	15.381	14.668	14.593
	Off (S5)	3.544	3.470	4.845	4.179	3.463	3.402
	Zero Power Mode (ErP)	0.	692	1.3	361	0.6	651

System Technical Specifications

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Example Z4 G4 Workstation	Processor	1x Intel Xeon						
			3x 32GB DDR4-2666 (Registered DIMM)					
Configuration #4	Graphics	<u>1x NVIDIA Q</u> ı	x NVIDIA QuadroP6000					
	Disks / Optical	4x 2TB SATA	<u> 7200 ; 0x O</u>	DD				
	Power Supply	750W 90% c	ustom PSU					
	Other	N/A						
Energy		115	VAC	230	VAC	100	VAC	
Consumption		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	65.9	959	69.	321	68.	635	
(Watts)	Windows Busy Typ(S0)	ТВ	D	TE	3D	TE	3D	
	Windows Busy Max (S0)	463.23		456.95		503.125		
	Sleep (S3)	6.336	6.102	6.971	6.189	6.266	6.264	
	Off (S5)	1.047	1.036	1.254	1.222	1.014	0.995	
	Zero Power Mode (ErP)	0.2	.03	0.3	399	0.1	91	
		115	VAC	230	VAC	100	VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
Heat Dissipation	Windows Idle (S0)	225	.052	236	.523	234	.183	
(Btu/hr)	Windows Busy Typ(S0)	TB	3D	TE	3D	TE	3D	
	Windows Busy Max (S0)	1580).541	1559	9.113	1716	663	
	Sleep (S3)	21.618	20.821	23.785	21.117	21.379	21.372	
	Off (S5)	3.572	3.534	4.278	4.169	3.459	3.394	
	Zero Power Mode (ErP)	0.6	92	1.3	361	0.6	52	

Example Z4 G4	Processor	1x Intel Core	i7-7800X 3.5	GHz 6C			
Workstation	Memory	2x 8GB DDR	4-2666 (non-	ECC DIMM)			
Configuration #5	Graphics	1x NVIDIA Q	uadro P1000				
	Disks / Optical	1x 1TB SATA	A 7200 : 1x S	lim DVD-RON	M SATA		
	Power Supply	1000W 90%	custom PSU				
	Other	N/A					
Energy	1	115	VAC	230	VAC	100	VAC
Consumption		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	46.9	909	47.	175	46.	909
(Watts)	Windows Busy Typ(S0)	TE	3D	TE	3D	TBD	
	Windows Busy Max (S0)	201.83 199.97		203.41			
	Sleep (S3)	3.041	2.971	3.165	3.041	2.971	3.165
	Off (S5)	0.978	0.898	1.159	0.978	0.898	1.159
	Zero Power Mode (ErP)	0.1	99	0.3	579	0.1	87
						i	
		115			VAC	i I	VAC
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
Heat Dissipation	Windows Idle (S0)	160.	053	160.	.961	160.	.053
(Btu/hr)	Windows Busy Typ(S0)	ТВ	BD	TE	3D	TE	3D
	Windows Busy Max (S0)	688.	644	682.	.297	694	.035
	Sleep (S3)	10.376	10.137	10.799	10.376	10.137	10.799

System Technical Specifications

Off (S5)	3.337	3.064	3.954	3.337	3.064	3.954
Zero Power Mode (ErP)	0.6	78	1.2	93	0.6	38

Example Z4 G4	Processor	1x Intel Core	i7-7920X 2.9	GHz 12C			
Workstation	Memory	4x 16GB DDR4-2666 (non-ECC DIMM)					
Configuration #6	Graphics	1x NVIDIA Q	1x NVIDIA Quadro P4000				
	Disks / Optical	2x 2TB SATA	2x 2TB SATA 7200 : 1x Slim DVD-ROM SATA				
	Power Supply	1000W 90%	custom PSU				
	Other	N/A					
Energy		115	VAC	230	VAC	100	VAC
Consumption		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	53.3	392	51.3	332	53.	367
(Watts)	Windows Busy Typ(S0)	TE	BD	TE	3D	TE	3D
	Windows Busy Max (S0)	318	.58	307	.82	319	9.71
	Sleep (S3)	3.558	3.486	3.694	3.558	3.486	3.694
	Off (S5)	0.972	0.895	1.160	0.972	0.895	1.160
	Zero Power Mode (ErP)	0.2	01	0.3	91	0.1	86
		115		230			VAC
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
Heat Dissipation	Windows Idle (S0)	182.	174	175.	.144	182	.088
(Btu/hr)	Windows Busy Typ(S0)	TE	BD	TE	3D	TE	3D
	Windows Busy Max (S0)	1086	.994	1050	.281	1090	0.851
	Sleep (S3)	12.139	11.894	12.604	12.139	11.894	12.604
	Off (S5)	3.316	3.054	3.957	3.316	3.054	3.957
	Zero Power Mode (ErP)	0.6	85	1.3	34	0.6	34

NOTE: Power consumption measurements do not take advantage of the Intel Turbo Boost Technology. As a result, power consumption measurements may be higher.

Declared Noise Emissions

Declared Noise Emissions (Entry-level and High-end configurations)			
System Configuration	Processor Info	Intel [®] Xeon [®] W-2125 4.0 2666 4C CPU	
(Entry level)	Memory Info	32GB (4x8GB) DDR4-2666 ECC Reg RAM	
		1-NVIDIA® Quadro® P400 2GB	
		1-500GB SATA 7200RPM 3.5"? HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer	
		465 W	

System Technical Specifications

Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	3.2	13
	Hard drive Operating (random reads)	3.4	15

System Configuration	Processor Info	Intel® Xeon® W-2155 3.3 2666 10C
(High end)	Memory Info	128GB (8x16GB) DDR4-2666 ECC Reg RAM
	Graphics Info	1-NVIDIA [®] Quadro [®] P6000 24GB
	Disks/Optical	2-4TB SATA 7200RPM Ent 3.5"? / 1-HP 9.5mm Slim Blu Ray Disc Writer
	Power Supply	750 W

Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	3.5	22
	Hard drive Operating (random reads)	3.7	23

System Configuration	Processor Info	Intel [®] Core i9-7900X 3.3 2666 10C
(Entry Level 2)	Memory Info	32GB (4x8GB) DDR4-2666 nECC RAM
	Graphics Info	1-NVIDIA® Quadro® P400 2GB
	Disks/Optical	1-500GB SATA 7200RPM Ent 3.5"? / 1-HP 9.5mm Slim Blu Ray Disc Writer
	Power Supply	1000 W

Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	3.4	16
1	Hard drive Operating (random reads)	3.5	17

System Configuration	Processor Info	Intel®Core i9-7980XE 2.6 2666 18C
(High end 2)	Memory Info	128GB (8x16GB) DDR4-2666 nECC RAM
	Graphics Info	1-NVIDIA® Quadro® P6000 24GB
	Disks/Optical	2-4TB SATA 7200RPM Ent 3.5"? / 1-HP 9.5mm Slim Blu Ray Disc Writer
	Power Supply	1000 W

System Technical Specifications

Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	3.5	20
	Hard drive Operating (random reads)	3.7	21

NOTE: Higher noise levels may be experienced with non-HP approved graphic card(s). Some consumer graphics cards have side blowing fans that may heat up thermal sensor(s) on the mother board causing fans to ramp.

Environmental Data

Environmental Requirements	Temperature	Non-operating: -40° to 60° C (-40° to 140° F) Operating: 5° to 35° C (40° to 95° F) Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation Maximum rate of change: 10 °C/hr No direct sustained sunlight
	Humidity	Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb
	Maximum Altitude	Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet) Non-operating: 12,192 m (40,000 feet) Maximum operating temperature is reduced as altitude increases. See Temperature for details.
	Shock (non-repetitive)	Operating: ?-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ?-sine: 160 cm/s, 2-3ms (~105g) Non-operating square: 422 cm/s, 20g
	Vibration	Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g?/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g?/Hz

Physical Security and Serviceability

Access Panel	Tool-less Includes system board and memory information.
Hard Drives	Tool-less
Expansion Cards	Tool-less
Processor Socket	Tool-less
Blue User Touch Points	Yes, on primary serviceable components.
Color-coordinated Cables	Yes
and Connectors	
Memory	Tool-less
System Board	Screw-In
Dual Color Power/Failure	Yes
LED	

System Technical Specifications

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HDD Activity LED	Yes		
Configuration Record SW	Note: HDD Activity LED is not dual-color Yes		
-			
Over-Temp Warning on Screen	Yes, at POST screen on reboot		
Restore CD/DVD Set	Restores the computer to its original factory shippin	g image; can be obtained via HP Support.	
Dual Function Front Power Switch	Yes, causes a fail-safe power off when held for 4 seco	nds	
Padlock Support	Yes (optional): Locks side cover and secures chassis f	rom theft	
	7.0 mm (0.2756 in) diameter padlock loop at rear of s	system	
Cable Lock Support	Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3 mm x 7 mm slot at rear of system		
Universal Chassis Clamp	Yes (optional): Locks side cover and locks cables to c	nassis. Secures chassis from theft and allows multiple	
Lock Support	units to be chained together when used with optiona Threaded feature at rear of system	l cable	
Solenoid Lock and Hood	Yes (optional)		
Sensor	The Solenoid Hood Lock eliminates the need for a phy software and a password. You can also lock and unlo detects when the access panel has been removed	rsical key by making the chassis lockable through ck the chassis remotely over the network. The Sensor Ki	
Serial, Parallel, USB,	Yes, enables or disables serial, USB, audio, and netwo	rk ports	
Audio, Network,			
Enable/Disable Port			
Control			
Removable Media Write/Boot Control	Yes, prevents ability to boot from removable media of	on supported devices (and can disable writes to media)	
Power-On Password	Yes, prevents an unauthorized person from booting	up the workstation	
Setup Password	Yes, prevents an unauthorized person from changing the workstation configuration		
3.3V Aux Power LED on	Yes		
System PCA			
NIC LEDs (integrated)	Yes		
(Green & Amber)			
CPUs and Heatsinks	A T-15 Torx or flat blade screwdriver is needed to rer CPU removal is tool-less	nove the CPU heatsink before the CPU can be removed.	
Power Supply Diagnostic	Yes		
LED			
Front Power Button	Yes, ACPI multi-function		
Rear Power Button	Yes		
Front Power LED	Yes, white (normal), red (fault)		
Front Hard Drive Activity	Yes, white		
LED			
Front ODD Activity LED	Yes, on device		
Internal Speaker	Yes		
System/Emergency ROM Flash Recovery	Recovers corrupted system BIOS.		
Cooling Solutions	Air cooled forced convection heatsinks		
Power Supply Fans	80 mm x 80 mm x 25 mm (non-serviceable)		
CPU Heatsink Fan	Intel [®] Xeon [®] W Processor Family	Intel [®] Core TM X-series Processors	
	CPU configs <= 140W: 92 mm x 92 mm x 25 mm, 5- wire, PWM	CPU configs <= 140W: 92 mm x 92 mm x 25 mm, 5- wire, PWM	
	CPU configs > 140W: 92 mm x 92 mm x 25 mm, 6- wire, PWM (includes 6-to-5pin cable adapter)	CPU configs > 140W: 92 mm x 92 mm x 25 mm, 6- wire, PWM (includes 6-to-5pin cable adapter)	

System Technical Specifications

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Chassis Fan	Front:
	(Optional) 92 mm x 92mm x 25 mm, 4-wire, PWM
	Rear:
	120 mm x 120mm x 25 mm, 4-wire, PWM
Memory Heatsink Fan	Dual 60 mm x 60 mm x 25 mm, 6-wire, PWM, Blindmate (optional based on configuration)
HP PC Hardware	HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many
Diagnostics UEFI	components. The diagnostics can be invoked by pressing ESC then F2 upon the PC reboot, and is available as a download from HP Support.
Access Panel Key Lock	Yes, side panel barrel keylock (optional from the factory only)
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI).
•	
	 Allows the system to wake from a low-power mode.
	 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system
Trusted Platform Module	Infineon TPM 2.0 Certified
Chip	
Integrated Chassis Handle	s Yes, Front handle and dedicated rear recess
Power Supply	Requires T15 Torx or flat blade screwdriver
PCIe Card Retention	Yes, rear (all), middle (all), front (full-length cards with extender, using HP Z4 G4 Fan and Front Card Guide
	Kit)
Flash ROM	Yes
Diagnostic Power Switch	Yes
LED on board	
Clear Password Jumper	Yes
Clear CMOS Button	Yes
CMOS Battery Holder	Yes
DIMM Connectors	Yes

BIOS

BIOS 32-bit Services	Standard BIOS 32-bit Service Directory Proposal v0.4
PCI 3.0 Support	Full BIOS support for PCI Express through industry standard interfaces.
АТАРІ	ATAPI Removable Media Device BIOS Specification Version 1.0.
BBS	BIOS Boot Specification v1.01.
WMI Support	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.
BIOS Boot Spec 1.01+	Provides more control over how and from what devices the workstation will boot.
BIOS Power On	Users can define a specific date and time for the system to power on.
ROM Based Computer Setup Utility (F10)	Review and customize system configuration settings controlled by the BIOS.
System/Emergency ROM Flash Recovery with Video	Recovers system BIOS in corrupted Flash ROM.
Replicated Setup	Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigUtility.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).
SMBIOS	System Management BIOS 2.8, for system management information.
Boot Control	Disables the ability to boot from removable media on supported devices.
Memory Change Alert	Alerts management console if memory is removed or changed.
Thermal Alert	Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

System Technical Specifications

	 ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown. SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs.
Remote ROM Flash	Provides secure, fail-safe ROM image management from a central network console.
ACPI (Advanced Configuration and Power Management Interface)	Allows the system to enter and resume from low power modes (sleep states). Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
	Supports ACPI 5.0 for full compatibility with 64-bit operating systems.
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.
Remote Wakeup/Remote Shutdown	System administrators can power on, restart, and power off a client computer from a remote location with Intel Xeon W Processors. For systems with Intel Core X-Series Processors, Wake on LAN is supported, however to remotely restart or shutdown a system, a remote desktop application must be used to manually Restart or Shutdown.
Instantly Available PC (Suspend to RAM - ACPI sleep state S3)	Allows for very low power consumption with quick resume time.
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW applications can use and report this information.
System board revision level	Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.
Auto Setup when new hardware installed	System automatically detects addition of new hardware.
Keyboard-less Operation	The system can be booted without a keyboard.
Localized ROM Setup	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with local keyboard mappings.
Asset Tag	The user or MIS to set a unique tag string in non-volatile memory.
Per-slot Control	Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually.
Adaptive Cooling	Control parameters are set according to detected hardware configuration for optimal acoustics.
Pre-boot Diagnostics	(Pre-video) critical errors are reported via beeps and blinks on the power LED.
Industry Standard Specification Support	
Industry Standard	Revision Supported by the BIOS
UEFI Specification Revision	2.6
ACPI	Advanced Configuration and Power Management Interface, Version 5.0
ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
CD Boot	"El Torito" Bootable CD-ROM Format Specification Version 1.0
EDD	- Enhanced Disk Drive Specification Version 1.1 - BIOS Enhanced Disk Drive Specification Version 3.0
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0
PCI	PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1
PCI Express	PCI Firmware Specification, Revision 3.0, Draft .7 PCI Express Base Specification, Revision 2.0 PCI Express Base Specification, Revision 3.0
РММ	POST Memory Manager Specification, Version 1.01

System Technical Specifications

SATA	Serial ATA Specification, Revision 1.0a Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0
SPD	PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B
ТРМ	Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)
	Common Criteria EAL4+ Certified
	FIPS 140-2 Certified
	TCG TPM Certified products list:
	http://www.trustedcomputinggroup.org/certification/tpm-certified-products/
UHCI	Universal Host Controller Interface Design Guide, Revision 1.1
USB	Universal Serial Bus Revision 1.1 Specification
	Universal Serial Bus Revision 2.0 Specification
	Universal Serial Bus Revision 3.1 G1 Specification
	Universal Serial Bus Revision 3.1 G2 Specification
SMBIOS	System Management BIOS Reference Specification, Version 2.8
כטוטויוכ	System management bios Reference Specification, Version 2.0

External BIOS simulator found at: http://h20464.www2.hp.com/index.html

Eco-Label Certifications & This product has received or is in the process of being certified to the following approvals and may be labeled

Social and Environmental Responsibility

Declarations	with one or more of these marks:
Batteries	 ENERGY STAR® (energy-saving features available on selected configurations-Windows only) US Federal Energy Management Program (FEMP) China Energy Conservation Program The ECO declaration (TED) TCO Certified configurations available* *TCO Certified configurations available when ENERGY STAR configurations are selected with a USB Type-C® connector. ENERGY STAR available with a combination of high-performance CPU's, high-performance GPU's and select memory configurations. The Z4 G4 is registered EPEAT® Silver in the US and Canada. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options The battery in this product complies with EU Directive 2006/66/EC Battery type: Lithium Metal
	The battery in this product does not contain:
Restricted Material Usage	 Mercury greater than 5ppm by weight Cadmium greater than 10ppm by weight Lead greater than 40ppm by weight This product meets the material restrictions specified in HP's General Specification for the Environment. HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis
Low Halogen Statement End-of-Life Management and Recycling	This product is low halogen except for power cords, external cables and peripherals. Service parts obtained after purchase may not be low halogen. (Note: optional low halogen power cables are available for some countries in Europe) HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life.

System Technical Specifications

System reclinical Spe						
HP Inc. Corporate	For more information about HP's commitment to the er	nvironment:				
Environmental Information	Sustainability Report	Sustainability Report				
	Tas Jahol contifications ICO 14001 contificates					
Additional Information	 Eco-label certifications SO 14001 certificates This HP product is designed to comply with the V 	Naste Electrical and Electronic Equipment (WEEE)				
Additional information	Directive - 2002/96/EC. Product Disassembly Ins					
Packaging	• Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043. HP Workstation product packaging meets the HP's General Specification for the Environment					
· ·······						
	 Does not contain restricted substances listed in H 	IP Standard 011-1 General Specification for the				
	Environment					
	 Does not contain ozone-depleting substances (Ol 					
	Does not contain heavy metals (lead, mercury, ca	admium or hexavalent chromium) in excess of 100				
	ppm sum total for all heavy metals listed					
	 Maximizes the use of post-consumer recycled con All a solution a material is use used able 	ntent materials in packaging materials				
	 All packaging material is recyclable All packaging material is designed for ease of disa 	scombly				
	 Reduced size and weight of packages to improve 					
	 Plastic packaging materials are marked according 					
	 A multi-unit eco packaging option is available to 					
		nventional single-unit packaging. Please contact your				
	sales representative for additional details.					
Packaging Materials						
Internal	Cushions and plastic bags made of low density polyethy	/lene (LDPE).				
External	Outer carton, accessories carton, and insert made of co	rrugated paper board.				
Manageability	Intel® Xeon® W Processor Family	Intel [®] Core TM X-series Processors				
Industry Standard	This product meets the following industry standard	None apply				
Specifications	specifications for manageability functionality:					
	 DASH 1.1 (via Intel® LAN on 					
	motherboard)					
Intel Active Management	Intel [®] Active Management Technology (AMT) 11.1x					
Technology (AMT)	An advanced set of remote management features					
	and functionality providing IT administrators the					
	latest and most effective tools to remotely discover,					
	heal, and protect networked client systems					
	regardless of the system's health or power state. AMT 11.1x includes the following advanced					
	management functions:					
	 Power Management (on, off, reset, graceful 					
	shutdown, sleep and hibernate)					
	 Support in Max Power Savings 					
	(Shutdown and Hibernate Modes)					
	 Hardware Inventory (includes BIOS and 					
	firmware revisions)					
	Hardware Alerting					
	Agent Presence					
	System Defense Filters					
	 Serial Over LAN (SOL) USB Redirect (Media Redirection) 					
	USB Redirect (Media Redirection) ME Wake on LAN (WOL) even with Maximum					
	• ME Wake-on-LAN (WOL), even with Maximum					
	Dowor Savings Enabled					
	Power Savings Enabled					
	DASH 1.1 compliance					
	-					

the firewall may initiate a call for help via BIOS

System Technical Specifications

, ,	
Intel® vPro TM Technology	screen, periodic connections, or alert triggered connection Remote Scheduled Maintenance - pre- schedule when the system connects to the IT or service provider console for maintenance. Remote Alerts - automatically alert IT or service provider if issues arise Access Monitor - Provides oversight into Intel® AMT actions to support security requirements PC Alarm Clock Microsoft NAP Support Host Base set-up and configuration Management Engine (ME) firmware roll back Local Time Sync to UTC Remote Memory Dump Command - Creates memory dump for debug The HP Z4 G4 Workstation supports Intel® vPro TM Not supported
Remote Manageability	 Intel[®] Xeon[®] processor W-2100 product family featuring Intel[®] vProTM Technology Intel[®] C422 chipset Intel[®] I219LM GbE LAN The HP Z4 G4 Workstation is supported on the Microsoft System Center Configuration
Software Solutions	following optional remote manageability software Manager Consoles:
	 LANDesk Management Suite (HP recommended solution) Microsoft System Center Configuration Manager For questions or support for manageability needs, please visit http://www.hp.com/go/easydeploy
System Software Manager	r For easydeploy questions or support for SSM, please visit: <u>http://www.hp.com/go/ssm</u>
Service, Support, and Warranty	On-site Warranty and Service (Note 1): Three-years, limited warranty and service offering delivers on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty. NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP
	NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country. NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries. HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool . Service levels and response times for HP Care Packs may vary depending on your geographic location.
Product Change Notification	 Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile. PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition. Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call to concise advisories provide concise.

technical support.

System Technical Specifications

Stable & Consistent Offerings

	As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.
	HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.
Processors	N/A
Hard Drives	1TB SATA 7200 RPM
Graphics	N/A

Technical Specifications - Processors

Intel[®] Xeon[®] W-Series CPU

Intel® Xeon® W-2295 3.0 2933 18C CPU Intel® Xeon® W-2275 3.3 2933 14C CPU Intel® Xeon® W-2265 3.5 2933 12C CPU Intel® Xeon® W-2255 3.7 2933 10C CPU Intel® Xeon® W-2245 3.9 2933 8C CPU Intel® Xeon® W-2235 3.8 2933 6C CPU Intel® Xeon® W-2225 4.1 2933 4C CPU Intel® Xeon® W-2223 3.6 2933 4C CPU Intel® Xeon® W-2145 3.7 2666 8C CPU Intel® Xeon® W-2133 3.6 2666 6C CPU Intel® Xeon® W-2125 4.0 2666 4C CPU Intel® Xeon® W-2123 3.6 2666 4C CPU Intel® Xeon® W-2104 3.2 2400 4C CPU Intel® Xeon® W-2102 2.9 2400 4C CPU Intel[®] CoreTM X-Series CPU Intel[®] CoreTM i9-10980XE 3.0 2933 18C CPU Intel[®] CoreTM i9-10940X 3.3 2933 14C CPU Intel® CoreTM i9-10920X 3.5 293312C CPU Intel[®] CoreTM i9-10900X 3.7 2933 10C CPU Intel[®] CoreTM i7-9800X 3.8 2666 8C CPU

Note: This list is just to indicate support, not availability. The above processors have all been qualified with the HP Z4 G4, but may not be available to order.

Technical Specifications - Hard Drives

Storage/Hard Drives

HP SAS (Serial Attached	HP 300GB SAS 15K SFF HDD) Canacity	300GB	
SCSI) Hard Drives for HP	ששוו דוכ אכו כאכ שטטטכ זוו	Height	5.9 in; 15 cm	
Workstations		Width	Media Diameter	3.5 in; 8.9 cm
		Interface	12Gb/s SAS	,
		Synchronous Transfer Rate (Maximum)	Up to 1200 MB/s (SAS single port)*	
		Buffer	128MB	
		Seek Time (typical reads, includes controller overhead, including settling)	Average	2.0ms *
		Rotational Speed	15K rpm	
		Operating Temperature	41° to 131° F (5° to 55° (C)
		*Actual performance may	vary.	
SATA (Serial ATA) Hard	500GB SATA 7200 rpm	Capacity	500GB	
Drives for HP	6Gb/s 3.5" HDD	Height	1 in; 2.54 cm	
Workstations		Width	Media Diameter	3.5 in; 8.9 cm
			Physical Size	4 in; 10.17 cm
		Interface	Serial ATA (6.0Gb/s), NCQ	enabled
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
		Buffer	16MB	
		Seek Time (typical reads, includes controller overhead, including settling)	Single Track	2 ms*
			Average	11 ms*
			Full Stroke	21 ms*
		Rotational Speed	7,200 rpm	
		Logical Blocks	976,773,168	
		Operating Temperature	41° to 131° F (5° to 55° C))
		*Actual performance may v	ary.	
	1TB SATA 7200 rpm 6Gb/s	Capacity	1TB	
		Height	1 in; 2.54 cm	
		Width	Media Diameter	3.5 in; 8.9 cm
			Physical Size	4 in; 10.17 cm
		Interface	Serial ATA (6.0Gb/s), NCQ	enabled
		Synchronous Transfer Rate (Maximum)	Up to 600 MB/s*	
		Buffer	64MB	
		Cache	Adaptive	
		Seek Time (typical reads, includes controller overhead, including	Single Track	2 ms*
			Average	11 ms*
		settling)	Full Stroke	21 ms*

Technical Specifications - Hard Drives

Rotational Speed	7,200 rpm	
Operating Temperature	41° to 131° F (5° to 55° C)	
*Actual performance may vary.		

2.0TB SATA 7200 rpm 6Gb/s 3.5" HDD CMR	Capacity Height	2.0TB 1 in; 2.54 cm	
	Width	Media Diameter	3.5 in; 8.9 cm
		Physical Size	4 in; 10.17 cm
	Interface	Serial ATA (6.0 Gb/s), NCQ Enabled	
	Synchronous Transfer Rate (Maximum)	Up to 600 MB/s*	
	Buffer	64MB	
	Seek Time (typical reads,	Single Track	1.0 ms*
	includes controller	Average	11 ms*
	overhead, including settling)	Full Stroke	18 ms*
	Rotational Speed	7,200 rpm	
	Logical Blocks	3,907,029,168	
	Operating Temperature	41° to 131° F (5° to 55° C)	1
	*Actual performance may v	vary.	
2.0TB SATA 7200 rpm	Capacity	2.0TB	
6Gb/s 3.5" HDD SMR	Height	1 in; 2.54 cm	
	Width	Media Diameter	3.5 in; 8.9 cm
		Physical Size	4 in; 10.17 cm
	Interface	Serial ATA (6.0 Gb/s), NCQ Enabled	
	Synchronous Transfer Rate (Maximum)	Up to 600 MB/s*	
	Buffer	64MB	
	Seek Time (typical reads, includes controller overhead, including settling)	Single Track	1.2 ms*
		Average	12 ms*
		Full Stroke	21 ms*

Rotational Speed

Logical Blocks

Serial ATA (6.0 Gb/s), NCC	Enab
Up to 600 MB/s*	
64MB	
Single Track	1.2 m
Average	12 m
Full Stroke	21 m
7,200 rpm	
3,907,029,168	

Operating Temperature 41° to 140° F (5° to 60° C)

Technical Specifications - Hard Drives

	1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Capacity	1TB	
		Protocol	SATA	
		Form Factor	3.5"	
		Controller	AHCI	
		Reliability (MTBF)	2.0M hours	
		Rated Power On Hours	8760/yr	
		Annualized Failure Rate (based on Rated POH)	<0.62%	
		Rated for 24/7/365 operation	YES	
		Physical Size (Height)	1 in; 2.54 cm	
		Physical Size (Width)	4 in; 10.17 cm	
		Media Diameter	3.5 in; 8.9 cm	
		Interface	Serial ATA (6Gb/s), NCQ e	nabled
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
		Buffer	128MB	
		Seek Time (typical reads,	Single Track	0.32ms*
		includes controller overhead, including settling)	Average	7.45ms*
			Full Stroke	14.2ms*
		Operating Temperature	41° to 140° F (5° to 60° C)	
		Performance	Sequential Read	up to 226MB/s*
			Sequential Write	up to 226MB/s*
		Enterprise Class Features	High Reliability	
		*Actual performance may v	/ary.	
	4TB SATA 7200 rpm 6Gb/s	Capacity	4TB	
	3.5" HDD	Height	0.275 in; 0.7 cm	
	(Enterprise Class)	Width	Media Diameter	2.5 in; 6.36 cm
			Physical Size	2.75 in; 6.99 cm
		Interface	Serial ATA (6Gb/s), NCQ e	nabled
		Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
		Buffer	128MB	
		Seek Time (typical reads,	Single Track	0.7ms*
		includes controller	Average	8.5ms*
		overhead, including settling)	Full Stroke	15.7ms*
		Rotational Speed	7,200 rpm	
		Operating Temperature	32° to 140° F (0° to 60° C))
		*Actual performance may v	vary.	

HP 256GB SATA 6Gb/s SSD

500GB SATA 7.2K SED SFF HDD	Capacity Height Width	500GB 0.275 in; 0.7 cm Media Diameter Physical Size	2.5 in; 6.36 cm 2.75 in; 6.99 cm
	Interface	Serial ATA (6Gb/s)	
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
	Buffer	32MB	
	Seek Time (typical reads, includes controller	Single Track	1ms*
		Average	4.2ms*
	overhead, including settling)	Full Stroke	25ms (typical)*
	Rotational Speed	7,200 rpm	
	Operating Temperature	32° to 140° F (0° to 60° C)
	*Actual performance may v	vary.	

SATA SSDs for HP Workstations

Capacity	256GB	
Protocol	SATA	
Form Factor	2.5"	
Controller	AHCI	
NAND Type	3D TLC	
Endurance	192TBW (TB Written)	
Reliability (MTTF)	1.5M hours	
Physical Size (Height)	0.28 in; 0.7 cm	
Physical Size (Width)	2.5 in; 6.36 cm	
Interface	SATA 6Gb/s	
Synchronous Transfer Rat e (Maximum)	e Up to 600MB/s*	
Operating Temperature	32° to 158° F (0° to 70° (_)
Performance	Sequential Read	530MB/s (max)*
	Sequential Write	500MB/s (max)*
	Random Read	55K IOPS (max)*
	Random Write	83K IOPS (max)*

Technical Specifications - Hard Drives

HP 256GB SATA 6Gb/s SED	Capacity	256GB	
Opal 2 SSD	Protocol	SATA	
	Form Factor	2.5"	
	Controller	AHCI	
	NAND Type	3D TLC	
	Endurance	192TBW (TB Written)	
	Reliability (MTTF)	1.5M hours	
	Physical Size (Height)	0.28 in; 0.7 cm	
	Physical Size (Width)	2.5 in; 6.36 cm	
	Interface	6Gb/s SATA	
	Synchronous Transfer Rate (Maximum)		al Read)*
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	Sequential Read	530MB/s*
		Sequential Write	500 MB/s*
		Random Read	55K IOPS*
		Random Write	83K IOPS*
	Self-Encrypting Drive Support	OPAL 2	
	*Actual performance may va	ary.	
HP 512GB SATA 6Gb/s SSD	Capacity	512GB	
IIF 31200 3ATA 000/3 330	Protocol	SATA	
	Form Factor	2.5"	
		2.5	
	Controller	ΔΗCI	
	Controller NAND Type	AHCI 3D TI C	
	NAND Type	3D TLC	
	NAND Type Endurance	3D TLC 388TBW (TB Written)	
	NAND Type Endurance Reliability (MTTF)	3D TLC 388TBW (TB Written) 1.5M hours	
	NAND Type Endurance Reliability (MTTF) Physical Size (Height)	3D TLC 388TBW (TB Written) 1.5M hours 0.28 in; 0.7 cm	
	NAND Type Endurance Reliability (MTTF)	3D TLC 388TBW (TB Written) 1.5M hours 0.28 in; 0.7 cm 2.5 in; 6.36 cm	
	NAND Type Endurance Reliability (MTTF) Physical Size (Height) Physical Size (Width)	3D TLC 388TBW (TB Written) 1.5M hours 0.28 in; 0.7 cm 2.5 in; 6.36 cm SATA 6Gb/s	al Read)*
	NAND Type Endurance Reliability (MTTF) Physical Size (Height) Physical Size (Width) Interface Synchronous Transfer Rate	3D TLC 388TBW (TB Written) 1.5M hours 0.28 in; 0.7 cm 2.5 in; 6.36 cm SATA 6Gb/s	
	NAND Type Endurance Reliability (MTTF) Physical Size (Height) Physical Size (Width) Interface Synchronous Transfer Rate (Maximum)	3D TLC 388TBW (TB Written) 1.5M hours 0.28 in; 0.7 cm 2.5 in; 6.36 cm SATA 6Gb/s Up to 550MB/s (Sequenti	
	NAND Type Endurance Reliability (MTTF) Physical Size (Height) Physical Size (Width) Interface Synchronous Transfer Rate (Maximum) Operating Temperature	3D TLC 388TBW (TB Written) 1.5M hours 0.28 in; 0.7 cm 2.5 in; 6.36 cm SATA 6Gb/s Up to 550MB/s (Sequenti 32° to 158° F (0° to 70° C)
	NAND Type Endurance Reliability (MTTF) Physical Size (Height) Physical Size (Width) Interface Synchronous Transfer Rate (Maximum) Operating Temperature	3D TLC 388TBW (TB Written) 1.5M hours 0.28 in; 0.7 cm 2.5 in; 6.36 cm SATA 6Gb/s Up to 550MB/s (Sequenti 32° to 158° F (0° to 70° C Sequential Read) 530 MB/s*
	NAND Type Endurance Reliability (MTTF) Physical Size (Height) Physical Size (Width) Interface Synchronous Transfer Rate (Maximum) Operating Temperature	3D TLC 388TBW (TB Written) 1.5M hours 0.28 in; 0.7 cm 2.5 in; 6.36 cm SATA 6Gb/s Up to 550MB/s (Sequenti 32° to 158° F (0° to 70° C Sequential Read Sequential Write) 530 MB/s* 500 MB/s*

Technical Specifications - Hard Drives

HP

HP

512GB SATA SED SSD	Capacity	512GB	
	Protocol	SATA	
	Form Factor	2.5"	
	Controller	AHCI	
	NAND Type	3D TLC	
	Endurance	388TBW (TB Written)	
	Reliability (MTTF)	1.5M hours	
	Physical Size (Height)	0.28 in; 0.7 cm	
	Physical Size (Width)	2.5 in; 6.36 cm	
	Interface	SATA 6Gb/s	
	Synchronous Transfer Rat e (Maximum)	e Up to 600MB/s*	
	Operating Temperature	32° to 158° F (0° to 70° (<u>(</u>)
	Performance	Sequential Read	530 MB/s*
		Sequential Write	500 MB/s*
		Random Read	95K IOPS*
		Random Write	83K IOPS*
	Self-Encrypting Drive Support	OPAL 1 and 2	
	*Actual performance may v	ary.	
1TB SATA 6Gb/s SSD	Capacity	1TB	
	Protocol	SATA	
	Form Factor	2.5"	
	Controller	AHCI	
	NAND Type	3D TLC	
	Endurance	400TBW (TB Written)	
	Reliability (MTTF)	1.5M hours	
	Physical Size (Height)	0.28 in; 0.7 cm	
	Physical Size (Width)	2.5 in; 6.36 cm	
	Interface	SATA 6Gb/s	
	Synchronous Transfer Rat o (Maximum)	e Up to 550MB/s (Sequent	ial Read)*
	Operating Temperature	32° to 158° F (0° to 70° (<u>(</u>)
	Performance	Sequential Read	530 MB/s*
		Sequential Write	500 MB/s*
		Random Read	95K IOPS*
		Random Write	83K IOPS*
	*Actual performance may v	ary.	

Technical Specifications - Hard Drives

HP 2TB SATA 6Gb/s SSD	Capacity	2TB	
	Protocol	SATA	
	Form Factor	2.5"	
	Controller	AHCI	
	NAND Type	3D TLC	
	Endurance	400TBW (TB Written)	
	Reliability (MTTF)	1.5M hours	
	Physical Size (Height)	0.28 in; 0.7 cm	
	Physical Size (Width)	2.5 in; 6.36 cm	
	Interface	SATA 6Gb/s	
	Synchronous Transfer Rate (Maximum)	• Up to 550MB/s (Sequent	ial Read)*
	Operating Temperature	32° to 158° F (0° to 70° (<u>(</u>)
	Performance	Sequential Read	530 MB/s*
		Sequential Write	500 MB/s *
		Random Read	95K IOPS*
		Random Write	83K IOPS*
	*Actual performance may v	ary.	
HP Enterprise Class 240GB	Capacity	240GB	
SATA SSD	Protocol	SATA	
	Form Factor	2.5"	

Form Factor	2.5"	
Controller	AHCI	
NAND Type	3D TLC	
Endurance	2,200TBW (TB Written)	
Reliability (MTTF)	2.0M hours	
Physical Size (Height)	0.28 in; 0.7 cm	
Physical Size (Width)	2.5 in; 6.36 cm	
Interface	6Gb/s SATA	
Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
Operating Temperature	32° to 158° F (0° to 70° C)
Performance	Sequential Read	540 MB/s*
	Sequential Write	310 MB/s*
	Random Read	93K IOPS*
	Random Write	48K IOPS*
Enterprise Class Features	High Endurance NAND Power Loss Protection End-to-End Data Protect	ion
*Actual performance may va	arv	

Technical Specifications - Hard Drives

•	HP Enterprise Class 480GB	Canacity	480GB	
	SATA SSD	Protocol	SATA	
		Form Factor	2.5"	
		Controller	AHCI	
		NAND Type	3D TLC	
		Endurance	4,400TBW (TB Writter	n)
		Reliability (MTTF)	2.0M hours	.,
		Physical Size (Height)	0.28 in; 0.7 cm	
		Physical Size (Width)	2.5 in; 6.36 cm	
		Interface	6Gb/s SATA	
		Synchronous Transfer Rate (Maximum)	e Up to 600MB/s*	
		Operating Temperature	32° to 158° F (0° to 70)° C)
		Performance	Sequential Read	540 MB/s*
			Sequential Write	460 MB/s*
			Random Read	93K IOPS*
			Random Write	74K IOPS*
		Enterprise Class Features	High Endurance NANE Power Loss Protectio End-to-End Data Prot	n
		*Actual performance may v	ary.	
Performance PCIe SSDs for HP Workstations			256GB	
TOF HP WORKStations			PCIe	
			1.2	
			IVMe	
		71 -		
)pal 2	
			200TB	
		•	1.5M hours	
			CI Express 3.0 x4 electr	
			2° to 158° F (0° to 70° (-
		Performance S	equential Read	3500 MB/s *

Sequential Write 2200 MB/s *

Random Read240K IOPS *Random Write480K IOPS *

Technical Specifications - Hard Drives

HP ZTurbo Drive 512GB	Capacity	512GB	
	capacity	51260	
M.2 2280 TLC SSD	Protocol	PCIe	
	Form Factor	M.2	
	Controller	NVMe	
	NAND Type	3D TLC	
	SED Support	Opal 2	
	Endurance	300TB	
	Reliability (MTBF)	1.5M hours	
	Interface	PCI Express 3.0 x4 elect	rical x4 physical
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3500 MB/s*
		Sequential Write	2900 MB/s*
		Random Read	460 K IOPS*
		Random Write	500K IOPS*

*Actual performance may vary.

HP ZTurbo Drive 1TB M.2	Capacity	1TB	
2280 TLC SSD	Protocol	PCIe	
	Form Factor	M.2	
	Controller	NVMe	
	NAND Type	3D TLC	
	SED Support	Opal 2	
	Endurance	400TB	
	Reliability (MTBF)	1.5M hours	
	Interface	PCI Express 3.0 x4 elec	trical x4 physical
	Operating Temperature	32° to 158° F (0° to 70° C)	
	Performance	Sequential Read	3500 MB/s*
		Sequential Write	3000 MB/s*
		Random Read	580K IOPS*
		Random Write	500K IOPS*
	*Actual porformanco may	Varv	

Technical Specifications - Hard Drives

HP ZTurbo Drive 2TB M.2	Capacity	2TB	
2280 TLC SSD	Protocol	PCIe	
	Form Factor	M.2	
	Controller	NVMe	
	NAND Type	3D TLC	
	SED Support	Opal 2	
	Endurance	500TB	
	Reliability (MTTF)	1.5M hours	
	Interface	PCI Express 3.0 x4 elect	trical x4 physical
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3300 MB/s*
		Sequential Write	2400 MB/s*
		Random Read	500K IOPS*
		Random Write	440K IOPS*

*Actual performance may vary.

HP Z Turbo Drive Quad	Capacity	512GB	
Pro 2x256GB PCIe TLC SSD	Protocol	PCIe	
	Form Factor	PCIe Card, Full Height P	Cle Slot
	Controller	NVMe	
	NAND Type	3D TLC	
	SED Support	Opal 2	
	Endurance	200TB	
	Reliability (MTBF)	1.5M hours	
	Interface	PCIe Gen3 x4 architectu	re
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3500 MB/s*
		Sequential Write	2200 MB/s*
		Random Read	240K IOPS*
		Random Write	480K IOPS*
	4.6.1 . I		

Technical Specifications - Hard Drives

HP Z Turbo Drive Quad	Capacity	1TB	
Pro 2x512GB PCIe TLC SSD	Protocol	PCIe	
	Form Factor	PCIe Card, Full Height PC	Cle Slot
	Controller	NVMe	
	NAND Type	3D TLC	
	SED Support	Opal 2	
	Endurance	300TB	
	Reliability (MTBF)	1.5M hours	
	Interface	PCIe Gen3 x4 architectu	re
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3500 MB/s*
		Sequential Write	2900 MB/s*
		Random Read	460 K IOPS*
		Random Write	500K IOPS*
	*Actual performance may	vary.	
UD 7 Turks Duins Qued Due	Connector		
HP Z Turbo Drive Quad Pro 2x1TB PCIe TLC SSD		2TB	
	Protocol	PCIe	
	Form Factor	PCIe Card, Full Height PC	Cle Slot
	Controller	NVMe	
	NAND Type	3D TLC	

*Actual performance may vary.

Operating Temperature

SED Support Endurance

Performance

Interface

Opal 2

400TB

PCI Express 3.0 x4 electrical x4 physical

3500 MB/s*

3000 MB/s*

580K IOPS*

500K IOPS*

32° to 158° F (0° to 70° C)

Sequential Read

Sequential Write

Random Read

Random Write

HP Z Turbo Drive Dual Pro	Capacity	256GB	
256GB SSD	Protocol	PCIe	
	Form Factor	M.2 in Half-height, half-	length card
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	200TBW (TB Written)	
	Reliability (MTBF)	1.5M hours	
	Interface	PCI Express 3.0 x4 elect	rical x4 physical
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3500 MB/s*
		Sequential Write	2200 MB/s*
		Random Read	240K IOPS*
		Random Write	480K IOPS*
	*Actual porformanco mau	NORM.	

Technical Specifications - Hard Drives

HP Z Turbo Drive Dual Pro	Capacity	512GB	
512GB SSD	Protocol	PCIe	
	Form Factor	M.2 in Half-height, half-	length card
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	300TBW (TB Written)	
	Reliability (MTBF)	1.5M hours	
	Interface	PCI Express 3.0 x4 elect	rical x4 physical
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3500 MB/s*
		Sequential Write	2900 MB/s*
		Random Read	460 K IOPS*
		Random Write	500K IOPS*

*Actual performance may vary.

HP Z Turbo Drive Dual Pro	Capacity	1TB	
1TB SSD	Protocol	PCIe	
	Form Factor	M.2 in Half-height, half-	length card
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	400TBW (TB Written)	
	Reliability (MTBF)	1.5M hours	
	Interface	PCI Express 3.0 x4 elect	rical x4 physical
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3500 MB/s*
		Sequential Write	3000 MB/s*
		Random Read	580K IOPS*
		Random Write	500K IOPS*

HP Z Turbo Drive Dual Pro	Capacity	2TB	
2TB SSD	Protocol	PCle	
	Form Factor	M.2 in Half-height, half	-length card
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	500TBW (TB Written)	
	Reliability (MTBF)	1.5M hours	
	Interface	PCI Express 3.0 x4 elec	trical x4 physical
	Operating Temperature	32° to 158° F (0° to 70° C)	
	Performance	Sequential Read	3500 MB/s*
		Sequential Write	3000 MB/s *
		Random Read	600K IOPS*
		Random Write	500K IOPS*
	*Actual performance may	vary.	
		25668	

Mainstream PCIe SSDs for	HP 256GB M.2 2280 TLC	Capacity	256GB
HP Workstations	SSD	Protocol	PCIe

Technical Specifications - Hard Drives

Form Factor	M.2	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	200TB	
Reliability (MTBF)	1.5M hours	
Interface	PCI Express 3.0 x4 electrical x4 physical	
Operating Temperature	32° to 158° F (0° to 7	0° C)
Performance	Sequential Read	3100 MB/s *
	Sequential Write	1400 MB/s *
	Random Read	200 K IOPS *
	Random Write	320 K IOPS *

*Actual performance may vary.

HP 512GB M.2	2280 TLC
SSD	

HP 1TB M.2 2280

Capacity	512GB	
Protocol	PCIe	
Form Factor	M.2	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	300TB	
Reliability (MTBF)	1.5M hours	
Interface	PCI Express 3.0 x4 elect	rical x4 physical
Operating Temperature	32° to 158° F (0° to 70°	C)
Performance	Sequential Read	3300 MB/s*
	Sequential Write	2500 MB/s*
	Random Read	225 K IOPS*
	Random Write	430 K IOPS*

*Actual performance may vary.

Capacity	1TB	
Protocol	PCIe	
Form Factor	M.2	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	400TB	
Reliability (MTBF)	1.5M hours	
Interface	PCI Express 3.0 x4 elec	trical x4 physical
Operating Temperature	32° to 158° F (0° to 70°	C)
Performance	Sequential Read	3300 MB/s*
	Sequential Write	2500 MB/s*
	Random Read	400 K IOPS*
	Random Write	440 K IOPS*
	Protocol Form Factor Controller NAND Type Endurance Reliability (MTBF) Interface Operating Temperature	ProtocolPCleForm FactorM.2ControllerNVMeNAND Type3D TLCEndurance400TBReliability (MTBF)1.5M hoursInterfacePCI Express 3.0 x4 electOperating Temperature32° to 158° F (0° to 70°PerformanceSequential ReadSequential WriteRandom Read

Technical Specifications - Hard Drives

	HP 2TB M.2 2280 TLC SSD	Capacity	2TB	
		Protocol	PCIe	
		Form Factor	M.2	
		Controller	NVMe	
		NAND Type	3D TLC	
		Endurance	500TB	
		Reliability (MTBF)	1.5M hours	
		Interface	PCI Express 3.0 x4 elec	trical x4 physical
		Operating Temperature	32° to 158° F (0° to 70°	° C)
		Performance	Sequential Read	3300 MB/s*
			Sequential Write	2700 MB/s*
			Random Read	430 K IOPS*
			Random Write	500 K IOPS*
		*Actual performance may	vary.	
Intel® 905p Series AIC PCIe	Intel® 905p Series AIC	Capacity	280GB	
SSD 280GB PCIe SSD	Protocol	PCIe		

Protocol	PCIe	
Form Factor	PCIe Card, Half Height	
Controller	NVMe	
NVM Туре	3DXPoint	
Endurance	5.11 PBW (PB Written)	
Reliability (MTBF)	1.6M hours	
Operating Temperature	32° to 185° F (0° to 85°	C)
Performance	Sequential Read	2730 MB/s*
	Sequential Write	2280 MB/s*
	Random Read	587K IOPS*

Random Write

559K IOPS*

*Actual performance may vary.

Intel [®] 905p Series AIC	Capacity	480GB	
480GB PCIe SSD	Protocol	PCIe	
	Form Factor	PCIe Card, Half Height	
	Controller	NVMe	
	NVM Туре	3DXPoint	
	Endurance	8.76 PBW (PB Written)	
	Reliability (MTBF)	1.6M hours 32° to 185° F (0° to 85° C)	
	Operating Temperature		
	Performance	Sequential Read	2710 MB/s*
		Sequential Write	2280 MB/s*
		Random Read	582K IOPS*
		Random Write	561K IOPS*

Technical Specifications - Hard Drive Controllers

Hard Drive Controllers

MicroSemi 2100-4i4e 8- port SAS 12Gb/s RAID Card	PCI Bus RAID Levels PCI Data Burst Transfer Rate	8 lanes, PCI Express 3.0 Offers Integrated RAID (0, 1, and 10) Half Duplex x8, PCIe, 8000 MB/s	
	SAS Bandwidth	Half Duplex	1200 MB/s per lane
	PCI Card Type	3.3V Add-in Card	
	PCI Voltage	12 V ± 10%	
	PCI Power	9.8W typical, Airflow min 200 LFM	
	Bracket	Full height and low profile	
	Certification Level	PCI Express 3.0 compliant	
	SAS Processor	MicroSemi Series 8 SAS Controller	
	Internal Connectors	One x4 internal mini-SASHD (SFF-864	3)
	External Connectors	One x4 external mini-SASHD (SFF-864	14)
	Maximum Number of SCSI Devices	256 Non-RAID SAS/SATA devices	
	LED Indicators	Connector for Drive Activity Light NOTE: RAID 5 is not supported on Mic RAID Card	roSemi 2100-4i4e 8-port SAS 12Gb/s

Technical Specifications - Graphics

Graphics

NVIDIA® Quadro® P620 2GB Graphics	Form Factor	Dimensions: 2.713"? H x 5.7"? L Single Slot, Low Profile Weight: 129 grams
	Graphics Controller	NVIDIA® Quadro® P620 Graphics Card GPU: 512 CUDA cores Power: 40 Watts Cooling: Active
	Bus Type	PCI Express 3.0 x16
	Memory	Size: 2 GB GDDR5, 2000 MHz Memory Interface: 128-bit Memory Bandwidth: 64 GB/s
	Connectors	4mDP Outputs *
	Maximum Resolution	DisplayPort [™] 1.4: - up to 4x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)
	Image Quality Features	10-bit internal display processing pipeline 10-bit scan-out support
	Display Output	4 mDP Connectors
	Shading Architecture	Full Microsoft DirectX 12 Shader Model 5.1
	Supported Graphics APIs	OpenGL 4.5 DirectX 12 Vulkan 1.0 API support includes: CUDA C, CUDA C++, DirectCompute , OpenCL
	Available Graphics Drivers	Windows 11 Windows 10 Windows 8.1 Windows 7 Linux
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
	Notes	*P620 only have mini-DisplayPort [™] (mDP) video ports.
		Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters included After market option kit:Two mDP-to-DP Adapters included
		Additional mDP-to-DP Adapters are available as Factory Configuration or Option Kit accessories:
		- 2MY05AA - HP miniDP-to-DP Adapter Cables
		- 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

NVIDIA® T400 2GB Graphics	Form Factor	Dimensions: 2.713"? H x 6.137"? L Single Slot, Low Profile Weight: 124g
	Graphics Controller	NVIDIA® T400 Graphics Card GPU: 384 CUDA cores Power: 30 Watts Cooling: Active
	Bus Type	PCI Express 3.0 x16
	Memory	Size: 2 GB GDDR6 Memory Interface: 64-bit Memory Bandwidth: 80 GB/s
	Connectors	3x mDP
	Maximum Resolution	3x 5120 x 2880 x 24 bpp @ 60Hz
	Supported Graphics APIs	OpenGL 4.5 DirectX 12 Vulkan 1.0 API support includes: CUDA, OpenCL 1.x
	Available Graphics Drivers	Windows 11 Windows 10 Linux
		HP qualified drivers may be preloaded or available from the HP support Web site:
		http://welcome.hp.com/country/us/en/support.html
NVIDIA® T400 4GB Graphics	Form Factor	Dimensions: 2.713"? H x 6.137"? L Single Slot, Low Profile Weight: 124g
	Graphics Controller	NVIDIA® T400 Graphics Card GPU: 384 CUDA cores Power: 30 Watts Cooling: Active
	Bus Type	PCI Express 3.0 x16
	Memory	Size: 4 GB GDDR6 Memory Interface: 64-bit Memory Bandwidth: 80 GB/s
	Connectors	3x mDP
	Maximum Resolution	3x 5120 x 2880 x 24 bpp @ 60Hz
	Supported Graphics APIs	OpenGL 4.5
		DirectX 12 Vulkan 1.0 API support includes: CUDA, OpenCL 1.x
	Available Graphics Drivers	Vulkan 1.0 API support includes: CUDA, OpenCL 1.x

Technical Specifications - Graphics

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T600 4GB	Form Factor	Dimensions: 2.713"? H x 6.137"? L Single Slat Law Profile
Graphics		Single Slot, Low Profile Weight: 130 grams
	Graphics Controller	NVIDIA® T600 Graphics Card
		GPU: 640 CUDA cores
		Power: 40 Watts
		Cooling: Active
	Bus Type	PCI Express 3.0 x16
	Memory	Size: 4 GB GDDR6
		Memory Interface: 128-bit
		Memory Bandwidth: 160 GB/s
	Connectors	4x mDP
	Maximum Resolution	4x 5120 x 2880 x 24 bpp @ 60Hz
	Supported Graphics APIs	OpenGL 4.5
		DirectX 12
		Vulkan 1.0
		API support includes: CUDA C, CUDA C++, DirectCompute , OpenCL
	Available Graphics Drivers	• • •
		Linux
		HP qualified drivers may be preloaded or available from the HP support
		Web site: http://welcome.hp.com/country/us/en/support.html
		http://wetcome.np.com/country/us/en/support.neme
NVIDIA® Quadro® P1000	Form Factor	Dimensions:2.713"? H x 5.7"? L
4GB Graphics		Single Slot, Low Profile
•		Weight: 129 grams
	Graphics Controller	NVIDIA [®] Quadro [®] P1000 Graphics Card
		GPU: 640 CUDA cores
		Power: 47 WattsCooling: Active Cooling: Active
		Cooling. Active
	Bus Type	PCI Express 3.0 x16
	Memory	Size: 4 GB GDDR5, 2500 MHz
		Memory Interface: 128-bit memory interface
		Memory Bandwidth: 80 GB/s memory bandwidth
	Connectors	4mDP Outputs*
	Maximum Resolution	DisplayPort 1.4:
		- up to 4x 5120 x 2880 x 24 bpp @ 60Hz
		- supports Multi-Stream Transport (MST)
	Image Quality Features	10-bit internal display processing pipeline
		10-bit scan-out support
	Display Output	4 mDP Connectors
	Shading Architecture	Full Microsoft DirectX 12 Shader Model 5.1

Supported Graphics APIs	OpenGL 4.5 DirectX 12 Vulkan 1.0 API support includes: CUDA C, CUDA C++, DirectCompute , OpenCL
Available Graphics Drivers	Windows 11 Windows 10 Windows 8.1 Windows 7 Linux
	HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
Notes	*P400, P600 and P1000 only have mini-DisplayPort TM (mDP) video ports.
	Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters included After market option kit:Two mDP-to-DP Adapters included
	Additional mDP-to-DP Adapters are available as Factory Configuration or Option Kit accessories:
	- 2MY05AA - HP miniDP-to-DP Adapter Cables
	- 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

AMD Radeon TM Pro W6600 8GB Graphics	Form Factor	Full height, Single Slot, 241mm length
	Graphics Controller	AMD Radeon TM PR W6600 XT Graphics GPU: AMD RDNA 2 Memory: 8GB GDDR6 Power: 130 Watts, 6-pin Power Cable Cooling: Active, Dual Axial fan
	Bus Type	PCI Express 4.0 x16
	Connectors	4x DisplayPort 1.4 with DSC
	Maximum Resolution	DisplayPort™ 1.4 with DSC: - up to 4x @ 3840x2160px (4K) - up to 4x @ 5120x2880px (5K) - up to 1x @ 7680x4320px (8K)
	Display Outputs	4x DP
	Shading Architecture	Microsoft DirectX 12 Shader Model 6.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Feature Level 12_1 Vulkan 1.1 OpenCL 2.2
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit (selected distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

Technical Specifications - Graphics			
AMD Radeon [™] RX 6700 XT 12GB Graphics	Form Factor	Dual slot, Full Length (254mm L x 38mm W x 108.65mm H)	
	Graphics Controller	AMD Radeon TM RX 6700 XT Graphics GPU: 2560 Navi2 Stream Processors Memory: 12GB GDDR6 Power: 230 Watts, Standard graphics 8pin + 6pin auxiliary power Cooling: Active, Dual Axial fan	
	Bus Type Connectors	PCI Express 4.0 x16 3DP 1.4 + HDMI 2.1 Outputs	
	Maximum Resolution	DisplayPort TM 1.4 with DSC: - up to 4x 5210 x 3200 x 24 bpp @ 60Hz, uncompressed - up to 7680 x 4320, compressed	
	Display Outputs Shading Architecture Supported Graphics APIs	3 DP + 1 HMDI Microsoft DirectX 12 Shader Model 6.1 OpenGL 4.6 DirectX 12 Feature Level 12_1 Vulkan 1.1 OpenCL 2.2	
	Available Graphics Drivers	Windows 11 Linux® 64-bit (selected distributions)	
		Typically, latest drivers will be available from amd.com	
	Notes	This is a Prosumer or Consumer graphics card, and not a Professional graphics card. As such, it does not have formal professional application validation, but is intended per AMD to function properly for game development, real-time engine, and many prosumer application workloads. Customers using Prosumer or Consumer graphic cards are likely to experience higher acoustics in comparison with Professional graphic cards. The higher acoustics observed with non-professional graphics is expected, as HP Workstations' designs do not have control in this area.	
Radeon™ Pro WX 3100 4GB Graphics	8 Form Factor Graphics Controller	Low-Profile Single Slot (6.6"? Length) Radeon TM Pro WX 3100 Graphics Card GPU: 512 Stream Processors organized into 8 Compute Units Power: 50 Watts Cooling: Active	
	Memory	4GB GDDR5 memory Memory Bandwidth: 6 Gbps / 96 GB/s Memory Width: 128 bit	
	Connectors	2x Mini DisplayPort TM 1.4 plus 1x DisplayPort TM 1.4 - HDR ready connectors with HBR3 and MST support.	
		Factory Configured: No adapters included After market option kit: One mDP-to-DP cable adapters included	
	Maximum Resolution	Additional Mini DisplayPort TM -to-DisplayPort TM , DisplayPort TM -to-VGA or DisplayPort TM -to-DVI adapters are available as Factory Configuration or Option Kit accessories. 5K support @ 60Hz	
	Image Quality Features	• 1x single-cable 5K monitor, or 2x dual-cable 5K monitors 3x 4K support @ 60Hz Advanced support for 8-bit and 10-bit per RGB color component. High bandwidth scaler for high quality up and downscaling	

Display Output	3 full physical DP1.3 HBR3 / DP1.4 HDR outputs FreeSync support
GPU Architecture Supported Graphics APIs	Polaris DirectX [®] 12 OpenGL [®] 4.5 OpenCL [™] 2.0 Vulkan [™] 1.0
Available Graphics Drivers	
	HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
Notes	 HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
	 AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FireProTM and RadeonTM Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
	3. As of September 2016, certified for DisplayPort [™] 1.4 HBR3 and ready for DisplayPort [™] 1.4 HDR based on independent verification by DisplayPort [™] testing authority. HDR content requires that the system be configured with a fully HDR- ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.

Radeon™ Pro WX 3200 4GB Graphics	Form Factor Graphics Controller	Low-Profile Single Slot (2.75 "H x 6.6"? L) Radeon TM Pro WX 3200 Graphics Card GPU: 640 Stream Processors organized into 8 Compute Units Power: 56 Watts Cooling: Active
	Memory	4GB GDDR5 memory Memory Bandwidth: 96 GB/s Memory Width: 128 bit
	Connectors	4x Mini DisplayPort TM 1.4 - HDR ready connectors with HBR3 and MST support.
		Factory Configured: No adapters included After market option kit: One mDP-to-DP cable adapters included
		Additional Mini DisplayPort TM -to-DisplayPort TM , DisplayPort TM -to-VGA or DisplayPort TM -to-DVI adapters are available as Factory Configuration or Option Kit accessories.
	Maximum Resolution	5K support @ 60Hz
	Image Quality Features	• 1x single-cable 5K monitor, or 2x dual-cable 5K monitors 4x 4K support @ 60Hz Advanced support for 8-bit and 10-bit per RGB color component. High bandwidth scaler for high quality up and downscaling

Technical Specifications - Graphics

Display Output

	Display Output	4 full physical DP1.3 HBR3 / DP1.4 HDR outputs FreeSync support
	GPU Architecture	Polaris
	Supported Graphics APIs	DirectX [®] 12
		OpenGL [®] 4.6
		OpenCL TM 2.0
		Vulkan [™] 1.0
	Available Graphics Drivers	Windows 11
		Windows 10
		Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site:
		http://welcome.hp.com/country/us/en/support.html
	Notes	4. HDR content requires that the system be configured with a fully
		HDR-ready content chain, including: graphics card, monitor/TV,
		graphics driver and application. Video content must be graded in
		HDR and viewed with an HDR-ready player. Windowed mode
		content requires operating system support.
		5. AMD PowerTune and AMD ZeroCore Power are technologies
		offered by certain FirePro TM and Radeon TM Pro products, which are
		designed to intelligently manage GPU power consumption in
		response to certain GPU load conditions.
		6. As of September 2016, certified for DisplayPort TM 1.4 HBR3 and
		ready for DisplayPort TM 1.4 HDR based on independent
		verification by DisplayPort TM testing authority. HDR content
		requires that the system be configured with a fully HDR- ready
		content chain, including: graphics card, monitor/TV, graphics
		driver and application. Video content must be graded in HDR and
		viewed with an HDR-ready player. Windowed mode content
		requires operating system support.
Radeon™ Pro WX 4100 4GB	Form Factor	Low-Profile Single Slot (6.6"? Length)
Graphics	Graphics Controller	Radeon TM Pro WX 4100 Graphics card
-		GPU: 1024 Stream Processors organized into 16 Compute Units
		Power: 50 Watts
		Cooling: Active
	Memory	4GB GDDR5 memory
		Memory Bandwidth: 6 Gbps / 96 GB/s
		Memory Width: 128 bit
	Connectors	4x Mini DisplayPort TM 1.4 - HDR ready connectors with HBR3 and MST support.
		Factory Configured: Four mDP-to-DP cable adapters included After market option kit: Four mDP-to-DP cable adapters included
	Maximum Resolution	Additional DisplayPort-to-VGA or DisplayPort-to-DVI adapters are available as Factory Configuration or Option Kit accessories. 5K support @ 60Hz
		 1x single-cable 5K monitor, or 2x dual-cable 5K monitors 4x 4K support @ 60Hz
	Image Quality Features	Advanced support for 8-bit and 10-bit per RGB color component. High
	maye quality realules	bandwidth scaler for high quality up and downscaling
	Display Output	4 full physical DP1.3 HBR3 / DP1.4 HDR outputs
	•	FreeSync support

4 full physical DP1.3 HBR3 / DP1.4 HDR outputs

GPU Architecture Supported Graphics APIs	GCN 4th Generation DirectX [®] 12 OpenGL [®] 4.5 OpenCL TM 2.0 Vulkan TM 1.0
Available Graphics Drivers	Windows 11 Windows 10 Windows® 7 64-bit Linux® 64-bit (selected Enterprise distributions)
	HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
Notes	7. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
	8. AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro TM and Radeon TM Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
	9. As of September 2016, certified for DisplayPort TM 1.4 HBR3 and ready for DisplayPort TM 1.4 HDR based on independent verification by DisplayPort TM testing authority. HDR content requires that the system be configured with a fully HDR- ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windows mode content requires operating system support.
	Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters included After market option kit: Four mDP-to-DP Adapters included
	Additional mDP-to-DP Adapters are available as Factory Configuration or Option Kit accessories:
	10. 2MY05AA - HP miniDP-to-DP Adapter Cables
	11. 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

NVIDIA® T1000 4GB Graphics	Form Factor	Dimensions: 2.713"? H x 6.137"? L Single Slot
-	Graphics Controller	NVIDIA® T1000 Graphics Card Power: 50W Cooling: Active
	Bus Type	PCI Express 3.0 x16
	Memory	Size: 4GB GDDR6 Memory Bandwidth: Up to 160 GB/s Memory Width: 128-bit
	Connectors	4x mini DisplayPort™ 1.4a
	Maximum Resolution	7680 x 4320 @ 120Hz
	Display Output	Maximum number of displays: 4 displays
	Architecture	NVIDIA [®] Turing TM
	Supported Graphics APIs	xx
	Available Graphics Drivers	Windows 11 Windows 10 Windows 8.1 Microsoft Windows 7 Professional 64bit Linux® - Full OpenGL [®] implementation, complete with NVIDIA® Quadro® and ARB extensions
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® T1000 8GB Graphics	Form Factor	Dimensions: 2.713"? H x 6.137"? L Single Slot Weight: 132.6 grams
	Graphics Controller	NVIDIA® T1000 Graphics Card Power: 50W Cooling: Active
	Bus Type	PCI Express 3.0 x16
	Memory	Size: 8GB GDDR6 Memory Bandwidth: Up to 160 GB/s Memory Width: 128-bit
	Connectors	4x mini DisplayPort [™] 1.4a
	Maximum Resolution	7680 x 4320 @ 120Hz
	Display Output	Maximum number of displays: 4 displays
	Architecture	NVIDIA [®] Turing TM
	Available Graphics Drivers	Windows 10 Windows 8.1 Windows 7 Professional Linux® - Full OpenGL [®] implementation, complete with NVIDIA® Quadro® and ARB extensions HP qualified drivers may be preloaded or available from the HP support Web
		site: http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX A2000 6GB Graphics	Form Factor	Dimensions: 2.713"? H x 6.6"? L Dual slot, half-height Weight: 295 grams (without extender)
	Graphics Controller	NVIDIA® RTX A2000 Graphics Card Power: 70W Cooling: Active
	Bus Type	PCI Express 4.0 x16
	Memory	Size: 6GB GDDR6 Memory Bandwidth: Up to 288 GB/s Memory Width: 192-bit
	Connectors	4x mini-DisplayPort [™] 1.4a
	Maximum Resolution	Up to 4x 5120 x 2880 x 24bpp @ 60Hz
	Architecture	NVIDIA® Ampere TM
	Supported Graphics APIs	CUDA, OpenCL [™] 1.x
	Available Graphics Drivers	Microsoft Windows 10 Linux® 64-bit (selected Enterprise distributions) HP qualified drivers may be preloaded or available from the HP support Web site:
		http://welcome.hp.com/country/us/en/support.html
	Notes 1.	RTX A2000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately as AMO:
		a. 2MY05AA - HP Single miniDP-to-DP Adapter Cable
		b. 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables
	2.	Two mDP-to-DP adapters are included with the RTX A2000 when it is ordered as an AMO kit.

NVIDIA® RTX A2000 12GB Graphics	Form Factor Graphics Controller	Dimensions: 2.713"? H x 6.6"? L Dual slot, half-height Weight: 295 grams (without extender) NVIDIA® RTX A2000 Graphics Card Power: 70W
	Bus Type	Cooling: Active PCI Express 4.0 x16
	Memory	Size: 12GB GDDR6 Memory Bandwidth: Up to 288 GB/s Memory Width: 192-bit
	Connectors	4x mini-DisplayPort [™] 1.4a
	Maximum Resolution	Up to 4x 5120 x 2880 x 24bpp @ 60Hz
	Architecture	NVIDIA [®] Ampere TM
	Supported Graphics APIs	CUDA, OpenCL [™] 1.x
	Available Graphics Drivers	Microsoft Windows 11 Microsoft Windows 10 Linux® 64-bit (selected Enterprise distributions) HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
	Notes 1.	RTX A2000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately as AMO:
		a. 2MY05AA - HP Single miniDP-to-DP Adapter Cable

Technical Specifications - Graphics

b. 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

Two mDP-to-DP adapters are included with the RTX A2000 when it is ordered as an AMO kit.

NVIDIA® Quadro® P4000 8GB Graphics	Form Factor	Dimensions: 4.4"?H x 9.5"?L Single-slot, full-height Weight: 475 grams (without extender)
	Graphics Controller	NVIDIA® Quadro® P4000 Graphics Card GPU: 1792 CUDA cores Power: 120 Watts Cooling: Active
	Bus Type	PCI Express 3.0 x16
	Memory	Size: 8GB GDDR5 Memory Bandwidth: 243 GB/s Memory Width: 256-bit
	Connectors	4 x DisplayPort 1.4 3-pin mini-DIN connector via optional bracket 1 x 6-pin auxiliary power connector 4-pin header for stereo signal SYNC connector for Quadro® Sync II 2 x SLI connectors
		Factory Configured Option: No video cable adapter included After Market Option: No video cable adapter included
		Additional DisplayPort-to-VGA, DisplayPort-to-HDMI, or DisplayPort-to- DVI adapters are available as accessories
	Maximum Resolution	Dual-link internal TMDS (DVI 1.0): - up to 2560 x 1600 x 32 bpp @ 60 Hz
		Single-link internal TMDS (DVI 1.0): - up to 1920 x 1200 x 32 bpp @ 60 Hz
		HDMI™ 2.0b (requires DP to HDMI adapter): - up to 5120 x 2880 x 24 bpp @ 60Hz
		DisplayPort: - up to 4096 x 2160 x 30 bpp @ 60Hz - up to 2560 x 1600 x 30 bpp @ 120 Hz - supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST)
		Using two DP outputs, the P4000 can drive one dual DP input display with 5120 x 2880 x 30 bpp @ 60Hz resolution.
	Image Quality Features	Advanced support for 8-bit, 10-bit, and 12-bit per RGB color component. HDCP 2.2 support over DisplayPort, DVI, and HDMI connectors NVIDIA 3D Vision TM and other 3D stereo technologies NVIDIA Mosaic and nView
	Display Output	Maximum number of displays - 4 direct attached monitors
		Maximum number of monitors across all available Quadro P4000 outputs is 4.

Maximum number of monitors across all available Quadro P4000 outputs is 4.

Shading Architecture Supported Graphics APIs	Shader Model 5.1 OpenGL 4.5 DirectX 12 Vulcan 1.0
	API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL, Java, Python, and Fortran
Available Graphics Driver	 Windows 11 Windows 10 Windows 7 Linux[®] - Full OpenGL implementation, complete with NVIDIA and ARB extensions
	HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
Notes 2.	Quadro P4000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately.
3.	Quadro P4000 offered as an After Market Option does not include video cables. Video cable adapters must be ordered separately.

NVIDIA® Quadro® P5000 16GB Graphics	Form Factor	Full-Height Dual Slot (4.4"? Height x 10.5"? Length) Weight: 815 grams / 1.80 lbs
	Graphics Controller	NVIDIA® Quadro® P5000 graphics GPU: 2560 NVIDIA® CUDA® Parallel Processing Cores Power: 180 Watts Cooling: Active
	Memory	16GB GDDR5X memory Memory Bandwidth: Up to 288 GB/s Memory Width: 256 bit ECC Memory (disabled by default)
	Connectors	DP (x4) with HDR support DL-DVI(D) 3-pin mini-DIN connector SLI connector NVIDIA® Quadro® Sync connector (compatible with NVIDIA® Quadro® II Sync) One 8-pin auxiliary power connector
		Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.
		DVI to VGA, DisplayPort TM to VGA, DisplayPort TM to DVI, and DisplayPort TM to Dual-Link DVI adapters available as accessories.
	Maximum Resolution	5K support @ 60Hz 1x single-cable 5K monitor, or 2x dual-cable 5K monitors

Technical Specifications - Graphics Image Quality Features Advanced support for 8-bit, 10-bit, and 12-bit per RGB color component. HDCP 2.2 support over DisplayPortTM, DVI, and HDMI connectors NVIDIA[®] 3D VisionTM and other 3D stereo technologies NVIDIA Mosaic and nView Desktop Management Display Outputs¹ 4x DP1.4 HDR outputs (up to 3840x2160 UHD @ 120Hz refresh, or up to 8K at 30Hz) 1x Dual-link DVI-D output (up to 2560 x 1600 @ 60 Hz and 1920x1200 @ 120 Hz) NVIDIA Pascal[™] **GPU** Architecture DirectX[®]12, OpenGL[®] 4.5, OpenCLTM 1.0, VulkanTM 1.0 **Supported Graphics APIs** Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCLTM, Java, Python, and Fortran Windows 11 **Available Graphics Drivers** Windows 10 Windows 7 64-bit Linux[®] 64-bit HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html Notes 1- Supports up to a total of 4 displays NVIDIA® Ouadro® **Form Factor** Full-Height Dual Slot (4.4"? Height x 10.5"? Length) Weight: 967 grams / 2.14 lbs P6000 24GB Graphics **Graphics Controller** NVIDIA[®] Quadro[®] P6000 graphics GPU: 3840 NVIDIA[®] CUDA[®] Parallel Processing Cores Power: 250 Watts **Cooling: Active** Memory 24GB GDDR5X memory Memory Bandwidth: Up to 432 GB/s Memory Width: 384 bit ECC Memory (disabled by default) DP (x4) with HDR support Connectors DL-DVI(D) 3-pin mini-DIN connector SLI connector Quadro Sync connector (compatible with Quadro II Sync) One 8-pin auxiliary power connector Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card. DVI to VGA, DisplayPortTM to VGA, DisplayPortTM to DVI, and DisplayPortTM to Dual-Link DVI adapters available as accessories. **Maximum Resolution** 5K support @ 60Hz 1x single-cable 5K monitor, or 2x dual-cable 5K monitors

Image Quality Features	Advanced support for 8-bit, 10-bit, and 12-bit per RGB color component.
	HDCP 2.2 support over DisplayPort, DVI, and HDMI connectors NVIDIA 3D Vision TM and other 3D stereo technologies NVIDIA Mosaic and nView
Display Outputs ¹	4x DP1.4 HDR outputs (up to 3840x2160 UHD @ 120Hz refresh, or up to 8K at 30Hz)
	1x Dual-link DVI-D output (up to 2560 x 1600 @ 60 Hz and 1920x1200 @ 120 Hz)
GPU Architecture	NVIDIA Pascal TM
Supported Graphics APIs	DirectX [®] 12, OpenGL [®] 4.5, OpenCL TM 1.0, Vulkan TM 1.0 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL TM , Java, Python, and Fortran
Available Graphics Drivers	Windows 11 Windows 10 64-bit Windows 7 64-bit Linux [®] 64-bit
	HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
Notes	1- Supports up to a total of 4 displays

NVIDIA® Quadro® GP100 16GB Graphics	Form Factor Graphics Controller	Dual Slot (4.4"? Height x 10.5"? Length) Weight: 989 grams +72 grams extender NVIDIA® QUADRO® GP100 GPU: 3584 NVIDIA CUDA® Parallel Processing Cores Power: 235 Watts Cooling: Active
	Memory	16GB HBM2 Memory Bandwidth: Up to 717 GB/s Memory Width: 4096-bit ECC Memory (disabled by default)
	Connectors	DP (x4) with HDR support DL-DVI(D) 3-pin mini-DIN connector via optional bracket 4-pin header for stereo signal Quadro Sync connector (compatible with Quadro II Sync) One 8-pin auxiliary power connector (2x) NVLink connectors
		Factory configured option: 8-pin power adapter included with card. After market option Kit: 8-pin power adapter included with card.
		DVI to VGA, DisplayPort TM to VGA, DisplayPort TM to DVI, and DisplayPort TM to Dual-Link DVI adapters available as accessories.
	Maximum Resolution	5K support @ 60Hz 1x single-cable 5K monitor, or 2x dual-cable 5K monitors
	Image Quality Features	s HDR support over DisplayPort [™] 1.4 (SMPTE 2084/2086, BT. 2020) (4K @ 60 Hz 10b/12b HEVC Decode, 4K @ 60 Hz 10b HEVC Encode)

	HDCP 2.2 support over DisplayPort TM , DVI, and HDMI connectors NVIDIA 3D Vision TM technology NVIDIA Mosaic and nView Desktop Management
Display Outputs	4x DP1.4 MST & HDR2 outputs (up to 5120 x 2880 @ 60Hz) 1x Dual-link DVI-D output (up to 2560 x 1600 @ 60 Hz) 1x Single-link DVI-D output (up to 1920 x 1200 @ 60 Hz) HDMI [™] 2.0b (up to 5120 x 2880 @ 60Hz)*
	*requires DP to HDMI adapter
GPU Architecture	
Supported Graphics APIs	DirectX®12 , OpenGL® 4.5, Vulkan™ 1.0 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL, Java, Python, and Fortran
Available Graphics Drivers	Windows 11 Windows 10 Windows 7 Professional 64-bit Linux®
	HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
	Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters included After market option kit: No adapters included

NVIDIA® Quadro® GV100 32GB Graphics	Form Factor Graphics Controller	Dual Slot (4.4"? Height x 10.5"? Length) Weight: 980 grams + 72 grams extender NVIDIA® QUADRO® GV100 GPU: 5120 NVIDIA® CUDA® Parallel Processing Cores Power: 250 Watts Cooling: Active
	Memory	32GB HBM2 memory Memory Bandwidth: Up to 870 GB/s Memory Width: 5120-bit ECC Memory (disabled by default)
	Connectors	DP (x4) with HDR support 3-pin mini-DIN connector via optional bracket 4-pin header for stereo signal Quadro Sync connector (compatible with Quadro II Sync) One 8-pin auxiliary power connector (2x) NVLink for GV100 connectors (via optional kit) After market option Kit: no power adapter included with card. DisplayPort TM to VGA, DisplayPort TM to DVI (single-link and dual-link), and DisplayPort TM to HDMI adapters available as accessories.

Maximum Resolution	5K support @ 60Hz 1x single-cable 5K monitor, or 2x dual-cable 5K monitors
Image Quality Features	HDR support over DisplayPort TM 1.4 (SMPTE 2084/2086, BT. 2020) (4K @ 60 Hz 10b/12b HEVC Decode, 4K @ 60 Hz 10b HEVC Encode) HDCP 2.2 support over DisplayPort TM and HDMI connectors NVIDIA 3D Vision TM technology NVIDIA Mosaic and nView Desktop Management
Display Outputs	4x DP1.4 HDR2 outputs (up to 5120 x 2880 @ 60Hz)
GPU Architecture	NVIDIA® Volta TM
Supported Graphics APIs	DirectX®12, OpenGL® 4.5 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL TM , Java, Python, and Fortran
Available Graphics Drivers	Windows 11 Windows 8 & 8.1 64-bit Windows 7 64-bit Linux® 64-bit
	HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
	Factory Configured (Z4/Z8 G4 Workstation): No adapters included After market option kit: No adapters included

NVIDIA® Quadro® RTX 4000 8GB Graphics	Form Factor	Full-Height Single Slot (4.4"? Height x 9.5"? Length) Weight: 550 grams / 1.21 lbs
	Graphics Controller	NVIDIA® Quadro® RTX 4000 Graphics IGPU: 2304 NVIDIA® CUDA® Parallel Processing Cores Power: 160 Watts Cooling: Active
	Memory	8GB GDDR6 memory Memory Bandwidth: Up to 416 GB/s Memory Width: 384 bit
	Connectors	3x DP 1.4a and VirtualLink Quadro Sync connector (compatible with Quadro II Sync) One 8-pin auxiliary power connector
		Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.
		DVI to VGA, DisplayPort [™] to VGA, DisplayPort [™] to DVI, and DisplayPort [™] to Dual-Link DVI adapters available as accessories.
	Maximum Resolution	7680x4320 @ 60Hz

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	Image Quality Features	Advanced support for 8-bit, 10-bit, and 12-bit per RGB color component. HDCP 2.2 support over DisplayPort TM , DVI, and HDMI connectors NVIDIA® 3D Vision TM and other 3D stereo technologies NVIDIA® Mosaic and nView
	Display Outputs ¹	3x DP 1.4a and VirtualLink ² (7680x4320 @ 60Hz)
	Supported Graphics APIs	DirectX [®] 12, OpenGL [®] 4.5, OpenCL TM 1.0, Vulkan TM 1.0 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL TM , Java, Python, and Fortran
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
	Notes	 Supports up to a total of 4 displays VirtualLink's USB-CTM (data) cannot be disabled at a hardware level
NVIDIA® RTX A4000 16GB Graphics	Form Factor	Full-Height Single Slot (4.4"? Height x 9.5"? Length)
	Graphics Controller	NVIDIA® RTX A4000 Graphics GPU: 6144 NVIDIA® CUDA® Parallel Processing Cores Power: 140 Watts Cooling: Active
	Memory	16GB GDDR6 memory Memory Bandwidth: Up to 448 GB/s Memory Width: 256 bit
	Connectors	4x DP One 6-pin auxiliary power connector
		Factory configured option: No video cable adapter included with card.
		After market option Kit: No video cable adaptor included with card.
		DVI to VGA, DisplayPort TM to VGA, DisplayPort TM to DVI, and DisplayPort TM to Dual-Link DVI adapters available as accessories.
	Maximum Resolution	7680x4320 @ 60Hz
	Display Outputs ¹	4x DP
	Supported Graphics APIs	DirectX [®] 12, OpenGL [®] 4.5, OpenCL [™] 1.0, Vulkan [™] 1.0 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL [™] , Java, Python, and Fortran
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

Technical	Specifications	- Graphics
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NVIDIA® RTX A4500 20GB Graphics	Form Factor	Full-Height Dual Slot (4.4"? Height x 10.5"? Length)
	Graphics Controller Memory	NVIDIA® RTX A4500 Graphics GPU: 7168 NVIDIA® CUDA® Parallel Processing Cores Power: 200 Watts Cooling: Active 20GB GDDR6 memory Memory Bandwidth: Up to 640 GB/s Memory Width: 320 bit
	Connectors	4x DP One 8-pin auxiliary power connector
		Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.
		DVI to VGA, DisplayPort [™] to VGA, DisplayPort [™] to DVI, and DisplayPort [™] to Dual-Link DVI adapters available as accessories.
	Maximum Resolution	7680x4320 @ 60Hz
	Display Outputs ¹	4x DP
	Supported Graphics APIs	DirectX®12, OpenGL® 4.5, OpenCL™ 1.0, Vulkan™ 1.0 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® Quadro® RTX 5000 16GB Graphics	Form Factor	Full-Height Dual Slot (4.4"? Height x 10.5"? Length) Weight: 975 grams + 75 grams extender
	Graphics Controller	NVIDIA® QUADRO® RTX 5000 GPU: 3072 CUDA cores Power: 265 Watts Cooling: Active
	Memory	16GB HBM2 memory Memory Bandwidth: Up to 448 GB/s ECC Memory (disabled by default)
	Connectors	DP (x4) with HDR support 3-pin mini-DIN connector via optional bracket 4-pin header for stereo signal Quadro Sync connector (compatible with Quadro II Sync) One 8-pin auxiliary power connector (2x) NVLink for RTX 5000 connectors (via optional kit) After market option Kit: no power adapter included with card.

Maximum Resolution	DisplayPort [™] to VGA, DisplayPort [™] to DVI (single-link and dual- link), and DisplayPort [™] to HDMI adapters available as accessories. DisplayPort [™] 1.4: 7680x4320 @ 60Hz
Image Quality Features	 B HDR support over DisplayPort[™] 1.4 (SMPTE 2084/2086, BT. 2020) (4K @ 60 Hz 10b/12b HEVC Decode, 4K @ 60 Hz 10b HEVC Encode) HDCP 2.2 support over DisplayPort[™] and HDMI connectors NVIDIA 3D Vision[™] technology NVIDIA Mosaic and nView Desktop Management
Display Outputs	4x DP1.4 HDR2 outputs (up to 7680x4320 @ 60Hz)
GPU Architecture	NVIDIA® Volta TM
Supported Graphics APIs	DirectX®12, OpenGL® 4.5 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL TM , Java, Python, and Fortran
Available Graphics Drivers	Windows 11 Windows 10 Windows 8 & 8.1 64-bit Windows 7 64-bit Linux® 64-bit
	HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
	Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters included After market option kit: No adapters included
	*VirtualLink's USB-C TM (data) cannot be disabled at a hardware level

NVIDIA® Quadro® RTX 6000 24GB Graphics	Form Factor Graphics Controller	Full-Height Dual Slot (4.4"? Height x 10.5"? Length) Weight: 995 grams + 75 grams extender NVIDIA® QUADRO® RTX 6000 GPU: 4608 CUDA cores Power: 295 Watts Cooling: Active
	Memory	24GB HBM2 memory Memory Bandwidth: Up to 672 GB/s ECC Memory (disabled by default)
	Connectors	DP (x4) with HDR support 3-pin mini-DIN connector via optional bracket 4-pin header for stereo signal Quadro Sync connector (compatible with Quadro II Sync) One 8-pin auxiliary power connector (2x) NVLink for RTX 5000 connectors (via optional kit)

	After market option Kit: no power adapter included with card.
Maximum Resolution	DisplayPort [™] to VGA, DisplayPort [™] to DVI (single-link and dual- link), and DisplayPort [™] to HDMI adapters available as accessories. DisplayPort [™] 1.4: 7680x4320 @ 60Hz
Image Quality Feature	 HDR support over DisplayPort[™] 1.4 (SMPTE 2084/2086, BT. 2020) (4K @ 60 Hz 10b/12b HEVC Decode, 4K @ 60 Hz 10b HEVC Encode) HDCP 2.2 support over DisplayPort[™] and HDMI connectors NVIDIA 3D Vision[™] technology NVIDIA Mosaic and nView Desktop Management
Display Outputs	4x DP1.4 HDR2 outputs (up to 7680x4320 @ 60Hz)
GPU Architecture	NVIDIA [®] Volta TM
Supported Graphics APIs	DirectX®12, OpenGL® 4.5 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran
Available Graphics Drivers	Windows 11 Windows 10 Windows 8 & 8.1 64-bit Windows 7 64-bit Linux® 64-bit
	HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
	Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters included After market option kit: No adapters included
	*VirtualLink's USB-C TM (data) cannot be disabled at a hardware level

NVIDIA® RTX A5000 24GB Graphics	Form Factor	Full-Height Dual Slot (4.4"? Height x 10.5"? Length) Weight: 1049 grams + 80 grams extender
	Graphics Controller	NVIDIA® RTX A5000 GPU: 8192 CUDA Cores Power: 230W Cooling: Active
	Memory	24GB GDDR6 Memory Bandwidth: Up to 768GB/s ECC Memory (disabled by default)
	Connectors	DP (x4) with HDR support One 8-pin auxiliary power connector
		After market option Kit: no power adapter included with card.
		DisplayPort™ to VGA, DisplayPort™ to DVI (single-link and dual- link), and DisplayPort™ to HDMI adapters available as accessories.
	Maximum Resolution	DisplayPort™ 1.4a: 7680x4320 @ 120Hz
	Display Outputs	4x DP1.4a HDR2 outputs (up to 7680x4320 @ 120Hz)
	GPU Architecture	NVIDIA [®] Ampere TM
	Supported Graphics APIs	DirectX®12, OpenGL® 4.5 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran
	Available Graphics Drivers	Windows 11 Windows 10 Windows 7 64-bit HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters included After market option kit: No adapters included

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NVIDIA [®] RTX TM A6000 48GB Graphics	Form Factor	Full-Height Dual Slot (4.4"? Height x 10.5"? Length) Weight: 1230 grams / 2.71 lbs (with extender)
	Graphics Controller	NVIDIA® RTX TM A6000 Graphics GPU: 10752 NVIDIA® CUDA® Parallel Processing Cores Power: 300 Watts Cooling: Active
	Memory	48GB GDDR6 memory ECC optional Memory Bandwidth: Up to 768 GB/s Memory Width: 384 bit
	Connectors	4x DP 1.4a Quadro Sync II connector Ampere NVLink® Stereo Sync Requires 8-pin CPU auxiliary power
	Maximum Resolution	5120x2880 @ 60Hz (up to 4 displays)
	Display Outputs	4x DP 1.4 (7680x4320 @ 60Hz)
	Supported Graphics APIs	DirectX [®] 12, OpenGL [®] 4.6, OpenCL TM 1.0, Vulkan TM 1.0 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL TM , Java, Python, and Fortran TM
	Available Graphics Drivers	Windows 11 Windows 10 Linux® 64-bit
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® Quadro® RTX 8000 48GB Graphics	Form Factor	Full-Height Dual Slot (4.4"? Height x 10.5"? Length) Weight: 1070 grams / 2.35 lbs
	Graphics Controller	NVIDIA® Quadro® RTX 8000 Graphics GPU: 4608 NVIDIA® CUDA® Parallel Processing Cores Power: 295 Watts Cooling: Active
	Memory	48GB GDDR6 memory Memory Bandwidth: Up to 672 GB/s Memory Width: 384 bit
	Connectors	4x DP 1.4a and VirtualLink Quadro Sync connector (compatible with Quadro II Sync) One 8-pin + 6-pin auxiliary power connector
		Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.
		DVI to VGA, DisplayPort [™] to VGA, DisplayPort [™] to DVI, and DisplayPort [™] to Dual-Link DVI adapters available as accessories.
	Maximum Resolution	7680x4320 @ 60Hz

Technical Specifications - Graphics

	C	Advanced support for 8-bit, 10-bit, and 12-bit per RGB color component.
	HDCP 2.2 support over DisplayPort TM , DVI, and HDMI connectors NVIDIA [®] 3D Vision TM and other 3D stereo technologies NVIDIA [®] Mosaic and nView	
	Display Outputs ¹	4x DP 1.4a and VirtualLink (7680x4320 @ 60Hz) DirectX [®] 12, OpenGL [®] 4.5, OpenCL TM 1.0, Vulkan TM 1.0 Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0, OpenCL TM , Java, Python, and Fortran
	D Available Graphics V Drivers L H S	
		Windows® 10 64-bit Linux® 64-bit
		HP qualified drivers may be preloaded or available from the HP support Web site:
		http://welcome.hp.com/country/us/en/support.html
	Notes	 Supports up to a total of 4 displays VirtualLink's USB-CTM (data) cannot be disabled at a hardware level
MD Radeon TM Pro W6800	Form Factor	Dual slot, Full-height (4.4"? H x 10.5"? L)
2GB Graphics	Graphics Controller	Radeon TM Pro W6800 graphics
		GPU: 3840 cores Power: 261 Watts
		Cooling: Active fan heatsink
	Memory	32GB GDDR6 memory
	i lemory	Memory Bandwidth: Up to 512 GB/s
		Memory Width: 256 bit
	Connectors	6 mDP (miniDisplayPort TM) 1.4 Connectors with DSC
	Maximum Resolution	Up to 6x 5120 x 2880 x 24 bpp @ 60Hz
		 Supports Multi-Stream Transport (MST)
	GPU Architecture	RDNA TM 2
	Supported Graphics APIs	OpenGL [®] 4.6
		DirectX® 12 Ultimate (HW RayTracing) Vulkan™ 1.2
		API support includes OpenCL [™] 2.1
	Available Graphics Drivers	Windows 11
		Windows 10
		Linux [®] 64-bit
		HP qualified drivers may be preloaded or available from the HP support Web
		site:
		http://welcome.hp.com/country/us/en/support.html
	Notes	W6800 only has mini-DisplayPort [™] (mDP) video ports
		 Configure-to-order must specify AV options to add any
		required mDP-to-DP Adapters
		Two mDP-to-DP Adapters are included in the RTX A2000 AMO kits. If more mDP-to-DP Adapters are needed, Adapters can be ordered separately as AMC
		 2MY05AA - HP Single miniDP-to-DP Adapter Cable 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

Radeon[™] Pro WX 7100 8GB Form Factor

Full-Height Single Slot (9.5"? Length)

Technical Specifications - Graphics Graphics Radeon[™] Pro WX 7100 graphics **Graphics Controller** GPU: 2304 Stream Processors organized into 36 Compute Units Power: 130 Watts **Cooling: Active** 8GB GDDR5 memory Memorv Memory Bandwidth: 7 Gbps / 224 GB/s Memory Width: 256 bit Connectors 4x Display Port 1.4 - HDR ready connectors with HBR3 and MST support. Factory Configured: No video cable adapter included After market option kit: No video cable adapter included Additional DisplayPort-to-VGA or DisplayPort-to-DVI adapters are available as Factory Configuration or Option Kit accessories. 5K support @ 60Hz **Maximum Resolution** 1x single-cable 5K monitor, or 2x dual-cable 5K monitors **Image Quality Features** Advanced support for 8-bit, 10-bit, and 16-bit per RGB color component. High bandwidth scaler for high quality up and downscaling **Display Output** 4 full physical DP1.3 HBR3 / DP1.4 HDR outputs FreeSync support **GPU** Architecture **GCN 4th Generation** DirectX[®]12 **Supported Graphics APIs** OpenGL[®] 4.5 OpenCLTM 2.0 Vulkan[™] 1.0 Available Graphics Drivers Windows 11 Windows 10 Windows 7 64-bit Linux[®] 64-bit HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html Notes 12. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support. 13. Radeon VR Ready Creator Products are select Radeon Pro and AMD FirePro[™] GPUs that meet or exceed the Oculus Rift or HTC Vive recommended specifications for video cards/GPUs. Other hardware (including CPU) and system requirements recommended by Oculus Rift or HTC Vive should also be met in order to operate the applicable HMDs as intended. As VR technology, HMDs and other VR hardware and software evolve and/or become available. these criteria may change without notice. 14. AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FireProTM and RadeonTM Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions. 15. As of September 2016, certified for DisplayPort[™] 1.4 HBR3 and ready for DisplayPort[™] 1.4 HDR based on independent verification by DisplayPort[™] testing authority. HDR content

requires that the system be configured with a fully HDR-ready

content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.

Radeon [™] Pro WX 9100 16GB Graphics	Form Factor	Dual Slot (4.4"? Height x 10.5"? Length)
	Graphics Controller	Radeon TM Pro WX 9100 graphics GPU: 4096 Stream Processors Power: 250 Watts Cooling: Active
	Memory	16GB HBM2 memory Memory Bandwidth: Up to 483 GB/s Memory Width: 2048 bit
	Connectors	6x Mini DisplayPort 1.4 - HDR ready connectors with HBR3 and MST support.
		Factory Configured: No video cable adapter included After market option kit: No video cable adapter included
		Additional DisplayPort-to-VGA or DisplayPort-to-DVI adapters are available as Factory Configuration or Option Kit accessories.
	Maximum Resolution	8K support @ 60Hz Single monitor, single or dual-cable
	Image Quality Features	Advanced support for 8-bit, 10-bit, and 16-bit per RGB color component. High bandwidth scaler for high quality up and downscaling
	Display Output	6 full physical mDP 1.4 HDR Ready outputs FreeSync support
	GPU Architecture	Vega TM
	Supported Graphics APIs	DirectX [®] 12.1 OpenGL [®] 4.5 OpenCL TM 2.0 Vulkan TM 1.0
	Available Graphics Drivers	Windows 11 Windows 10 Windows 7 available from AMD Linux® 64-bit
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
	Notes	 HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support. Radeon VR Ready Creator Products are select Radeon Pro and AMD FireProTM GPUs that meet or exceed the Oculus Rift or HTC Vive recommended specifications for video cards/GPUs. Other hardware (including CPU) and system requirements recommended by Oculus Rift or HTC Vive should also be met in order to operate the applicable HMDs as intended. As VR technology, HMDs and

Technical Specifications - Graphics

other VR hardware and software evolve and/or become available, these criteria may change without notice.

- 3. AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro[™] and Radeon[™] Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
- 4. As of September 2016, certified for DisplayPort[™] 1.4 HBR3 and ready for DisplayPort[™] 1.4 HDR based on independent verification by DisplayPort[™] testing authority. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.

Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters included After market option kit:Two mDP-to-DP Adapters included

Additional mDP-to-DP Adapters are available as Factory Configuration or Option Kit accessories:

- 2MY05AA HP miniDP-to-DP Adapter Cables
- 2KW87A6 HP (Bulk 12) miniDP-to-DP Adapter Cables

NVIDIA® Quadro® Sync II	Part number	1WT20AA
	Dimensions (HxD)	6.0 inches ? 4.2 inches
	Devices Supported	NVIDIA® Quadro® P4000 NVIDIA® Quadro® P5000 NVIDIA® Quadro® P6000 NVIDIA® RTX TM A6000 NVIDIA® RTX TM A5000 NVIDIA® RTX TM A4000
	Bus Type	Requires one free mechanical PCIe bus slot. 6-pin PCI or SATA power connector
	PCI Form Factor	Full Height, half length, single slot
	Ports	2 RJ45 connectors for carrying frame lock signals over CAT5 cables. BNC Connector for external house synchronization.
	Internal Connectors	6 NVIDIA SLI® style edge fingers for connection to compatible GPUs
		 Included with the board are 4 12-Inch Short Sync Cables to connect to GPU's Included with the board are 2 24-Inch Long Sync Cables to connect to GPU's
	System Requirements	Requires one free mechanical PCIe bus slot. 6-pin PCI or SATA power connector Must be used with NVIDIA Quadro P4000, P5000 or P6000 graphics cards. Requires Quadro driver version R375 or later.
	Temperature - Operating	0° to 55° C
	Temperature - Storage	-40° to 60° C
	Relative Humidity - Operating	10% to 80%
	Power Requirements	Board power dissipation: <15W

Operating Systems Supported	Windows 11 Windows 10 Windows 7 64-bit Linux® 64-bit
Kit Contents	Contains: • Quadro Sync II Card • 4 x 12-Inch Short Sync Cables • 2 x 24-Inch Long Sync Cables (Two) • Quick Start Guide

Technical Specifications – Optical and Removable Storage

Optical and Removable Storage

HP 9.5mm Slim DVD Writer	Description Mounting Orientation Interface Type Dimensions (WxHxD) Supported Media Types	9.5mm height, tray-load Either horizontal or vertical SATA/ATAPI 128 x 9.5 x 127mm DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW	
	Disc Capacity	DVD-ROM Full Stroke DVD Full Stroke CD	8.5 GB DL or 4.7 GB standard < 200 ms (seek) < 200 ms (seek)
	Maximum Data Transfer Rates	CD ROM Read	CD-ROM, CD-R Up to 24X CD-RW Up to 24X
		DVD ROM Read	DVD+RW Up to 8X DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD-R Up to 8X DVD-R Up to 8X
	Power	Source DC Power Requirements DC Current	SATA DC power receptacle 5 VDC ± 5%-100 mV ripple p-p 5 VDC -< 800 mA typical, <1600 mA maximum
	Operating Environmental (all conditions non- condensing) Kit Contents	Temperature Relative Humidity Maximum Wet Bulb Temperature	41° to 122° F (5° to 50° C) 10% to 80% 84° F (29° C)
		HP SATA DVD Writer drive, installat	

Technical Specifications – Optical and Removable Storage

HP 9.5mm Slim DVD-ROM	Description	9.5mm height, tray-load	
Drive	Mounting Orientation	Either horizontal or vertical	
	Interface Type	SATA / ΑΤΑΡΙ	
	Dimensions (WxHxD)	128 x 9.5 x 127mm	
	Disc Capacity	DVD-ROM	Single layer: Up to 4.7 GB Double layer: Up to 8.5 GB
	Access Times	DVD-ROM Single Layer	< 110 ms (typical)
		CD-ROM Mode 1	< 110 ms (typical)
		Full Stroke DVD	< 230 ms (typical)
		Full Stroke CD	< 220 ms (typical)
	Power	Source	SATA DC power receptacle
		DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p
		DC Current	5 VDC - <800mA typical, < 1600 mA maximum
	Operating Environmental	Temperature	41° to 122° F (5° to 50° C)
	(all conditions non-	Relative Humidity	10% to 80%
	condensing)	Maximum Wet Bulb Temperature	84° F (29° C)
	Kit Contents	9.5mm Slim DVD-ROM Drive, 5.25" ODD Bay adapter/carrier, slim SATA data/power cable, installation guide	

HP HH DVD Writer (16X RW	Description	HP Half Height DVD Writer	
DVD-R)	Mounting Orientation	Either Horizontal or vertical	
	Interface Type	SATA	
	Dimensions (WxHxD)	146x42x165mm	
	Supported Media Types	DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-R	
	Disc Capacity	DVD-ROM	8.5 GB DL or 4.7 GB standard
		Full Stroke DVD	145ms (seek)
		Full Stroke CD	120ms (seek)
	Maximum Data Transfer Rates	CD ROM Read	CD-ROM, CD-R Up to 24X CD-RW Up to 24X
		DVD ROM Read	DVD+RW Up to 13X DVD-RW Up to 13X DVD+R DL Up to 12X DVD-R DL Up to 12X DVD-ROM Up to 12X DVD-ROM DL Up to 12X DVD-R Up to 16X DVD-R Up to 16X
	Power	Source	SATA DC power receptacle
		DC Power Requirements	5 VDC ± 5% -100 mV ripple p-p 12 VDC ± 10% -200 mV ripple p-p
		DC Current	5 VDC -<1500mA typical, <2000 mA maximum.

	Operating Environmental	able Storage Temperature 41° to 122° F (5° to 50° C)		
	(all conditions non-	Relative Humidity	10% to 90% (Non-Condensing)	
	condensing)	-	_	
	Operating Systems Supported	Windows 11, Windows 10, Windo Linux WS4**,5,6 Desktop/Workst	ows 7 Professional 64-bit. Red Hat Enterprise ation.	
		No driver is required for this device, Native support is provided by operating system. HP SATA DVD Writer drive, Installation guide.		
	Kit Contents			
HP 9.5mm Slim BDXL Blu-	Description	9.5mm height, tray-load		
Ray Writer	Mounting Orientation	Either horizontal or vertical		
	Interface Type	SATA/ATAPI		
	Dimensions (WxHxD)	128 x 9.5 x 127mm		
	Supported Media Types	BD-ROM BD-R BD-RE DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW		
	Disc Capacity	DVD-ROM	8.5 GB DL or 4.7 GB standard	
		Blu-ray	25 GB (single-layer) 50 GB (dual-layer) 100/128 GB (BDXL)	
		Full Stroke DVD	< 230 ms (seek)	
		Full Stroke CD	< 220 ms (seek)	
		Blu-ray	< 230 ms (seek) (Full Stroke Blu-ray)	
		Startup Time	(Time to drive ready from tray loading) BD-ROM (SL/DL) 25S / 28S BD-R (SL/DL) 25S / 28S BD-RE (SL/DL) 25S / 28S DVD-ROM (SL/DL) 18S / 18S DVD-R (SL/DL) 25S / 25S DVD-RW 25S DVD-RW 25S DVD+R (SL/DL) 25S / 25S DVD+RW 25S CD-ROM 15S	
	Maximum Data Transfer Rates	CD ROM Read	CD-ROM, CD-R Up to 24X CD-RW Up to 24X	
		DVD ROM Read	DVD+RW Up to 8X DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X	

Technical Specifications – Optical and Removable Storage

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		Blu-ray	BD-ROM Up to 6X BD-ROM DL Up to 6X BD-R Up to 6X BD-R DL Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X
	Power	Source	SATA DC power receptacle
		DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p
		DC Current	5 VDC -900 mA typical, 2000mA maximum
	Operating Environmental	Temperature	41° to 122° F (5° to 50° C)
	(all conditions non-	Relative Humidity	10% to 80%
	condensing)	Maximum Wet Bulb Temperature	84° F (29° C)
	Kit Contents	9.5mm Slim BDXL Blu-Ray Writer, 5.25" ODD Bay adapter/carrier, slim SATA data/power cable, installation guide	
		As Blu-ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.	
HP SD Card Reader	Description	Supports hardware ECC (Error Correction Code) function Supports hardware CRC (Cyclic Redundancy Check) function Supports SD 4-bit parallel transfer mode	
	Interface Type	USB 3.1 G1 High-speed interface	
	Dimensions (WxHxD)	1.15 x .9 x .15 in (29.00 x 23.6 x 3.15 Bay	mm) Fits conveniently in the Front IO
	Supported Media Types	Secure Digital Card (SD) Secure Digital High Capacity (SDHC) SD Extended Capacity Memory Card (SD Ultra High Speed II(SD UHSII)	SDXC)
		These additional media types are supported with a card adapter.	
		miniSD miniSD High Capacity Micro SD Memory Card (MicroSD) Micro SD High Capacity Memory Card (MicroSDHC)	
		Test Parameters/Conditions - Power applied, unit operating on system ±5%	
	Kit Contents	SD card reader	
	Approvals		ass Storage Class Bulk only Transport
		Specification Rev. 1.0, Compliant Intel Front Panel I/O Conne BSMI, C-Tick, VCCI, MIC, cUL, TUVT	
	Weight	0.35 lbs. (0.16 kg)	

Technical Specifications - Controller Cards

Controller Cards

HP Thunderbolt-3 Dual	Data Transfer Rate	Supports up to 40 Gb/s (40,000 Mb/s)
Port2 PCIe 1-port I/O Card	Devices Supported	Thunderbolt TM , Thunderbolt TM 2 and Thunderbolt TM 3 certified for Windows devices
	Bus Type	PCIe Slot. Slot 4 only
	Ports	Two Thunderbolt™ 3 external USB type-C output connectors (Rear) Two full size DisplayPort input connectors (Rear)
	Internal Connectors	One 2x5-Pin header connector
	System Requirements	Genuine Windows 10 Professional, slot 4 PCH PCIe slot.
	Temperature - Operating	50° to 131° F (10° to 55° C)
	Temperature - Storage	-22° to 140° F (-30° to 60° C)
	Relative Humidity - Operating	20% to 80%
	Compliances	FCC Part 15B, cULus 60950, CE Mark EN55022B(1995)/EN55024-1998 STD, Taiwan BSMI CNS13438, Korea MIC
	Operating Systems Supported	Genuine Windows 10 Professional.
	Kit Contents	HP Thunderbolt [™] 3 Dual Port PCIe I/O Card, 2- DisplayPort cables, GPIO (General-Purpose Input/Output) cables, Installation documentation and warranty card.

*Maximum speed requires DisplayPortTM and PCIe aggregation.

Technical Specifications - Networking and Communications

Networking and Communications

Integrated Intel I219 PCIe	Connector	RJ-45
GbE Controller	Controller	Intel I219 GbE platform LAN connect networking controller
	Data Rates Supported	10/100/1000 Mbps
	Boot ROM Support	PXE, UEFI
	Connect Speed LED	Link/Activity LED
	Indicators	 Off = No link Blinking = Activity Speed LED Off = 10Mbps Amber = 100Mbps Green = 1000Mbps
	Management Capabilities	Wake-On-LAN, Intel [®] Active Management Technology TM (AMT) 11.1x NOTE: Intel [®] AMT TM is not available on Intel Core X configs.
Integrated Intel I210	Connector	RJ-45
(not available on Intel	Controller	Intel [®] I210
Core X configs)	Data Rates Supported	10/100/1000 Mbps
	Boot ROM Support	PXE, UEFI
	Connect Speed LED Indicators	 Link/Activity LED Off = No link
		 Blinking = Activity
		Speed LED
		 Off = 10Mbps Amber = 100Mbps Green = 1000Mbps
	Management Capabilities	Wake-On-LAN

•	5	
Intel [®] I210-T1	Networking Interface	RJ-45
	System Interface	PCI Express 2.1 x1
	Networking Speeds Supported	10Mbps, 100Mbps, 1Gbps
	Cabling (up to 100m)	Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps
	Power Consumption (active-typical)	0.81W
	Physical Dimensions	Length: 6.7cm (2.64 inches) (Bracket) Width: 1.8cm (0.709 inches) Full-height end bracket: 12.07cm (4.755 inches) Low-profile end bracket: 8cm (3.15 inches)
	Connect Speed LED Indicators	 Link/Activity LED Off = No link Blinking = Activity
		Speed LED
		 Off = 10Mbps Green = 100Mbps Amber = 1Gbps
	Operating Temperature	0 °C to 55 °C (32 °F to 131 °F)
	Hardware Certifications	USA: FCC B, EU: UL CE, Japan: VCCI, Taiwan: BSMI, Australia/New Zealand: CTICK, Korea: KCC, Canada: ICES-003/NMB-003
Intel® 1350-T2	Networking Interface	2 x RJ-45
	System Interface	PCI Express 2.1 x4
	Networking Speeds Supported	10Mbps, 100Mbps, 1Gbps
	Cabling (up to 100m)	Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps
	Power Consumption (active-typical)	4.4W
	Physical Dimensions	Length: 13.54cm (5.33 inches) Width: 6.89 (2.71 inches) Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)
	Connect Speed LED Indicators	Link/Activity LED Off = No link Blinking = Activity Speed LED
		 Off = 10Mbps Green = 100Mbps

•	5	• Amber = 1Gbps
	Operating Temperature	0 °C to 55 °C (32 °F to 131 °F)
	Hardware Certifications	USA: FCC B,
		EU: UL CE, Japan: VCCI,
		Taiwan: BSMI,
		Australia/New Zealand: CTICK,
		Korea: KCC,
		Canada: ICES-003/NMB-003
Intel® 1350-T4	Networking Interface	4 x RJ-45
	System Interface	PCI Express 2.1 x4
	-	-
	Networking Speeds Supported	10Mbps, 100Mbps, 1Gbps
	Cabling (up to 100m)	Cat3 (or higher) for 10Mbps
		Cat5 (or higher) for 100Mbps
		Cat5e (or higher) for 1Gbps
	Power Consumption (active-typical)	5W
	Physical Dimensions	Length: 13.54cm (5.33 inches)
		Width: 6.89 (2.71 inches)
		Full-height end bracket: 12.0cm (4.725 inches)
		Low-profile end bracket: 7.92cm (3.117 inches)
	Connect Speed LED Indicators	Link/Activity LED
	indicators	• Off = No link
		• Blinking = Activity
		Speed LED
		• Off = 10Mbps
		 Green = 100Mbps
		• Amber = 1Gbps
	Operating Temperature	0 °C to 55 °C (32 °F to 131 °F)
	Hardware Certifications	USA: FCC B,
		EU: UL CE,
		Japan: VCCI, Taiwan: BSMI,
		Australia/New Zealand: CTICK,
		Korea: KCC,
		Canada: ICES-003/NMB-003

Intel [®] X550-T2	Networking Interface	2 x RJ-45
	System Interface	PCI Express 3 x4
	Networking Speeds	100Mbps, 1Gbps, 2.5Gbps, 5Gbps, 10Gbps
	Supported	
	Cabling (up to 100m)	Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps Cat6a (or higher) for 10Gbps
	Power Consumption (active-typical)	3.9W at 100Mbps 5.5W at 1Gbps 11.2W at 10Gbps
	Physical Dimensions	5.2 in x 2.7 in (without bracket)
	Connect Speed LED Indicators	Link/Activity LED
	indicators	 Off = No link Blinking = Activity Speed LED
		• Off = No link
		• Amber = <10Gbps
		• Green = 10Gbps
	Operating Temperature	0 °C to 55 °C (32 °F to 131 °F)
	Hardware Certifications	USA: FCC B,
		EU: UL CE,
		Japan: VCCI,
		Taiwan: BSMI,
		Australia/New Zealand: CTICK,
		Korea: KCC, Canada: ICES-003/NMB-003
Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC	Network Interface System Interface Networking Speeds Supported Cabling	1Gb LC Fiber 850 nm PCIeG2 x1, Half Height, Half Length 1000Base-X (1Gbps) 50/125 µm (core/cladding) multimode fiber optic cable up to 500m
	Cabling	$62.5/125 \mu\text{m}$ (core/cladding) multimode fiber optic cable up to 220m
	Power Consumption	1.5 Watts
	(active- typical) Physical Dimensions Connect Speed LED	8.8 cm x 6.9 cm (3.5 in x 2.7 in) ON: 1Gbps Link OFF: Link down
	Indicators Operating Temperature Hardware Certifications	-25°C to 70°C (-13°F to 158°F) IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC), IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation) RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Allied Telesis AT-2911T/2-901	Networking Interface	2 RJ-45
	System Interface	PCI Express 3 x1
	Networking Speeds Supported	10Mbps, 100Mbps, 1Gbps
	Cabling (up to 100m)	Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps
	Power Consumption (active-typical)	2.4W
	Physical Dimensions	Length: 8.8cm (3.5 inches) Width: 6.89 (2.71 inches) Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)
	Connect Speed LED Indicators	Link/Activity LED Off = No link Blinking = Activity
	Operating Temperature	0 °C to 40 °C (32 °F to 104 °F)
	Hardware Certifications	USA: FCC B, EU: UL CE, UKCA Japan: VCCI, Taiwan: BSMI, Australia/New Zealand: CTICK, Korea: KCC, Canada: ICES-003/NMB-003

Intel® X710-DA2	Networking Interface	2 SFP+ Ports for LC SFP+ Transceivers
10GBASE-SR Converged	System Interface	PCI Express 3.0 x8
Network Adapter	Networking Speeds Supported	1Gbps (with a 3 rd party transceiver), 10Gbps
	Cabling	LC fiber optic cabling with LC SFP+ Transceivers
	Power Consumption (active-typical)	4.3W
	Physical Dimensions	6.578 in x 2.703 in
	Connect Speed LED Indicators	Link/Activity LED
		 Off = No link Blinking = Activity Speed LED
		 Off = 10Mbps Green = 100Mbps Amber = 1Gbps
	Operating Temperature	0 °C to 55 °C (32 °F to 131 °F)
	Hardware Certifications	USA: FCC B, EU: UL CE, Japan: VCCI, Taiwan: BSMI, Australia/New Zealand: CTICK, Korea: KCC, Canada: ICES-003/NMB-003

Technical Specifications - Networking and Communications

Note: Windows 7 is NOT supported

10GbE SFP+ SR	Connector Type	LC
Transceiver	Cable Type	62.5/125um or 50/125um (core/cladding), graded-index, low metal content, multimode fiber optic, complying with ITU-T G.651 and ISO/IEC 793-2 Type A1b or A1a, respectively.
	Cable Length	2-300m
	Wavelength	850nm
	Form Factor	SFP+
	Physical Dimensions	0.47(h) x 0.54(w) x 2.19(d) inches (1.19 x 1.38 x 5.57 cm)
	Operating Temperature	0C to 45C (32F to 113F)
	Operating Humidity	0% to 85%, noncondensing
Intel® 8265 WLAN	Networking Speeds	802.11ac MU-MIMO (up to 867 Mbps) Bluetooth 4.2
	IEEE WLAN Standard	IEEE 802.11a/b/g/n/ac, 802.11d, 802.11e, 802.11h, 802.11i, 802.11w; 802.11r, 802.11k, 802.11v pending
	Bluetooth	4.2
	System Interface	PCI Express 2.1 x1
	Antenna	2x2

Summary of Changes

Summary of Changes

Date of change:	Version History:		Description of change:
November 1, 2017	From v1 to v2	Added	HP DisplayPort to HDMI Adapter, NVIDIA SLI 2-slot Graphics Connector and
			NVIDIA Quadro Sync II to Graphics section
		Changed	Graphics, Storage / Hard Drives and Memory sections, changed Front and
		-	internal view info on the Overview section, changed Operating Systems
			section, changed System Board section, changed System Configuration,
			DECLARED NOISE EMISSIONS and Physical Security and Serviceability section
November 29, 2017	From v2 to v3	Added	Processors, hard drives and graphics to offerings, added Intel Xeon W-2195
			to Processors section
		Changed	Wattage links on power supply section updated and Voltage links on
		e	efficientcy section updated
February 5, 2018	From v3 to v4	Added	Features and Supported Configurations for Intel® Core TM X- Series Processor
			Family
		Changed	Formatting
February 27, 2018	From v4 to v5	Added	Intel Core i9-X processors footnotes added to processors pre-installed
			section
March 27, 2018	From v5 to v6	Added	NVIDIA Quadro GP100 16GB Graphics, NVIDIA Quadro GV100 32GB Graphics
		laaca	and AMD Radeon Pro WX 9100 16GB Graphics as High End 3D in Graphics
			section
August 13, 2018	From v6 to v7	Added	Footnote to Networking and Communications section
//dgust 15, 2010		Changed	Operating Systems section
August 24, 2018	From v7 to v8	Changed	Format
September 21, 2018		Added	Intel Optane SSD 905p AiC 280GB & 480GB
		Changed	NVIDIA Quadro P6000 Graphics specs
February 11, 2019	eptember 26, 2018 From v9 to v10 ebruary 11, 2019 From v10 to v11		NVIDIA Quadro RTX 5000 16GB and NVIDIA Quadro RTX 6000 24GB Graphics,
1 2010		Added	added Intel Core i9-9980XE, Intel Core i9-9920X, Intel Core i9-9820X and
			Intel Core i7-9800X processors
		Changed	Storage section and Format changes
May 9, 2010	Erom u11 to u12		
May 8, 2019	From v11 to v12	Changed Changed	Storage and Graphics sections
June 12, 2019	From v12 to v13	Changed Changed	Storage section
June 24, 2019	From v13 to v14	Changed Changed	RAID Support
July 15, 2019	From v14 to v15	Changed Changed	Corrected Intel 905p Series AIC 480GB PCIe SSD
July 18, 2019	From v15 to v16	Changed Changed	HP SD 4 Card Reader part number
July 23, 2019	From v16 to v17	Changed	Windows 10 Pro High End added to Processors and under Intel Core X-series
			Processors Preinstalled
	F 4 F 4 F		Power supply-high end section re-arranged
September 1, 2019	From v17 to v18	Added	Footnote to Memory section, Added HP Z Turbo Drive 1TB SED TLC Z4/Z6 G4
			SSD Kit & module to Storage section, Added Intel® Wi-Fi 6 AX200 & BT PCIe t
			Networking section
October 26, 2019	From v18 to v19	Changed	Graphics section
November 1, 2019	From v19 to v20	Added	HP QX310 Removable NVMe Frame/Carrier w/PCIe card to Optical and
			Removable Storage section
December 5, 2019	From v20 to v21	Added	Intel Xeon W-2200, Intel Core i9-10900X X-series processors and added new
			HP Z4 G4 Memory Cooling Solution on Other Hardware section
		Changed	Storage / Hard Drives, Memory and System Board sections
January 2, 2020	From v21 to v22	Changed	Front I/O and Rear I/O Overview subsections and changed Storage section
February 6, 2020	From v22 to v23	Changed	Storage / Hard Drives, Optical and Removable Storage and Physical Security
			and Serviceability
June 5, 2020	From v23 to v24	Added	AMD Radeon Pro W5500 and AMD Radeon Pro W5700 to Graphics section
		Changed	HARD DRIVE CONTROLLERS section
January 5, 2021	From v24 to v25	Changed	Processors, Memory, Graphics, Racking and Physical Security, Operating
			Systems and Hard Drives sections
January 7, 2021	From v25 to v26	Changed	Hard Drives section
February 1, 2021	From v26 to v27	Changed	NETWORKING AND COMMUNICATIONS section
March 1, 2021	From v27 to v28	Changed	Overview and Memory sections
<u>Mai (11 1, 2021</u>			

Summary of Changes

April 21, 2021	From v29 to v30	Changed	Memory section
May 1, 2021	From v30 to v31	Changed	Graphics and Software sections
June 1, 2021	From v31 to v32	Changed	Memory section
July 1, 2021	From v32 to v33	Changed	Graphics section
July 16, 2021	From v33 to v34	Changed	Racking and Physical Security section
August 1, 2021	From v34 to v35	Changed	Graphics section
September 1, 2021	From v35 to v36	Changed	Input Devices, Graphics and Memory sections
October 1, 2021	From v36 to v37	Changed	Processor Matrix, Graphics and System Board sections
December 1, 2021	From v37 to v38	Changed	Operating Systems, Graphics, Networking and Communications and Input
		_	Devices sections
December 15, 2021	From v38 to v39	Changed	OPERATING SYSTEM and Social and Environmental Responsibility sections
January 1, 2022	From v39 to v40	Changed	Graphics, OPERATING SYSTEM and Application Software sections
February 1, 2022	From v40 to v41	Changed	Input Devices section
March 1, 2022	From v41 to v42	Changed	Graphics, Social and Environmental Responsibility sections
April 1, 2022	From v42 to v43	Changed	Processors, Graphics and Stable & Consistent Offerings sections
May 2, 2022	From v43 to v44	Changed	Graphics section
June 1, 2022	From v44 to v45	Changed	Graphics, Networking and Communications sections
July 1, 2022	From v45 to v46	Changed	SATA Hard Drives, Graphics, NETWORKING AND COMMUNICATIONS sections
September 1, 2022	From v46 to v47	Changed	Format page 18

title

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Technical Specifications

HP Z34c G3 WQHD Curved Display

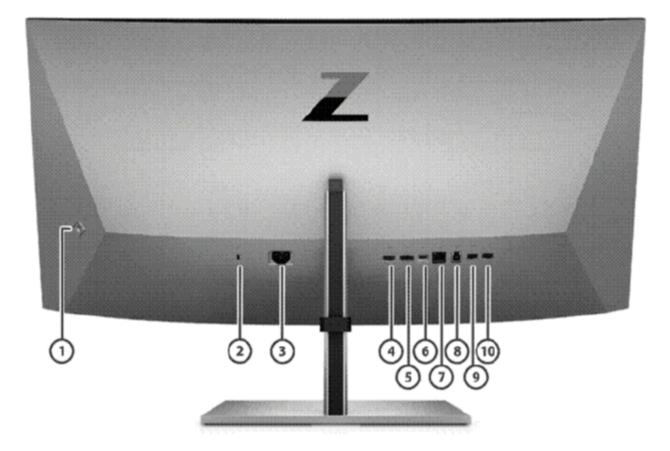


- 1. Tilt levers
- 2. Microphones (2)
- 3. Camera Light
- 4. Camera RGB Lens
- 5. Camera IR Lens

Front

- 6. Camera IR Light
- 7. Speakers
- 8. USB Ports (2)
- 9. Power Button
- 10. Power LED

Technical Specifications HP Z34c G3 WQHD Curved Display



- 1. OSD Button
- 2. Security Cable Slot
- 3. Power Connector
- 4. HDMI Port
- 5. DisplayPort[™] connector

- Back
- 6. USB Type-C®?
- 7. RJ-45 (Network) Port
- 8. USB-B Port (Upstream)
- 9. USB Port (Includes KVM connection)
- 10. USB Port

Model: 30A19AA		
Panel Specifications	Display Size (Diagonal)	34 inches
	Panel Technology	IPS
	Curved	1900R
	Max Refresh Rate	60Hz
	Panel Bit Depth	1.07B colors / 10 bit (8bit + FRC)
	Aspect Ratio	21:9
	Brightness (Typical)	350 nits
	Contrast Ratio (Static)	1,000: 1
	Dynamic Contrast Ratio	10M:1
	Flicker Free	Yes
	Pixel Pitch	0.2325 x 0.2325 mm
	Pixels Per Inch (PPI)	110 PPI
	Backlight Lamp Life Minimum	30000k
	(To Half Brightness - In Hours)	

	Backlight Type	Edge-lit
	Screen Treatment	Anti-glare
	Hardness	3H
	Haze	25
	Response Time (Typical)	6ms GtG (with overdrive)
	Horizontal Viewing Angle (Typical CR>10)	178°
	Vertical Viewing Angle (Typical CR>10)	178°
	Panel Active Area Metric (W x H)	799.8 x 334.8 mm
	Panel Active Area Imperial (W x H)	31.49 x 13.18 in
	NOTE: Performance specifications represe manufacturers; actual performance may va	nt the typical specifications provided by HP's component ry either higher or lower.
Color	sRGB	99%
	BT.709	99%
	DCI-P3	85%
Color Management	Factory Color Calibrated	Yes
	Calibrated Color Presets	sRGB, (D65), P3 (D65), BT.709 (D65), Warm, Neutral, Cool, Native, HP Enhance+
	Color Space/ Subsampling Support	RGB 4:4:4
	RGB Channel Adjust	Yes, Gain, downstream from color preset
	Default Color Temperature	6500K
Monitor Specifications	Bezel Type	3-sided borderless
	Color Of Stand	Black/ Silver
	Color Of Head	Black/ Silver
	Tilt	-5° to +10°
	Swivel	Yes, -30° to +30°
	Height Adjust Range	150mm
	Vesa Mounting	VESA Mount adapter 100 x 100 mm
	Security Lock	Standard Security Lock Slot
	Detachable Stand	Yes
	Warranty	3/3/0 for LA, NA, EMEA, APJ;
		(3/3/3 in select APJ Countries)
	Low Blue Light	Yes, HP Eye Ease (TUV Low Blue Light Hardware Solution certified)
	Zero Bright Dot Warranty	Yes
	Webcam	5 MP
	Webcam Features	Tilt/IR Sensor/Pop-up privacy
	Windows Hello Compatible	Yes
	Microphone	Yes (noise cancelling)
	Speaker Output Power	2 x 5W
	Certified Collaboration Software	Zoom
	Display Software	HP Display Center, HP Display Manager*
		*(GUIDE USERS TO SOFTWARE URL. HP DISPLAY CENTER: https://www.microsoft.com/en-us/p/hp- display-
		center/9nt6fq9kqf90#activetab=pivot:overviewtab
On Screen Display	On Screen Display	Brightness+, Color, Image, Input, Power, Menu,
(OSD)		Management, Information, Exit

	Power Consumption- Typical	60 W
	Energy Saving/Stand By Mode	0.5 W
	Power Consumption- Max	250 W
Specs	Power Source	90 - 265 VAC 47/63
Power & Operating	Power Supply	Internal
	Manageability	PXE, WOL (In-band), MAPT (In-band)
	User Updateable Firmware	Yes
	User Presets	SRGB
	SWITCH	OSD buttons (up/down/left/right/enter)
Special Features	Picture-in-Picture, Picture-by- Picture	Yes
	KVM Keyboard Port	Yes
	ETHERNET	Yes
	USB-B (Hub enablement)	1 USB-B
	USB- A	4 SuperSpeed USB Type-A 5Gbps signaling rate
	USB Type-C® Data	1 SuperSpeed USB Type-C®? 5Gbps signaling rate (Up to 100W USB Power Delivery)
	USB Type-C® Video Input	100W USB Power Delivery, Alt Mode DisplayPort ^{TM-} 1.4)
	HDCP	DisplayPort TM and HDMI
Connector 1 3hes	HDMI	1 HDMI 2.0
Connector Types	DisplayPort™	1 DisplayPort TM 1.4
	Languages	10(German, Simplified Chinese, Traditional Chinese, English, Spanish, EU French, Italian, Japanese, Dutch (Nederlands), Brazilian Portuguese)
	Audio	Built-in speakers
	User-Assignable Function Buttons	Yes, 4 (7 Options)
	User Programmable Modes	Yes, 16
	Maximum Pixel Clock	323.3 MHz
	Maximum Horizontal Scan Rate	89.8 kHz
	Minimum Horizontal Scan Rate	87.9 kHz
	Maximum Vertical Scan Rate	61 Hz
	Minimum Vertical Scan Rate	59 Hz
		3440 x 1440 @ 50 Hz (HDMI only)
		2560 x 1440 @ 60 Hz 3440 x 1440 @ 60 Hz
		2560 x 1080 @ 60 Hz
		1920 x 1200 @ 60 Hz
		1920 x 1080 @ 60 Hz
		1680 x 1050 @ 60 Hz
		1440 x 900 @ 60 Hz 1600 x 900 @ 60 Hz
		1280 x 1024 @ 60 Hz
		1280 x 800 @ 60 Hz
		1280 x 720 @ 60 Hz
		1024 x 768 @ 60 Hz
	Resolutions	800 x 600 @ 60 Hz
	Preset Graphic Modes/Supported Resolutions	640 x 480 @ 60Hz 720 x 400 @ 70 Hz
	Maximum Resolution	3440 x 1440 @ 60 Hz
		10-bit color using one DP, HDMI, or USB-C (DP alt mod
		must be capable of supporting 3440 x 1440 at 60 Hz with
		NOTE: DisplayPort 1.2 or HDMI 1.4 required to drive pane at its native resolution. The video card of the connected F

	Operational Mode at 115 VAC	29.37 W		
	Operational Mode at 230 VAC	29.41 W		
EU Energy	On-mode Power Consumption	40.12 W		
Efficiency Class (ErP LOT-5)	Energy Efficiency Class	2 G		
Operating	Operating Temperature - Celsius	5° - 35°C		
Conditions	Operating Temperature - Fahrenheit			
	Non-Operating Temperature - Celsius	-40° - 65°C		
	Non-Operating Temperature - Fahrenheit	-40° - 149°F		
	Operating Humidity	20 - 80% Relative Humidit	y (non-condensing)	
	Non-Operating Humidity	5 - 95%		
	Operating Altitude	0 - 5,000 m (16,400 ft.)		
	Non-operating Altitude	<u>0 - 12,192 m (40,000 ft.)</u>		
Certifications and Compliances	Agency Approvals and Certifications	WW application CE/ CB/ KC/ KCC/ NOM/ PSB/ ICE/ TUV-S/ ISO 9241-307/ EAC/ UL/ CSA/ PSB/ ISC/ CCC/ CEL/ CECP/ SEPA/ TCO/ TCO Certified Edge/ Energy Sta Erp lot 5/ Ergo/ HW low blue light / ISC/ VCCI/ FCC/ BSMI/ WEEE/ Zoom Certified/ Window Hello		
	Microsoft WHQL Certification	Win 10		
	SmartWay Transport Partnership - NA only	Yes (NA sku)		
			1	
		Metric	<u>Imperial</u>	
Unit Product/Package Specifications	Product Dimensions (Unpacked with stand) (W x D x H)	81.38 x 27.25 x 58.52 cm	32.04 x 10.73 x 23.04 in	
	Product Dimensions (Packed) (W x D x H)	95.2 x 22.6 x 50.4 cm	37.48 x 8.9 x 19.84 in	
	Display Head Dimensions (Unpacked without stand) (W x D x H)	81.38 x 10.5 x 38.92 cm	32.04 x 4.13 x 15.32 in	
	Base Area Footprint	300 x 250 mm	11.81 x 9.84 in	
	Bezel Measurements	top 1.6 mm	top 0.06 in	
	(Unpacked with stand) (W x D x H)	side 1.6 mm	side 0.06 in	
		bottom 42 mm	bottom 1.65 in	
	Product Weight (Unpacked with stand)	11.1 kg	24.47 lb	
	Product Weight (Packed)	16.2 kg	35.7 lb	
	Product Weight (Head Only)	8.6 kg	19 lb	
Pallet Information	Pallet Dimensions (L x W x H mm)	Slip Sheet: 1130 x 952 x 2016 mm (20' ft & 40' ft & 40HQ) Pallet: 1130 x 952 x 2144 mm (20' ft & 40' ft & 40HQ)	Slip Sheet: 44.49 x 37.48 x 79.37 inc (20' ft & 40' ft & 40HQ) Pallet: 44.49 x 37.48 x 84.41 inc (20' ft & 40' ft & 40HQ)	
	Pallet Total Weight	Slip Sheet: 328.9 kg (20' ft & 40' ft & 40HQ) Pallet: 342.7 kg (20' ft & 40' ft & 40HQ)	Slip Sheet:725.1 lb (20' ft & 40' ft & 40HQ) Pallet: 755.52 lb (20' ft & 40' ft & 40HQ)"	

Technical Specifications

	Pallet Product per Layer	5 per layer (slip sheet & pallet)	
	Total Products per Pallet	20 sets per pallet (slip sheet & pallet)	
	Container Load, 20-Foot	240 sets (slip sheet and pallet)	
	Container Load, 40-Foot	480 sets (slip sheet and pallet)	
	Container Load, 40-Foot HighQ	480 sets (slip sheet and pallet)	
What's in the box?	AC power cord (1.8m) 6.2 ft DP cable (1.8m) 6.2 ft USB-A-B (1.8m) 6.2 ft HDMI cable (1.8m) 6.2 ft USB-C-C (1.8m) 6.2 ft Warranty Card QSP Color calibration report VESA Adapter		
User Guide and Warranty Languages	User Guide Languages	Arabic, Bahasa Indonesia, Bulgarian, Chinese-S, Chinese-T, Czech, Danish, Dutch, English, Estonian, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Kazakh, Korean, Latvian, Lithuanian, Norwegian, Polish, Portuguese (Brazilian), Portuguese (Iberian), Romanian, Russian, Serbian, Slovak, Slovenian, Spanish, Swedish, Thai, Turkey, Ukrainian	
	Warranty Languages	Arabic, Bahasa Indonesia, Bulgarian, Chinese-S, Chinese-T, Czech, Danish, Dutch, English, Estonian, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Kazakh, Korean, Latvian, Lithuanian, Norwegian, Polish, Portuguese (Brazilian), Portuguese (Iberian), Romanian, Russian, Serbian, Slovak, Slovenian, Spanish, Swedish, Thai, Turkey, Ukrainian	

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT® Gold: registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label*
Sustainable Impact Specifications	 Ocean-bound plastic in (Webcam, Holder Deco, Joystick) 80% post-consumer recycled plastic Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable Recycled Plastic cushions
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook"?.

Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC	. 60Hz	230VAC, 50Hz	1	00VAC, 50Hz
Normal Operation	29.37		29.44 W		29.41 W
(Short idle)	0.07		0.07.11/		0.05.11/
<u>Sleep</u> Off	0.27		0.27 W 0.13 W		0.25 W 0.13 W
	model family applicable U computers. It energy efficie	. HP compu .S. Environr f a model fa ency data lis	sted is for an ENERGY ST uters marked with the ENE mental Protection Agency mily does not offer ENER sted is for a typically config and a Microsoft Windows	RGY STAR® Log (EPA) ENERGY S GY STAR® compl gured PC featuring	STAR® specifications for iant configurations, then g a hard disk drive, a high
Heat Dissipation*	115VAC	, 60Hz	230VAC, 50Hz	1	00VAC, 50Hz
Normal Operation					
(Short idle)	100.45 E		100.68 BTU/hr		00.58 BTU/hr
Sleep	0.92 B		0.92 BTU/hr		0.86 BTU/hr
Off	0.44 B *NOTE: Hea level is attain	t dissipatior	0.44 BTU/hr n is calculated based on th nour.		0.44 BTU/hr s, assuming the service
Longevity and Upgrading Additional Information	 This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the spare parts are available throughout the warranty period and or for up to "5"? years after the end of production. This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see http://www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product is 97.9% recycle-able when properly disposed of at end of life. 				
Packaging Materials	External:	PAPER/C	corrugated		2936 g
		PAPER/P	aperboard		950 g
	Internal:	PLASTIC	/Polyethylene Expanded -	EPE	210 g
	The plastic packaging material contains at least 12.6% recycled content.				
RoHS Compliance	The corrugated paper packaging materials contains at least 100% recycled conterHS ComplianceHP Inc. complies fully with materials regulations. We were among the first companieextend the restrictions in the European Union (EU) Restriction of Hazardous Substation(RoHS) Directive to our products worldwide through the HP GSE. HP has contributeddevelopment of related legislation in Europe, as well as China, India, and Vietnam.We believe the RoHS directive and similar laws play an important role in promotingwide elimination of substances of concern. We have supported the inclusion of addisubstances-including PVC, BFRs, and certain phthalates-in future RoHS legislationpertains to electrical and electronics products.We met our voluntary objective to achieve worldwide compliance with the new EU Rrequirements for virtually all relevant products by July 2013, and we will continue toscope of the commitment to include further restricted substances as regulations co			he first companies to Izardous Substances P has contributed to the , and Vietnam. le in promoting industry- nclusion of additional RoHS legislation that	

Technical Specifications

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	To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.				
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):				
	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants - may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DBP) Diisobutyl phthalate (DBP) Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyl (PBBs) Polybrominated Biphenyl (PCB) Polychlorinated Biphenyl (PCT) Polychlorinated Terphenyls (PCT) Polychlorinated Terphenyls (PCT) Polychlorinated Biphenyl (PCT) Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) 				
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in 				
	 packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. 				
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.				
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.				

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Technical Specifications

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HP, Inc. Corporate Environmental	For more information about HP's commitment to the environment:
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and
• • •	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1- 2018 standard.
	 External power supplies, WWAN modules, power cords, cables and peripherals excluded.
	 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
	 Plastic cushions are made from >90% recycled plastic.

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Summary

Change Log			
November 2, 2021	V1 to V2	Update	Native Resolution section
November 11, 2021	V2 to V3	Add	Environmental Data
	V3 to V4		

Technical Specifications

HP Z40c G3 WUHD Curved Display



- 1. Tilt levers
- 2. Microphones (2)
- 3. Camera Light
- 4. Camera RGB Lens
- 5. Camera IR Lens
- 6. Camera IR Light

Front

- 7. Speakers
- 8. USB Ports (2)
- 9. PbP or Brightness buttons
- 10. Power Button
- 11. Power LED

Technical Specifications

HP Z40c G3 WUHD Curved Display



- 1. **OSD Button**
- 2. Security Cable Slot
- 3. **Power Connector**
- 4. **HDMI Port**

- Back DisplayPort™ connector 5.
- 6. Thunderbolt ports (2)
- RJ-45 (Network) Port 7.
- 8. USB Ports (2)

Model: 3A6F7AA		
Panel Specifications	Display Size (Diagonal)	39.7 inches
-	Panel Technology	IPS
	Curved	2500R
	Max Refresh Rate	60HZ
	Native Resolution	WUHD (5120 x 2160)
	Panel Bit Depth	10 bit (8bit +FRC)
	Aspect Ratio	21:9
	Brightness (Typical)	300 nits
	Contrast Ratio (Static)	1,000: 1
	Dynamic Contrast Ratio	10M:1
	Flicker Free	Yes
	Pixel Pitch	0.18 x 0.18mm
	Pixels Per Inch (PPI)	139 PPI
	Backlight Lamp Life Minimum (To Half Brightness - In Hours)	30k
	Backlight Type	Edge-lit
	Screen Treatment	Anti-glare
	Hardness	3H

	Haze	25%	
	Response Time (Typical)	14ms GtG	
	Horizontal Viewing Angle		
	(Typical CR>10)	178°	
	Vertical Viewing Angle	178°	
	(Typical CR>10)		
	Panel Active Area Metric (W x H)	92.928 x 39.204 cm	
	Panel Active Area Imperial (W x H)	36.59 x 15.43 in	
	NOTE: Performance specifications represent manufacturers; actual performance may variable.	nt the typical specifications provided by HP's component y either higher or lower.	
Color	sRGB	100%	
	DCI-P3	98%	
	BT.709	100%	
Color Management	Factory Color Calibrated	Yes	
Ŭ	Calibrated Color Presets	DCI P3 D65, BT.709, sRGB D65	
	Color Space/ Subsampling Support	RGB 4:4:4, YCBCR 4:4:4, YCBCR 4:2:2	
	RGB Channel Adjust	Yes, Gain	
	Default Color Temperature	DCI P3 (D65)	
Monitor Specifications	Bezel Type	3-sided borderless	
	Color Of Stand	Black/ Silver	
	Color Of Head	Black/ Silver	
	Tilt	-5° to +20°	
	Swivel	±30°	
	Height Adjust Range	150 mm	
	VESA Mounting	100 mm x 100 mm (bracket included)	
	Security Lock	Standard Security Lock Slot	
	Detachable Stand	Yes	
	Warranty	3/3/0 for LA, NA, EMEA, APJ; (3/3/3 in select APJ Countries)	
	Low Blue Light	Yes, HP Eye Ease (TUV Low Blue Light Hardware Solution certified)	
	Zero Bright Dot Warranty	Yes	
	Webcam	13 MP	
	Webcam Features	Independent tilt -20° to 5°; Windows Hello support (IR Sensor); Pop-up privacy	
	Windows Hello Compatible	Yes	
	Microphone	Yes (noise cancelling)	
	Speaker Output Power	2 x 5W	
	Certified Collaboration Software	Zoom	
	Display Software	HP Display Center, HP Display Manager*	
		*Host PC requires Windows 10. HP Display Center is available on the Microsoft store.	
On Screen Display (OSD)	On Screen Display	Brightness+, Color, Image, Input, PbP, Power, Menu, Management, Exit	
·/	Native Resolution	WUHD (5120 x 2160)	
		 NOTE: DisplayPort 1.4 or HDMI 2.0 required to drive panel at its native resolution. The video card of the connected PC must be capable of supporting 5120 ? 2160 at 60 Hz with 10-bit color using one DP, HDMI, or USB-C (DP alt mode). 	
	Maximum Resolution	5120?2160 @60Hz	
	Preset Graphic Modes/Supported Resolutions	640 x 480 @ 60 Hz 720 x 400 @ 70 Hz 800 x 600 @ 60 Hz 1024 x 768 @ 60 Hz 1280 x 800 @ 60 Hz	

	1	
		1280 x 1024 @ 60 Hz
		1440 x 900 @ 60 Hz
		1600 x 900 @ 60 Hz
		1600 x 1200 @ 60 Hz
		1680 x 1050 @ 60 Hz
		1920 x 1080 @ 60 Hz
		1920 x 1200 @ 60 Hz
		2560 x 1440 @ 60 Hz
		2560 x 1600 @ 60 Hz
		2560 x 2160 @ 60 Hz (PbP)
		3840 x 2160 @ 30 Hz
		3840 x 2160 @ 50 Hz
		4096 x 2160 @ 30 Hz
		4096 x 2160 @ 30 Hz
		5120 x 2160 @ 30 Hz
		5120 x 2160 @ 60 Hz (Except HDMI)
	Minimum Vertical Scan Rate	29 Hz
	Maximum Vertical Scan Rate	71 Hz
	Minimum Horizontal Scan Rate	15.0 kHz
	Maximum Horizontal Scan Rate	134.0 kHz
	Maximum Pixel Clock	710.0 MHz
	User-Assignable Function Buttons	Yes, 4 (8 options)
	Audio	Built-in speakers
	Languages	11 (English, Spanish, German, French, Italian,
		Netherlands, Portuguese, Japanese, T-Chinese and S-
	1	Chinese, Russian)
	1	
Connector Types	DisplayPort™	1 DisplayPort™ 1.4
	HDMI	1 HDMI 2.0
	HDCP	Yes, DisplayPort and HDMI
	USB Type-C® Video Input & Data	2 Thunderbolt 3.0 up to 40Gbps signaling rate (Up to 100W
	Transfer	USB Power Delivery, Alt Mode DisplayPort [™] ? 1.4,
		SuperSpeed USB 5Gbps signaling rate)
	USB- A	4 SuperSpeed USB Type-A 5Gbps signaling rate
	ETHERNET	Yes
Special Features	Picture-in-Picture, Picture-by-Picture	Yes, PBP only
	SWITCH	OSD buttons (up/down/left/right/enter)
		PbP or Brightness buttons (L/R when PbP on, Plus
		("+")/Minus ("-") when PbP off.
	Remote Manageability	In-Band MAPT, In-Band WoL, PXE Boot
	Video legal limiting (64-960)	Yes
	User Updateable Firmware	Yes
	Device Bridge 2.0	Yes
Power & Operating	Power Supply	Internal
Specs	Power Source	100 - 240 VAC 50/60 Hz
Specs		
	Power Consumption- Max	310 W
	Energy Saving/Stand By Mode	0.5 W
	Power Consumption- Typical	72 W
Energy Star Data	Operational Mode at 100 VAC	52.54 W
	Operational Mode at 115 VAC	52.51 W
	Operational Mode at 230 VAC	52.63 W
Ell Energy Efficiency	On mode Dewer Consumption	<u> </u>
EU Energy Efficiency	On-mode Power Consumption	51
Class (ErP LOT-5)	Energy Efficiency Class	G
Operating Conditions	Operating Temperature - Celsius	5° - 35°C
	Operating Temperature - Fahrenheit	41° - 95°F
	Non-Operating Temperature - Celsius	

	Non-Operating Temperature - Fahrenheit	-4° - 140°F		
	Operating Humidity	20 - 80% Relative Humidity (non-condensing) 5 - 95%		
	Non-Operating Humidity			
	Operating Altitude	0 - 5,000 m (16,400 ft.)		
	Non-operating Altitude	0 - 12,192 m (40,000 ft.)		
		0 12,132 m (+0,000 n.)		
Certifications and Compliances	Agency Approvals and Certifications	WW application CE, CB,KC/KCC/NOM/PSB/ISC/EAC/GS/TUV-S/ISO 9241-307/ Low Blue Light/UAE/Ukraine/South Africa/BIS/cTUVus/ISC/CCC/CEL/CECP/SEPA/Energ Star/TCO/VCCI/FCC/BSMI/E- Standby/WEEE/Zoom/Microsoft Hello		
	Microsoft WHQL Certification	Win 10		
	SmartWay Transport Partnership - NA only	Yes (NA sku)		
		Metric	Imperial	
Unit	Product Dimensions	94.74 x 29.25 x 64.48 cm	37.3 x 11.52 x 25.38 in	
Product/Package Specifications	(Unpacked with stand) (W x D x H)	94.74 X 29.25 X 04.46 Cm	37.3 X 11.32 X 23.36 III	
	Product Dimensions (Packed) (W x D x H)	107.0 x 22.6 x 55.8 cm	42.16 x 8.9 x 21.97 in	
	Display Head Dimensions (Unpacked without stand) (W x D x H)	94.74 x 14.195 x 44.71 cm	37.3 x 5.59 x 17.6 in	
	Base Area Footprint (w x d mm)	300 x 270 mm	11.81 x 10.63 in	
	Bezel Measurements (Unpacked with stand) (W x D x H)	42.6 mm	1.68 in	
	Product Weight (Unpacked with stand)	14.3 kg	31.53 lb	
	Product Weight (Packed)	20.6 kg	45.42 lb	
	Product Weight (Head Only)	11.62 kg	25.62 lb	
Pallet Information	Pallet Dimensions (L x W x H mm)	1080 x 1150 x 1801 mm (Gma Pallet) 1080 x 1150 x 1811 mm (Block Pallet) 1080 x 1150 x 2246.2 mm (Paper Slip Sheet)	42.52 x 45.28 x 70.91 in (Gma Pallet) 42.52 x 45.28 x 71.3 in (Block Pallet) 42.52 x 45.28 x 88.43 in (Paper Slip Sheet)	
	Pallet Total Weight	327.69Kg (GMA Pallet) 325.33Kg (Block Pallet) 420.26Kg (Paper Slip Sheet)	722.43 lb (GMA Pallet) 717.23 lb (Block Pallet) 926.51 lb (Paper Slip Sheet)	
	Pallet Layers	4 or 3 layers per (slip sheet		
	Pallet Product per Laver	5 per laver	a panety	
	Total Products per Pallet		t & pallet)	
	Container Load, 20-Foot	20sets or 15sets (slip sheet & pallet)		
	Container Load, 20-Foot	150sets (Pallet)		
		330sets (Pallet)		
	Container Load, 40-Foot HighQ	440 sets (Slip Sheet)		
What's in the box?	AC power cord (1.9m) 6.2 ft HDMI cable (1.8m) 5.9 ft DP Cable (1.8m) 5.9 ft Thunderbolt cable(1m) 3.3 ft Warranty Card QSP Color calibration report			
	VESA Adapter			

User Guide and Warranty Languages	User Guide Languages Arabic, Bahasa Indonesia, Bulgarian, Chinese-S, Chinese-T, Czech, Danish, Dutch, English, Estonia Finnish, French, German, Greek, Hebrew, Hungari Italian, Japanese, Kazakh, Korean, Latvian, Lithuan Norwegian, Polish, Portuguese (Brazilian), Portugu (Iberian), Romanian, Russian, Serbian, Slovak, Slovenian, Spanish, Swedish, Thai, Turkey, Ukrain					
	Warranty Languages	Chinese-T Finnish, F Italian, Jap Norwegiar (Iberian), I	Arabic, Bahasa Indonesia, Bulgarian, Chinese-S, Chinese-T, Czech, Danish, Dutch, English, Estonian, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Kazakh, Korean, Latvian, Lithuanian Norwegian, Polish, Portuguese (Brazilian), Portuguese (Iberian), Romanian, Russian, Serbian, Slovak, Slovenian, Spanish, Swedish, Thai, Turkey, Ukrainian			
ENVIRONMENTAL I	DATA					
Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label* 					
Sustainable Impact Specifications	 Ocean-bound plastic in Stand 85% post-consumer recycled plastic Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable Recycled Plastic cushions 					
System Configuration		or the Energy Consumption a ased on a "Typically Configu	nd Declared Noise Emissions data for			
Energy Consumption		ased on a Typically Configu				
(in accordance with US ENERGY STAR®	115VAC 60Hz	230VAC 50Hz	100VAC 50Hz			
(in accordance with US ENERGY STAR®	115VAC, 60Hz 52.33 W	230VAC, 50Hz 52.63 W	100VAC, 50Hz 5.43 W			
(in accordance with US ENERGY STAR® test method) Normal Operation (Short idle) Normal Operation		· · · ·				
(in accordance with US ENERGY STAR® test method) Normal Operation (Short idle) Normal Operation (Long idle)	52.33 W N/A	52.63 W N/A	5.43 W N/A			
(in accordance with US ENERGY STAR® test method) Normal Operation (Short idle) Normal Operation	52.33 W	52.63 W	5.43 W			
(in accordance with US ENERGY STAR® test method) Normal Operation (Short idle) Normal Operation (Long idle) Sleep	52.33 W N/A 0.32 W 0.22 W Note: Energy efficiency data lis model family. HP computers applicable U.S. Environ computers. If a model fa energy efficiency data lis	52.63 W N/A 0.37 W 0.37 W sted is for an ENERGY STAF iters marked with the ENERC mental Protection Agency (EF mily does not offer ENERGY	5.43 W N/A 0.32 W 0.22 W R® compliant product if offered within the GY STAR® Logo are compliant with the PA) ENERGY STAR® specifications for STAR® compliant configurations, then ed PC featuring a hard disk drive, a high			
(in accordance with US ENERGY STAR® test method) Normal Operation (Short idle) Normal Operation (Long idle) Sleep	52.33 W N/A 0.32 W 0.22 W Note: Energy efficiency data lis model family. HP computers applicable U.S. Environ computers. If a model fa energy efficiency data lis	52.63 W N/A 0.37 W 0.37 W sted is for an ENERGY STAF uters marked with the ENERC mental Protection Agency (EF mily does not offer ENERGY sted is for a typically configure	5.43 W N/A 0.32 W 0.22 W R® compliant product if offered within the GY STAR® Logo are compliant with the PA) ENERGY STAR® specifications for STAR® compliant configurations, then ed PC featuring a hard disk drive, a high			
(in accordance with US ENERGY STAR® test method) Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off Heat Dissipation* Normal Operation	52.33 W N/A 0.32 W 0.22 W Note: Energy efficiency data lis model family. HP compu applicable U.S. Environr computers. If a model fa energy efficiency data lis efficiency power supply, 115VAC, 60Hz	52.63 W N/A 0.37 W 0.37 W 0.37 W sted is for an ENERGY STAF uters marked with the ENERGY mental Protection Agency (EF mily does not offer ENERGY sted is for a typically configure and a Microsoft Windows® of 230VAC, 50Hz	5.43 W N/A 0.32 W 0.22 W Re compliant product if offered within the GY STAR® Logo are compliant with the PA) ENERGY STAR® specifications for STAR® compliant configurations, then ed PC featuring a hard disk drive, a high operating system. 100VAC, 50Hz			
(in accordance with US ENERGY STAR® test method) Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off Heat Dissipation* Normal Operation (Short idle)	52.33 W N/A 0.32 W 0.22 W Note: Energy efficiency data lis model family. HP compu applicable U.S. Environr computers. If a model fa energy efficiency data lis efficiency power supply,	52.63 W N/A 0.37 W 0.37 W 0.37 W sted is for an ENERGY STAF uters marked with the ENERC mental Protection Agency (EF mily does not offer ENERGY sted is for a typically configure and a Microsoft Windows® of	5.43 W N/A 0.32 W 0.22 W R® compliant product if offered within the BY STAR® Logo are compliant with the PA) ENERGY STAR® specifications for STAR® compliant configurations, then ed PC featuring a hard disk drive, a high operating system.			
(in accordance with US ENERGY STAR® test method) Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off Heat Dissipation* Normal Operation (Short idle) Normal Operation	52.33 W N/A 0.32 W 0.22 W Note: Energy efficiency data lis model family. HP compu applicable U.S. Environr computers. If a model fa energy efficiency data lis efficiency power supply, 115VAC, 60Hz	52.63 W N/A 0.37 W 0.37 W 0.37 W sted is for an ENERGY STAF uters marked with the ENERGY mental Protection Agency (EF mily does not offer ENERGY sted is for a typically configure and a Microsoft Windows® of 230VAC, 50Hz	5.43 W N/A 0.32 W 0.22 W R® compliant product if offered within the GY STAR® Logo are compliant with the PA) ENERGY STAR® specifications for STAR® compliant configurations, then ed PC featuring a hard disk drive, a high operating system. 100VAC, 50Hz			
(in accordance with US ENERGY STAR® test method) Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off Heat Dissipation* Normal Operation (Short idle)	52.33 W N/A 0.32 W 0.22 W Note: Energy efficiency data lis model family. HP compu applicable U.S. Environr computers. If a model fa energy efficiency data lis efficiency power supply, 115VAC, 60Hz 179 BTU/hr	52.63 W N/A 0.37 W 0.37 W 0.37 W sted is for an ENERGY STAF uters marked with the ENERGY mental Protection Agency (EF mily does not offer ENERGY sted is for a typically configure and a Microsoft Windows® of 230VAC, 50Hz 180 BTU/hr	5.43 W N/A 0.32 W 0.22 W Re compliant product if offered within the BY STAR® Logo are compliant with the PA) ENERGY STAR® specifications for STAR® compliant configurations, then ed PC featuring a hard disk drive, a high operating system. 100VAC, 50Hz 18.6 BTU/hr			

	*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.					
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the spare parts are available throughout the warranty period and or for up to "5"? years after the end of production.					
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see http://www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product is 98.3% recycle-able when properly disposed of at end of life. 					
Packaging Materials	External:	PAPER/Paperboard	5313 g			
	Internal:	PLASTIC/Polyethylene Expanded - EPE	162 g			
RoHS Compliance	 The plastic packaging material contains at least 57% recycled content. The corrugated paper packaging materials contains at least 90% recycled content. HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances-including PVC, BFRs, and certain phthalates-in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement. 					
Material Usage	 This product does not contain any of the following substances in excess of regule (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specific Asbestos Certain Azo Colorants Certain Brominated Flame Retardants - may not be used as flame retardar Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Disobutyl phthalate (DIBP) Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel - finishes must not be used on the external surface designed to be finishes 					

Technical Specifications				
	 handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) 			
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. 			
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other 			
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and			
footnotes	 http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. Fiber cushions made from 100% recycled wood fiber and organic materials. Plastic cushions are made from >90% recycled plastic. 			

Technical Specifications

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Summary

Change Log	-09					
January 6, 2022	V1 to V2	Add	Environmental Data			
January 10, 2022	V2 to V3	Update	Color section			
	V3 to V4					